

Business & Financial Roadmap

Carlo Ferro

Chief Financial Officer



Who We Are

2

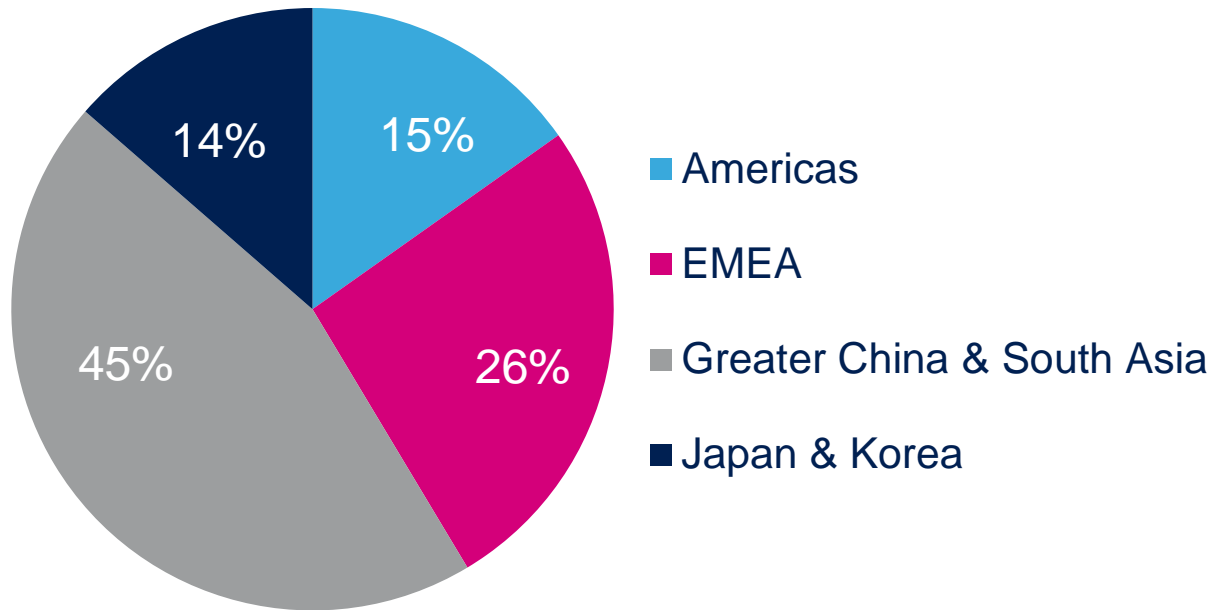
- A global semiconductor leader
- 2014 revenues of **\$7.40B**
- Listed: NYSE, Euronext Paris and Borsa Italiana, Milan

- Research & Development
- Main Sales & Marketing
- Front-End
- Back-End

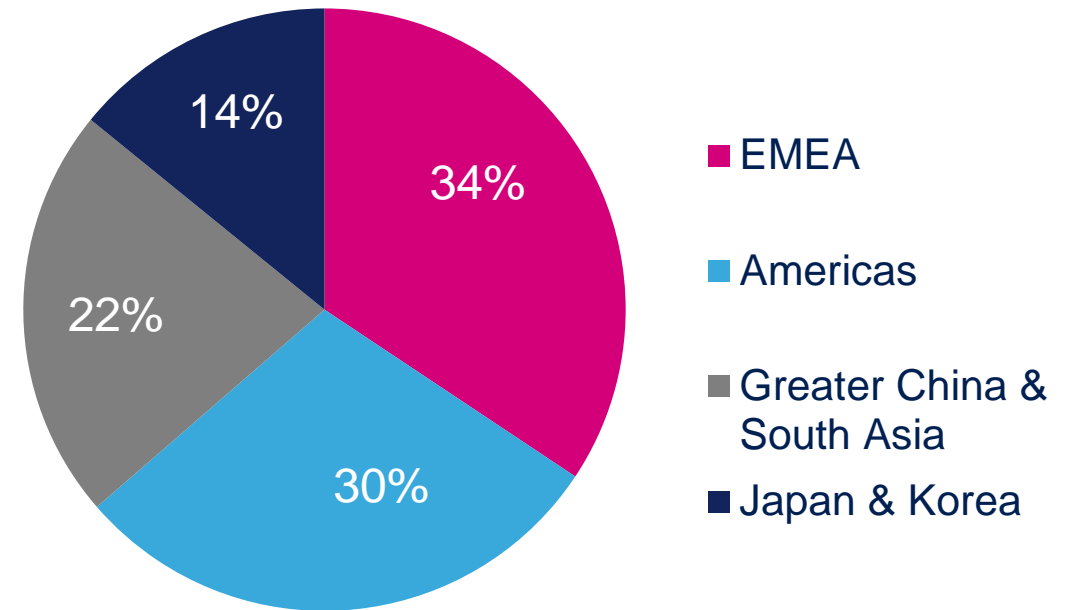
- Approximately **43,600** employees worldwide
- Approximately **8,700** people working in R&D
- **11** manufacturing sites
- Over **75** sales & marketing offices

A global Semiconductor Player

FY 14 Revenues
by shipment location



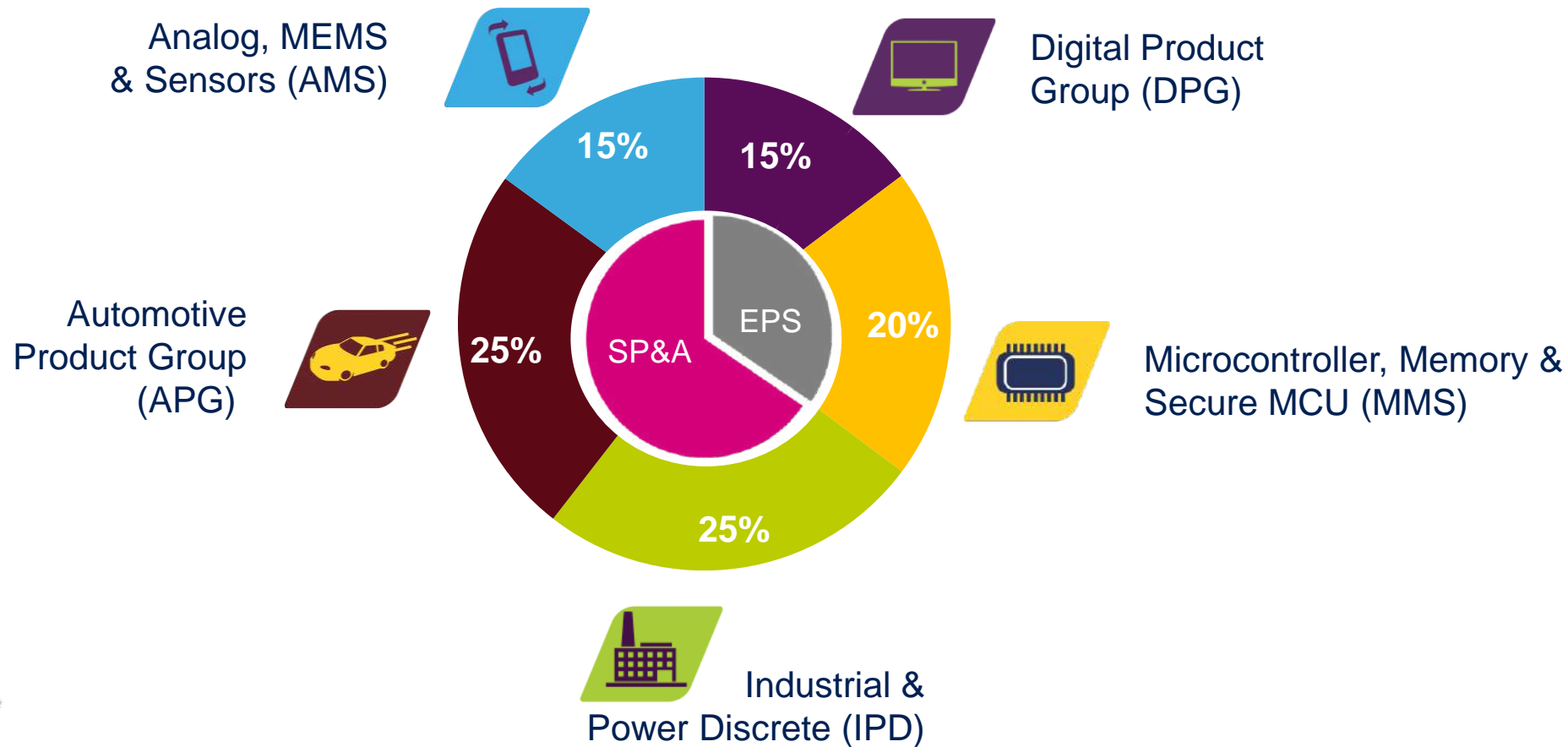
FY 14 Revenues
by region of origin



FY 14 Revenues = \$7.40B

Well diversified Product Portfolio

Revenues by Product Group FY 2014

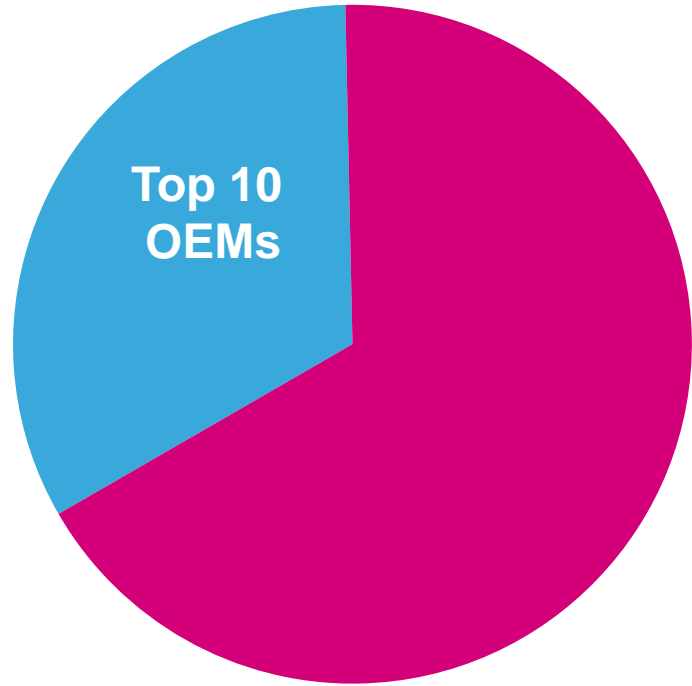


Expanding the Customer Base

Top 10 OEMs* FY 14

- Apple
- Bosch
- Cisco
- Conti
- Delta
- HP
- Microsoft
- Samsung
- Seagate
- Western Digital

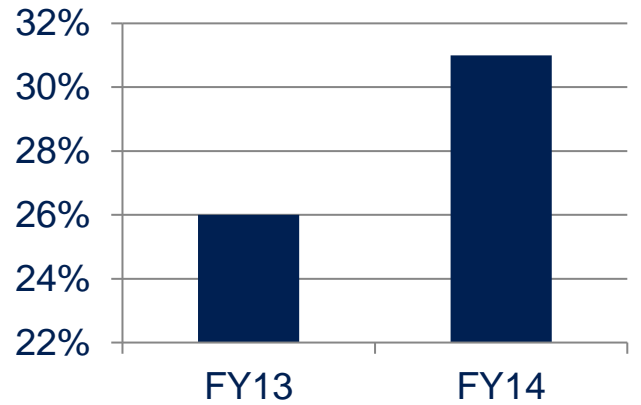
FY 14 Revenues



Top 4 Distributors* FY 14

- Arrow Electronics
- Avnet
- Wintech
- Yosun

Distribution (as % of total revenues)

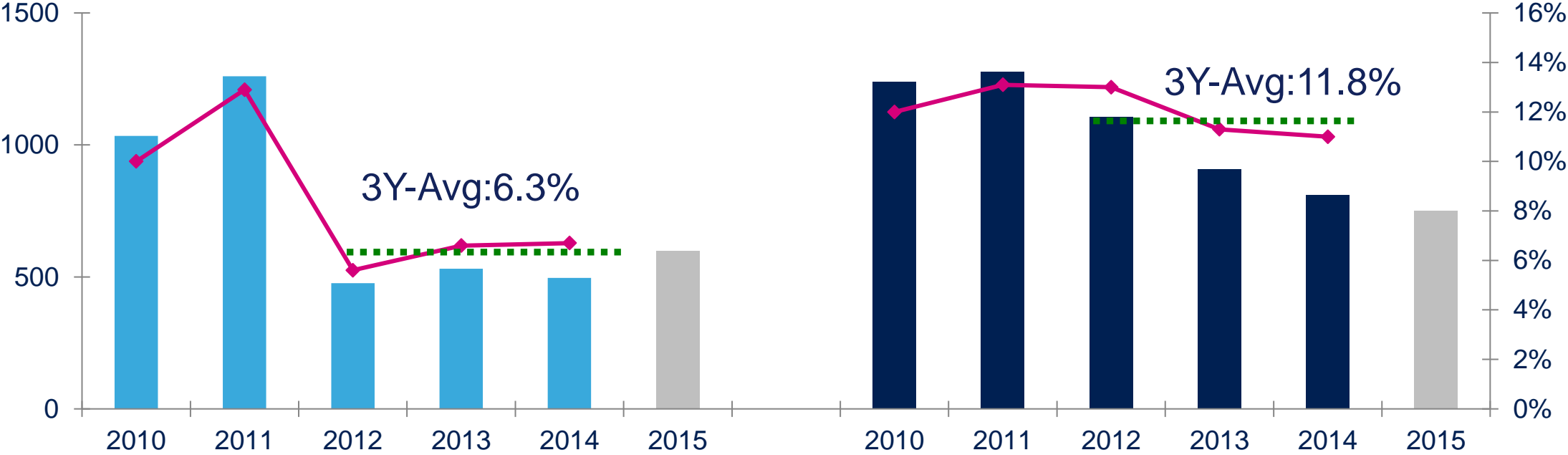


*Listed alphabetically

Stabilizing Capital Intensity

Capital Expenditures

Depreciation & Amortization

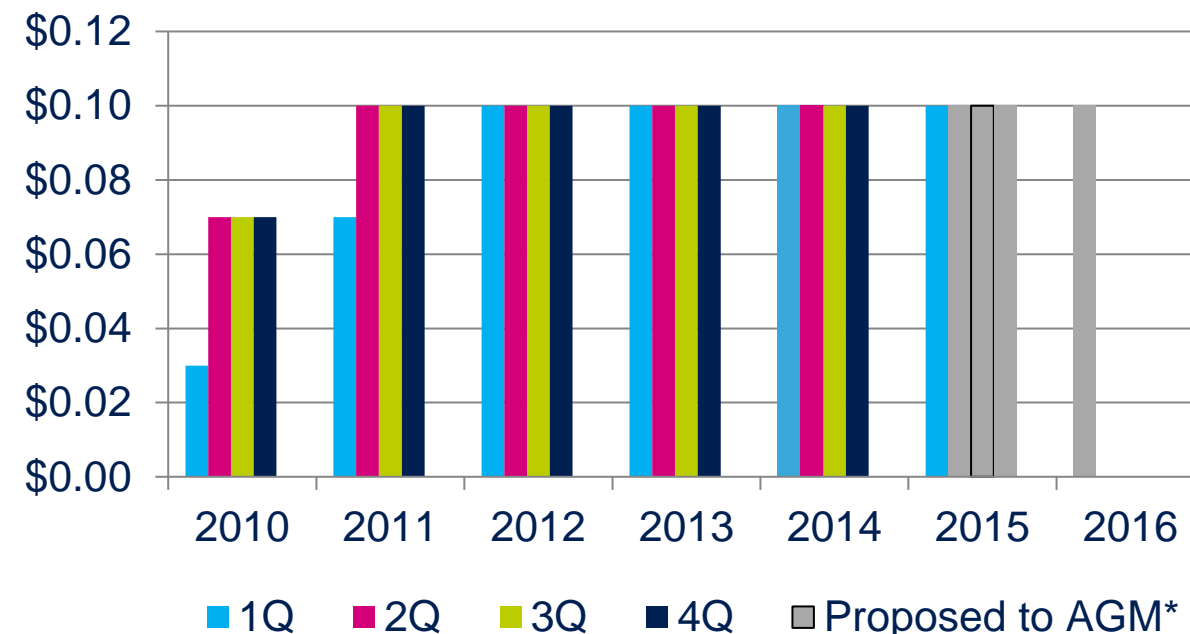


■ Capex
 ■ D&A
 ■ Outlook (US\$M)
◆ Capex / Sales and D&A / Sales (%)



Solid Capital Structure Rewarding Shareholders

End of period (US\$M)	Mar 28 2015	Dec 31 2014	Mar 29 2014
Total Liquidity	2,287	2,351	1,745
Short term debt	(200)	(202)	(225)
Long-term debt	(1,575)	(1,599)	(908)
Total Financial Debt	(1,775)	(1,801)	(1,133)
Net Financial Position*	512	550	612

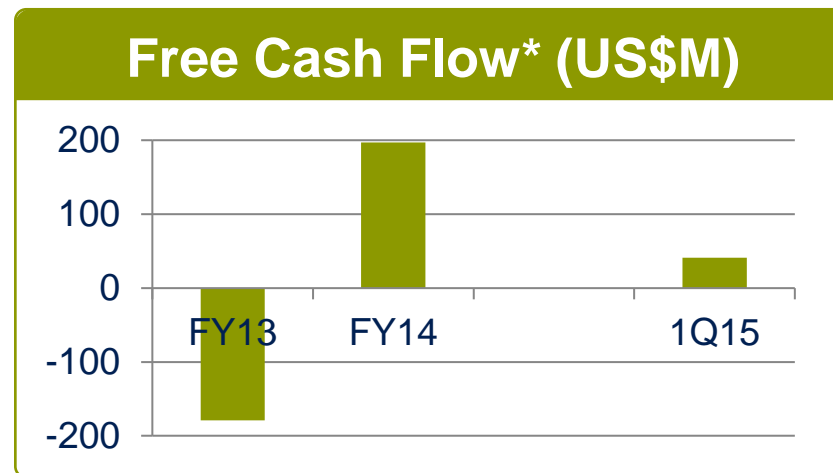
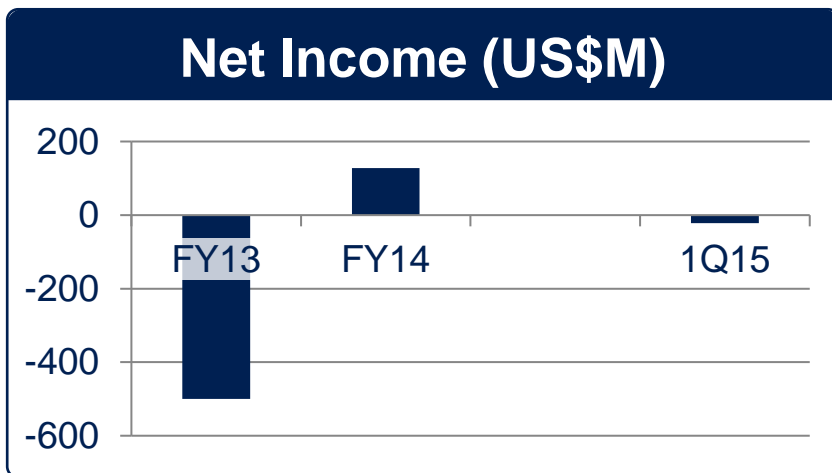
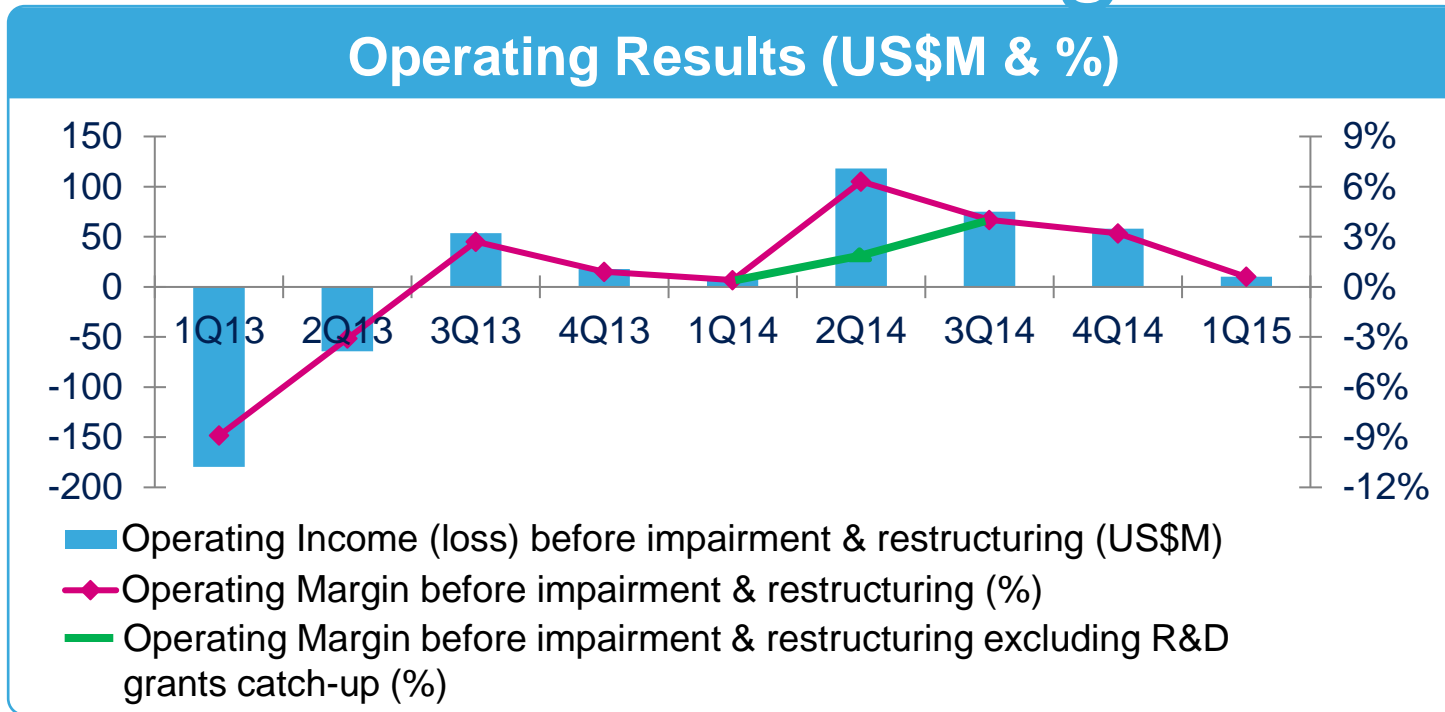
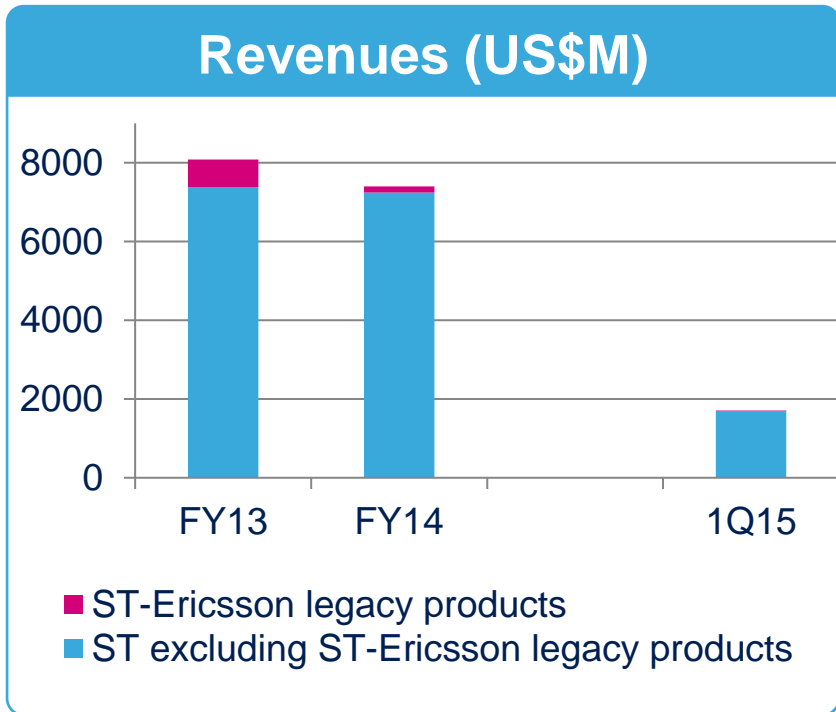


*2Q15, 3Q15, 4Q15 and 1Q16 dividend proposed to the AGM

Continuing to Reward Shareholders

Cash dividend of \$0.10 per share for each of the 2nd, 3rd, and 4th quarter of 2015 and 1st quarter of 2016 to be proposed to the 2015 AGM

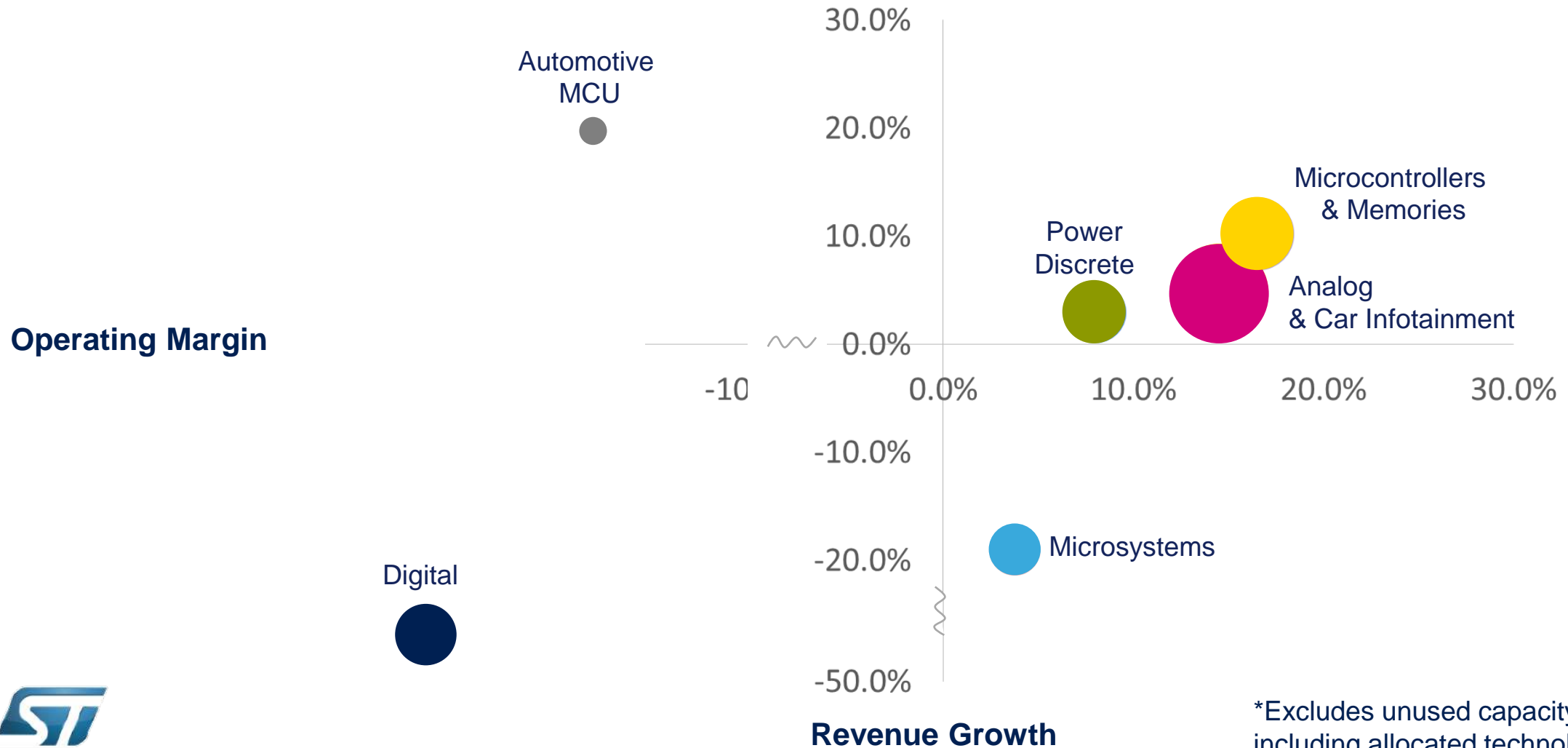
2014 – A Year of Progress



*See appendix

Business Portfolio Growth and Profitability

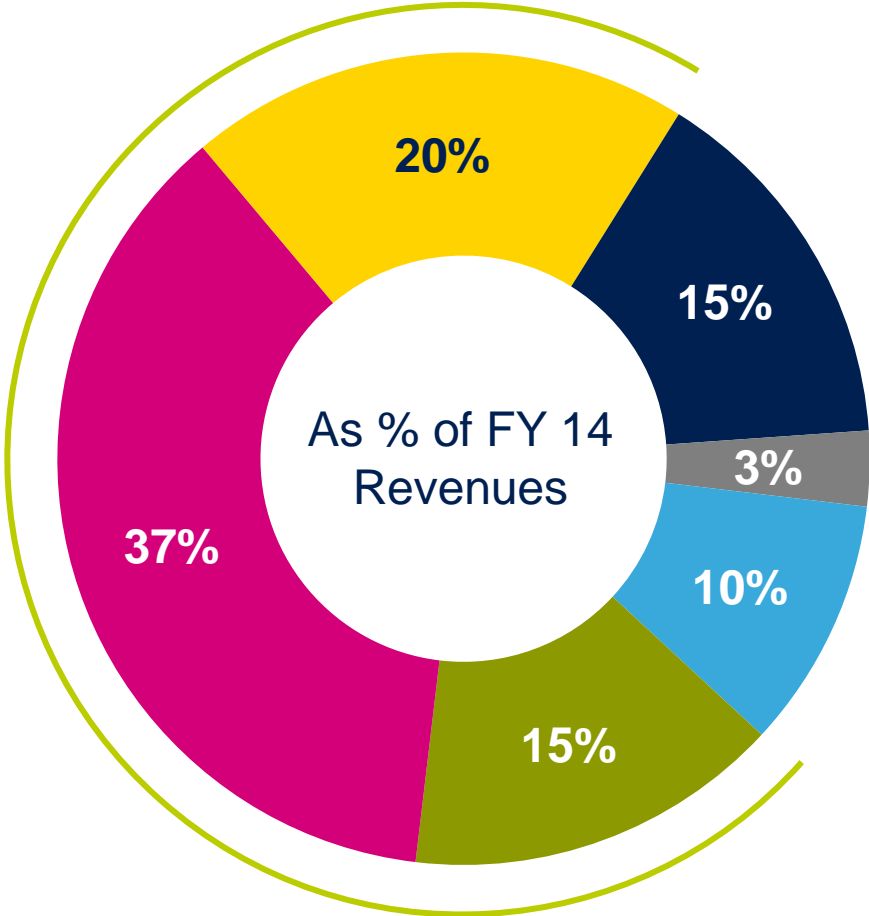
Operating Margin 2014* vs. Revenue Growth 2014/2013



*Excludes unused capacity charges and including allocated technology and SG&A

High Value Portfolio

72% of revenue generated from profitable and growing business



Action: Fix loss-making Digital business and turn investment in Specialty Image Sensors into profitability

Action: Turn investment to fast growth and profitability in Automotive MCU

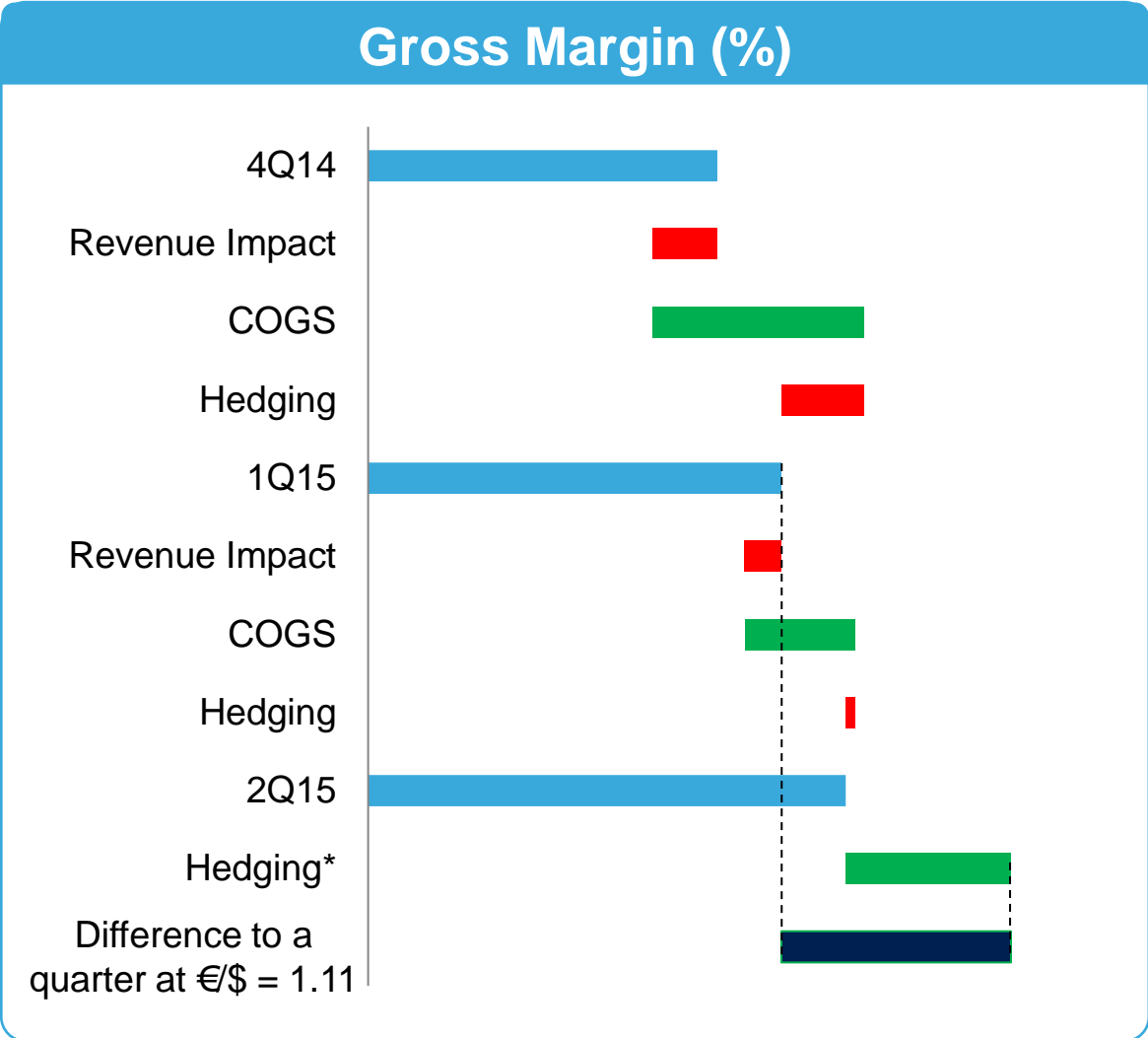
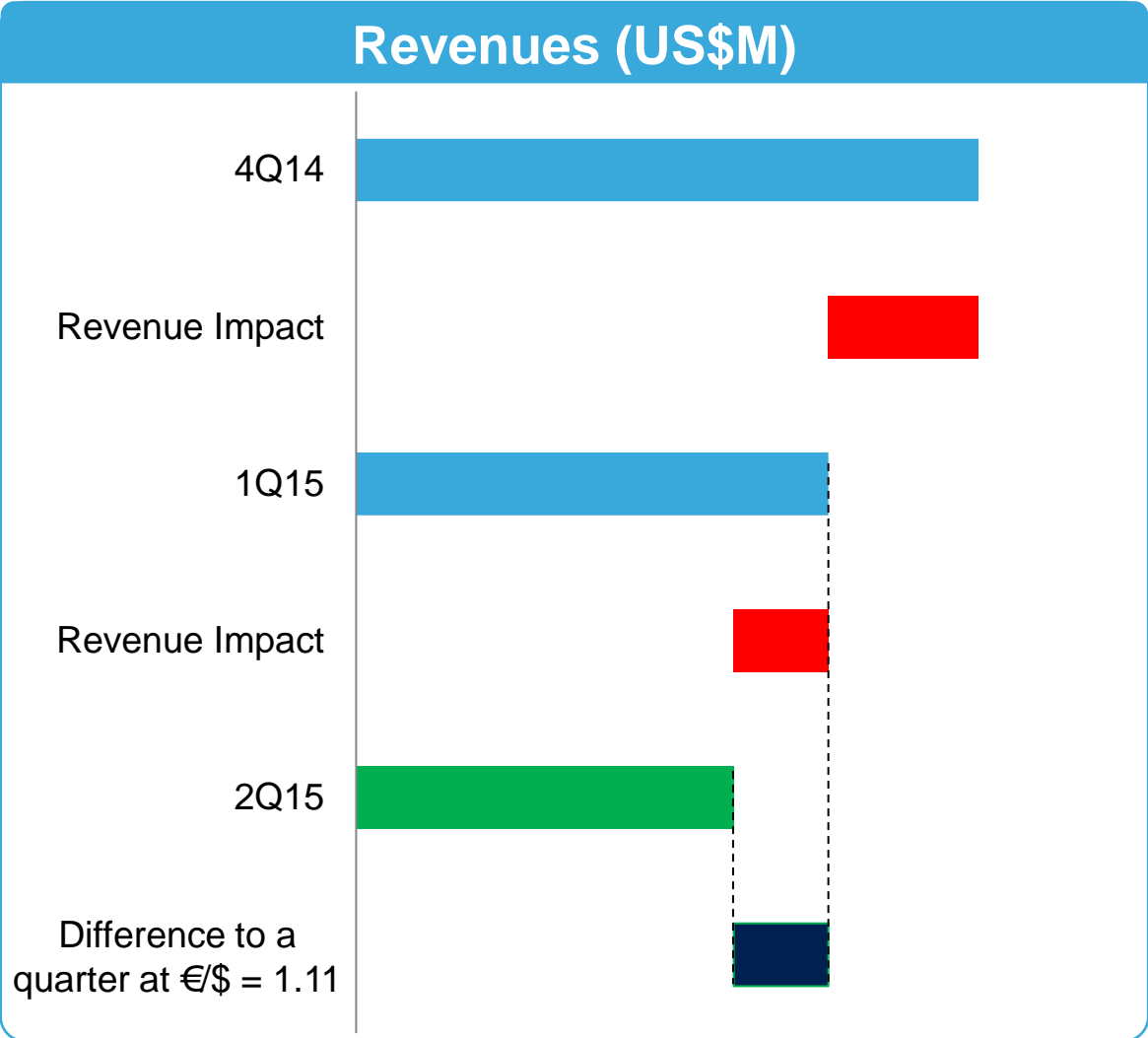
Action: Accelerate revenue growth in Microsystems

- Microcontrollers
- Microsystems

- Digital
- Power Discrete

- Automotive MCU
- Analog & Car Infotainment

Currency Impact: Most of the Benefits to Come (1 of 2)

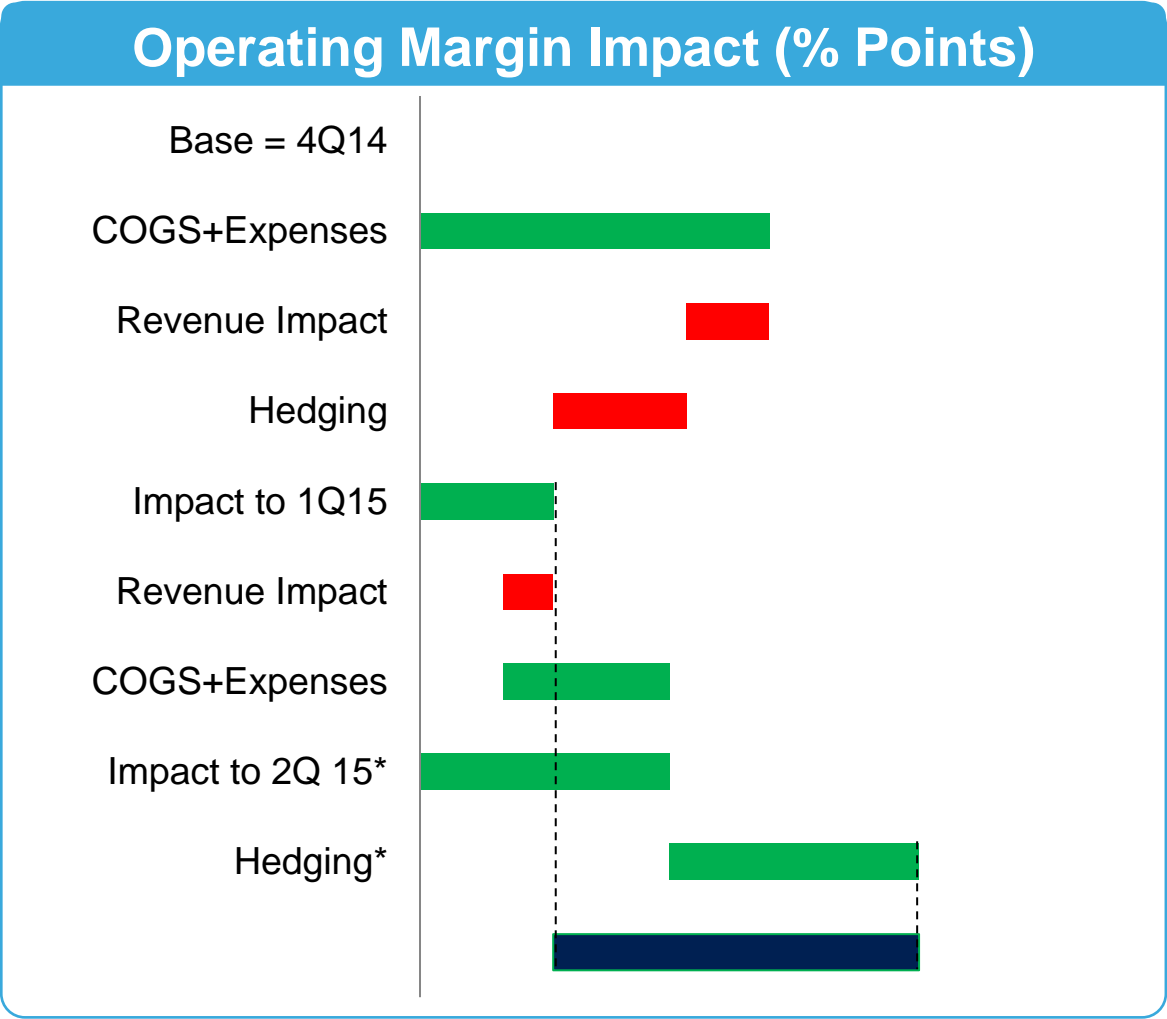
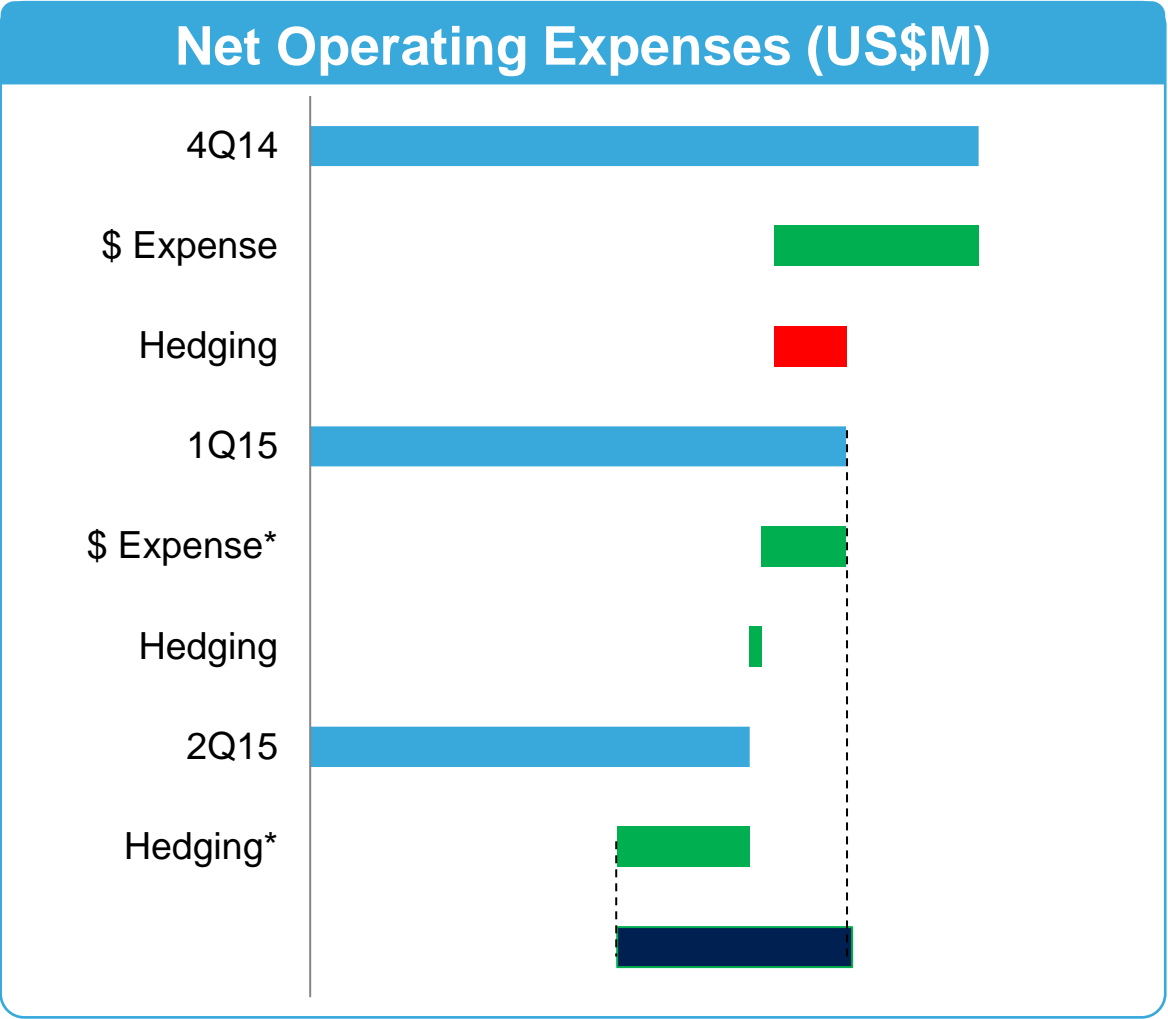


Benefit from 1Q15 ~ 250bps



* Estimates based on constant currency rate of €/\$ at 1.11

Currency Impact: Most of the Benefits to Come (2 of 2)



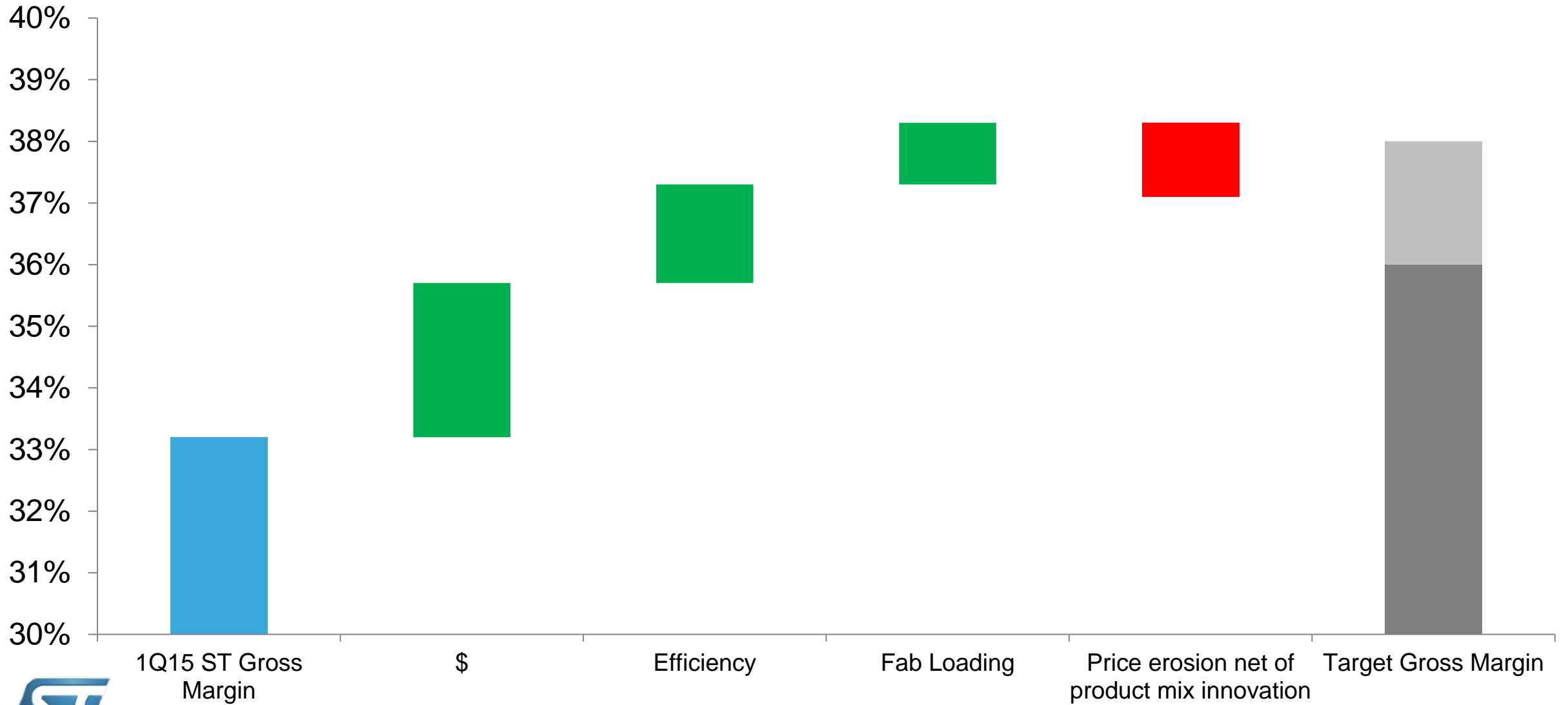
Benefit from 1Q15 ~ \$37M

Benefit from 1Q15 ~ 440bps

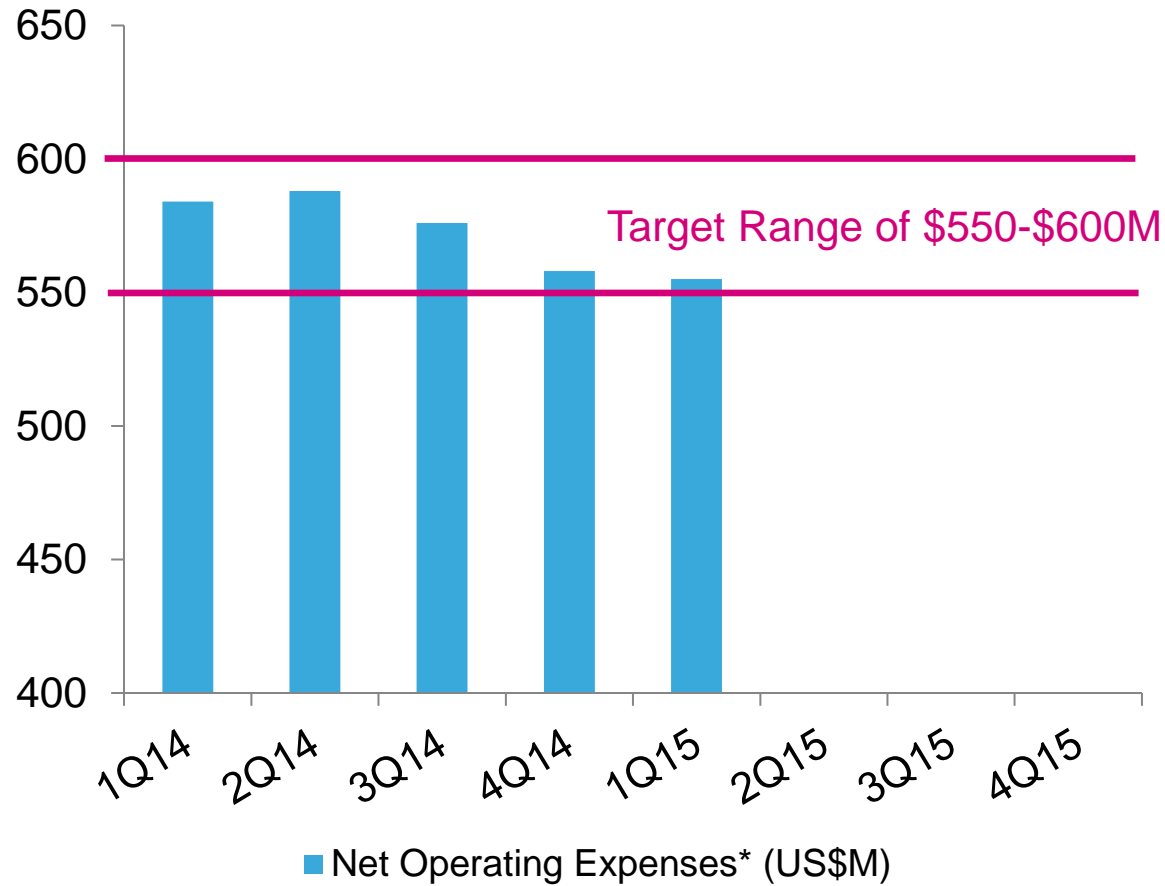
* Estimates based on constant currency rate of €/\$ at 1.11



Key Initiatives to increase Gross Margin



Net Operating Expenses on Target



Net Operating Expenses*

1Q15 SG&A and R&D, net of grants, at \$555M

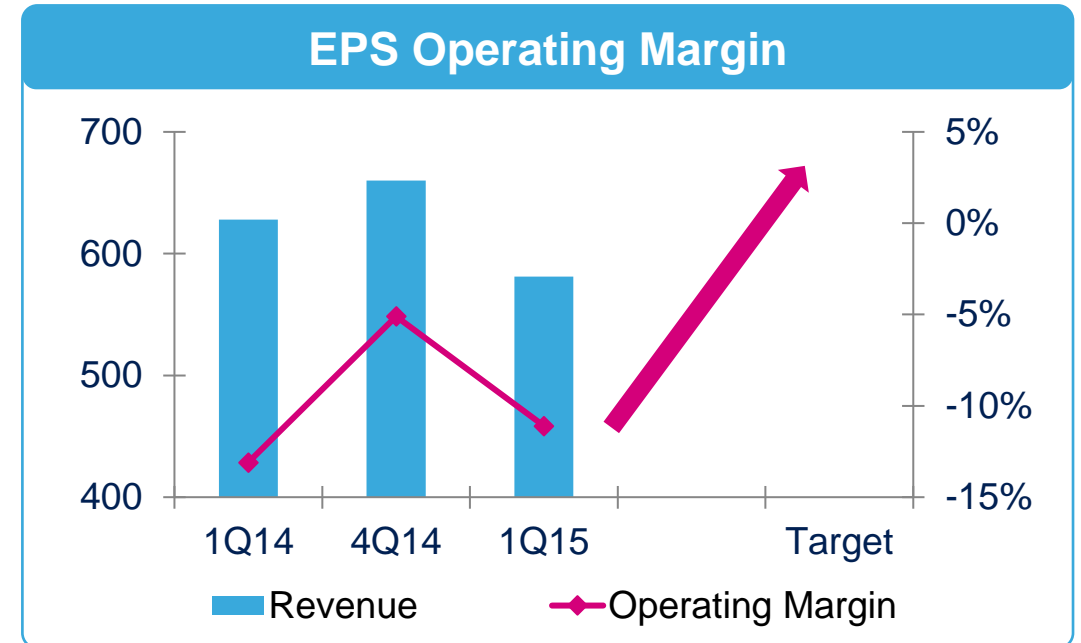
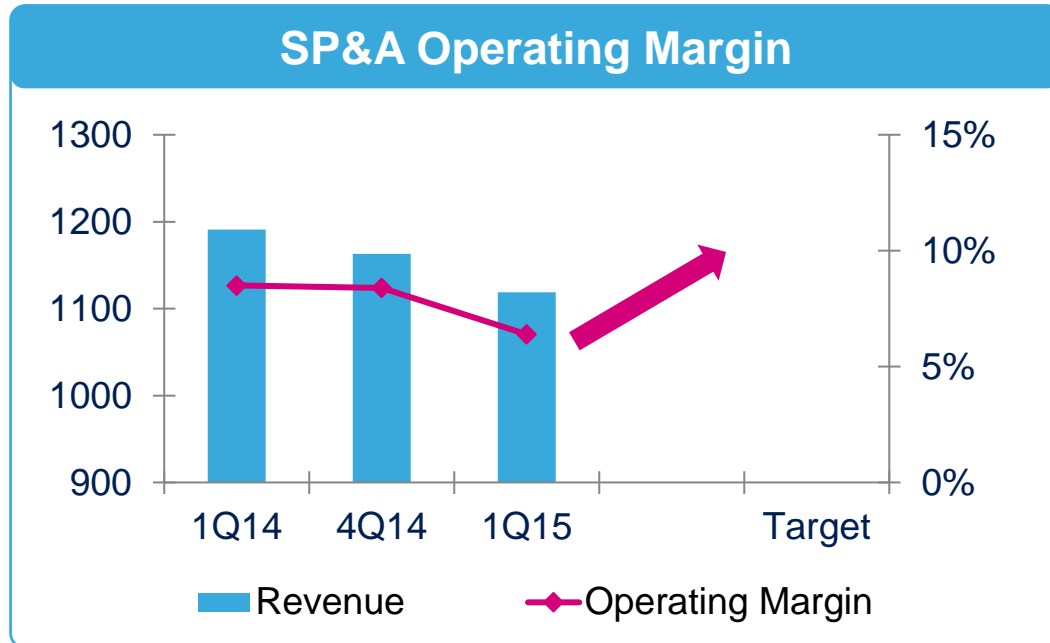
- Combined R&D and SG&A at \$591M
- Starting to benefit from stronger \$
- EPS cost reduction plan targeting \$100M annualized savings:
 - ~30% of target savings in 1Q15 actual

Well in line with low-end of quarterly net operating expenses target of \$550-\$600M



* Net Operating Expenses: R&D + SG&A – recurring R&D grants

SP&A and EPS to support Financial Model



Operating Margin Mid-term Targets

SP&A about 10-15%
IPD from about 10% to mid-teens
APG from about 10% to mid-teens
AMS from a few points to high single-digit

EPS about 5%
MMS maintaining mid/high-teens
DPG to fix current losses



From January 1, 2015, unused capacity charges have been allocated to the associated product segments

Appendix



Financial Performance

<i>In US\$M, except EPS</i>	1Q14	4Q14	1Q15
Net Revenues	1,825	1,829	1,705
Gross Margin	32.8%	33.8%	33.2%
Operating Income (Loss) before impairment, restructuring*	8	58	10
Operating Margin before impairment, restructuring*	0.4%	3.2%	0.6%
Net Income – Reported	(24)	43	(22)
EPS Diluted	(0.03)	0.05	(0.03)
Adjusted EPS Diluted*	(0.01)	0.07	0.01
Free Cash Flow*	(51)	208	41
Net Financial Position	612	550	512
Effective Exchange Rate €/\$	1.35	1.29	1.23

Pre-Tax Items to Adjusted Earnings*

OPERATING RESULT	<i>In US\$M</i>	1Q14	4Q14	1Q15
	NET EARNINGS	U.S. GAAP Net Earnings	(24)	43
Impairment & Restructuring Charges		12	20	29
Estimated Income Tax Effect		(1)	(2)	(1)
Adjusted Net Earnings*		(13)	61	6

- **In 2Q15, we expect to increase our revenues by about 3.5% sequentially, with most of our product groups contributing. Gross margin is anticipated to increase by about 60 basis points to 33.8%, including existing hedging contracts significantly mitigating the positive impact from currency**
- 2Q15 revenues are expected to increase about 3.5% on a sequential basis, plus or minus 3.5 percentage points
- 2Q15 gross margin is expected to be about 33.8%, plus or minus 2.0 percentage points.

Outlook based on an assumed effective currency exchange rate of approximately \$1.16= €1.00 for 2Q15 and includes the impact of existing hedging contracts. 2Q15 will close on June 27, 2015

- **Free cash flow** is defined as net cash from operating activities minus net cash from (used in) investing activities, excluding proceeds from the sale of marketable securities and net cash variation for joint venture deconsolidation. We believe free cash flow provides useful information for investors and management because it measures our capacity to generate cash from our operating and investing activities to sustain our operating activities. Free cash flow is not a U.S. GAAP measure and does not represent total cash flow since it does not include the cash flows generated by or used in financing activities. In addition, our definition of free cash flow may differ from definitions used by other companies.
- **Net financial position** resources (debt) represents the balance between our total financial resources and our total financial debt. Our total financial resources include cash and cash equivalents, marketable securities, short-term deposits and restricted cash, and our total financial debt includes short term borrowings, current portion of long-term debt and long-term debt, all as reported in our consolidated balance sheet. We believe our net financial position provides useful information for investors because it gives evidence of our global position either in terms of net indebtedness or net cash position by measuring our capital resources based on cash, cash equivalents and marketable securities and the total level of our financial indebtedness. Net financial position is not a U.S. GAAP measure.
- **Operating income before impairment and restructuring** excludes impairment, restructuring charges and other related closure costs. It is used by management to help enhance an understanding of ongoing operations and to communicate the impact of the excluded items.
- **Adjusted net earnings and earnings per share (EPS)** are used by our management to help enhance an understanding of ongoing operations and to communicate the impact of the excluded items like impairment, restructuring charges and other related closure costs, net of the relevant tax impact.

Embedded Processing Solutions (EPS)

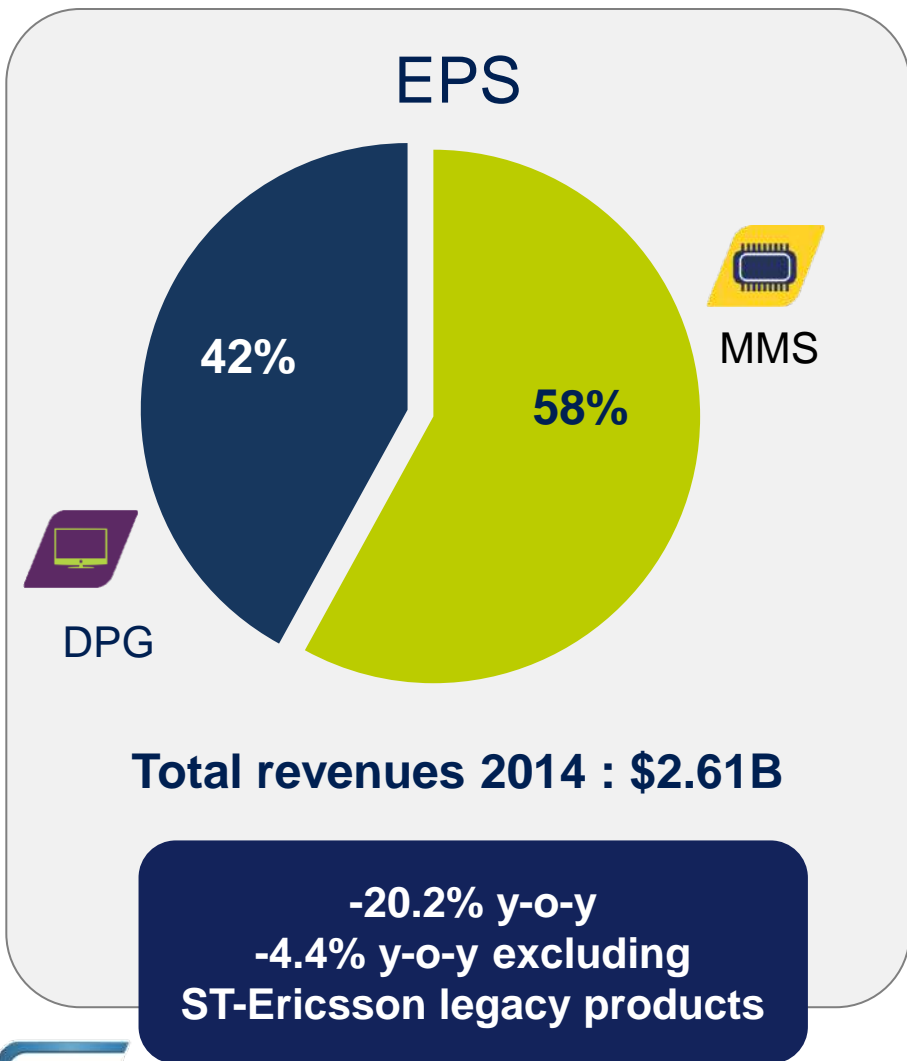
Jean-Marc Chery

Chief Operating Officer






EPS – Embedded Processing Solutions



2 Product Groups

 **DPG**
 Digital Product Group

 **MMS**
 Microcontroller, Memory & Secure MCU

2 Front-End Manufacturing Sites

Focus on digital CMOS (300mm) & derivative technologies (200/300mm)

Partnerships for process development and manufacturing



Managing two opposite dynamics

MMS

Leading revenue growth & profitability

DPG

Turnaround situation & loss-making

Addressing the DPG Issues

Current focus on growth opportunities

- Rebuilding higher end market position in UHD/HEVC STB & Home Gateway
- Leveraging on FD-SOI and mixed signal/photonics technologies in ASICs for networking, computer peripherals, consumer applications and automotive
- Leveraging on growing and emerging applications in Imaging through differentiated technology

Facing variety of top line issues

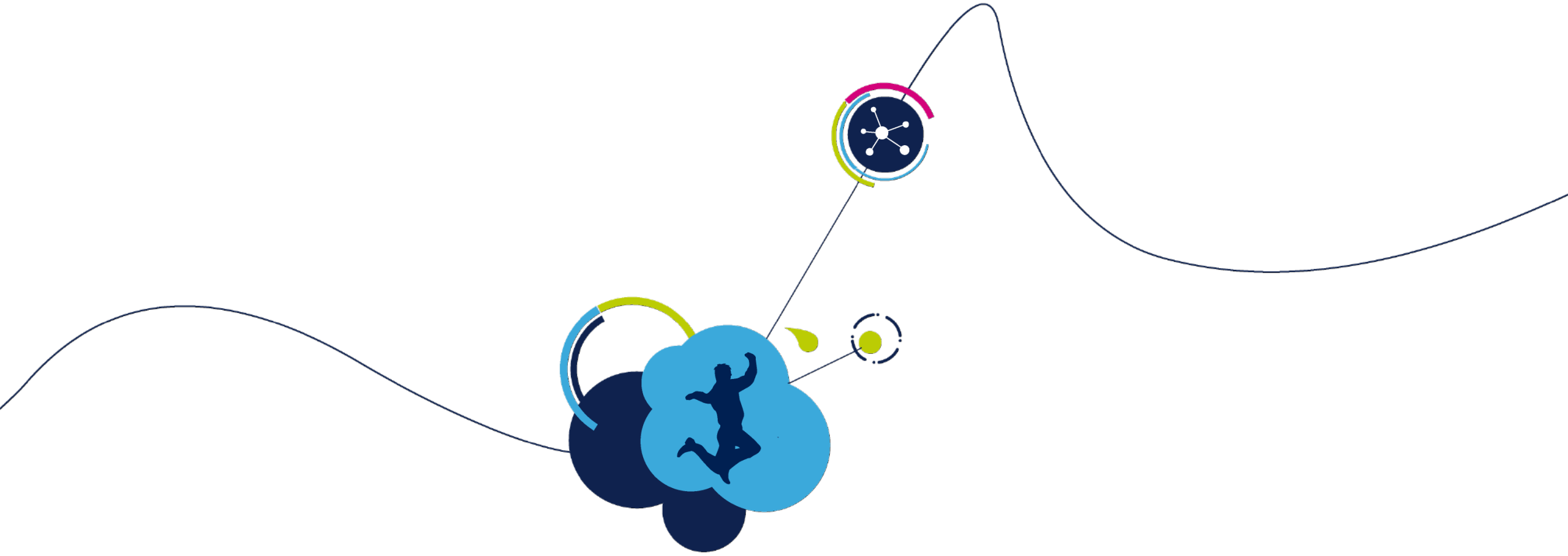
- Legacy broadcast STB Business declining faster than expected
- Unexpected cancellation and postponement in important consumer ASIC programs
- Slower market adoption of UHD/HEVC with increasing competition on HD broadcast STB.

Ready to react to changes

Cost saving plan on track
(annualized \$100M OPEX savings)

Revised technology roadmap and
strategy

DPG product families under scrutiny,
exploring options



EPS Product Strategy and Portfolio



DPG – Digital Product Group

Products

Key Focused Applications

Strategic Positioning

Consumer
ASSP

Broadcast Set-Top Box
& connected Client/Servers

Home Gateways,
including DOCSIS

- Leadership in the transition to HEVC/UHD Set-Top Box and DOCSIS 3.1 headless gateways and cable modems toward the Smart Home

Digital &
Mixed
Signal ASIC

Networking ASICs,
including FD-SOI and
mixed process devices

Others FD-SOI based
ASICs for automotive,
consumer, industrial
applications

- Leadership in high-speed, highly integrated devices for networking and the transition from copper to optical fiber
- Leadership in ultra-low power & ultra-low leakage embedded processing solutions

Imaging

Photonic sensors

Specialized imaging
sensors

- Leadership in Time-Of-Flight sensors and specialized imaging sensors through close cooperation with key players in consumer, automotive, emerging and fast growing applications

STB & Home Gateway: Product Portfolio

HOME GATEWAY
Network Access
DOCSIS
Telephony
Routing

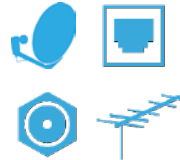
CLIENT & SERVER
Content anywhere
High Multimedia
performance
Ultra HD


BROADCAST STB
Cost-effective
multimarket
solutions

ST
Alicante
STID12x
DOCSIS 3.1

ST
Monaco
STIH4xx
Cannes
STIH3xx

ST
Liege 2
STIH301
Liege
STIH2xx




 Complete and cost-optimized HW/SW portfolio

 Ad-hoc devices for specific use cases

 HW/SW compatibility within each product family

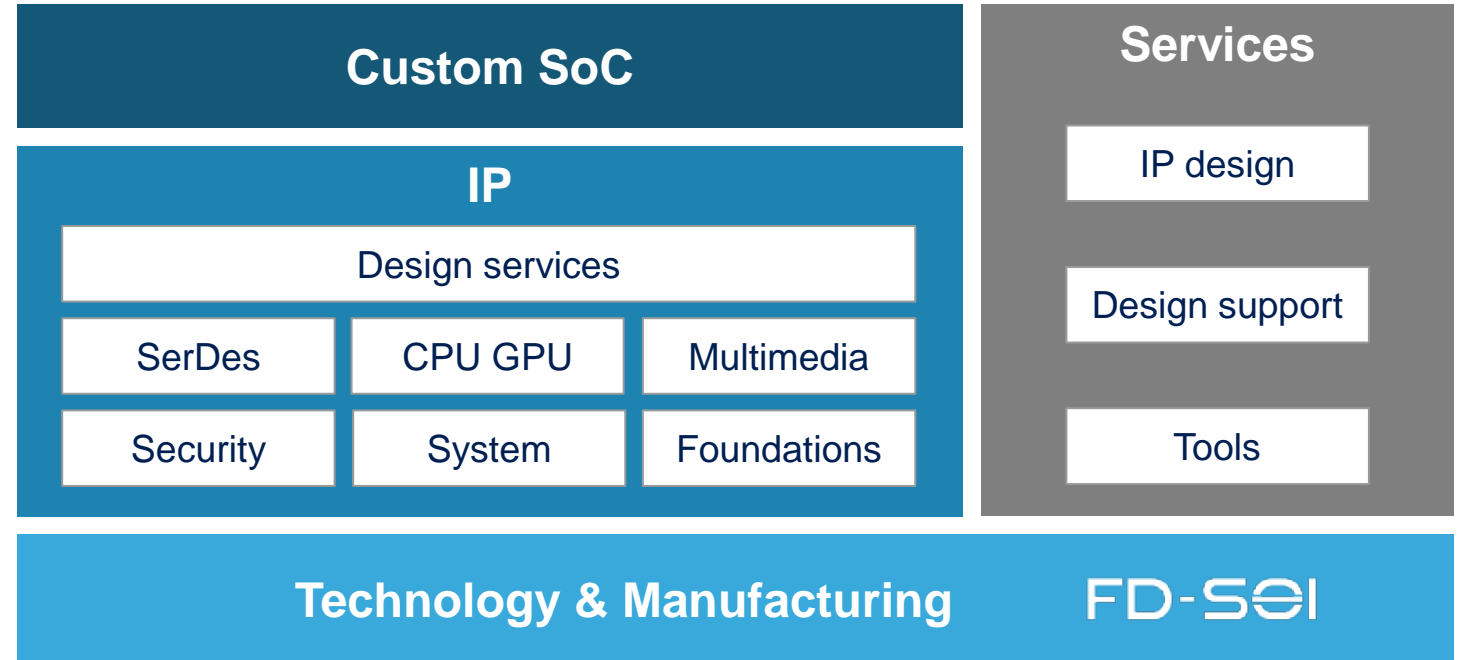
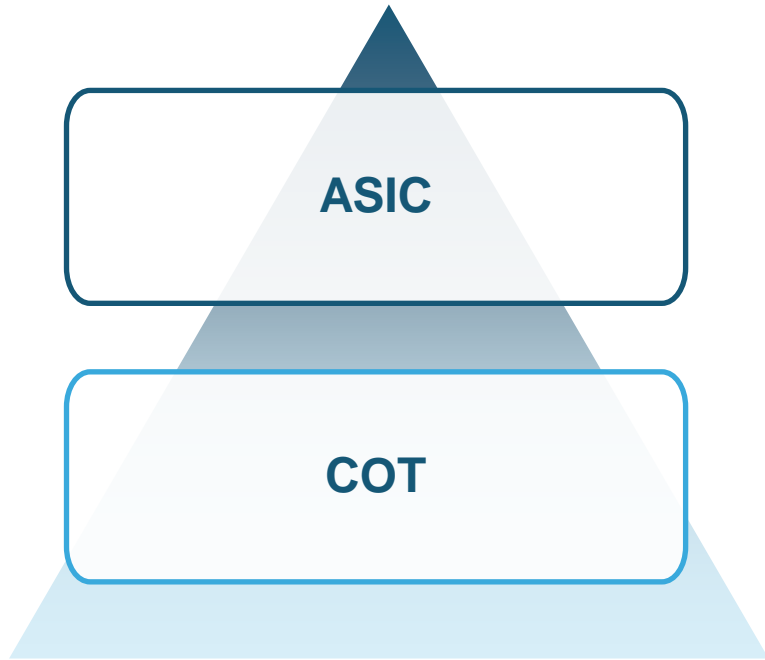
 From entry broadcast to high-end HEVC on ARM

 Strong ecosystem



Digital & Mixed Signal ASICs

Flexible Model



Consumer



Networking



Computer Peripherals

Digital & Mixed Signal ASICs IP & Technology Portfolio

28

**MIXED
PROCESS &
SILICON
PHOTONICS**

- Best-in-class BiCMOS technology enables multiple applications, including ICs for fiber optic modules
- Fully integrated silicon photonics technology brings savings in bill of material, production throughput, power consumption and space

**28/14nm
FD-SOI
PROCESS**

- FD-SOI technology enables mixed analog/digital ICs with high performance, ultra-low power and high resilience to space radiation
- Complete foundation IP, including High Speed SerDes (up to 28GBps) and special memories (TCAM)

**40/32/28 nm
BULK
PROCESS**

- Bulk technology enables cost sensitive and high integration ICs
- Complete foundation IP, including High Speed SerDes (up to 14GBps) and special memories (TCAM)

Imaging Opportunities leveraging Technologies

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Proprietary Technologies

Time-of-Flight

Specialized imaging
silicon processes and pixels

Imaging processing IP



Differentiated Offering

Photonic sensors

Proximity

Ranging

Gesture

Depth map

Specialized imaging sensors

Custom solutions

Large pixel

Visible & IR

Key Applications & Segments

Hybrid autofocus

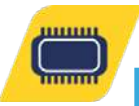
User & gesture detection

3D sensing

Consumer devices

Automotive

Emerging applications
& new usages



MMS – Microcontroller, Memory & Secure MCUs

Products

Key Focused Applications

Strategic Positioning

General Purpose Microcontroller

Mass Market aiming to serve more than 40,000 customers

Fast growing IoT & wearable markets associated with Secure Microcontroller

- Leadership in 32-bit Microcontrollers market bringing higher computing power, lower leakage and power consumption, more connectivity features and smaller form factors

Memory

Consumer, automotive markets driven by need for parameters storage

Others market requiring contact/contactless interfaces or specific features such as brand protection

- Leadership based on best-in-class product quality and performance and state-of-the-art proprietary process

Secure Microcontroller

Secure identification solutions such as banking, e-government, transportation anticipating contactless migration

Fast growing IoT & Wearable markets

- Leadership in 32-bit Secure Microcontrollers market bringing best-in-class security and contactless with smaller form factors



General Purpose Microcontrollers

Wearable & IoT

IoT-based Smart Lock



Market's smallest wrist heart monitor



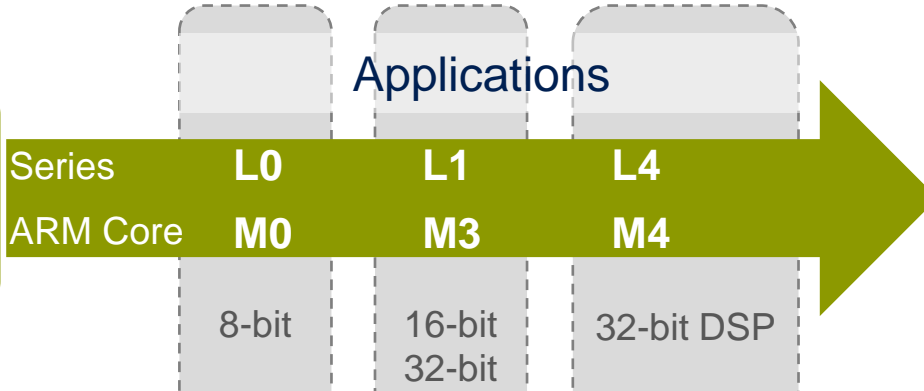


General Purpose Microcontrollers

Product Portfolio



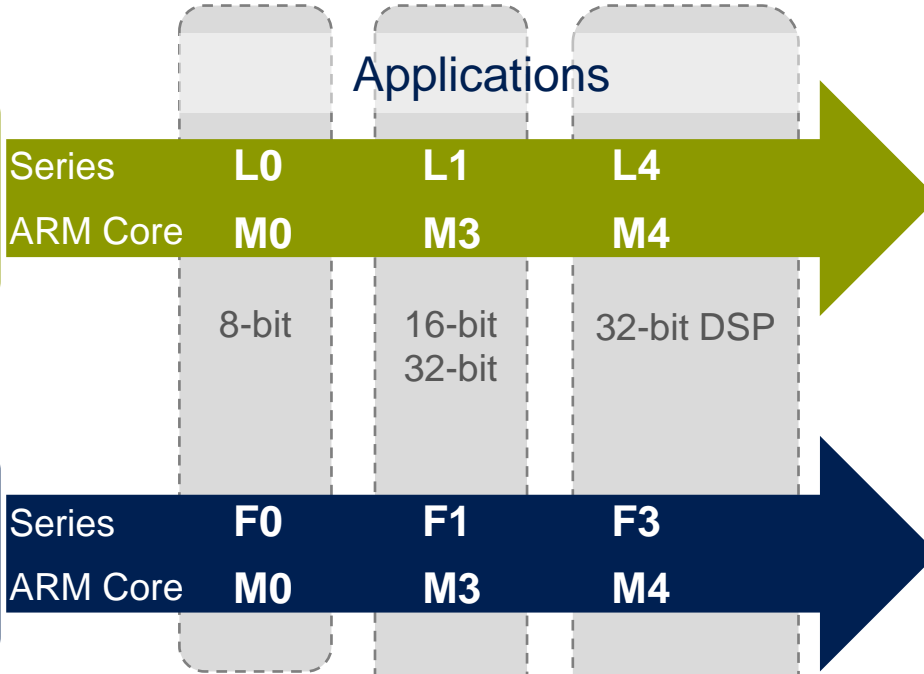
STM32L
Low Power



- Battery operated applications
- Ultra-low-power applications
- 8 to 32-bit + DSP applications



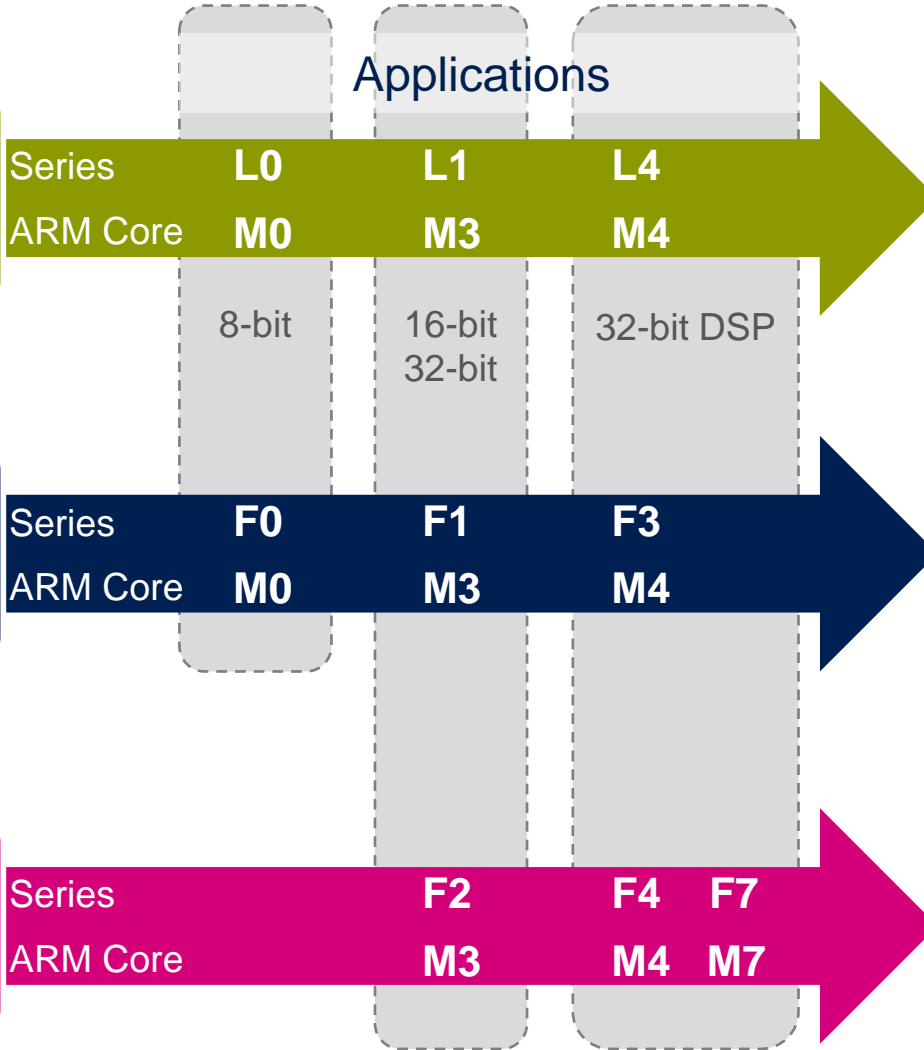
STM32F
Mainstream



- Multi-segments/applications
- Mainstream with >200P/N
- 8 to 32-bit + DSP application



STM32F
High performance

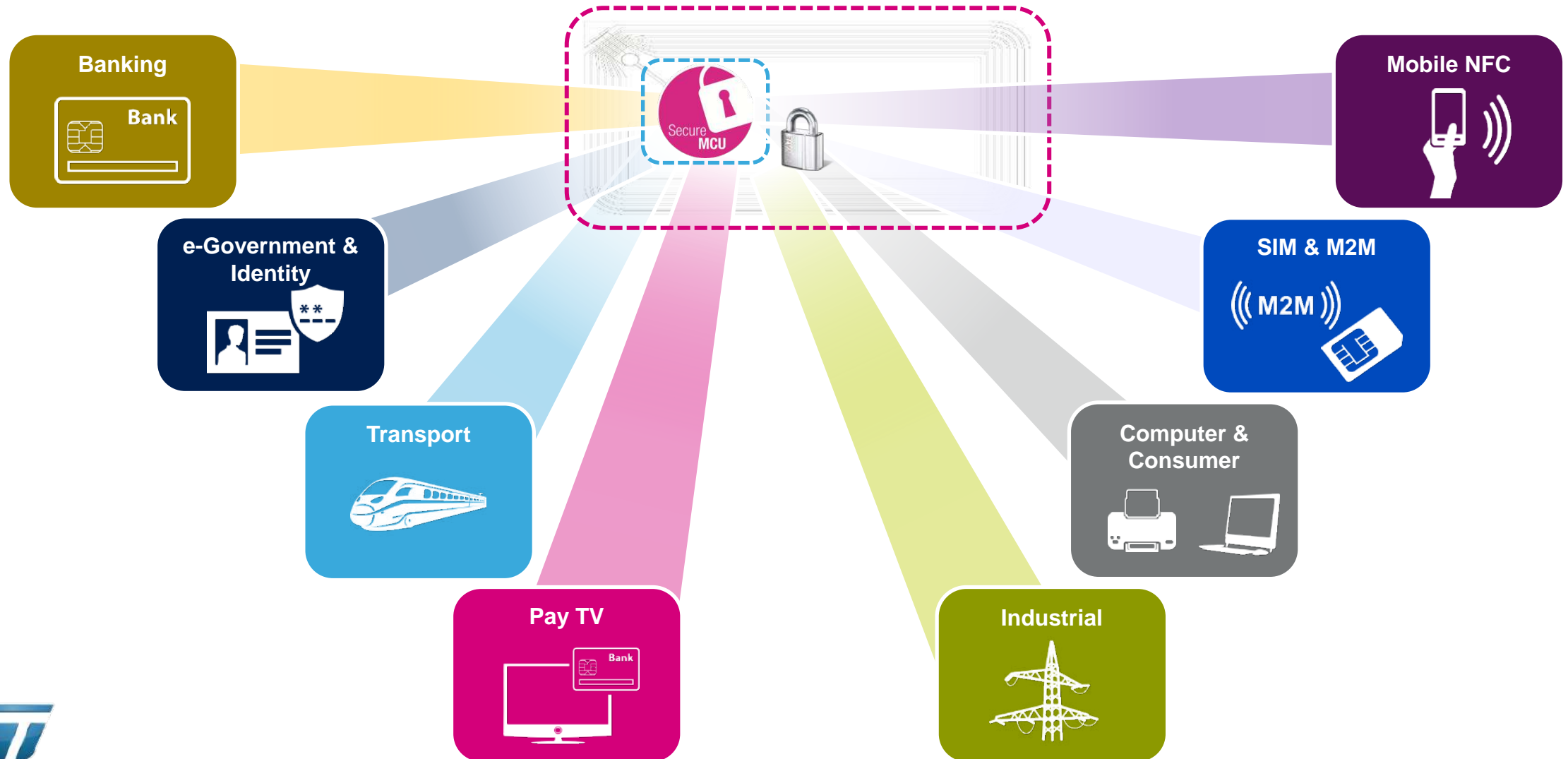


- High-end applications computing power, connectivity
- Bridge to MPU



Secure Microcontrollers

Perimeter

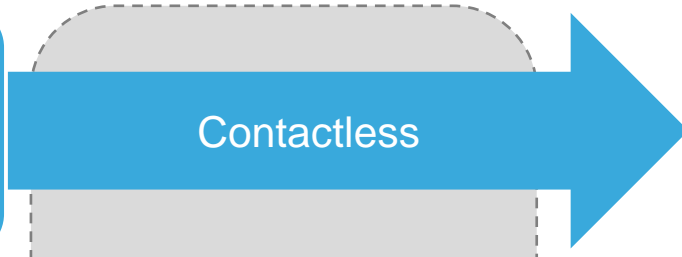




Secure Microcontrollers Product Portfolio

Personal security

Bank
SmartCard



- Contactless platform : ST31
- e-Flash flexibility

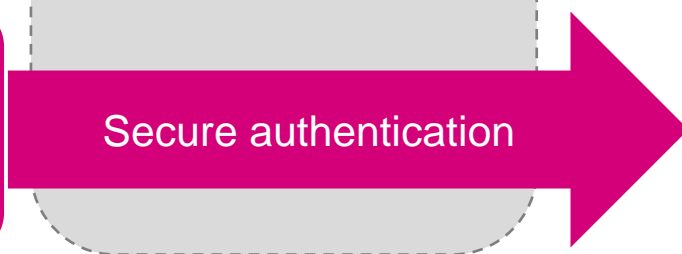
Embedded security

Mobile

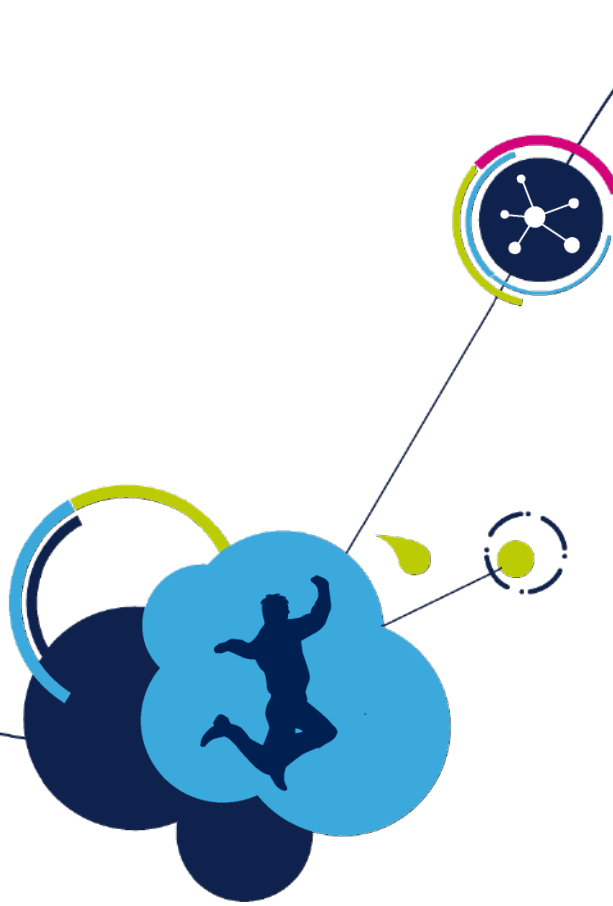


- NFC Secure Element : ST33
- NFC full solution: SE + CLF
- Secure SIM : ST33

Consumer



- End-to-end turn key solutions
- Hardware, software & customization



EPS Technology R&D and Manufacturing Strategy

- Mass Production
- Development
- Research

FD-SOI Roadmap

+35% speed
-50% power

FD-SOI 14nm

Derivatives

Feature Path

Body bias, cost, simplicity, reliability

Performance Path

FD-SOI 28nm

RF, Mixed Signal

Ultra Low Power

Embedded Non Volatile

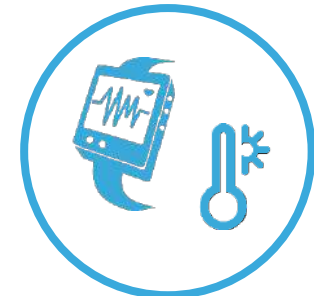
Feature Path

Differentiated options for the long lasting 28nm process node

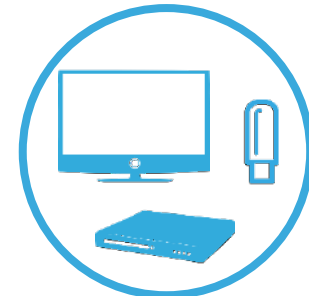
FD-SOI Fast Growing Ecosystem



Addressing Digital & Mixed Signal Markets



IoT, Wearable



Consumer



Automotive

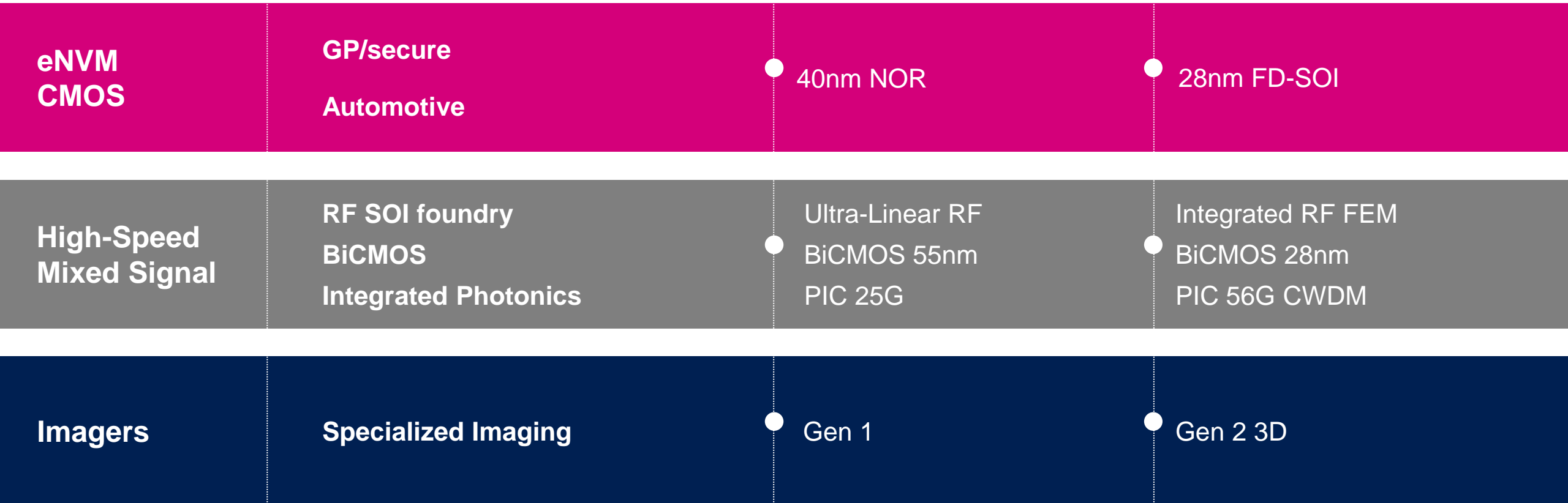


Infrastructure



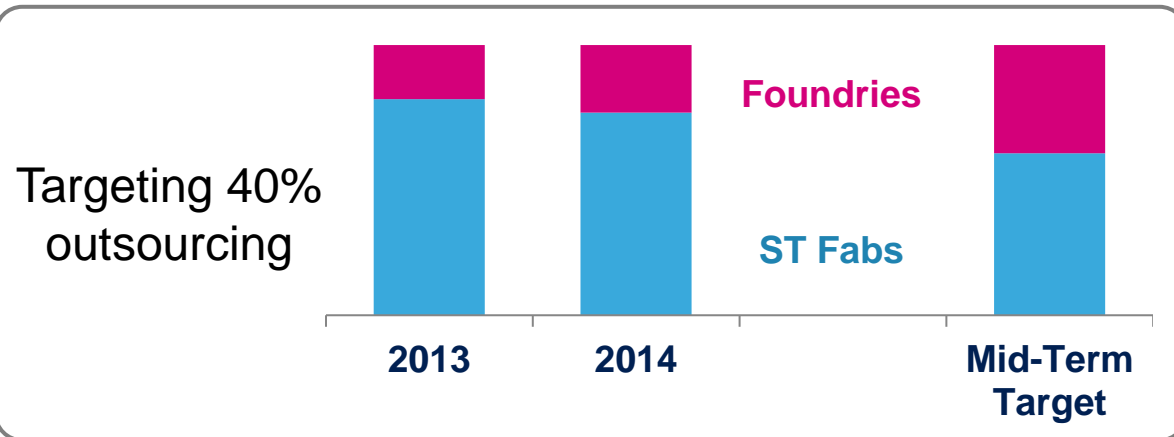
Smartphone

Differentiated Technology Roadmap



EPS Manufacturing Strategy

- Multiple sourcing through technology & manufacturing partnerships
- Rousset / Crolles clustering
- Crolles 300mm increase of scale on differentiated technologies according to demand



Technology		Driver/First	Second
CMOS Bulk	≥40nm	Crolles 300	Foundry
	<40nm	Foundry	Crolles 300
CMOS FD-SOI	28nm	Crolles 300	Foundry
Differentiated Imaging		Crolles 300	
BiCMOS	≥90nm	Crolles 200	
	<90nm	Crolles 300	
Si Photonics		Crolles 300	
RF SOI		Crolles 200	Crolles 300
HCMOS9A		Crolles 200	Crolles 300
eNVM	≥90nm	Rousset 200	Foundry
	<90nm	Crolles 300	

- EPS managing two opposite dynamics
 - MMS leading revenue growth and profitability
 - DPG product families under scrutiny, exploring options but business as usual is no longer an option
- Differentiated and focused technology roadmap driving internal manufacturing volume

Ready to react to changes

Sense & Power and Automotive (SP&A)

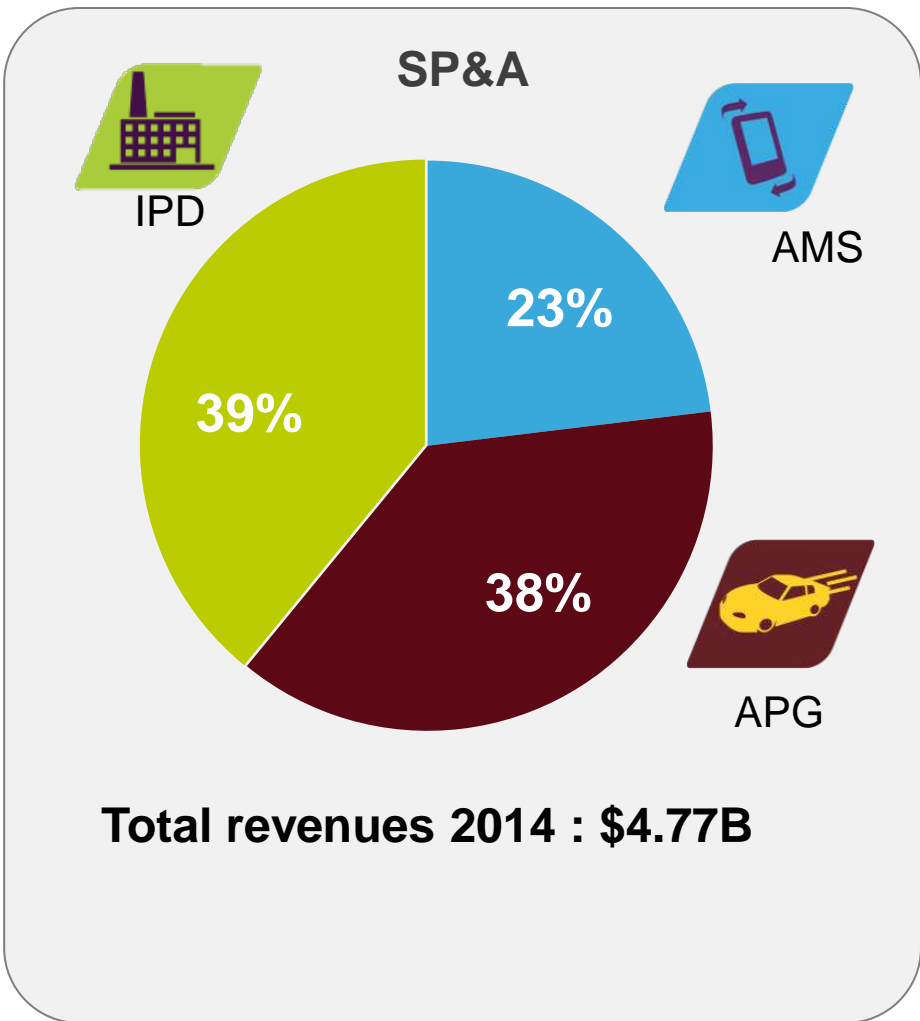
Georges Penalver

Corporate Strategy Officer





SP&A – Sense & Power and Automotive



3 Product Groups



AMS

Analog, MEMS and Sensors



IPD

Industrial & Power Discrete

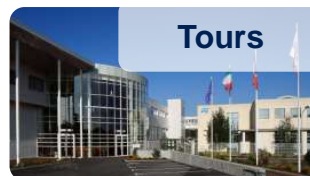


APG

Automotive Product Group

4 Front-End Manufacturing Sites

Focus on analog, power and MEMS technologies



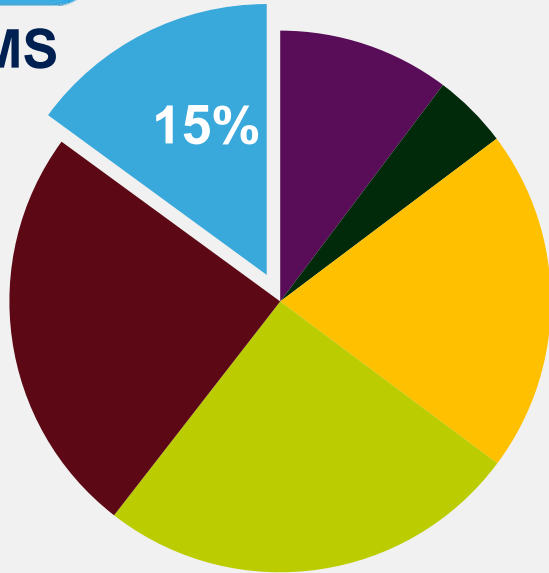


AMS – Analog, MEMS & Sensors

Contribution to ST revenues FY14



AMS



Portfolio

MOTION SENSORS

Accelerometer, gyroscope,
Magnetic sensor

MICROPHONES

Analog & Digital

ENVIRONMENTAL SENSORS

Pressure, UV

ACTUATORS

Fluidics MEMS
Micro-Mirror

Sensor Hub
& Sensor Fusion

TOUCH

FingerTip

LOW POWER ANALOG

Standard Analog
High-end Analog

RF

Bluetooth, SubGhz, Wi-Fi



Back to growth, Diversification and addressing New Markets

Application-driven Innovation

- Continue to differentiate our industry leading products (motion MEMS, microphones, touchscreen ..)
- Adapting existing technologies to new uses (e.g. fluidic)
- New technologies for existing markets (Thin-film piezo)
- New technologies for new markets (MEMS μ mirrors)

Customer & Market Diversification

- Beyond the top customers
- Increasing footprint in Greater China
- Broader reach through distribution
- Longer-term position build up in automotive

Technology & Partnerships

- Retain strong, differentiated technology portfolio with in-house manufacturing for fast ramp and supply security
- Partnerships to accelerate time to market and build-up of new skills and competences








Portfolio Diversification

- Motion MEMS for OIS and pedestrian navigation
- Expanding in new areas (environment & microphones)
- New generation of touch screen controllers
- Products for automotive and industrial
- MEMS actuators (Thermal, Piezo, Electrostatic)
- Investing in low power Analog and RF to grow in IoT



AMS – Strategy Execution

2012-2015 Revenue evolution drivers

-  Consumer motion MEMS
-  Standard Analog & Logic (pruning)
-  Inkjet
-  μ Mirrors
-  Automotive/Industrial MEMS
-  Touchscreen and High-End Analog
-  MEMS Microphones

2015 Focus

- Grow **new generation 6-axis ultra-low power motion MEMS** with key customers
- Continued expansion of **touchscreen controllers & MEMS microphones** business
- Wider adoption of **environmental sensors**
- Broadening our **customer base in China**
- **MEMS micro Mirrors** in PC applications
- Addressing **Mass Market** through STM32 Open Development Environment and Open SW solutions
- **Automotive MEMS** ramp up
- **Bluetooth Low Energy** for Internet of Things

Back to year-over-year quarterly growth starting in 2Q15



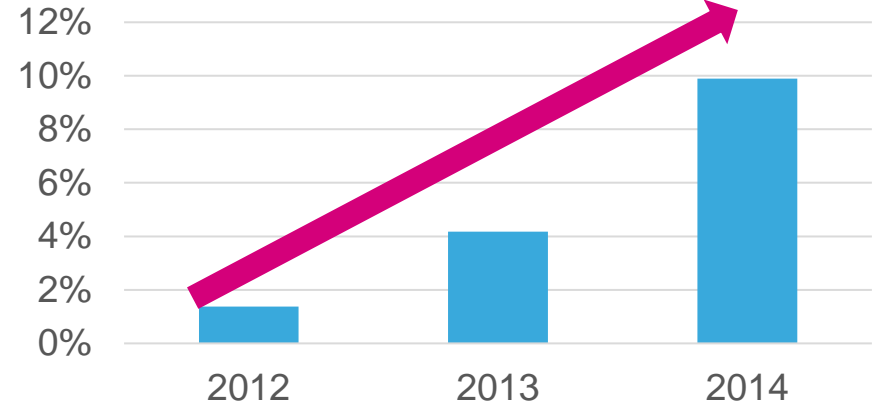
AMS – Strategy in Action



“Brand new STMicroelectronics 3mmx3mm LGA package featuring a 3D digital gyroscope and 3D digital accelerometer” Chipworks



ST MEMS Microphone Market Share



Intel Realsense™

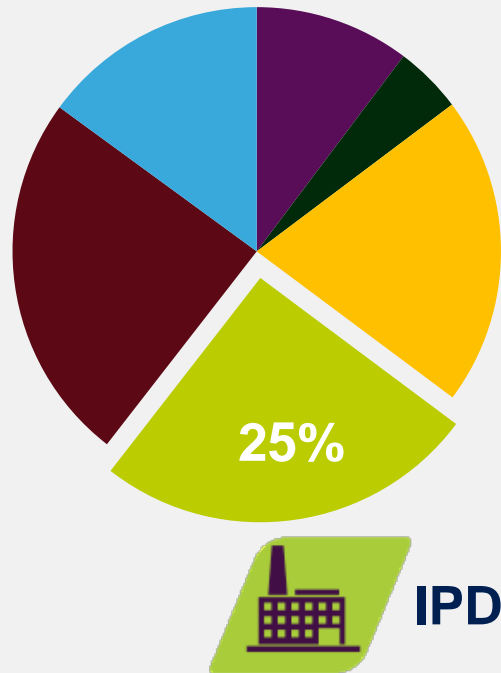


New Touchscreen technologies for flagship smartphones





IPD – Industrial & Power Discrete

Contribution to ST revenues
FY14



A Complete Portfolio for Power Applications

Power Discrete and Intelligent Power Module

 Power Transistors	 Intelligent Power Module	 Thyristors & AC Switches	 Diodes & Rectifiers	 Protection Devices
---	---	---	--	---

Smart Power ICs

 Lighting ICs	 Industrial Analog ASSP	 Energy Management ICs	 Motor Control ICs	 Galvanic Isolation ICs
 Digital Power Conversion ICs	 AC/DC & Isolated DC/DC Power Supply	 Data Storage PCOMBO & PMIC	 EMI Filtering, Signal Conditioning	 Display PMIC



Leverage technology & portfolio to target fastest growing markets

Targeting the fastest growing Markets

- **Portable** - Power management & interfaces
- **Automation** - Motion control
- **Power Conversion** - Digital power & LED lighting, server power supply
- **Energy Management** - Energy monitoring & harvesting, power line modem, electric and hybrid vehicles

Reinforce Market Position

- Reinforce position and increase share in major accounts
- Customer base expansion in mass market
- Increase efforts in the Chinese market

Differentiated Technology Portfolio

- Smart Power - Advanced BCD
- Power Discrete, SiC and GaN
- Tunable antenna
- Miniaturized packages (Flip Chip, Wafer Scale)
- Proprietary IP for mixed Digital-Analog designs

Strengthening Portfolio in Key Areas

- Expanding Smart Power for industrial, server and portable
- New Power Discrete & Intelligent Power Module families
- Filtering and protection for wireless



Targeting solid and growing Applications

Market Boosters

Cloud

Industry 4.0

IoT

Energy

Power Conversion

High-efficiency and power density

Digital Power Supply

Server Power Supply

LED Lighting

\$8.7B*

Automation

Efficient, safe, comfortable, secure

Motion Control

Factory Automation

Home & Building Automation

\$7.1B*

Portable

Miniaturized, ultra-low power & high-efficiency

Display Power Management

Chargers

Filtering & Protection

HDD and SSD

\$4.7B*

Energy Management

Generation, Distribution, Storage and Control

Energy Monitoring & Harvesting

PLM Communication

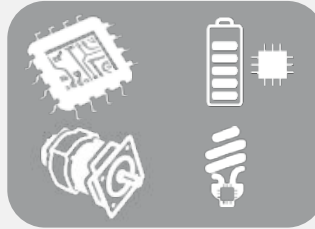
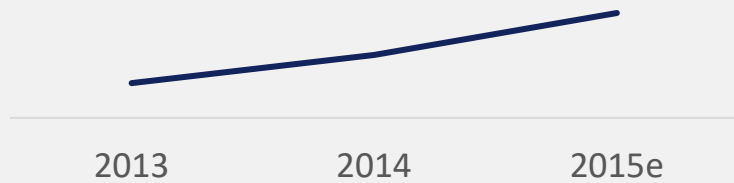
Electric and Hybrid Vehicle

\$2.2B*



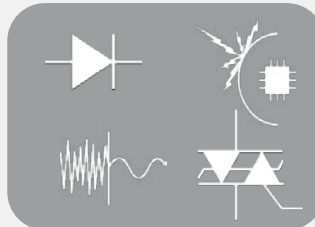
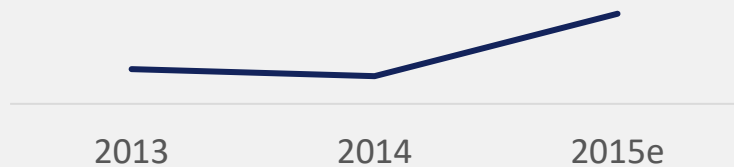
Growing across all Product Lines in 2015

Industrial and Power Conversion ICs



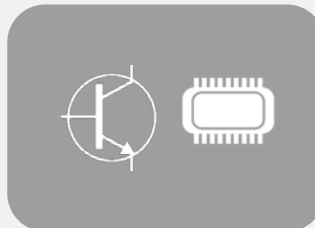
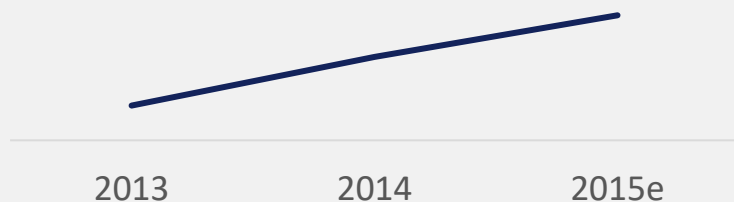
- PMICs for AMOLED in tablets and smartphones
- Digital controllers for lighting and power conversion
- PMICs for Servers
- Motion control and factory automation ICs

Discrete



- RF Modules with RF Couplers and Filters for mobile
- SiC Diodes in servers, telecom and automotive
- SCR and high performance rectifiers for energy management

Power Transistors

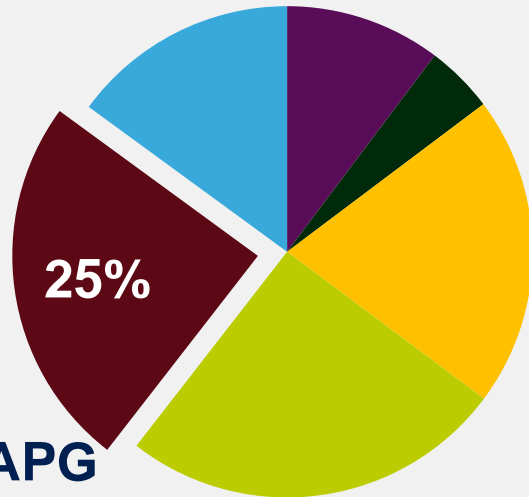


- Low Voltage Trench MOSFETs for industrial, servers and automotive
- IGBTs and Intelligent Power Modules
- High Voltage Super Junction and SiC Transistors for energy management and EHV



APG – Automotive Product Group

Contribution to ST revenues
FY14



Portfolio

Infotainment

Telematics & Connectivity

Car Entertainment

Body electronics

Door modules, Steering

Lighting, Wipers, BCM

Chassis

Braking
Vehicle control

Passive Safety
Active safety

Powertrain

Thermal Engine
Electrical Engine

Transmission



Driving Innovation in Automotive

- The car is a technology hub
- ST driving innovation in automotive focused on:
 - Car electrification and fuel economy
 - Autonomous driving system and Active Safety
 - Connected car and infotainment
- Addressing digital in the car

Manufacturing & Technology Key

- Leverage independent manufacturing
- Keep leadership in smart power technologies on lithography and cost
- Use eFlash proprietary technology as a key differentiator
- Leverage RF technology to gain market share on Active Safety complementing our vision-based processor offer

Customer relations, China, partnering

- Continued strong customer relationships (EU, Japan, US)
- Dedicated approach for China
- Strengthened customer support for our complex functions
- Extend partnerships with car makers to maintain leading edge innovation level

Flexible Product Portfolio

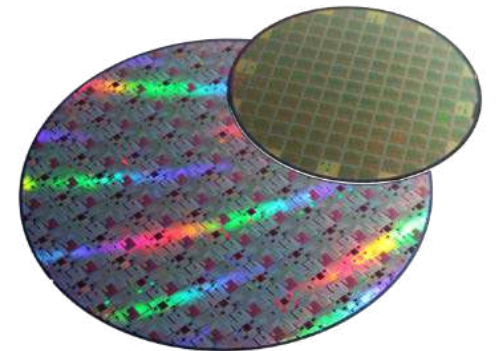
- Keep leadership in our traditional application perimeter
- Expand coverage on fast growing Automotive applications
- Keep ASIC leadership maintaining strong innovation level
- Turn strong 32-bit microcontrollers design win pipeline into double-digit sales growth
- Extend the offer with an ASSP product family to serve the mass market and emerging countries



APG – Strategy Execution

2015 Focus

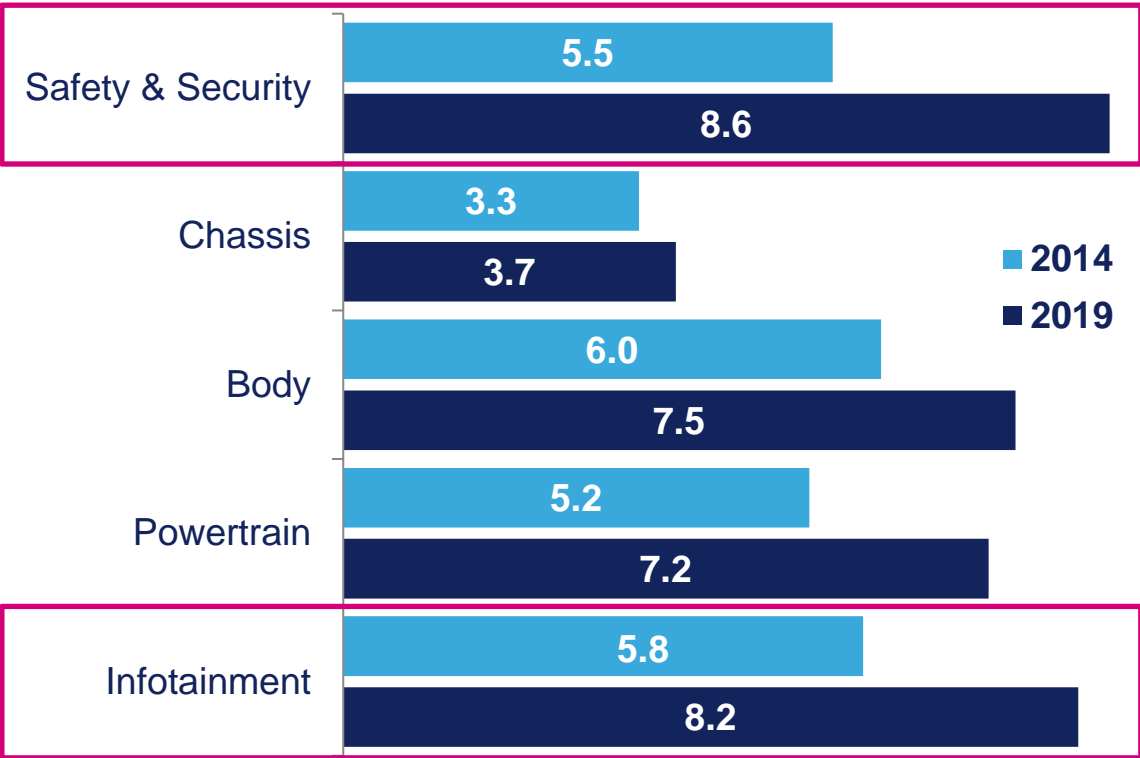
- **Active Safety** (camera and radar-based) products, thanks to growing penetration of these products in the market, also leveraging our FD-SOI technology
- Continue to gain market share in **32-bit microcontrollers**, thanks to our strong design-win pipeline with a double digit growth
- Further **broadening of customer base** with distribution and in the mass market, leveraging our capability to support full system development in automotive
- Growing revenues derived from **leading-edge technologies**: 40/28nm embedded flash on 300mm, 110/90nm smart power, 110nm VIPower, 28nm FD-SOI



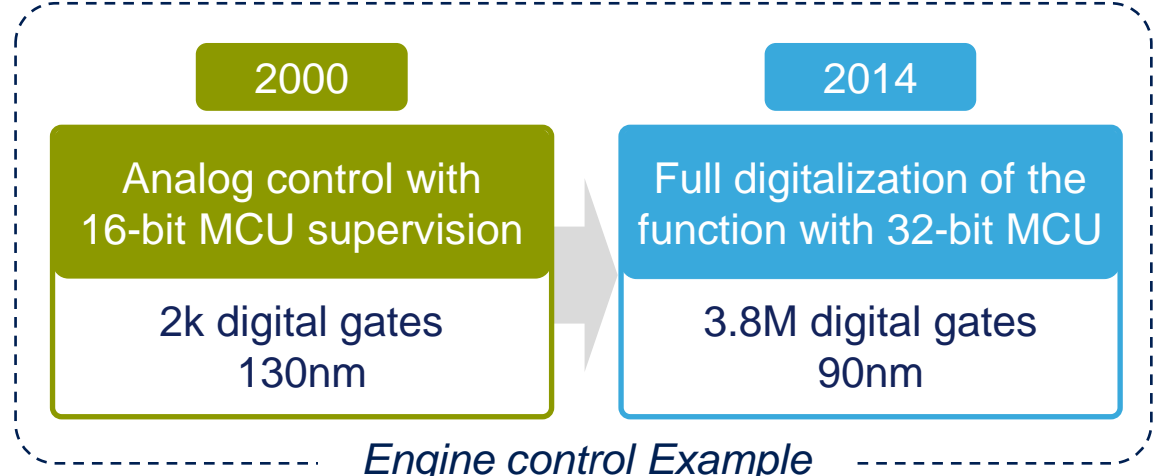
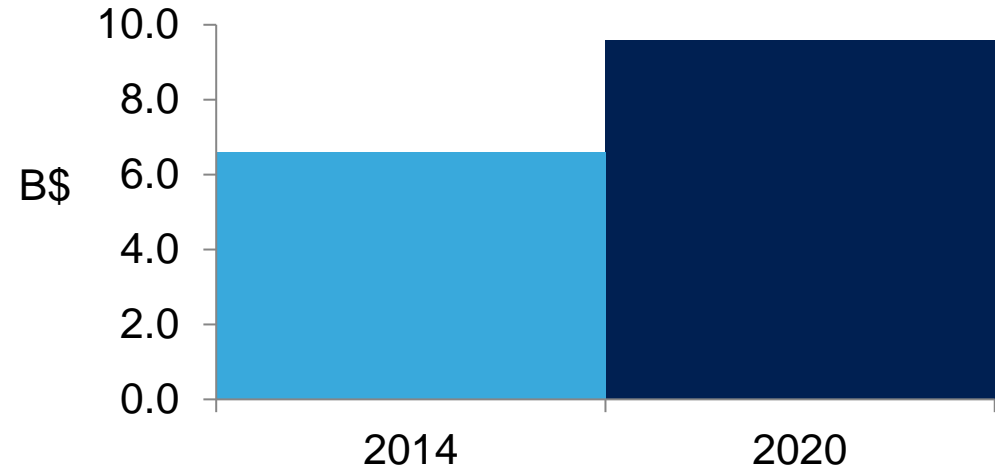


Digitalization in Automotive

Fastest growing applications in the car have very high digital content



Digital ICs in car rapidly growing
ST addressing large portion



Source: Strategy Analytics, ST

- AMS moving back to growth in 2Q15
 - Diversification strategy starting to bring results
- IPD targeting growing applications representing a TAM of about \$23B
 - Clear opportunities to continue to grow especially with large accounts and in the mass market
- APG building on strong positions
 - Expanding and capturing opportunities also in digital, building revenues and profitability

Market Trends

Georges Penalver

Chief Strategy Officer



Societal Trends driving Opportunities

In 2017

Societal trends

13% of the Population over 60 years old

55% of the Population living in cities

39% Global middle class

6% more energy required vs 2014

22 billion Connected Devices

Opportunities

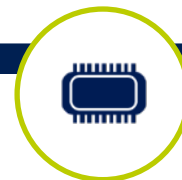
20 sensors in a smartphone
40 billion sensors installed

65 Million new Smart Meters installed

95 million cars sold
\$333 semiconductor content per car

24 billion microcontrollers sold

56 million UltraHD TVs sold



Three Domains of growth Opportunity for ST

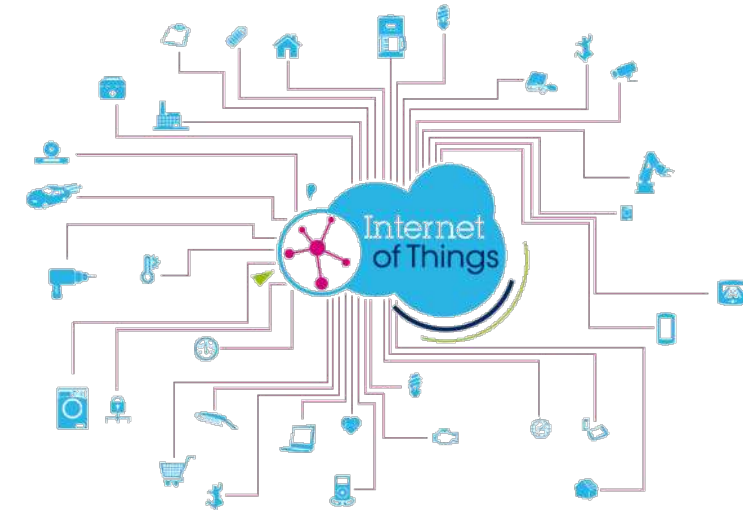
Smart Driving



Smart Environments



Smart Things



- Assisted and safer driving
- Green driving
- Connected driving



In 2015

88 million
cars sold

\$312 semiconductor
content per car

9% of new cars
equipped with active
distance detection
systems

50
Sensors per
car

Source : Strategy Analytics, ST

ST Offering

Infotainment & Telematics
Radio/GNSS/Car2X

Vehicle Electrification
Power & Smart Power

Active Safety
Vision-based ASSP/Radar

Digital processing
8/32-bit MCU & Multicore

Sensors
Motion MEMS/Camera

#3 WW Automotive Supplier
#1 in Active Safety systems
#1 Engine control
#1 in Motion MEMS for Navigation

Smart Environments

- Addressing resource management challenges
- Managing energy throughout the production & consumption chain
- Technologies for the smart city and smart industry



In 2015

2.5 TWh more energy required vs 2014

65 million smart meters shipped

\$55 billion Investment in the smart grid WW

Source : IHS, ST

ST Offering

Smart Power

Intelligent Power Modules

Power Discrete

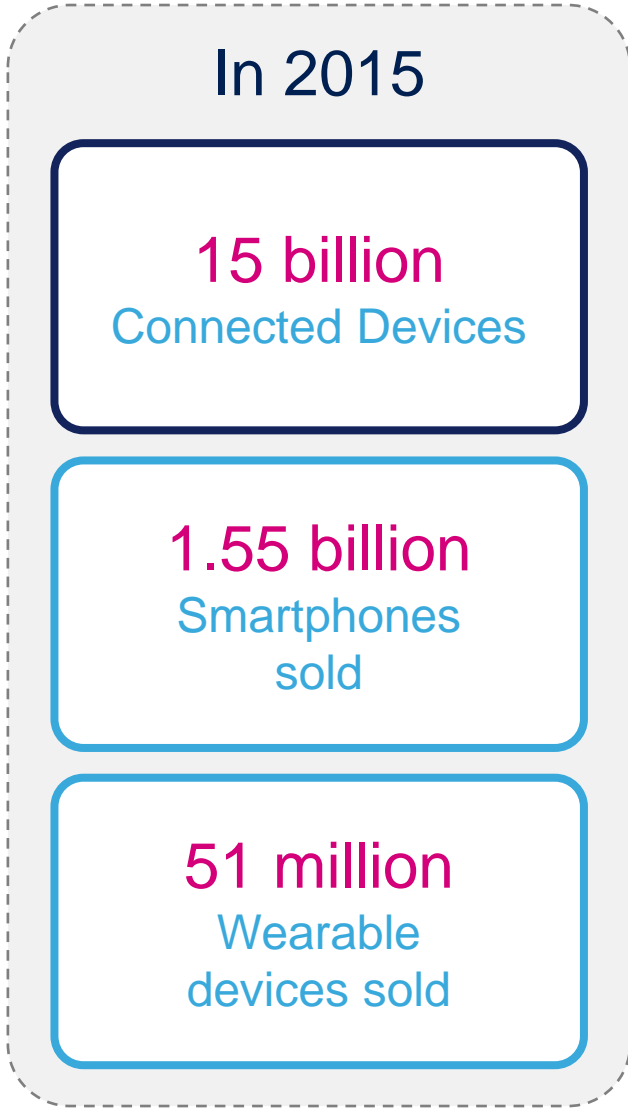
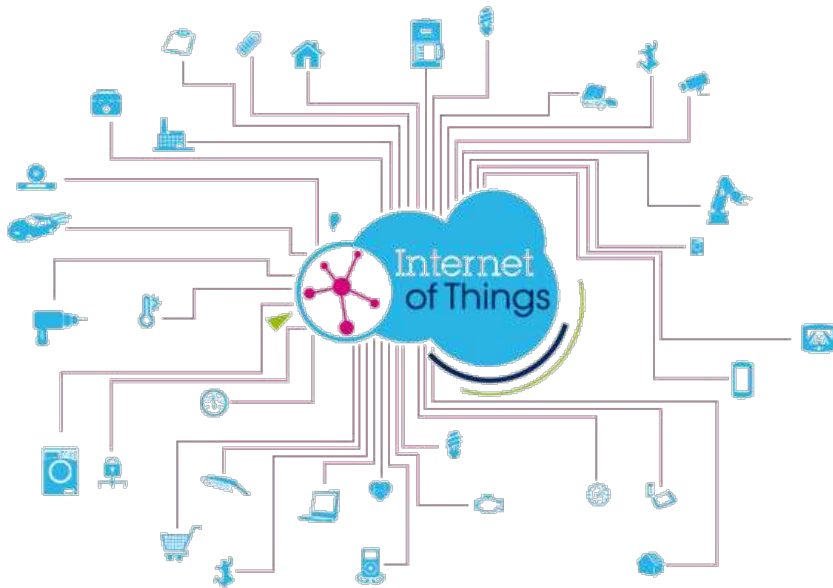
Power Line connectivity

Microcontrollers & Secure solutions

Sensors
Motion, environment, light

#1 in Industrial & ASIC
#1 High Voltage Power MOSFET
#1 Thyristors & Triacs

- Making new and old things smart and connected
- Building on mobile and the first wave of wearable
- New applications & business models



Source : IHS, ST

ST Offering

Sensors
Motion, environment, light

Microcontrollers
Memories & Security

Ultra-low power (ULP)
connectivity

Analog and mixed signal
components

Power and energy
management

STM32 Open
Development Environment

#1 in MEMS for consumer and mobile
#1 in 32-bit ARM Cortex-M
Microcontrollers

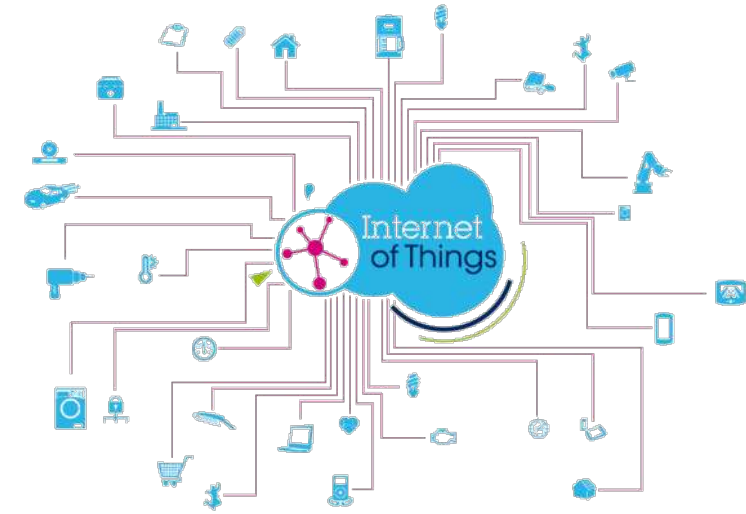
Smart Driving



Smart Environments



Smart Things



Smart Driving

Marco Cassis, Executive Vice President
President, Japan and Korea Region

Paul Cihak, Executive Vice President
General Manager, Sales & Marketing, EMEA

Marco Monti, Executive Vice President
General Manager, Automotive Product Group



Smart Driving

#3 WW Automotive Supplier
#1 in Active Safety systems
#1 Engine control
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Source : Strategy Analytics, ST

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 car

ST Offering

Infotainment & Telematics
 Radio/GNSS/Car2X

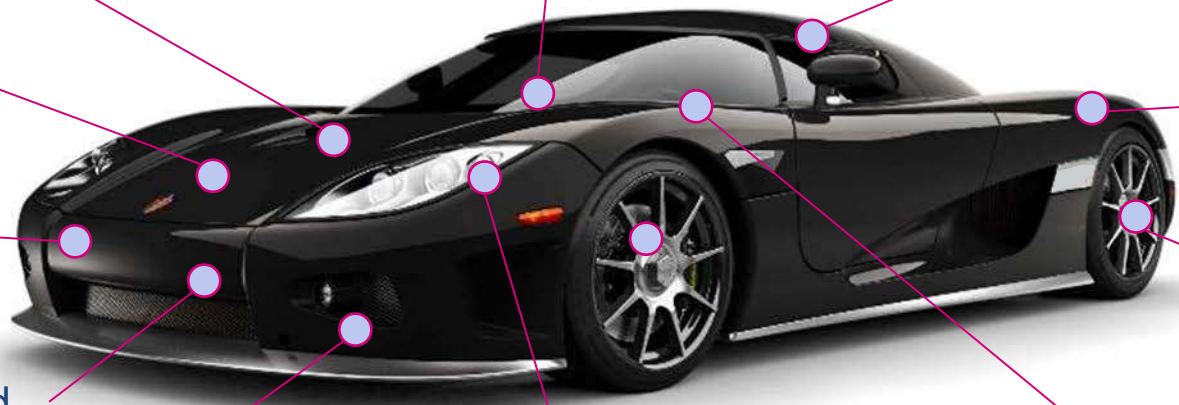
Vehicle Electrification
 Power & Smart Power

Active Safety
 Vision-based ASSP/Radar

Digital processing
 8/32-bit MCU & Multicore

Sensors
 Motion MEMS/Camera

In 2014...



3 out of 4 cars produced have at least one ST component in Engine Management

100% market share in US satellite radio (Sirius XM)

350 Million Power Transistors shipped

30 Million 32-bit MCUs shipped

1 out of 6 Infotainment & Navigation systems had ST Motion MEMS inside

8 out of 10 cars shipped with an ADAS system on board had an ST ADAS CPU on board

850 Million Lamps (1 out of 2) driven by ST

About 30 ST components in each new vehicle

2.5 Million VIPower chips shipped every day

2 out of 3 cars produced had at least one ST component in braking

2 out of 3 cars produced are equipped with an ST Sound System (excluding aftermarket)

Smart Environments

Orio Bellezza, Executive Vice President
General Manager, Front-End Manufacturing & Technology R&D (SP&A)

Paul Grimme, Executive Vice President
Mass Market and Online Marketing Programs

Carmelo Papa, Executive Vice President
General Manager, Industrial & Power Discrete Group



Smart Environments

#1 in Industrial & ASIC
#1 High Voltage Power MOSFET
#1 Thyristors & Triacs



Source : IHS, ST

In 2015

2.5 TWh more energy
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vs 2014

65 million
Smart meters
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\$55 billion
Investment in the smart
grid WW

ST Offering

Smart Power

Intelligent Power Modules

Power Discrete

Power Line connectivity

Microcontrollers
& Secure solutions

Sensors



Power Line connectivity 

Sensors 



Microcontrollers & Secure solutions 



Smart Things

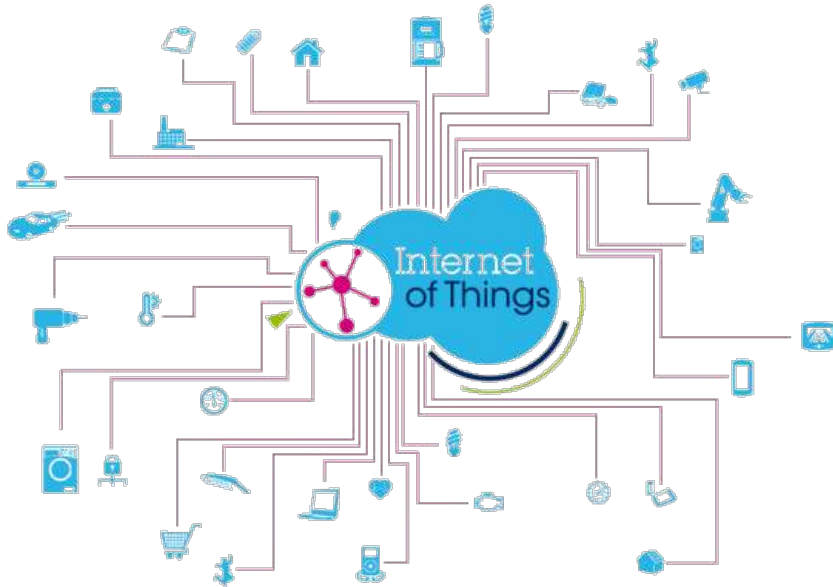
Claude Dardanne, Executive Vice President
General Manager, Microcontroller, Memory & Secure MCU Group

Bob Krysiak, Executive Vice President
President, Region Americas

Benedetto Vigna, Executive Vice President
General Manager, Analog, MEMS & Sensors Group

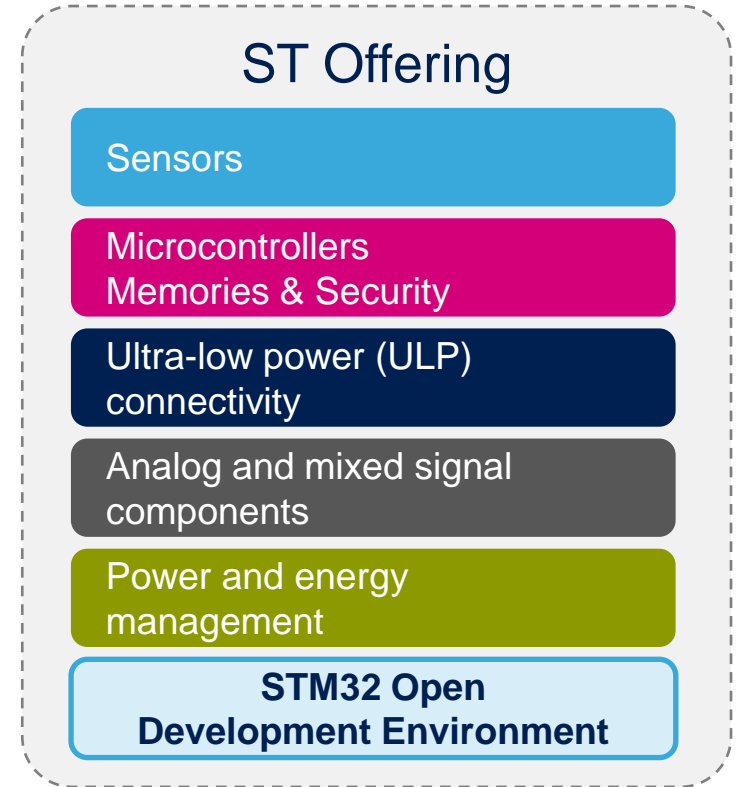
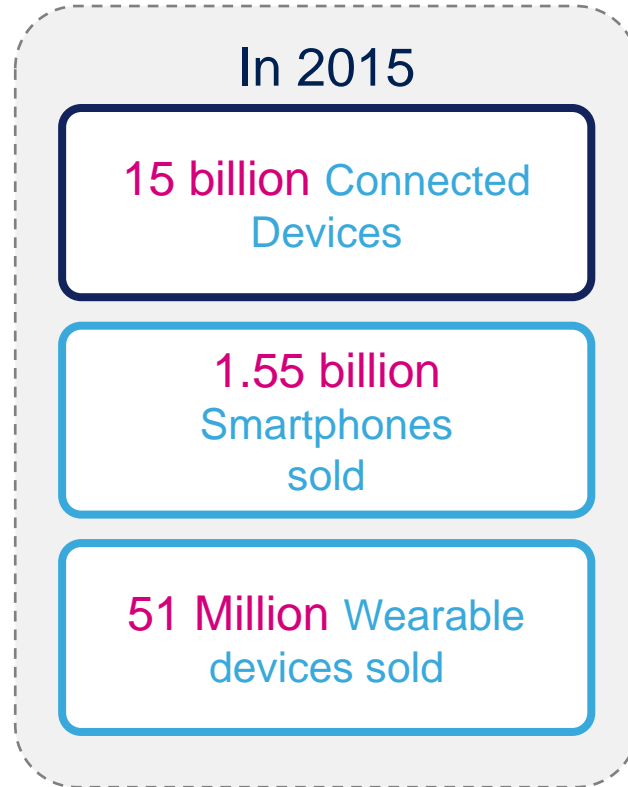








#1 in MEMS Sensors for consumer and Mobile
#1 in 32-bit ARM Cortex-M Microcontrollers



Source : IHS, ST


Smart Things





- Motion sensors 
- Environmental sensors 
- Microphones 
- FingerTip Touch 
- Ranging 
- μ-mirrors 

- General Purpose Microcontrollers 
- Secure MCU 
- Dynamic NFC tags 
- EEPROM 
- Sensor fusion 



- AMOLED power supply 
- Wireless charging 
- Energy harvesting 
- Power conversion 
- Thin film batteries 

- Ultra-Low Power connectivity 
- Long range connectivity 
- Positioning 
- Audio 
- Analog ICs 
- Protection & filtering 

Digital Product Group (DPG)

Gian Luca Bertino

Executive Vice President
General Manager, Digital Product Group

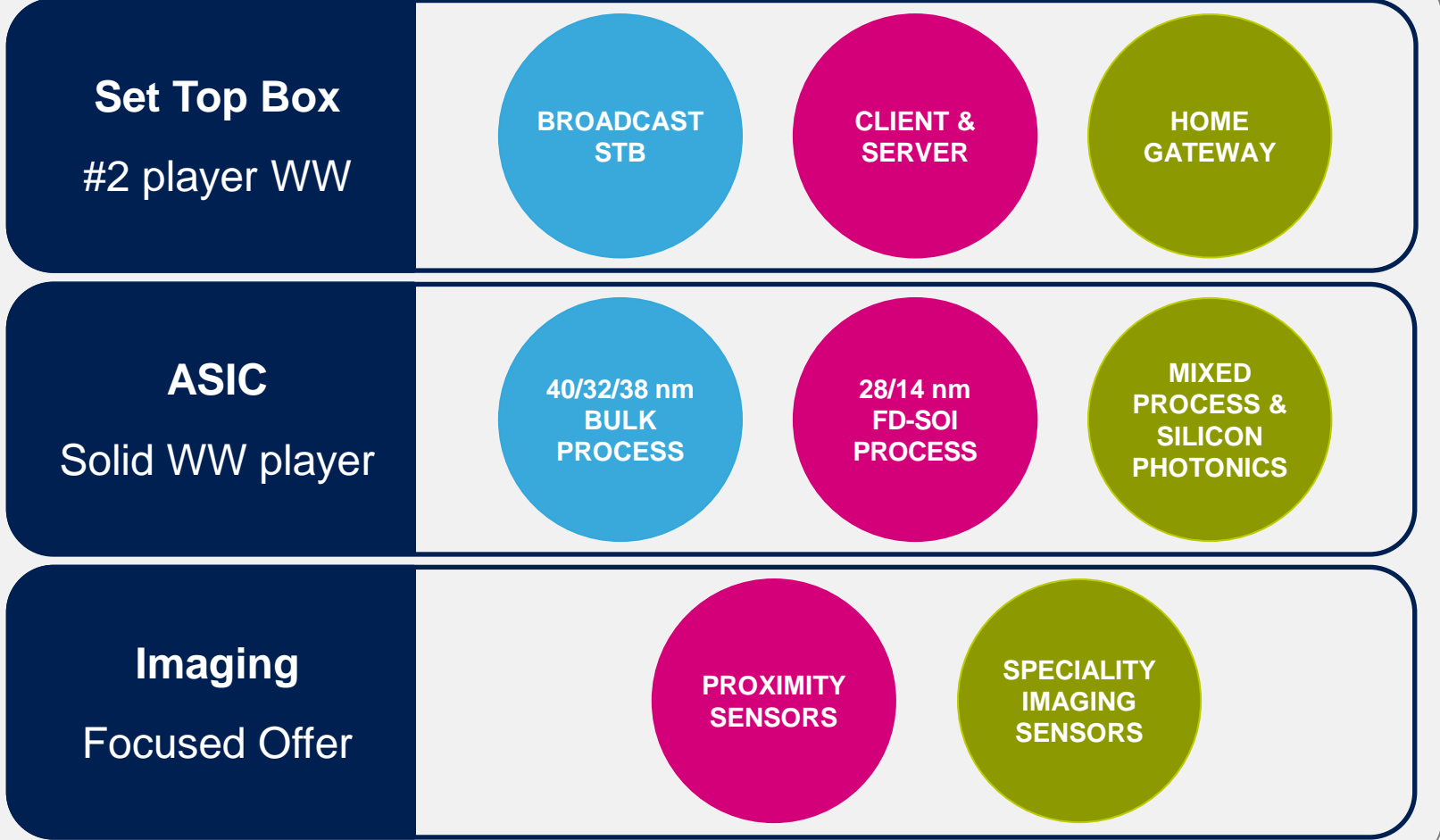
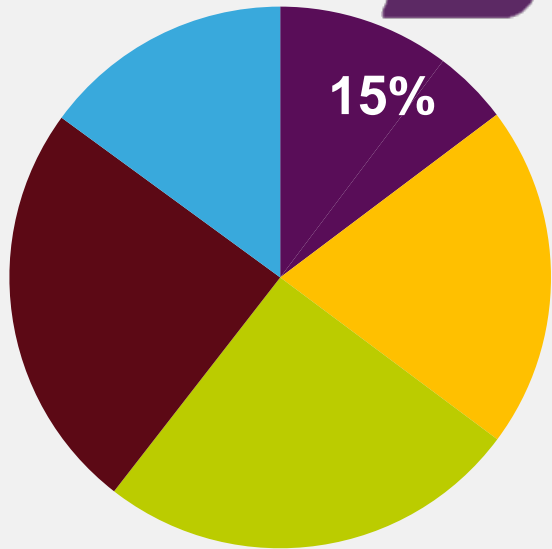




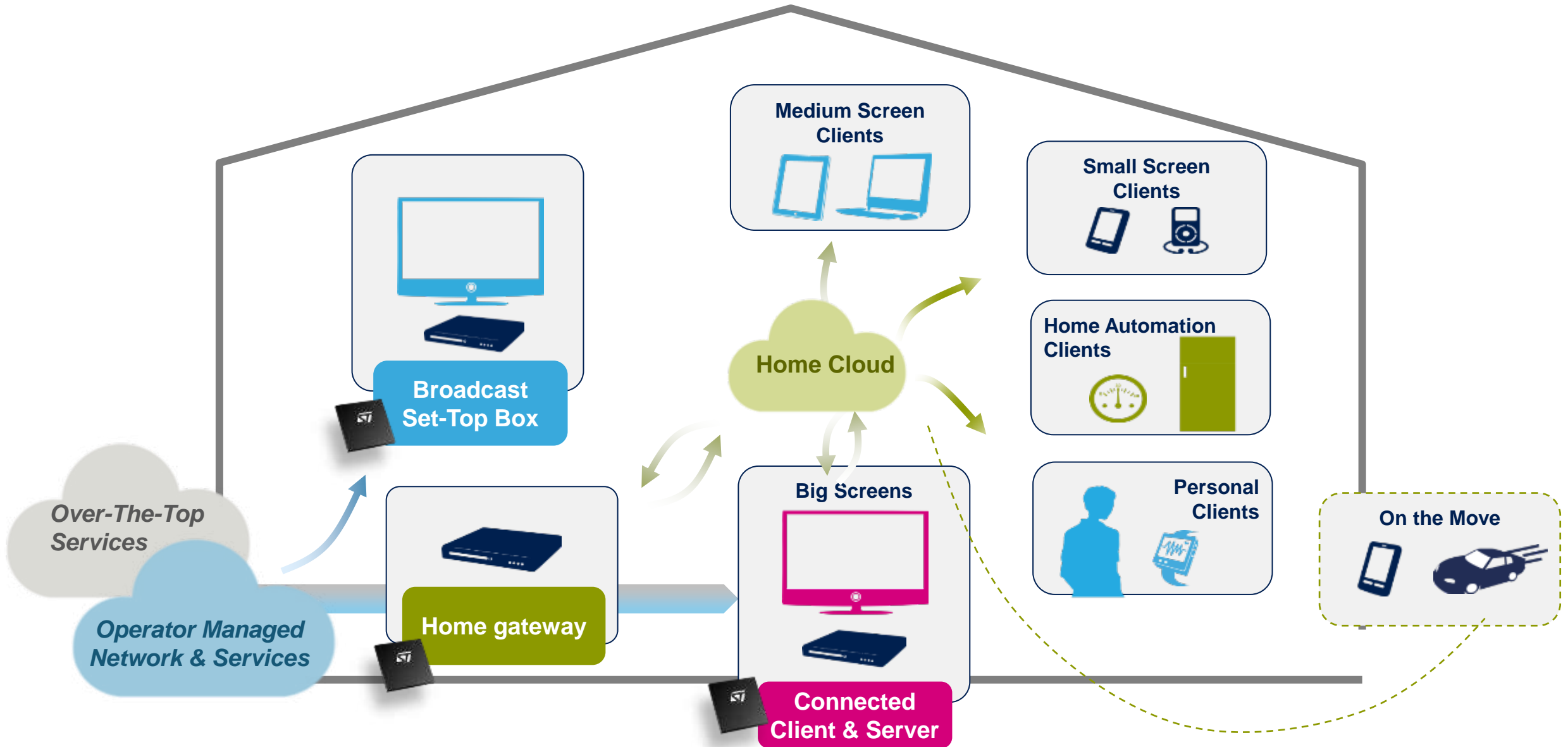
DPG – Digital Product Group

Contribution to ST revenues
FY14

DPG 



STB: Towards the Home Cloud



STB & Home Gateway: Product Portfolio

HOME GATEWAY

Network Access
DOCSIS
Telephony
Routing


Alicante
STiD12x
DOCSIS 3.1



CLIENT & SERVER

Content Anywhere
High Multimedia
performance
Ultra HD


Monaco
STiH4xx
Cannes
STiH3xx




BROADCAST STB

Cost-effective
multimarket
solutions


Liege 2
STiH301
Liege
STiH2xx



 Complete and cost-optimized HW/SW portfolio

 Ad-hoc devices for specific use cases

 HW/SW compatibility within each product family

 From entry broadcast to high-end HEVC on ARM



Experience “Beyond HD” Viewing Experience with STiH418



Multi 1080p60 decode + GFX display as UHD



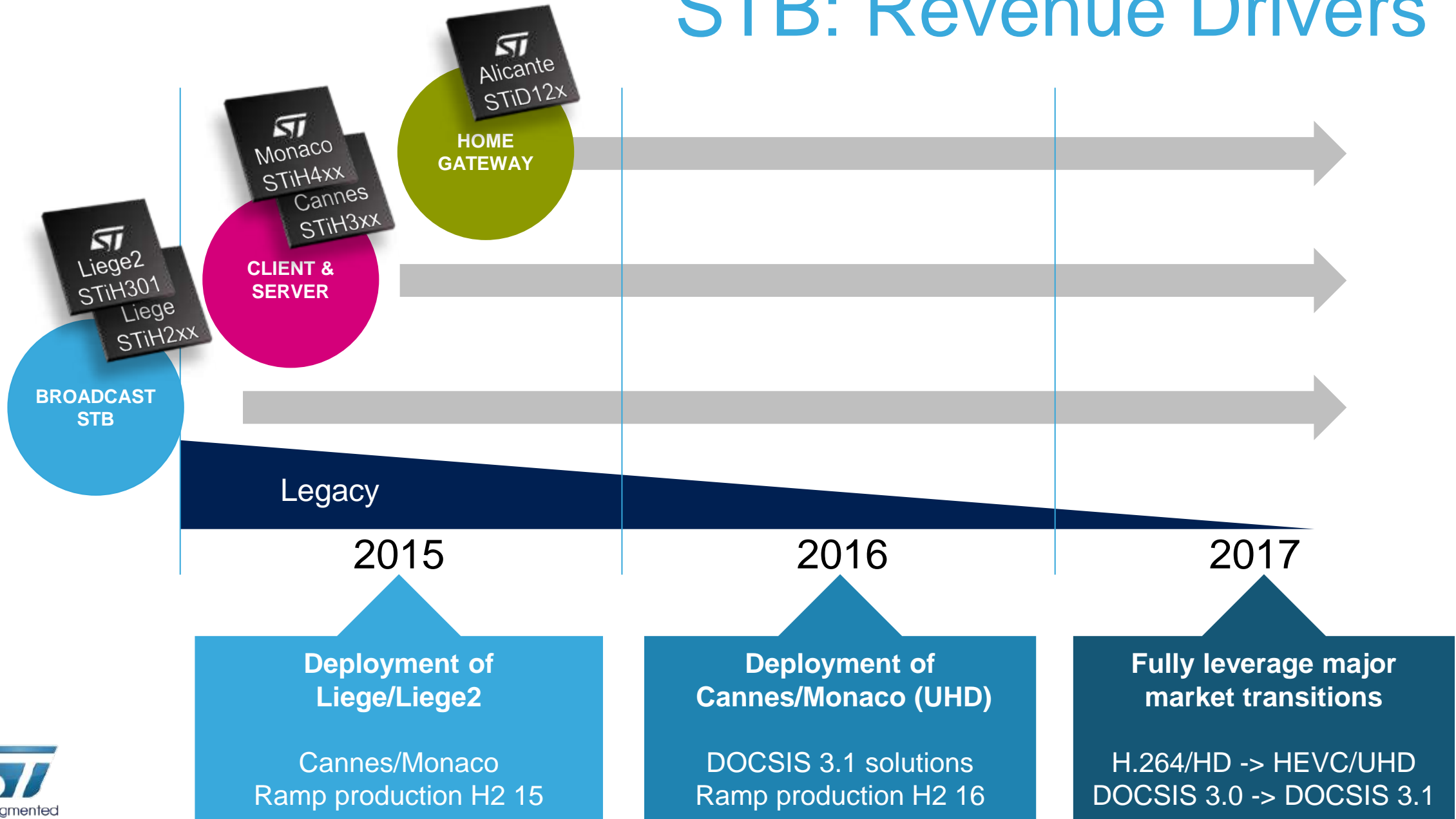
HDMI2
3840x2160 / 60Hz 16:9
HDCP 2/2



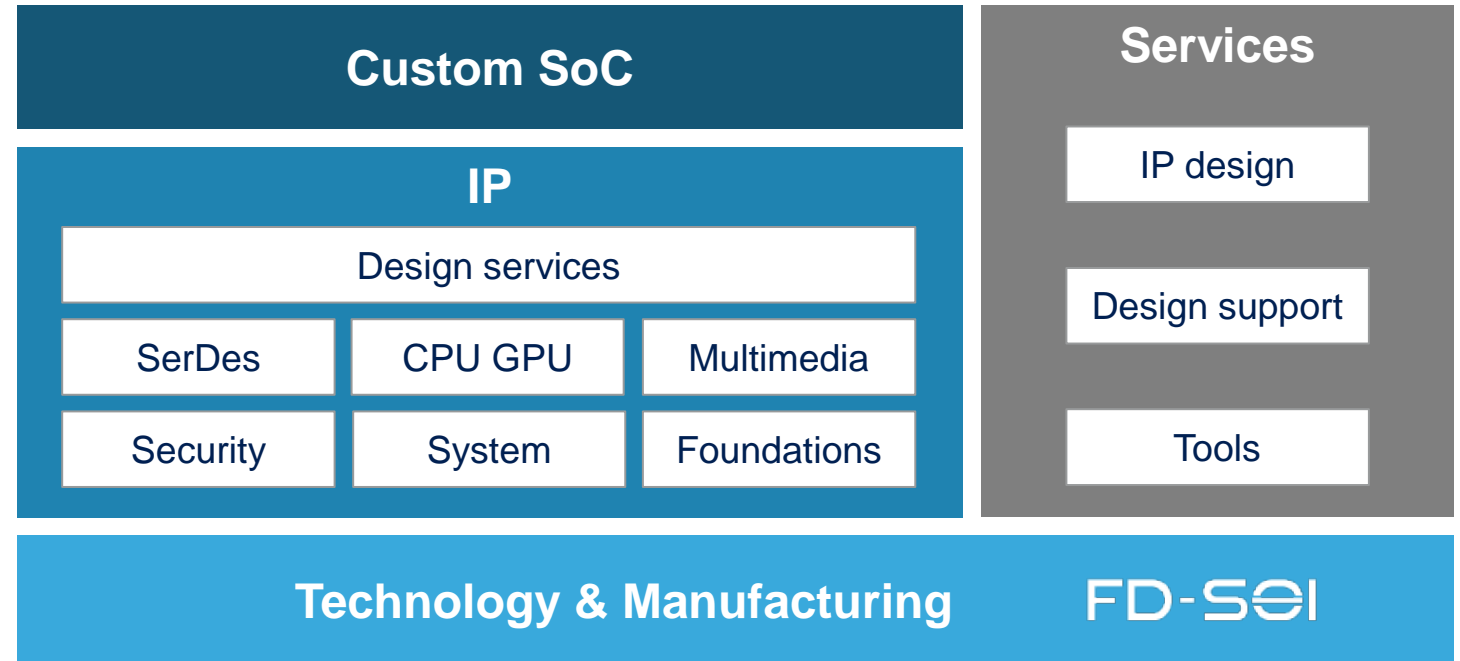
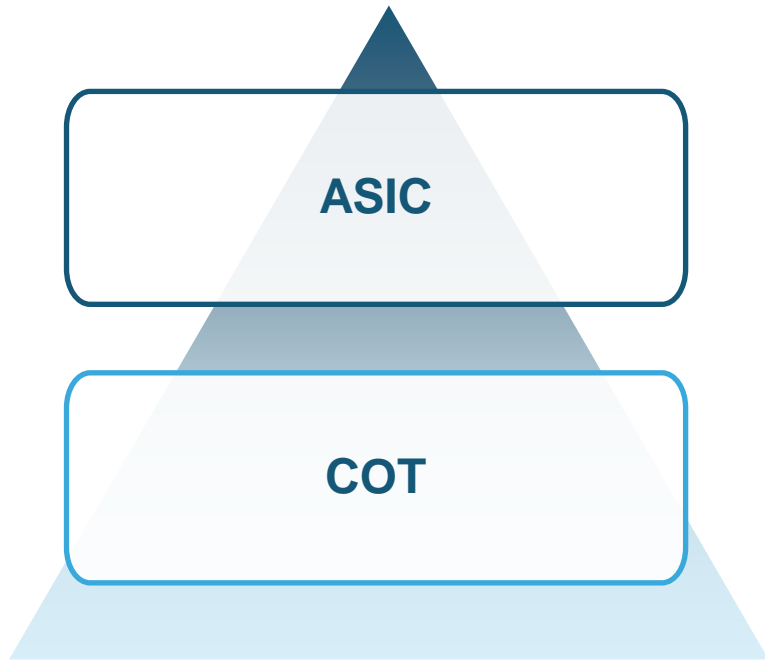
Original UHD HEVC or VP9 content full screen



STB: Revenue Drivers



ASIC: Flexible Business Model



Consumer



Networking



Computer Peripherals

ASIC: Complete Offer



**MIXED
PROCESS &
SILICON
PHOTONICS**

- Best in Class BiCMOS technology enables multiple applications, including ICs for fiber optic modules
- Fully integrated silicon photonics technology brings savings in bill of material, production throughput, power consumption and space



**28/14nm
FD-SOI
PROCESS**

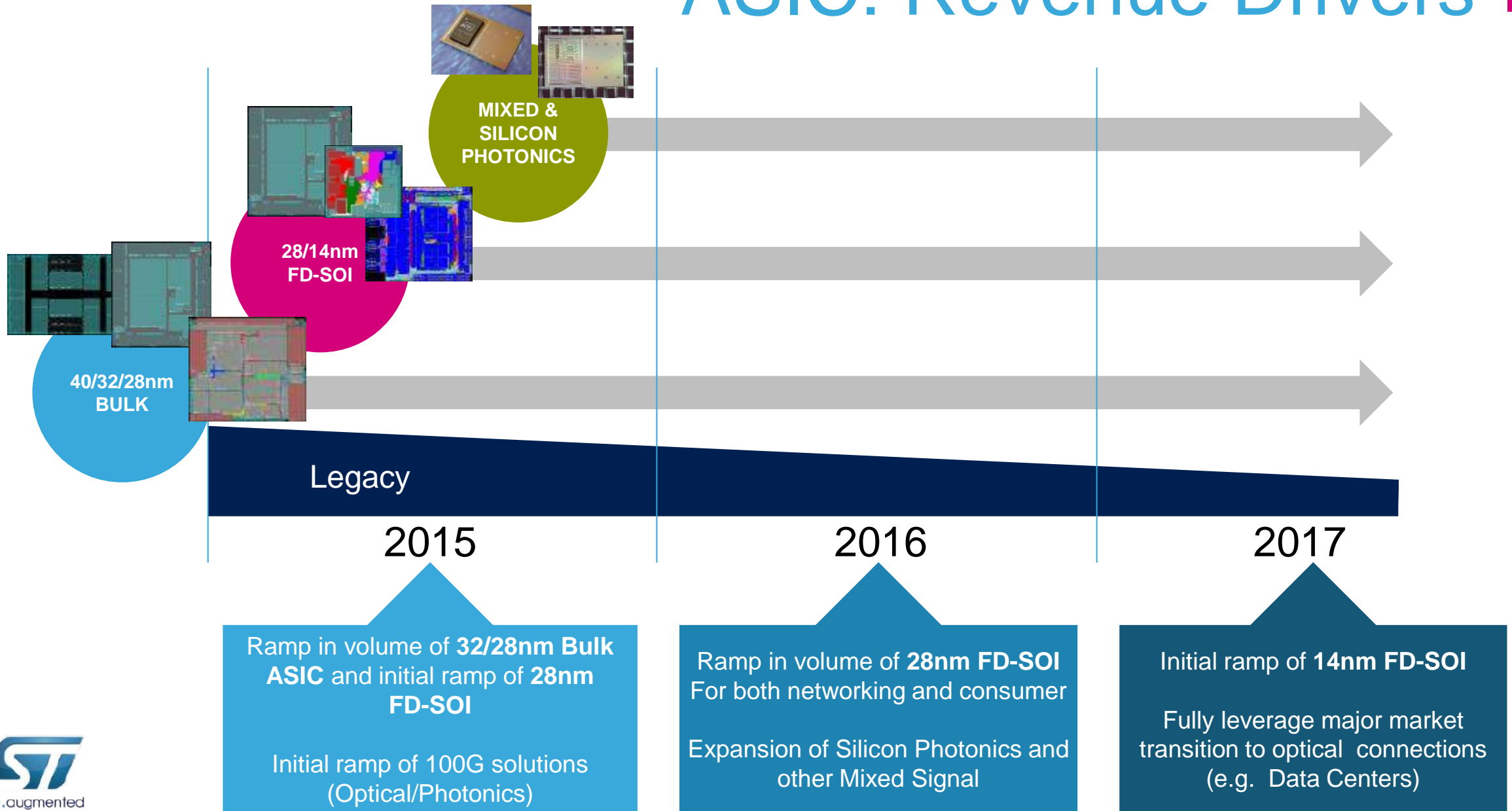
- FD-SOI technology enables mixed analog/digital ICs with high performance, ultra-low power and high resilience to space radiation
- Complete foundation IP, including High Speed SerDes (up to 28GBps) and special memories (TCAM)



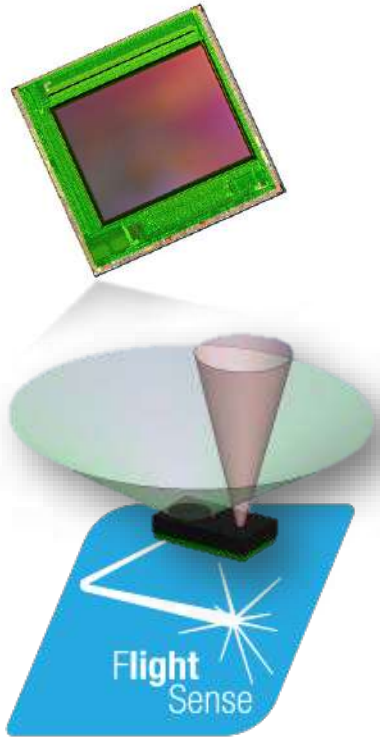
**40/32/28nm
BULK
PROCESS**

- Bulk technology enables cost sensitive and high integration ICs
- Complete foundation IP, including High Speed SerDes (up to 14GBps) and special memories (TCAM)

ASIC: Revenue Drivers



Imaging: Focused Offer



**SPECIALIZED
IMAGING
SENSORS**

- Large Pixel sensors, Stitched large sensors, Medical Image sensors, Customs solutions
- Proprietary Pixel technology, Including Specialized Silicon Process and market proven IP

**PROXIMITY
SENSORS**

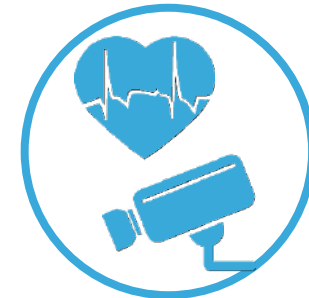
- Photonic sensors for proximity, ranging gesture, depth map
- Flight Sense Proprietary Technology, including Specialized Silicon Process and market proven IP



Consumer

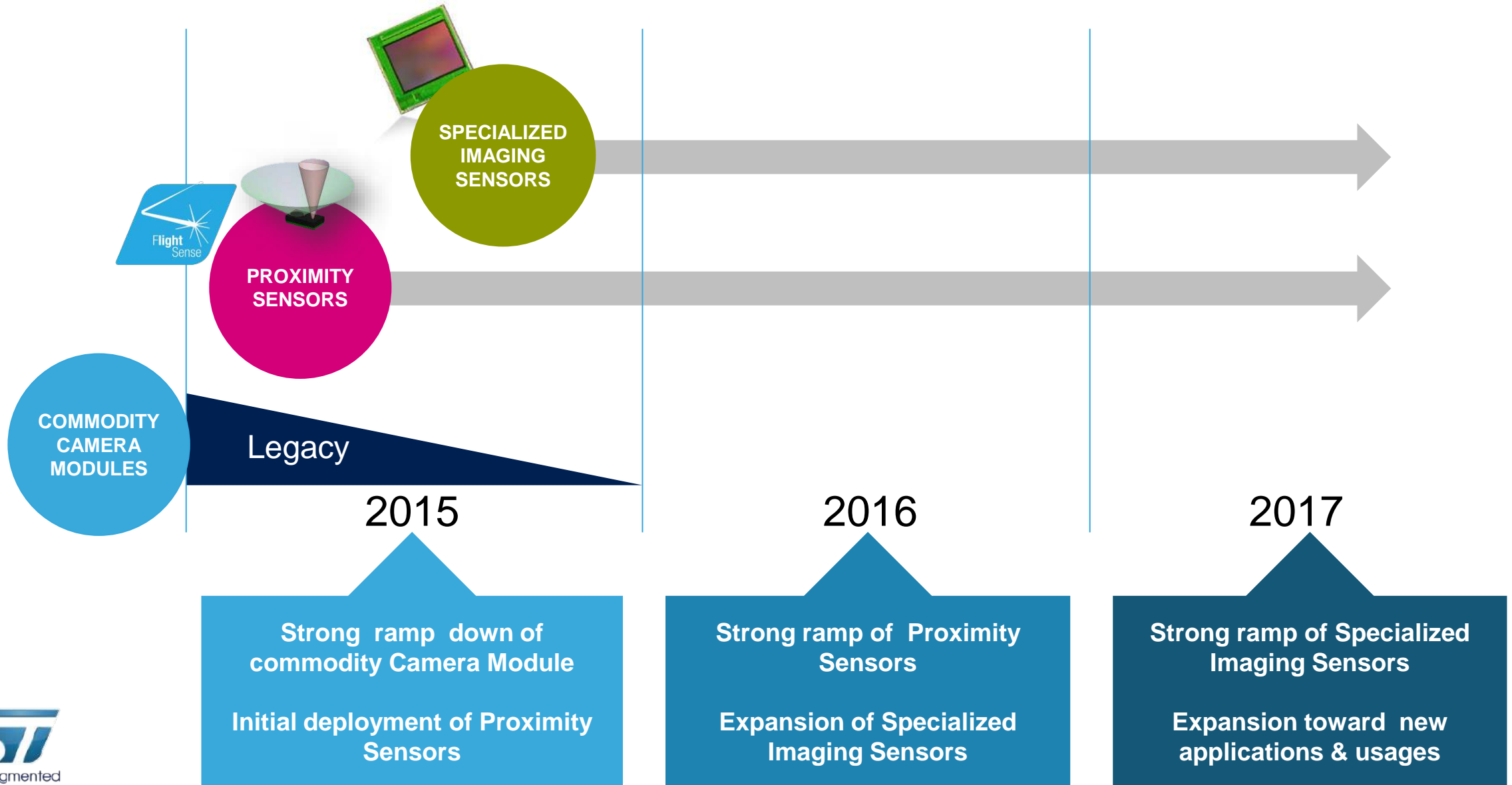


Automotive



Security, Medical

Imaging: Revenue Drivers



- Leadership in the transition to HEVC/UHD Set-top Box and DOCSIS 3.1 headless gateways and cable modems toward smart home
- Leadership in high speed, highly integrated devices for networking and the transition from copper to optical fiber
- Leadership in ultra low power & leakage embedded processing solutions
- Leadership in differentiated sensors through close cooperation with key players in consumer, automotive, hybrid auto focus and surveillance

Microcontroller, Memory & Secure MCU (MMS)

Claude Dardanne

Executive Vice President
General Manager MMS Group



MMS Positioning in 2014

EEPROM memories

#1 worldwide supplier 2014

Secure Microcontrollers

#4 worldwide supplier 2014

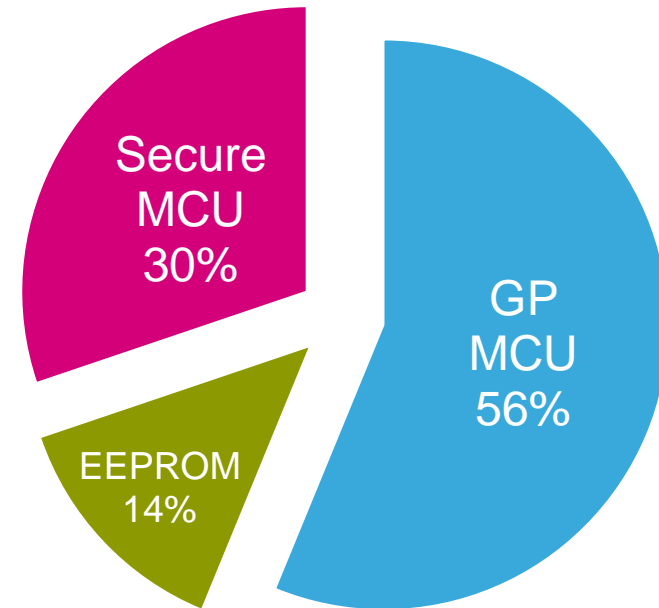
General Purpose Microcontrollers *

#4 worldwide supplier 2014

Consolidated MCU *

#2 worldwide supplier 2014

MMS 2014 Business by Activities



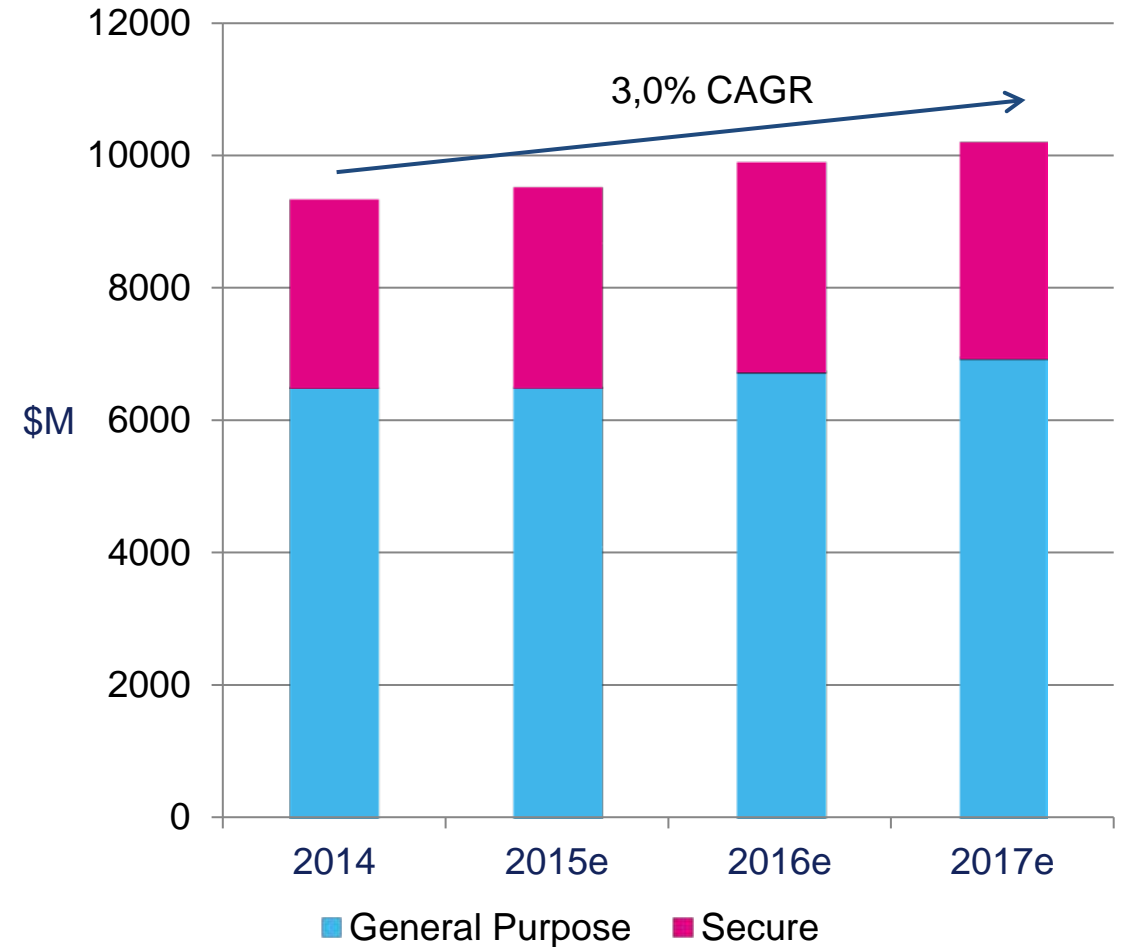
- MMS = 20% contribution to ST 2014 revenue
- Major growth opportunities :
 - General Purpose MCU
 - Secure MCU

Microcontroller Market Trend

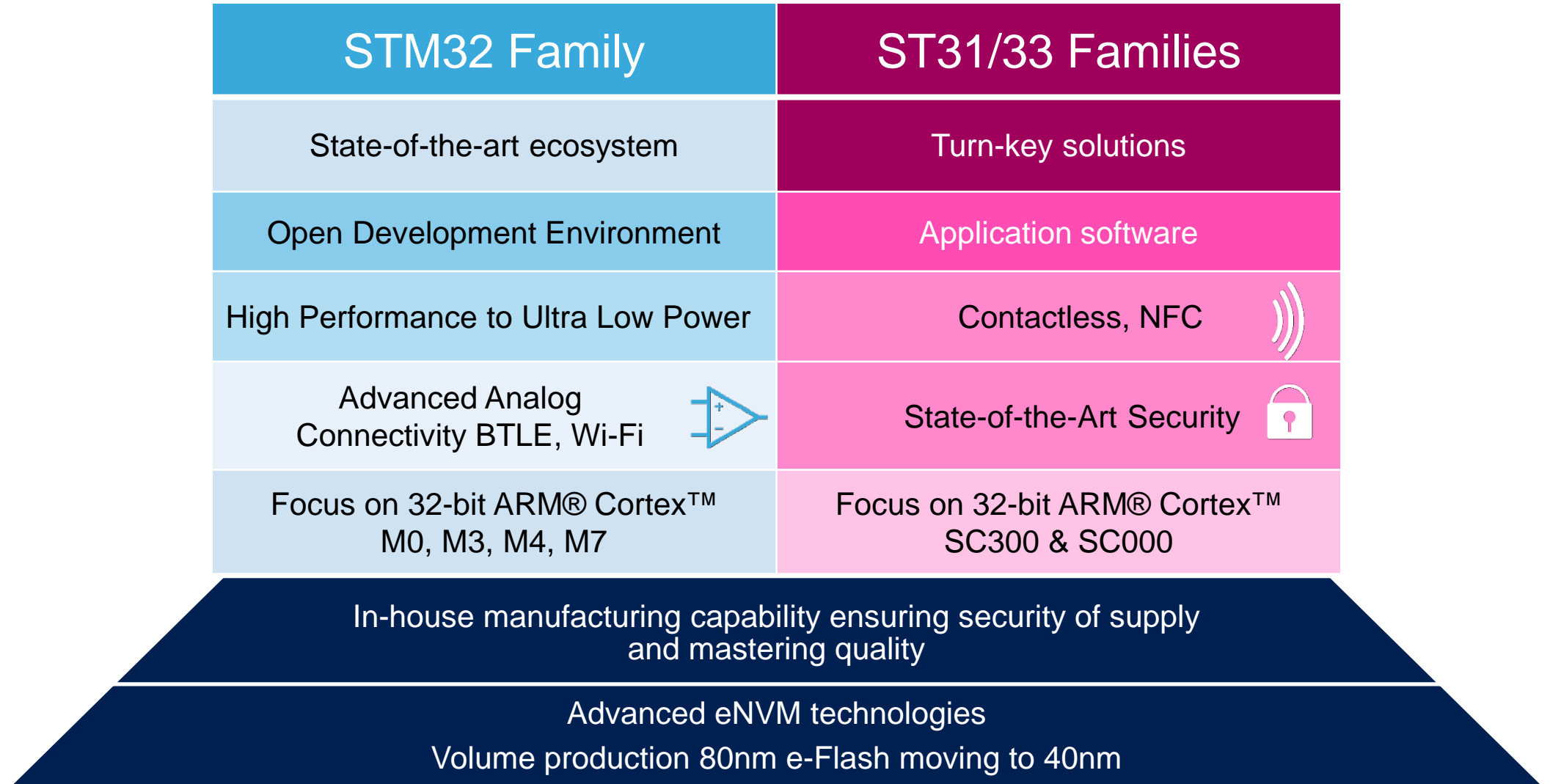
Market Dynamics

- Traditional multi-market & application development still driving part of the General Purpose MCU growth
 - Industrial
 - Consumer
- Secure MCU growth driven by :
 - Secure Smartcard solutions : Banking, ID
 - Mobile transactions
 - Object authentication (Brand protection...)
- IoT providing additional growth:
 - Applications embedding GP MCU with various levels of security
 - Much higher growth expected from the Mass Market

General Purpose + Secure MCU TAM



Microcontrollers Enablers



General Purpose MCU Market

- Addressing multi-application, multi-customer
- STM32 platform with added value

Performance

- Higher computing
- Advanced peripherals
- More connectivity

Ultra low power

- Low power consumption
- Optimized functional modes
- Smaller form factor

Easy development

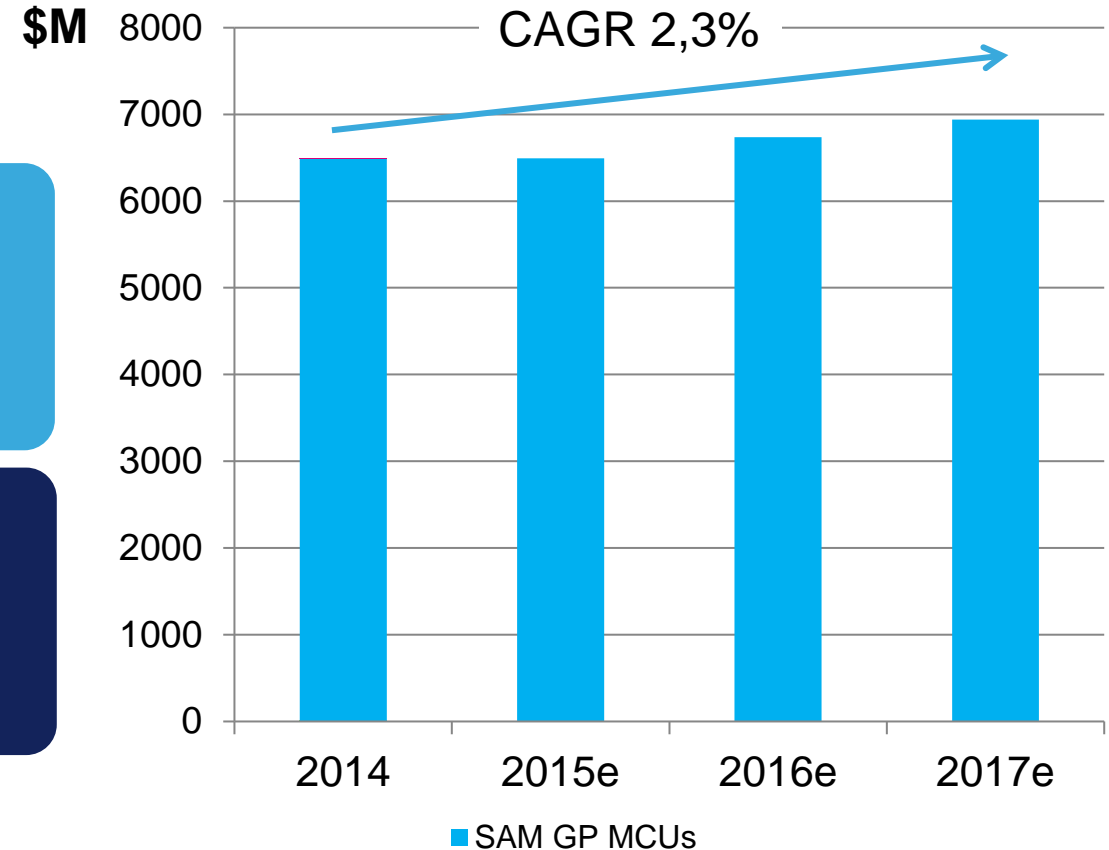
- Extended ecosystem
- Low entry barrier
- Open development environment

Cost effective

- High level of integration
- Reduced development efforts
- Easy application upgrades

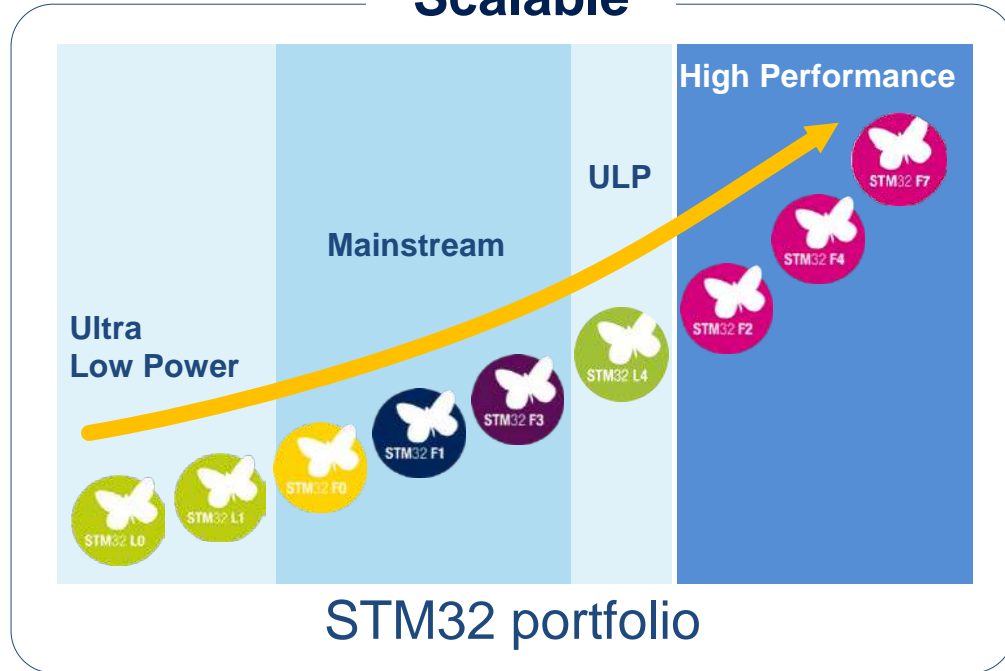
Above features fitting perfectly IoT needs

General Purpose MCU SAM*

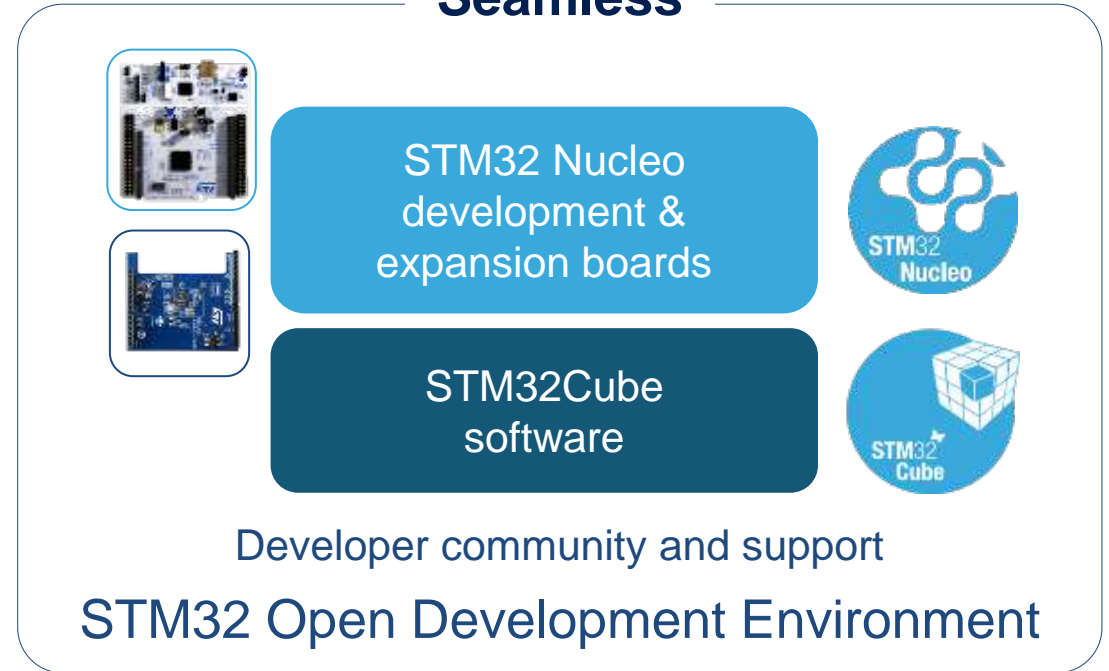


STM32 Solutions for Mass Market

Scalable



Seamless



- STM32 Family ~ 600 part numbers available
- More than 30,000 customers worldwide
- Ready to support IoT growth

- Secure Element & Contactless
- ST31 & ST33 platforms with added value :

State of the art security

- Certified HW solutions
- High performance crypto accelerators

Connectivity

- Best interoperability
- Highest robustness

Turn-key solutions

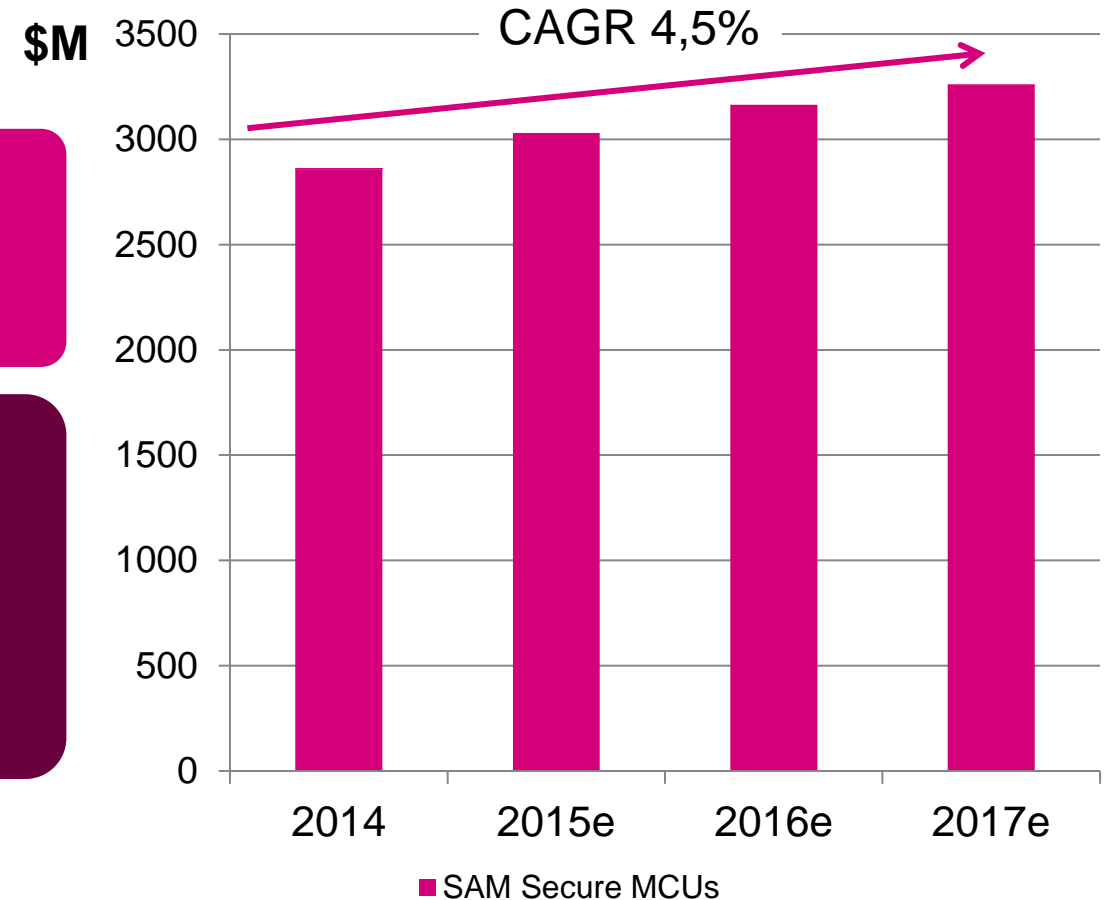
- Certified HW&SW solutions
- Dedicated development tools & support team
- Product customization and personalization services

Cost effective

- Products based on State-of-the-art flash process
- Reduced development effort
- Easy application upgrades
- Advanced packaging options

Above features fitting perfectly IoT needs

Secure MCU SAM



Banking

- Growth driven by china & US EMV contactless migration.
- Global market moving to dual interface & contactless

ID

- Growth driven by national ID programs
- Running deployment of ePassport

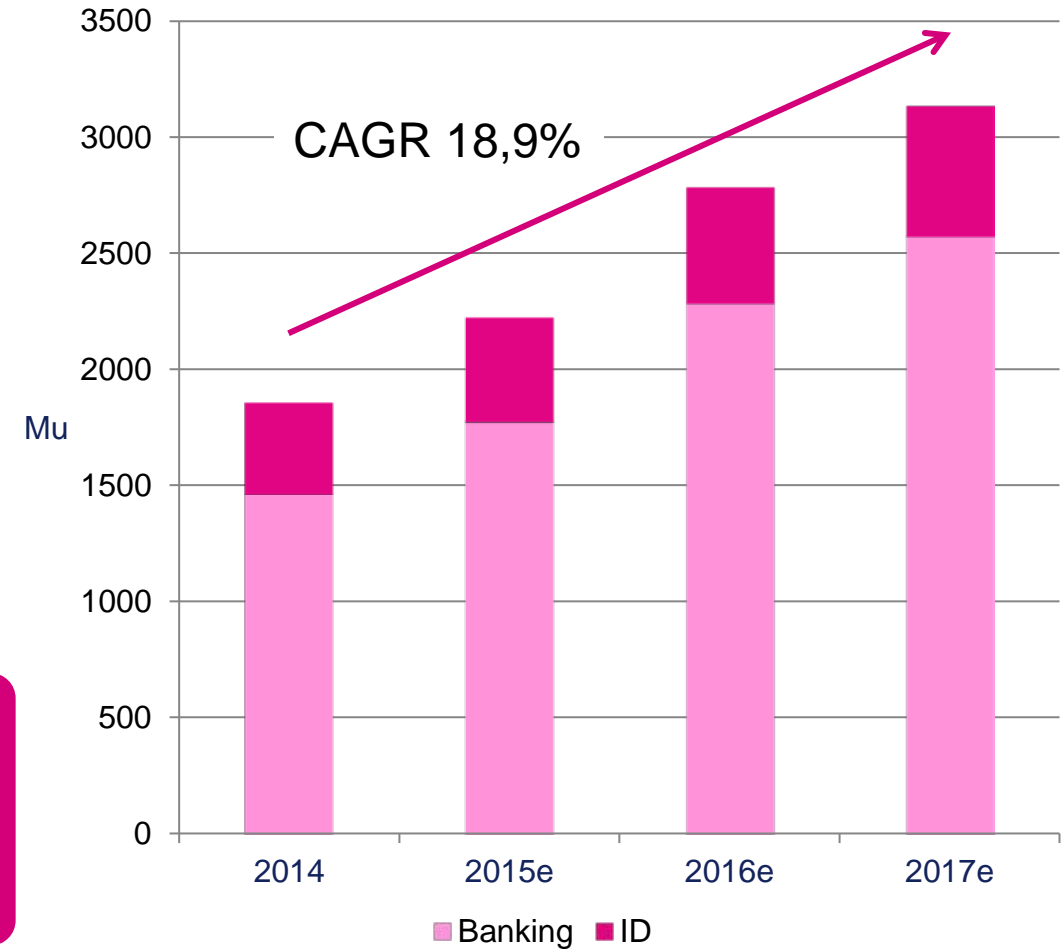


ST solution

ST31 series of highly secure 32-bit MCU - contact/contactless – flash-based platform embedding advanced software



WW volume TAM



Source : ST estimation + various sources including ABI, Eurosmart, Nilson Report,

Secure Mobile Transactions

Market

- Strong growth expected in the next 3 years
- Smartphone pervasion generating need for secure mobile transaction functionalities

ST, complete solution provider

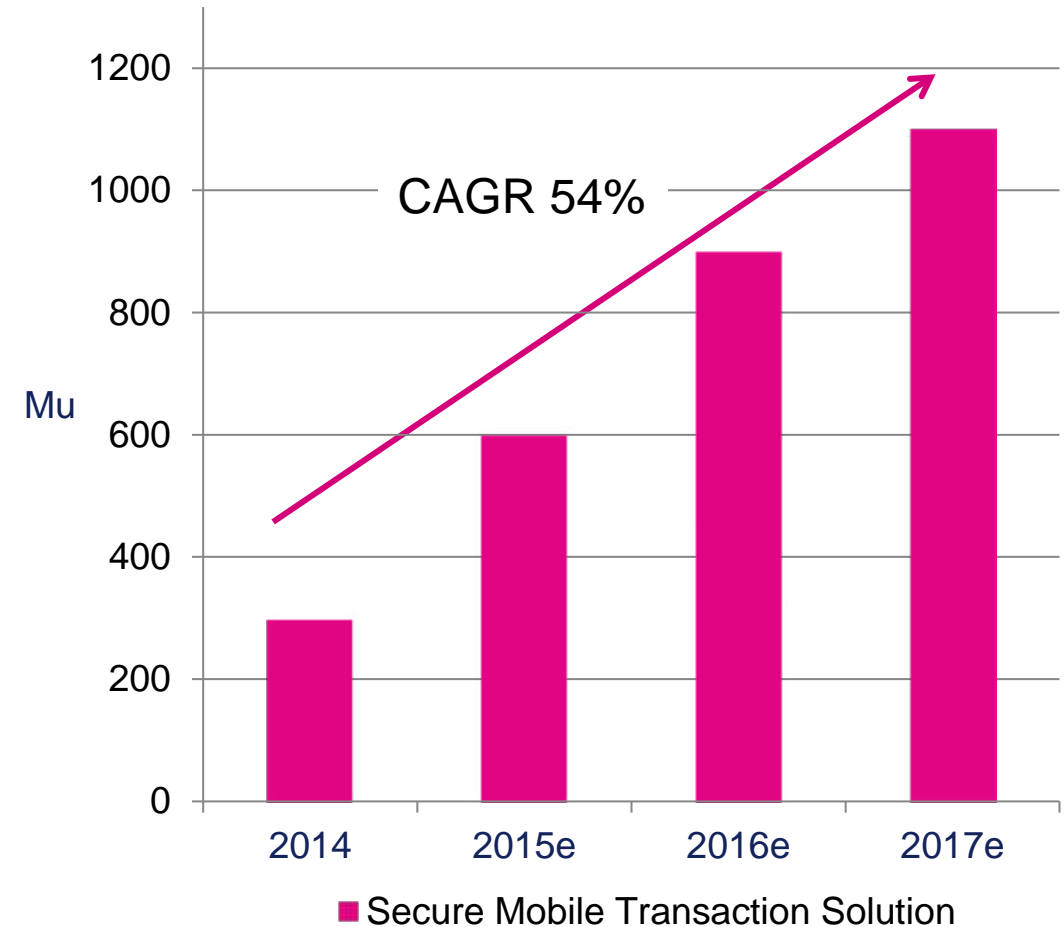


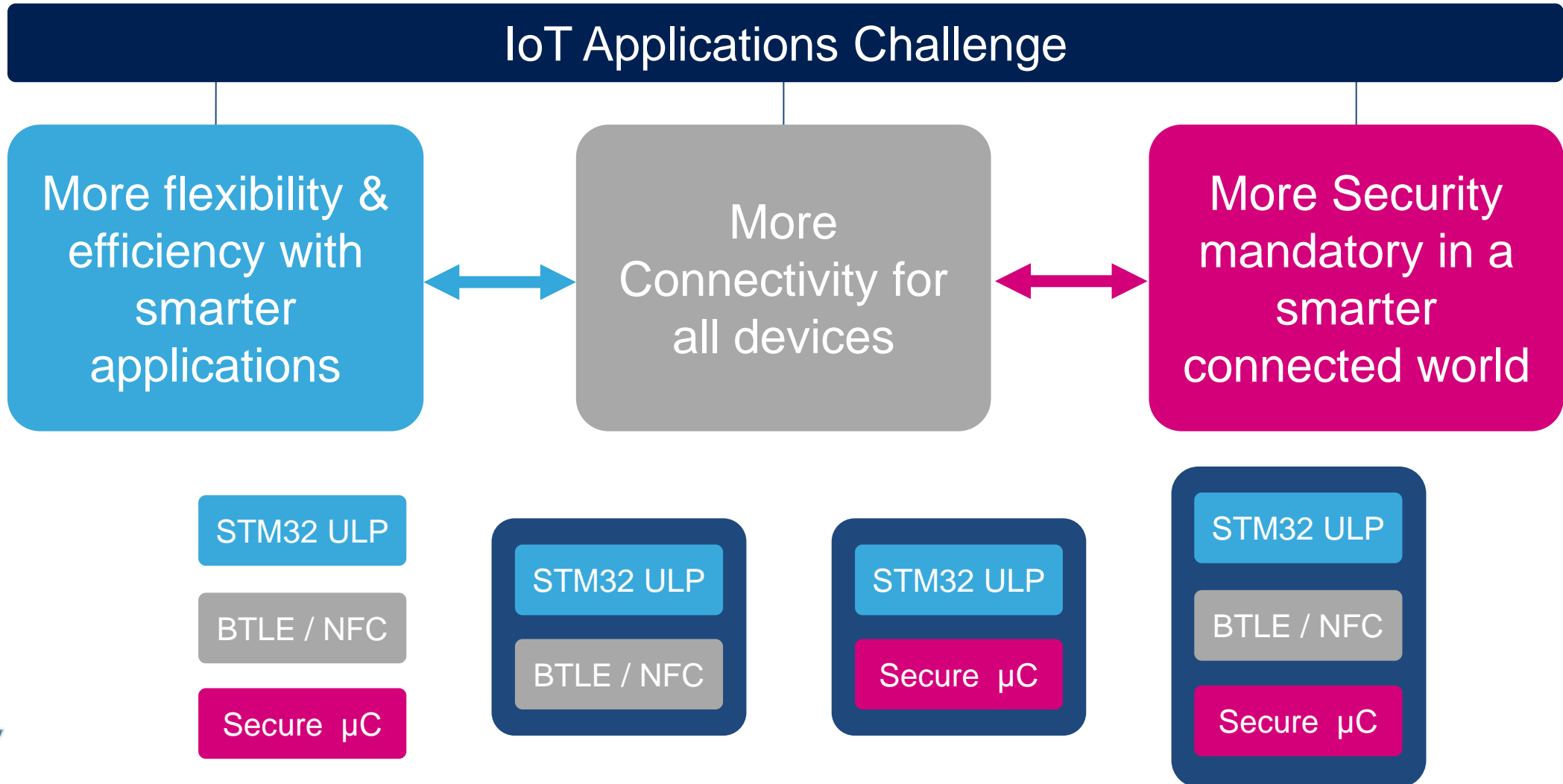
ST33 family : Best in Class Secure Element (SIM form factor or Embedded)
ST #1 WW Supplier



ST21NFC Controllers

WW volume TAM



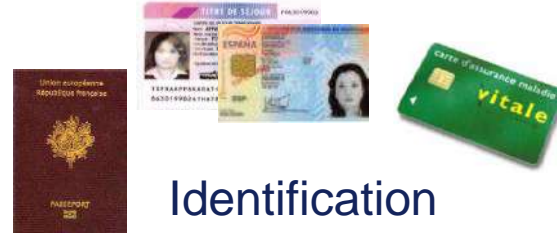


GP & Secure MCUs for IoT

Highly Sophisticated Attacks



Payment



Identification

- Protection of critical assets
- Strong security for private data



- Resistance to attacks for connected devices

Smart Grid, Industrial Gateways

Healthcare



Smart meter Appliances Smart home

- Devices require different levels of Security, from General Purpose MCU to Secure MCU

Basic



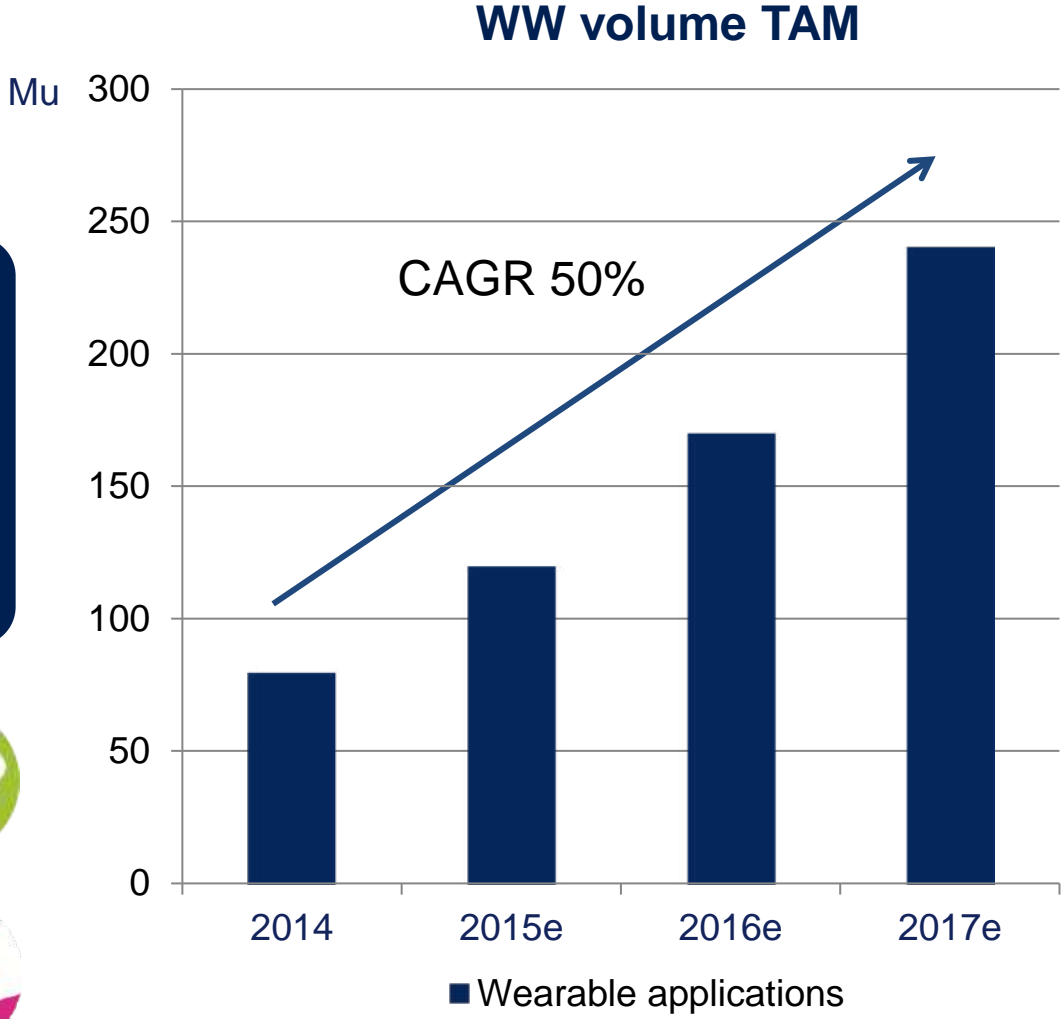
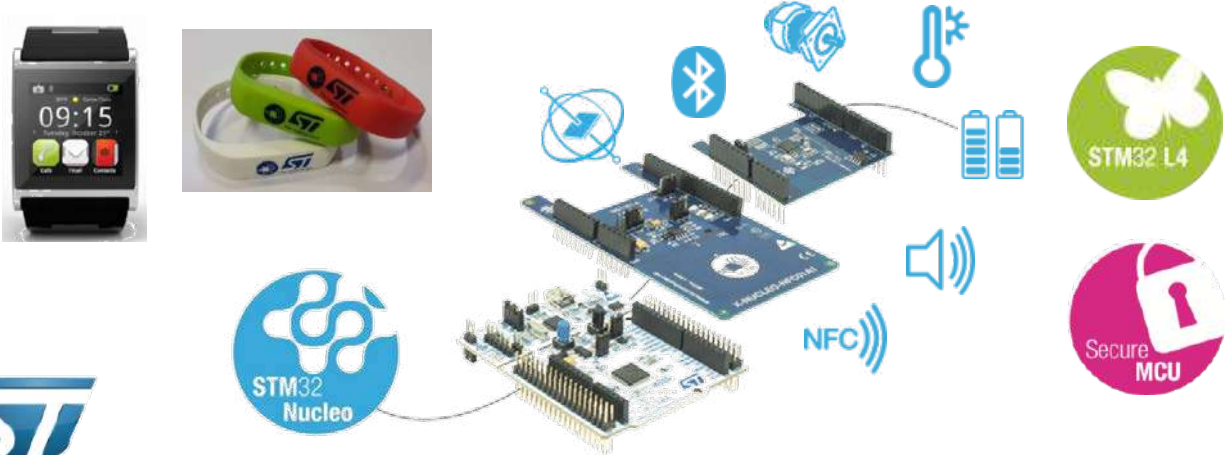
Wearables

The 1st wave of IoT products

- Growth linked to smartphone business
- Smart watches, fitness, smart glasses, health...

ST solution

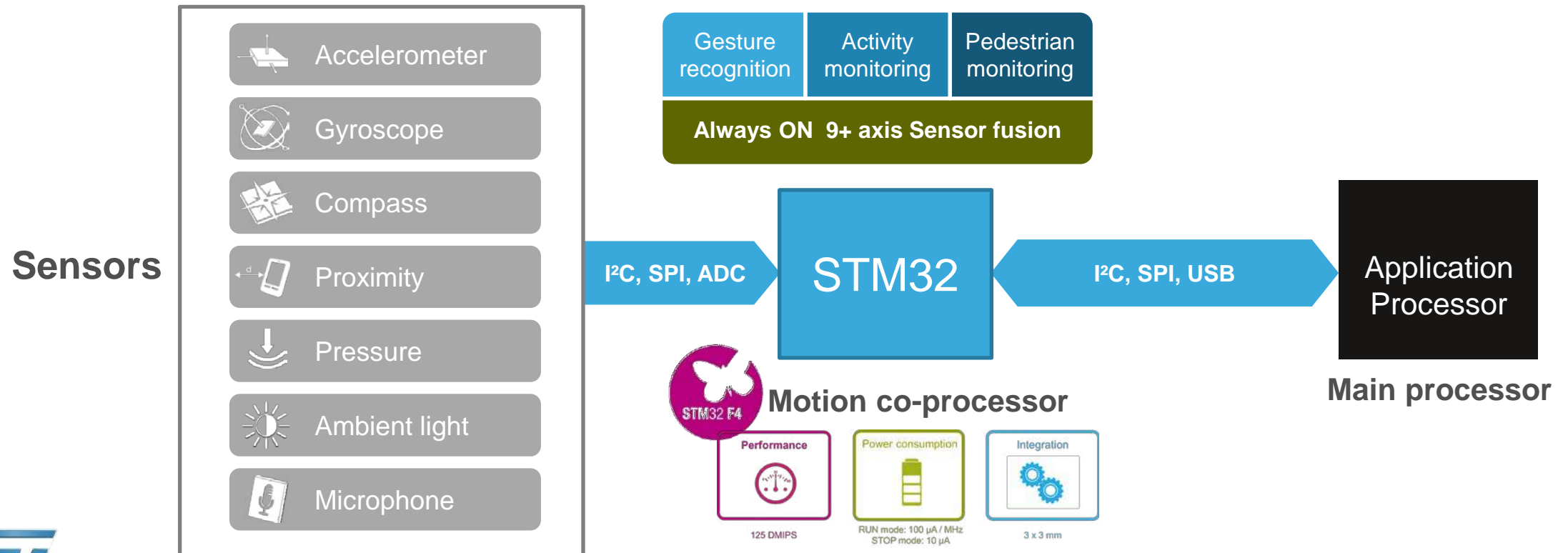
- Ultra-low power 32-bit MCU: sensor hub, application processor
- Connectivity : Bluetooth Low Energy
- Security : anti-counterfeiting & personal data protection
- Seamless development tool : STM32 Nucleo based



Source : ST estimation + various sources including ABI,

Sensor Hub Solutions

- Major success in smartphones and accessories
- Enable “always on” application improving dramatically battery life
- STM32F4 computing power allows to host gesture monitoring and pedestrian indoor navigation



Secure Transaction & Wearable

Wearable applications embedding Secure Transactions capabilities → mainly smartwatches

ST SOLUTION

Ultra low power 32-bit MCU : sensor Hub, application Processor → STM32L series

Connectivity :

- Bluetooth Low Energy
- NFC controller

Security : Secure Element



Running deployment



Gateway & Concentrators



Smart Meter

ST SOLUTION

STM32 Family

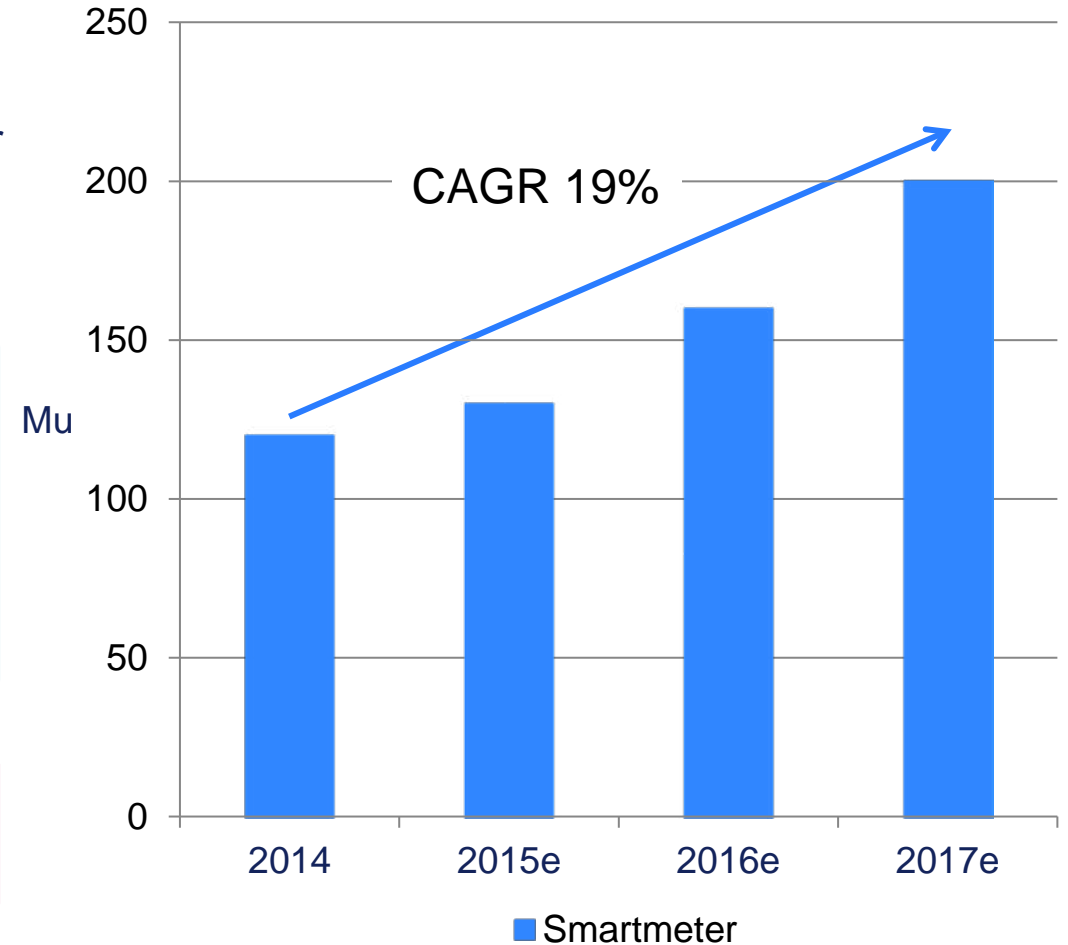
- Very high performance & power efficiency
- Increased reliability / long life-time support
- Safety capable
- Powerline connectivity

ST31 & ST33 Embedded security solution

- Secure element for safety and security

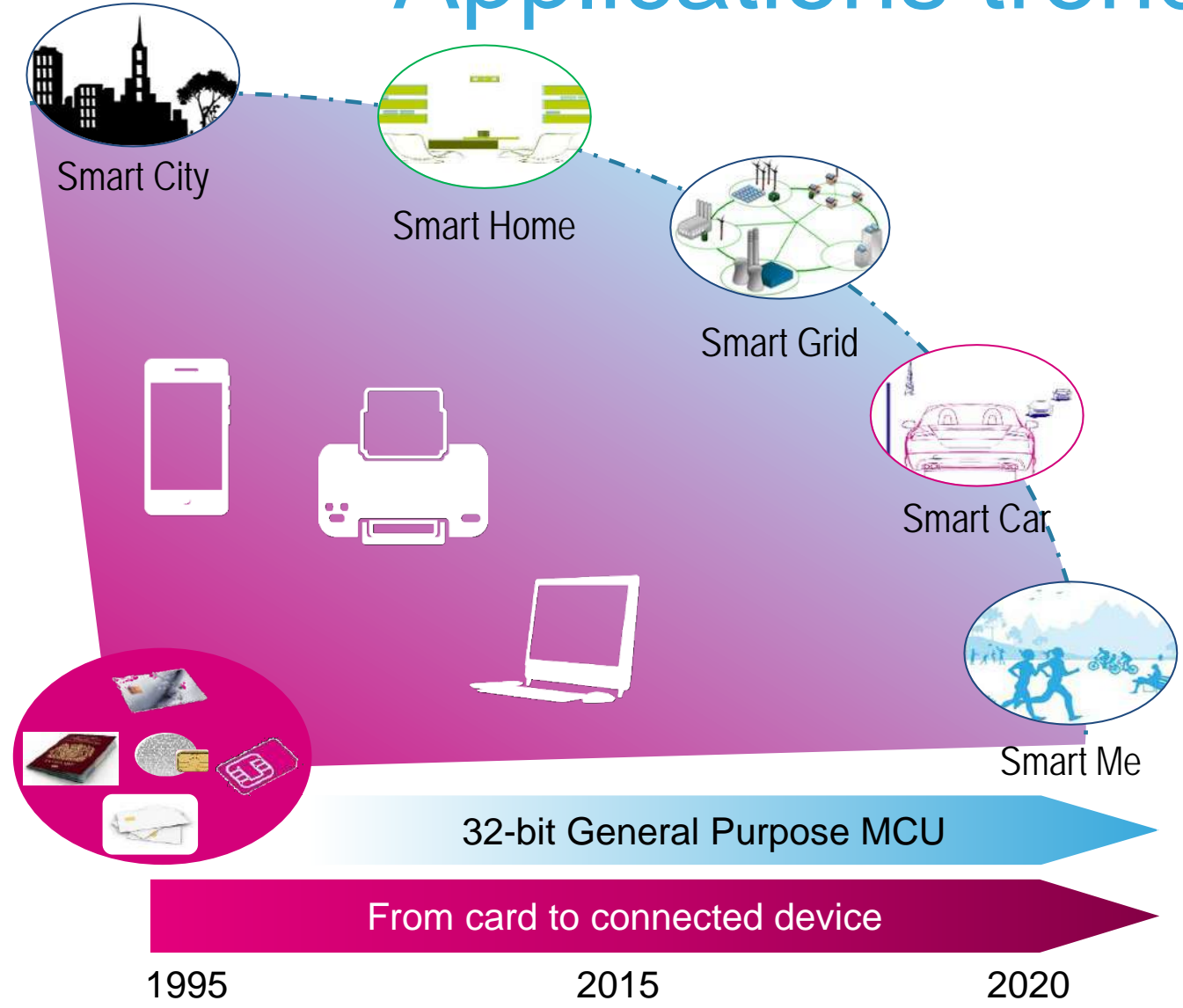


WW volume TAM

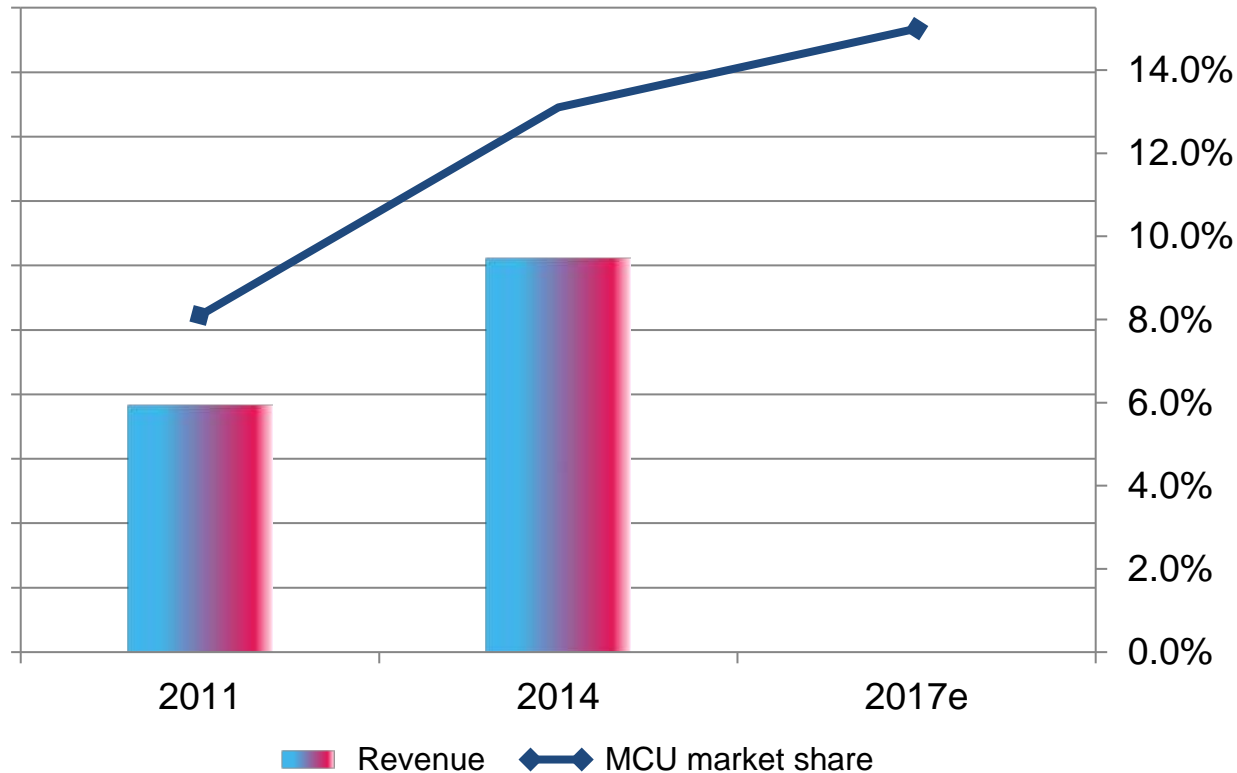


Source : ST estimation + various sources including ABI,

Applications trend



ST → General Purpose + Secure MCU Revenue



- MCU share % vs TAM (Source WSTS)
- Excluding Automotive MCUs



Pursue double digit profitable growth and market share gain capitalizing on solid foundation

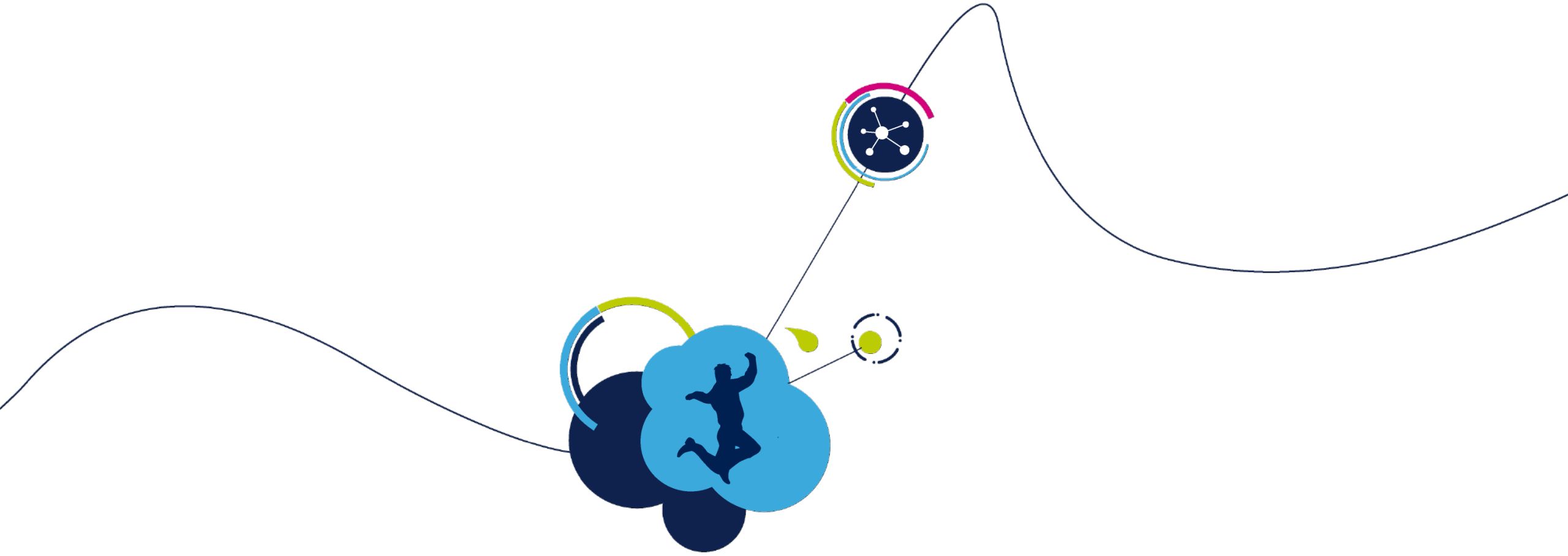
Maintain WW leadership :

- 32-bit General Purpose MCU
- 32-bit Secure Element

Reinforce & proliferate advanced connectivity solutions : Bluetooth Low Energy, NFC...

Deploy secure software solutions dedicated to the Banking & ID markets

Drive evolution of IoT market embedding more connectivity and security on top of General Purpose MCU → become the #1 player



Q & A

Analog, MEMS & Sensors (AMS)

Benedetto Vigna

Executive Vice President
General Manager, Analog, MEMS, Sensor Group



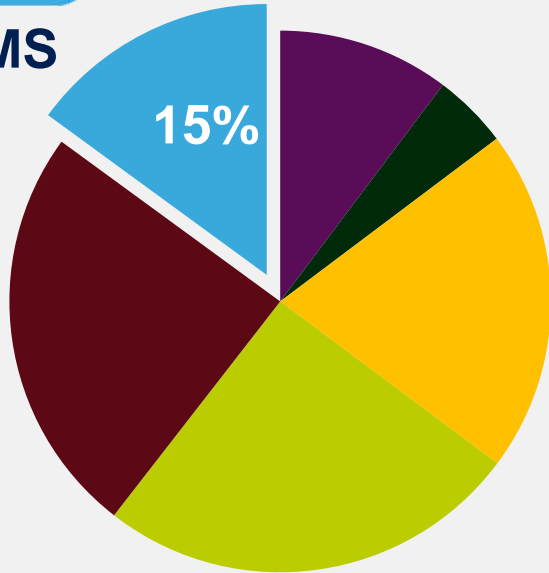


AMS – Analog, MEMS & Sensors

Contribution to ST revenues FY14



AMS



Portfolio

MOTION SENSORS

Accelerometer, gyroscope,
Magnetic sensor



MICROPHONES

Analog & Digital



ENVIRONMENTAL SENSORS

Pressure, UV



ACTUATORS

Fluidics MEMS
Micro-Mirror



Sensor Hub
& Sensor Fusion

TOUCH FingerTip



LOW POWER ANALOG

Standard Analog
High-end Analog



RF

Bluetooth, SubGhz, Wi-Fi



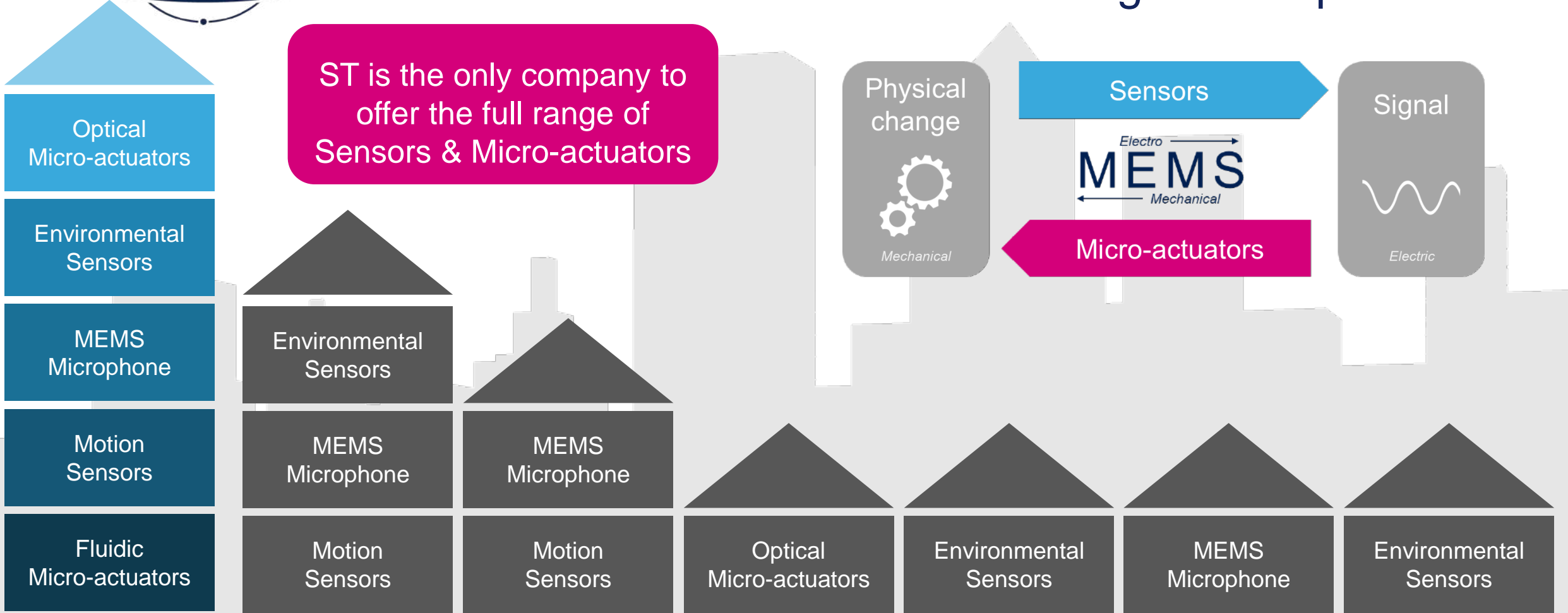
#1 in MEMS Sensors for consumer and mobile
#2 in MEMS Sensors & Micro-actuators



MEMS Competitive Landscape

ST offering vs Competition

ST is the only company to offer the full range of Sensors & Micro-actuators



AMS Product & Market Strategy

New products

New products for traditional markets




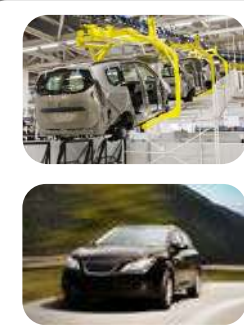

New products for new markets



Traditional products for traditional markets



Traditional products in new markets for ST










New Markets



AMS – Strategy Execution

2012-2015 Revenue evolution drivers

-  Consumer motion MEMS
-  Standard Analog & Logic (pruning)
-  Inkjet
-  μ Mirrors
-  Automotive/Industrial MEMS
-  Touchscreen and High-End Analog
-  MEMS Microphones

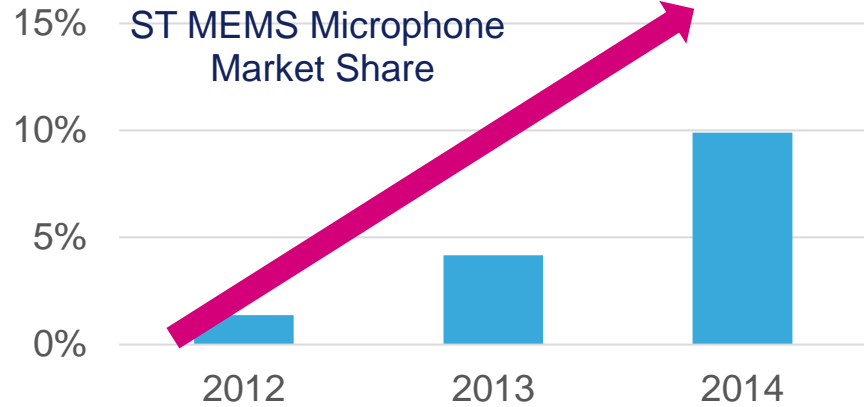
2015 Focus

- Grow **new generation 6-axis ultra-low power motion MEMS** with key customers
- Continued expansion of **touchscreen controllers & MEMS microphones** business
- Wider adoption of **environmental sensors**
- Broadening our **customer base in China**
- **MEMS micro Mirrors** in PC applications
- Addressing **Mass Market** through STM32 Open Development Environment and Open SW solutions
- **Automotive MEMS** ramp up
- **Bluetooth Low Energy** for Internet of Things

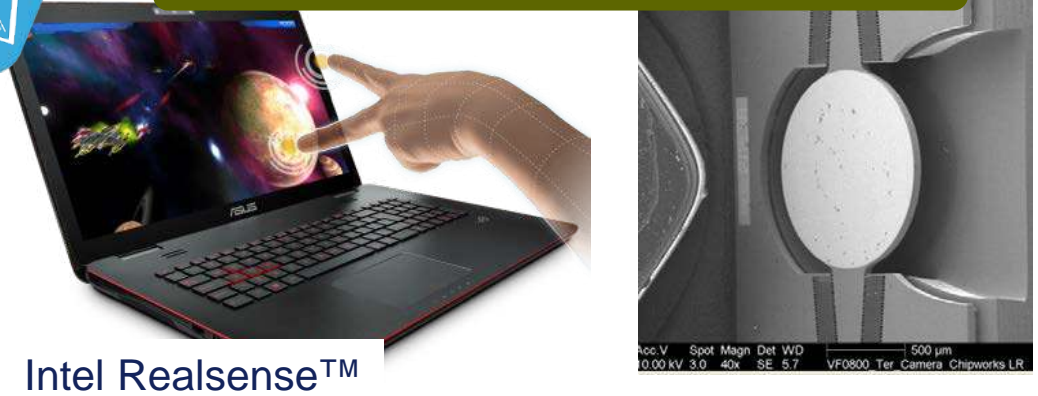
Back to year-over-year quarterly growth starting in 2Q15

AMS - Strategy in Action

New products for traditional markets



New products for new markets



Traditional products for traditional markets



“Brand new STMicroelectronics 3mmx3mm LGA package featuring a 3D digital gyroscope and 3D digital accelerometer” Chipworks



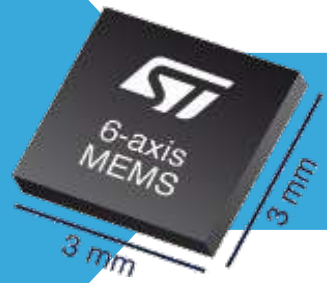
New products for traditional markets



New Touchscreen technologies for flagship smartphones

Consumer Motion MEMS Roadmap

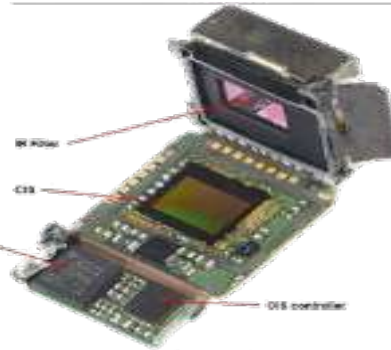
Ultra-low-power for the consumer Markets



Ultra-low-power, low-cost evolution

Low-noise
low-thickness

Optical Image
Stabilization (OIS)



Toys and gaming
appliances

New Markets
penetration
Cost effectiveness



High Accuracy

Gaming and gesture
devices

Low-Cost MEMS



4x Higher Accuracy



Always-on
for tracking

Wearable





Motion MEMS Continued Innovation

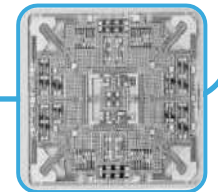
- Accelerometer
- 6-Axis Inertial module
- Optical Image Stabilization
- Gyroscope
- 6-Axis eCompass
- Magnetometer
- 9-Axis Inertial module

>5 Billion motion MEMS shipped to date

Highlights

Renewal of product portfolio/continuing to lead innovation

- Launched new industry leading 6-axis sensor
- 3rd generation Gyroscope for **Optical Image Stabilization** <5mm², thickness <0.75mm



iNEMO Ultra - LSM6DS3
The 6X Ultra



Ultra low power	Ultra small size
Ultra performing	Ultra capable
Ultra smart	Ultra scalable

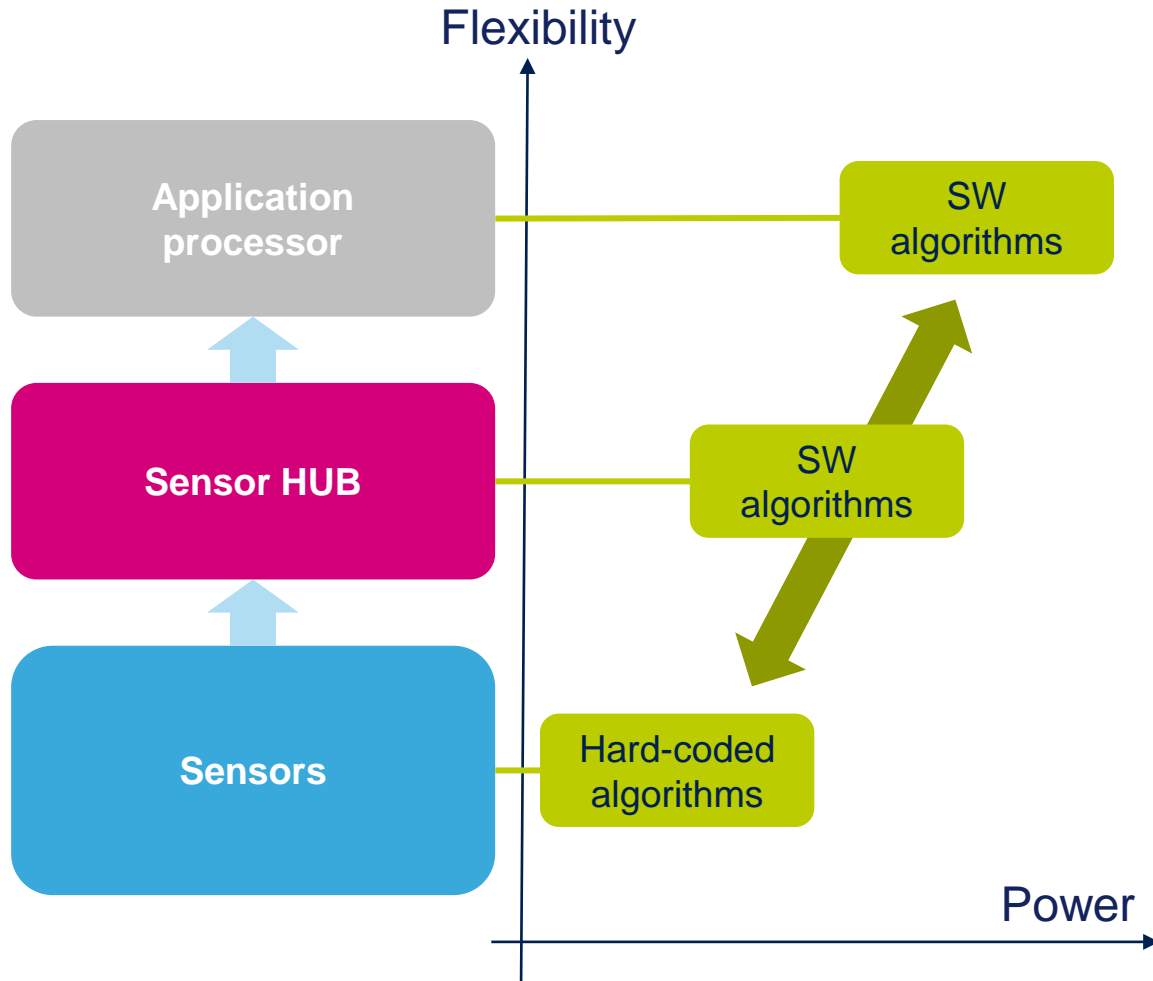


“This is the first time that we see a **true 6X sensor** in an Apple product that doesn’t require an external accelerometer.” Chipworks

Achieving lowest power Sensor Systems

Optimized for every Architecture

110

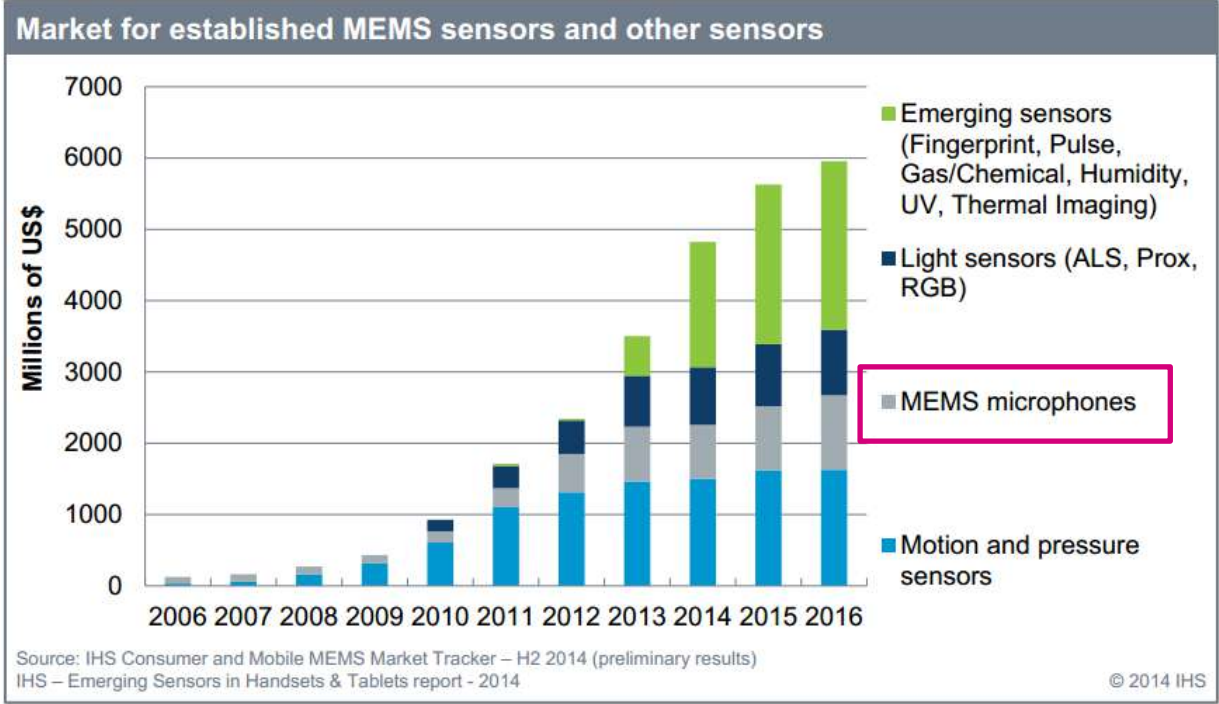


Always-on sensor systems must be ultra low power

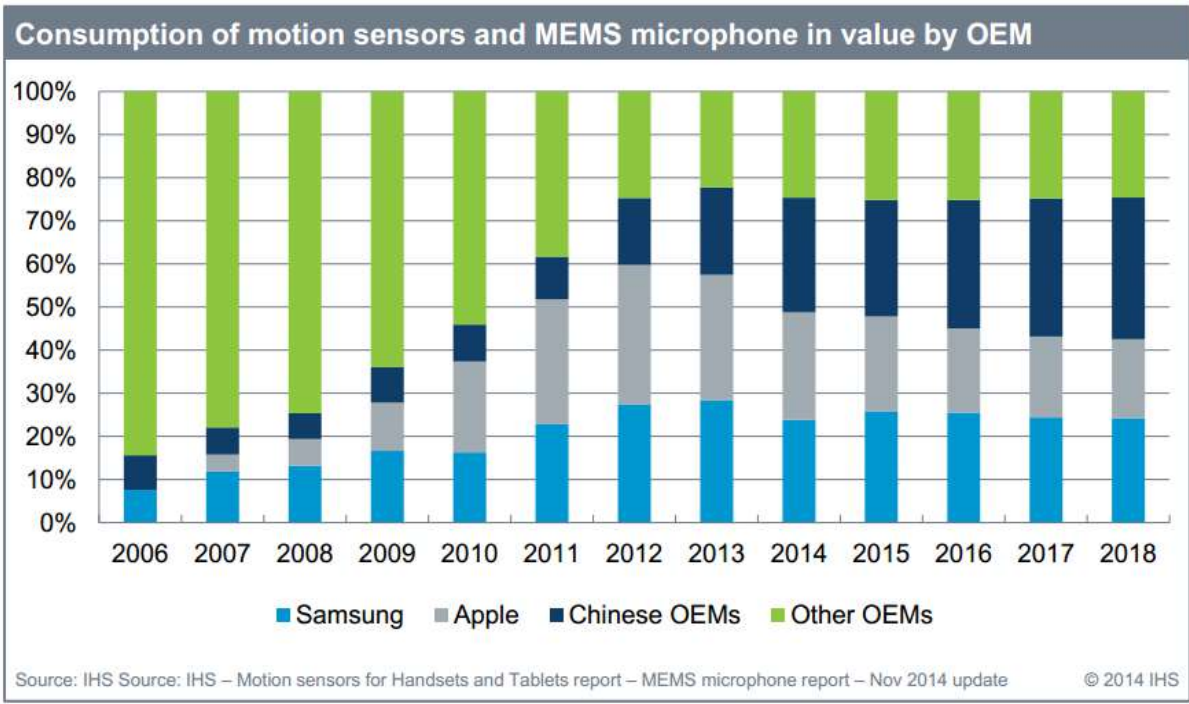
- Hardware and Algorithms need to be individually optimized for ultra-low power
- Optimization at system level requires design that can be adapted to various architectures
- Building on ST's Open Software for sensors

The Mobile Market Opportunity

Growth in sensors lies outside of motion



Chinese OEMs growing for motion and microphones





Motion MEMS wins in China



Ascend Honor 4
Honor 4X



Ascend G7



Ascend GX1



Ascend Mate7



Ascend P7



Honor X1



Honor 6



Honor 3X



Honor 3C



G730



C199



Redmi Note
W/C and LTE



Mi3
W/C and T



Mi4



Mi PAD



One W8



One E8 vogue



One M8
M8 Lifestyle



One M8 Eye



Butterfly 2



19 models



V5 max



星星2号
Star 2



青漾2
Qingyang 2



Z max



小鲜
Xiaoxian



Blade Vec 4G



Q802C



Nubia X6



清漾
Qingyang



2 models



Xplay3S



Xshot



X5



Vibe Z2



Vibe X2 pro



Vibe X2



B8080-F



S810t



Elife E7



IUNI U2



MX4 Pro



ONEPLUS 1



大神 F1



Find7



MEMS Microphones

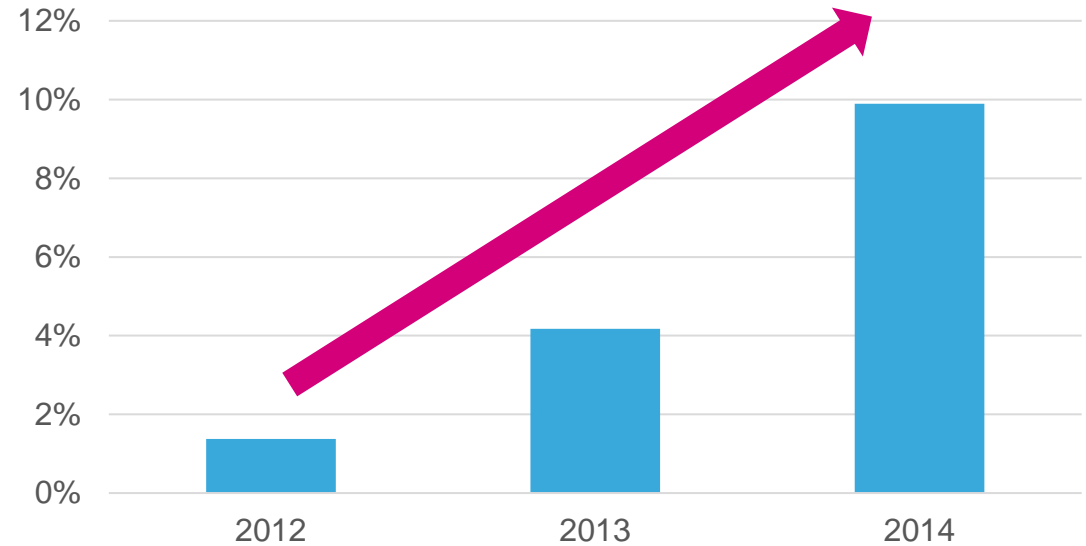
Strong Market Share gain

113

Microphones

- Successful organic growth of business
- Over **260 million** MEMS microphones shipped in 2014
 - Market share from <2% in 2012 to **10%** in 2014
- Focus on High Performance Microphones
 - Always-on feature
 - Audio fidelity required by Social Media
- Proliferation of analog and digital microphone designs across the customer base in mobile and PC

ST MEMS Microphone Market Share





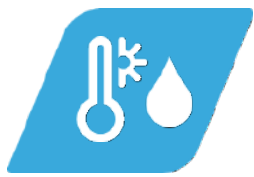
Winning most demanding Designs

FingerTip™ Touch-screen Controller

- Strong growth with touchscreen controllers
- High-profile wins beating out competition in some of the most demanding smartphones
- Winning value proposition
 - Very good high-end analog performance
 - Very low power consumption
 - High flexibility of solution and fast time to market
- FingerTip technology well positioned to address wearable, security and active pen applications



First to deliver a touchscreen controller for a curved smartphone display



Environmental Sensors

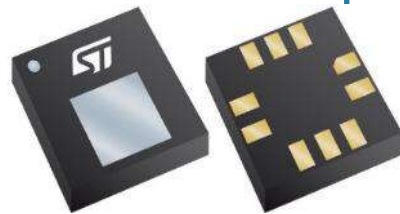
Broadening the Portfolio

115



Pressure

- Around **65 million** Pressure sensors shipped in 2014
- Introduced world's smallest pressure sensor in tiny package (2x2x0.76mm)
- Applications
 - Altimeter
 - Indoor navigation
 - Weather station



UV

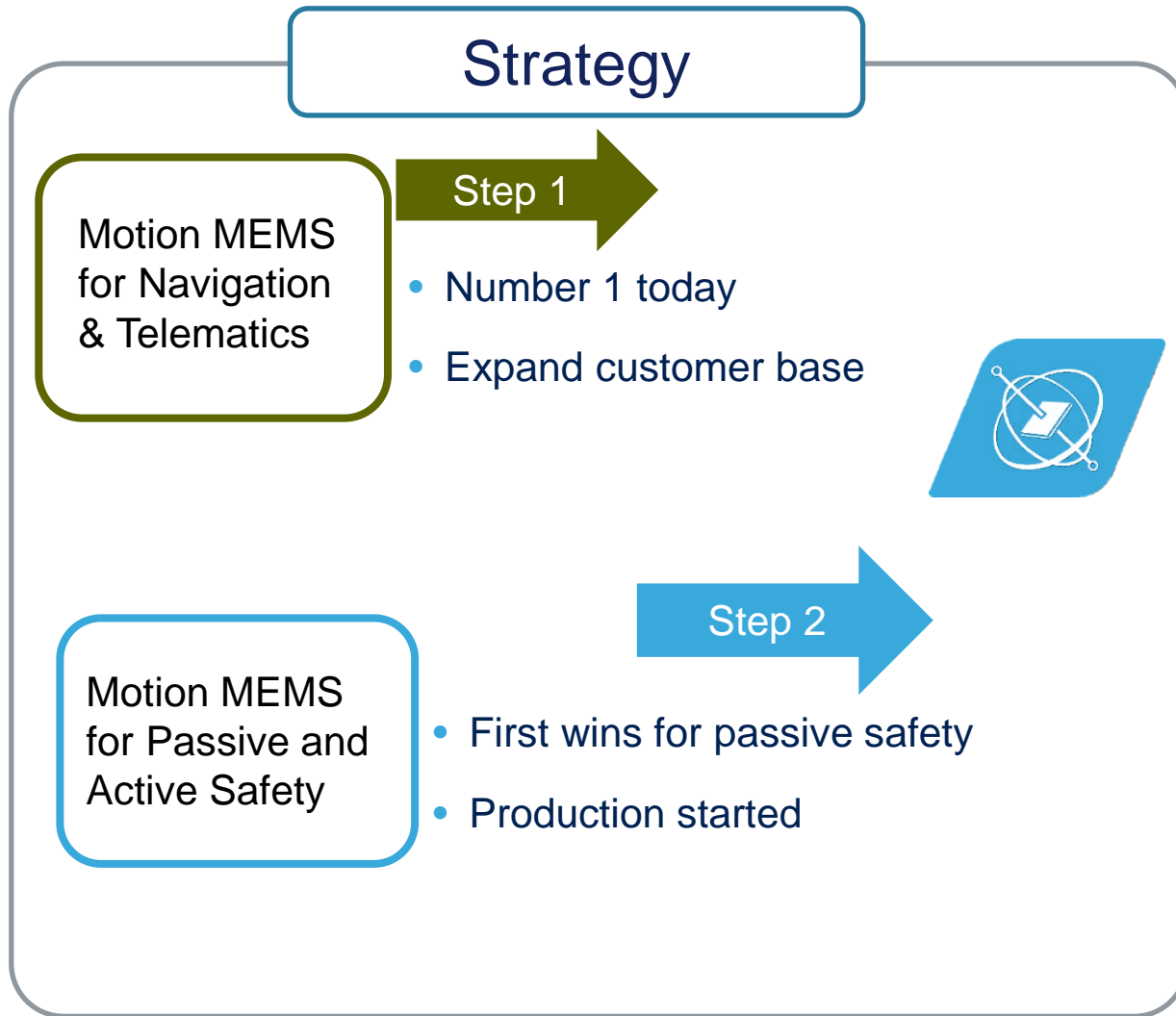
- Introduced and ramped the world's first sensor to provide a direct digital output of the Ultraviolet Index (UVI)



Humidity

Temperature

- Combined temperature & humidity sensor in production



More than 50 MEMS Sensors per Car

Automotive Motion MEMS Market = 1.2B\$

CAGR around 4%





High Value Motion MEMS

117



- Applications in Industrial, Medical, Aerospace & Defense
- Served by few major players and small MEMS specialists
- Growth is significant and opportunities for higher margins



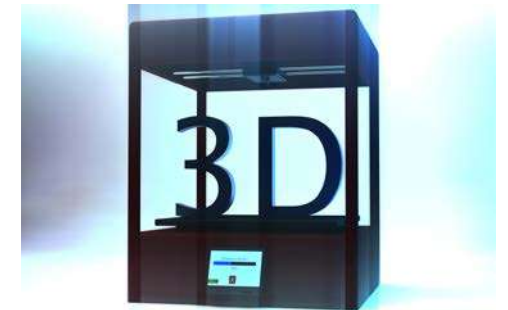


Thin-film Piezo MEMS Actuators

New Technologies for the next Wave

118

- Camera Autofocus
 - Lower power consumption and higher speed versus Voice-Coil Motor (VCM) based solution
 - Working with innovative lens maker PoLight for autofocus actuator in smart phones
- High-speed inkjet print head for commercial and industrial applications
 - Enables printing with high-viscosity materials
 - Adaptable to different printing materials



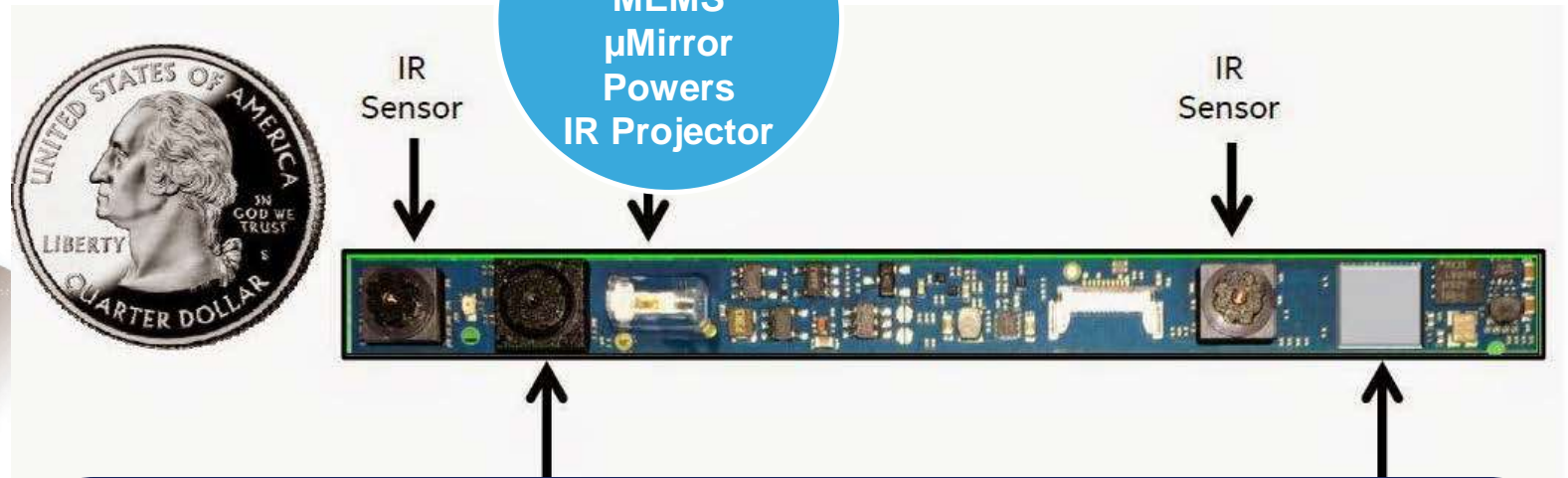
ST is the world leader with a Piezo MEMS technology on 8" silicon wafers



Intel RealSense™ Depth Camera



8 Products already on the market





Realsense™ Devices

Laptops with Intel® RealSense™ 3D Camera



Asus N551JQ* (15")

Bold, fresh styled Ultrabook™ with superior multimedia experience, gaming-grade graphics, and Intel® RealSense™ 3D camera.



ASUS ROG G771JM* (17")

High-performance gaming laptop with enthusiast-grade graphics, silent cooling system, and Intel® RealSense™ 3D camera.



Asus X751LD* (17")

A value-packed everyday notebook with Intel® RealSense™ 3D camera is the perfect all-round laptop for work and play.



HP Envy* 15t Touch RealSense Laptop

Full-featured notebook with advanced capacitive full HD touchscreen, BeatsAudio*, and Intel® RealSense™ 3D camera.



Dell Inspiron* 15 5548 (15")

Slim, lightweight laptop with full HD touch screen, 5th gen Intel® Core™ processor, and Intel® RealSense™ 3D camera.



Acer Aspire* V 17 Nitro (17")

Acer's Aspire* V 17 Nitro series of high-performance notebooks deliver superior performance, multimedia and entertainment features in a sleek and elegant design. Now featuring the Intel® RealSense™ 3D camera.



Lenovo ThinkPad* Yoga 15 (15")

The power of a ThinkPad* paired with a thin, light design and the flexibility of a convertible. Features IPS display, Dolby* Home Theater, next gen graphics, touch screen and the Intel® RealSense™ 3D camera.



Lenovo ThinkPad* E550 (15")

ThinkPad* is sleek, thin and fully -featured with massive storage, extended battery life, and Intel® RealSense™ 3D camera.



IoT: Wireless Opportunities

Investing in RF has significant potential for growth

Ultra-low power connectivity

BlueNRG

- Introduced an upgrade to our energy-efficient Bluetooth Smart network processor running the Bluetooth 4.1 protocol stack

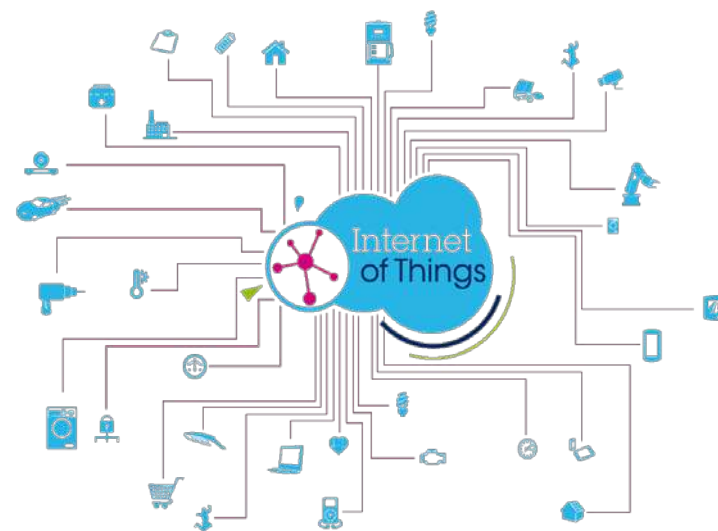


SPIRIT

- Very low power RF transceiver for SubGHz license-free ISM and SRD bands



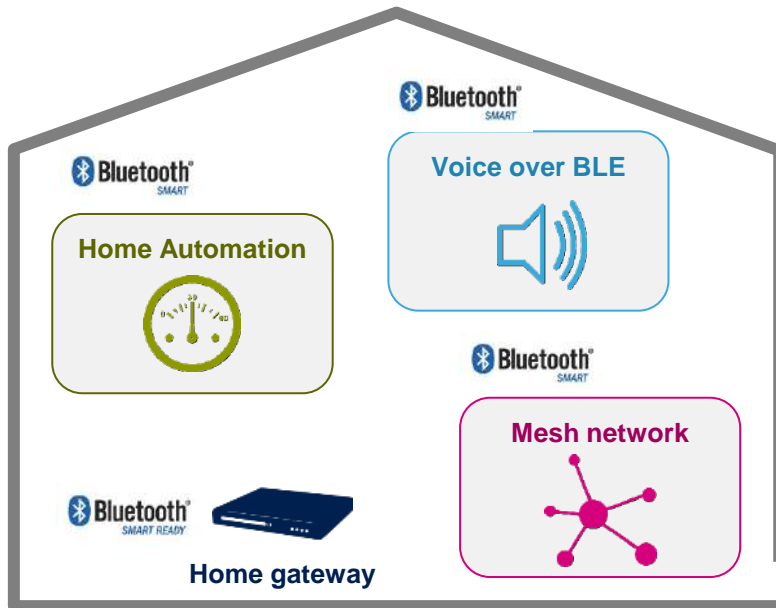
IoT devices for **Smart Me** and **Smart Home** need both Bluetooth Smart and subGhz radio



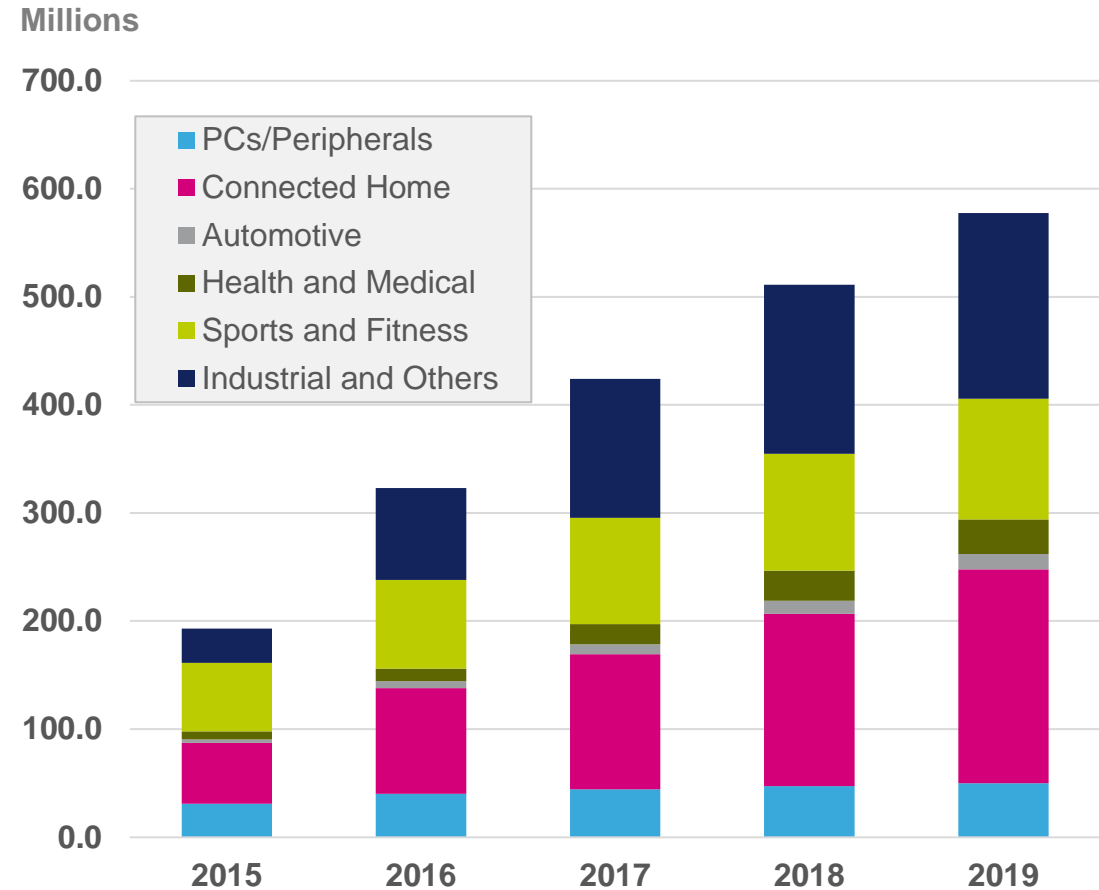


Bluetooth Smart Market

Smart home is forecasted to be the biggest market for Bluetooth Smart devices



Bluetooth Smart-enabled Devices - Shipments





ST is investing in analog and RF and has significant potential for growth

- Wide range of analog products needed by our customers to complete product design
- Opportunities to design-in alongside flagship solutions
- Push through distribution and online channels to increase market reach
- Target application marketing for wearable devices

Analog

Operational amplifiers

Large portfolio of highly power-efficient op amp in tiny packages

Current sensors

High accuracy current measurement for contactless battery chargers

Audio amplifiers

High-efficiency Class D and G amplifiers for headsets and speakers

Ultra-sound Pulsers

Highly-integrated ultrasound pulser ICs with four or eight independent channels.

Analog switches

Compact single and dual switches for audio and USB

Battery gas gauges

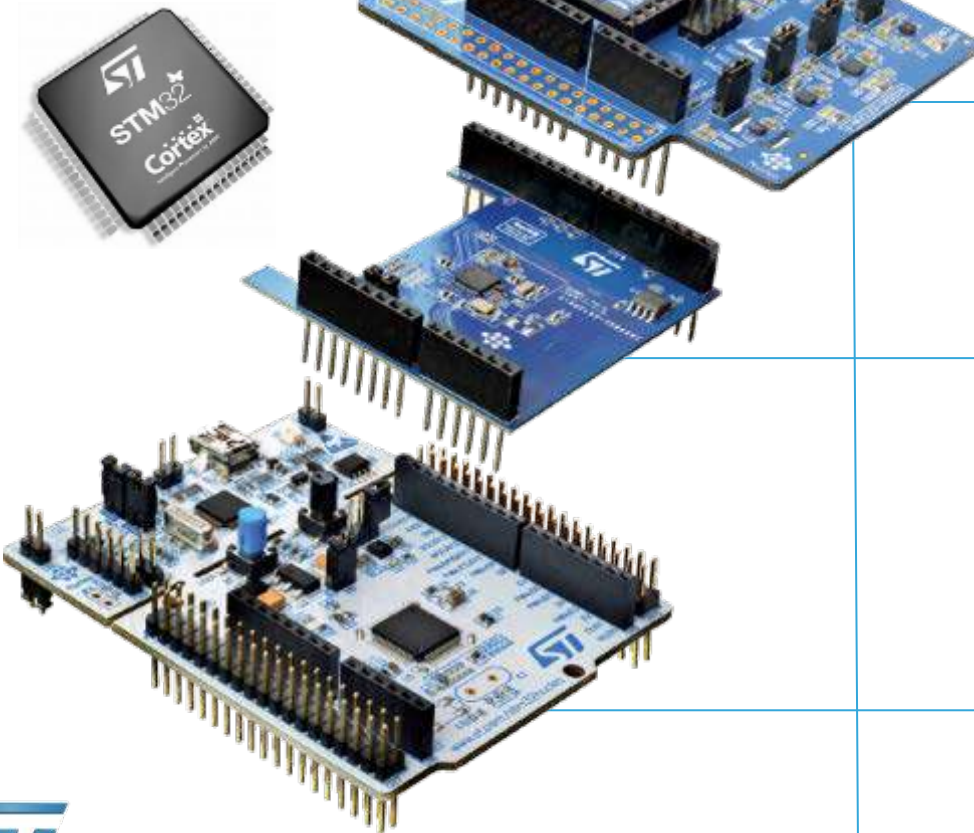
Low-power gas gauge providing very accurate battery life indicators

Smart reset

Customizable products providing safe and convenient reset

Easy access to portfolio for Developers

To increase our share in the mass market



Open.Software

- License SW for single-use on specific target hardware (STM32 Nucleo Development Board)
- Click through license on website

- Product differentiation is key for sustainable growth in the field of sensors
- Today, much more than traditional motion MEMS
 - Diversification strategy initiated in 2012 starting to deliver results with strong momentum in microphone and touchscreen controller
- New generation motion MEMS shows a good traction both in the consumer and automotive market
- Partnership with market leaders and emerging startups is key to drive the creation of new markets
 - Example of Intel and world of perceptual computing
- BlueNRG and SPIRIT cutting the wire for IoT

Automotive Product Group (APG)

Marco Monti

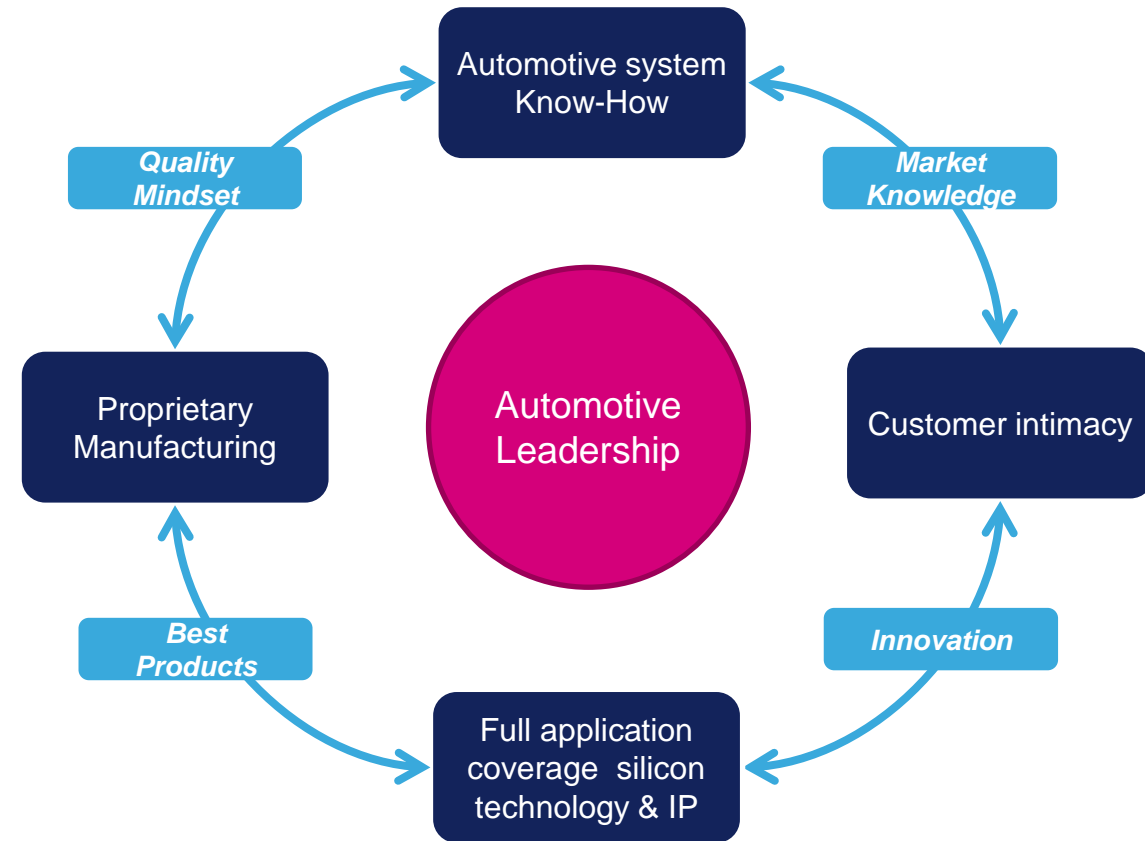
Executive Vice President,
General Manager, Automotive Product Group



ST in Automotive Today

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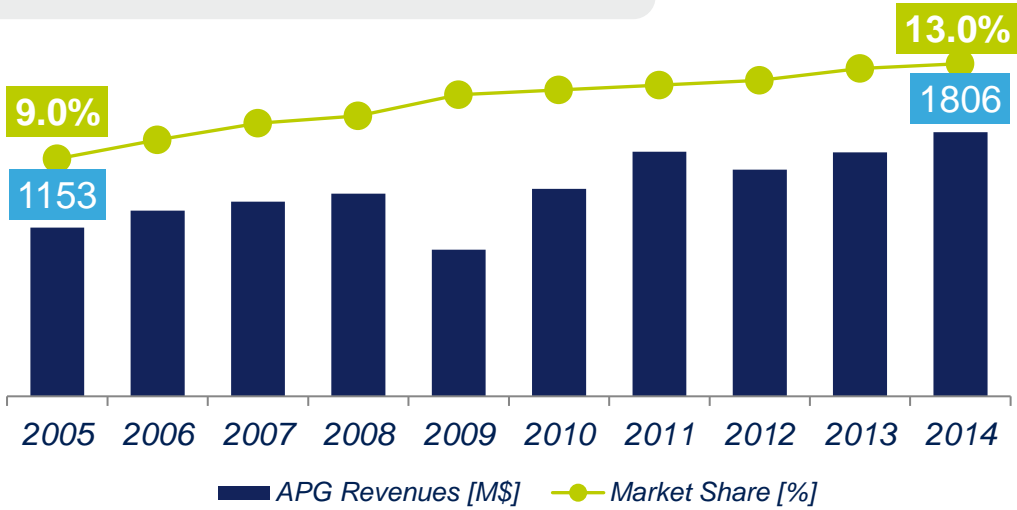
- 30+ years leadership in automotive
- Continuous growth in all regions
- Several partnerships with leading car makers and major OEMs
- Wide application coverage thanks to state of the art technology portfolio
- Proprietary and independent manufacturing mastering quality and automotive requirements
- Industrial / digital convergence IP reuse with a full automotive grade quality to support innovation



APG: Positioning

Market Leadership

Continuous Steady Growth



Automotive Electronics








~12 B\$ Serviceable Market
~11.8% Share





Car Infotainment

~2.0 B\$ Serviceable Market
~20% Share

Outperforming 2014 Market Growth

EMEA	+9%
Americas	+8%
Japan & Korea	+7%
GCSA	+10%
Total	+8.3%

WW Rank	Domain	Share
1 st	Engine control 	~32%
1 st	Charging 	~22%
1 st	ADAS Systems 	~70%
1 st	Braking 	~19%
2 nd	Airbag 	~14%
1 st	Car Lighting 	~45%
1 st	Door Zone 	~80%

WW Rank	Domain	Share
2 nd	Positioning 	~14%
1 st	Digital Tuners 	~50%
2 nd	Infotainment 	~13%
1 st	Audio 	~43%

APG 2014 Revenue: 1.8B\$

#3 WW Automotive Supplier

#2 WW Supplier On APG SAM (*)



All data bases on APG SAM in 2014. ADAS: video processing and radar Rx/Tx

Source: Strategy Analytics, ST

APG at a Glance in 2014

3 out of 4 cars produced have at least one APG component in Engine Management

8 out of 10 cars shipped with an ADAS system on board had an APG ADAS CPU on board

22 APG components in each new vehicle

100% market share in US satellite radio (Sirius XM)

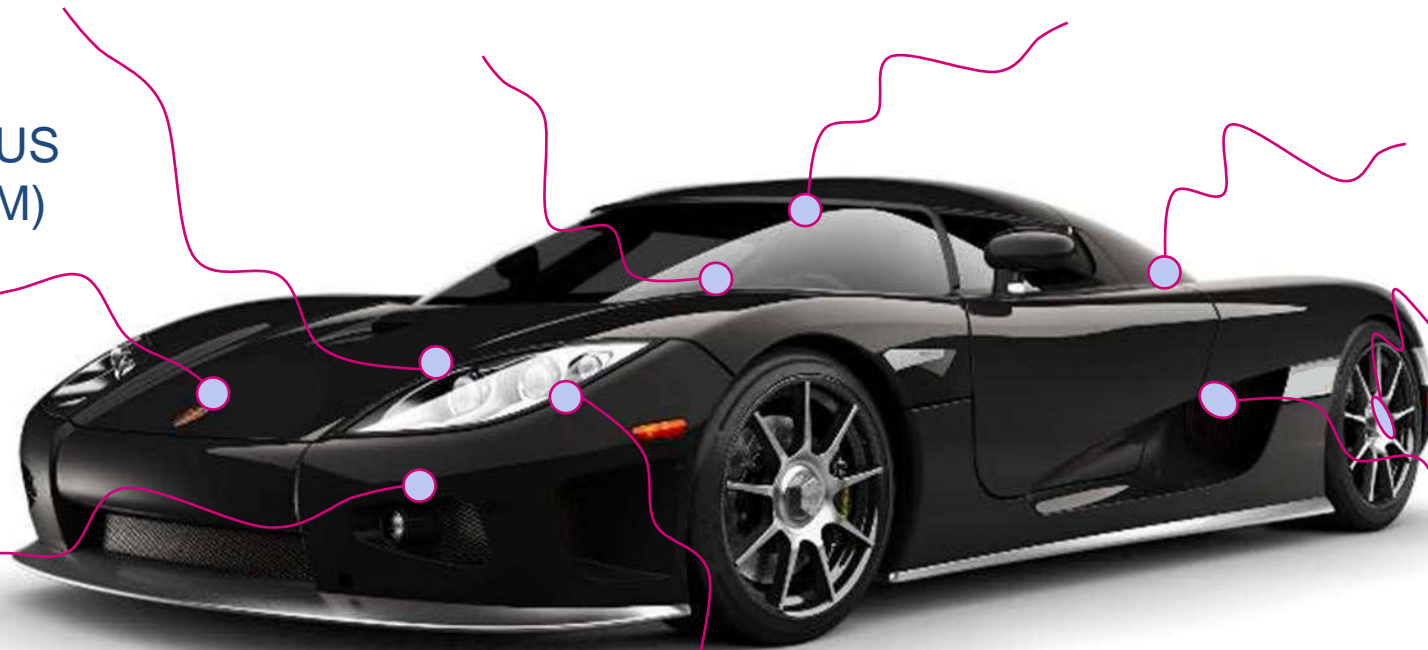
2.5 Million VIPower chips shipped every day

2 out of 3 cars produced had at least one APG component in braking

30 Million 32-bit MCUs shipped

2 out of 3 cars produced are equipped with an ST Sound System (excluding aftermarket)

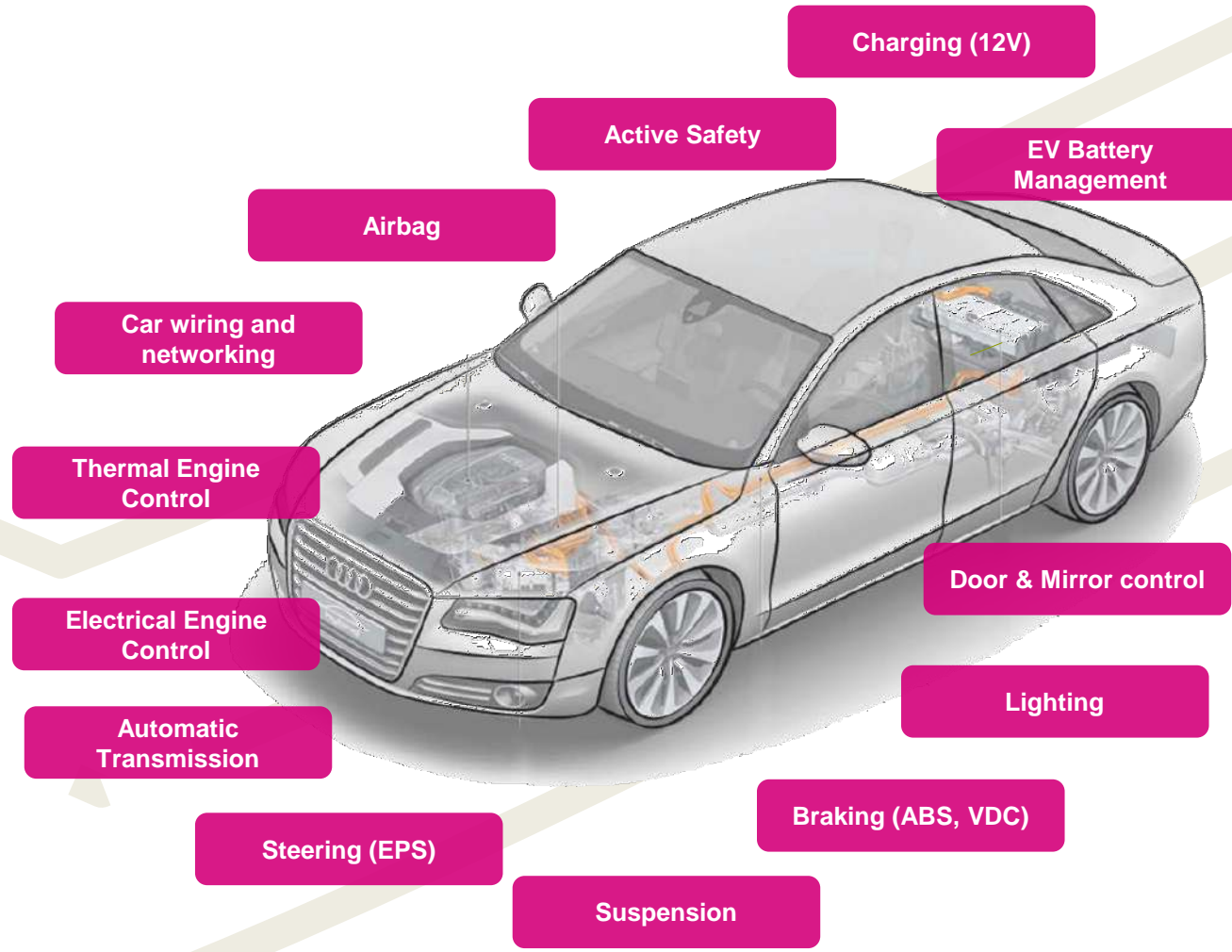
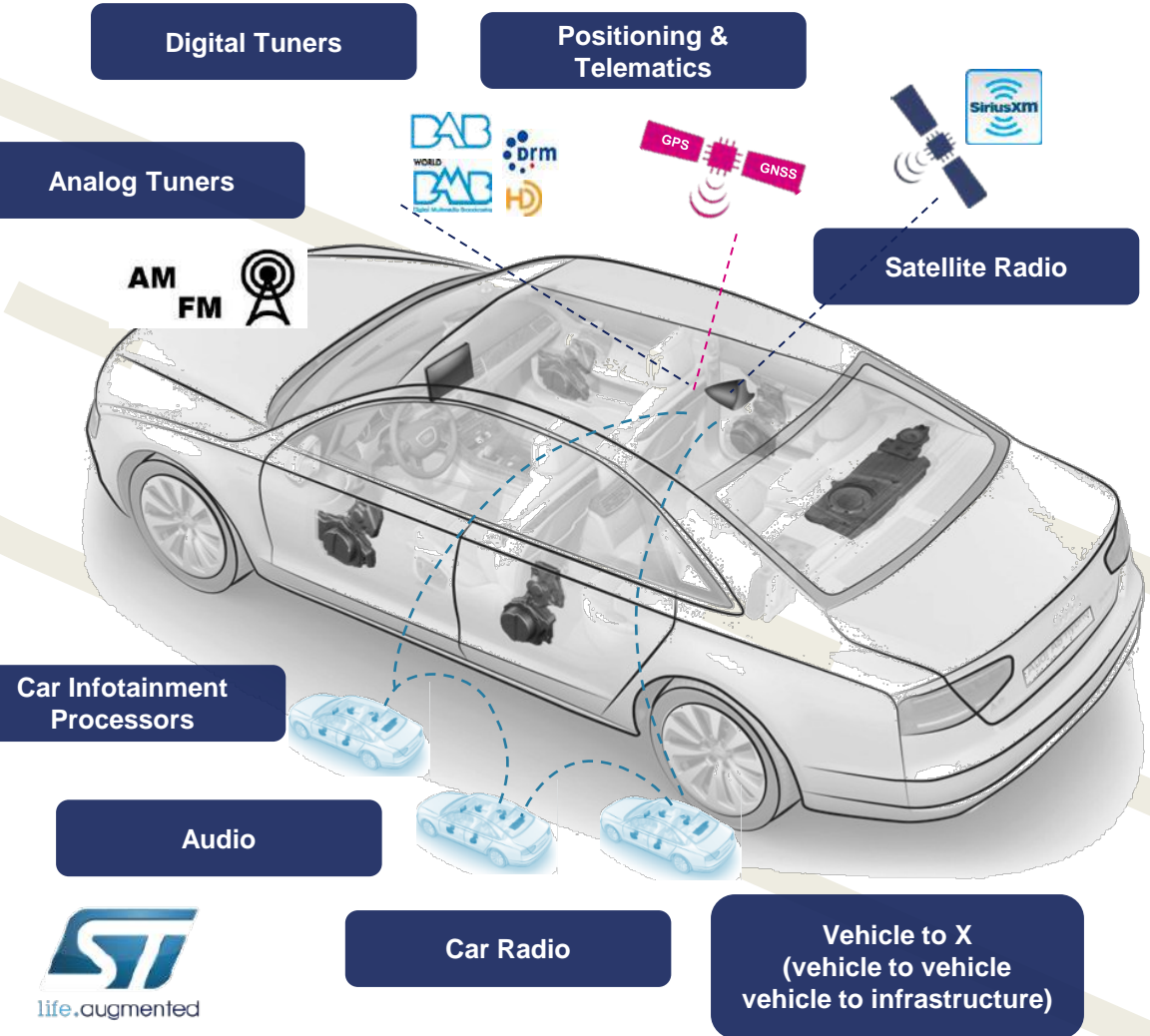
850 Million Lamps (1 out of 2) driven by APG



APG: Broad Coverage of Automotive Applications

Car Infotainment & Connectivity

Automotive Electronics



A truly broad Range Product Portfolio

In all automotive Applications

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Product Portfolio: from Commodity to complex digital ASICs

... in all automotive domains

Low

Complexity

- Driver & switches
- Voltage regulator
- Alternator regulator
- Bus transceiver
- Motor controller
- LED driver
- 8/16/32-bit Microcontrollers
- Analog & digital tuners
- 24/77 GHz Transceivers
- Super-integrated ASIC
- Vision based processor
- Multi-constellation GNSS

Low

Complexity

- Internal external light controller
- Door module
- Car power management
- Electrical engine
- Thermal engine
- Braking
- Steering
- Vehicle control
- Car networking
- Digital car radio infotainment
- Automatic gearbox
- ADAS Vision & Radar

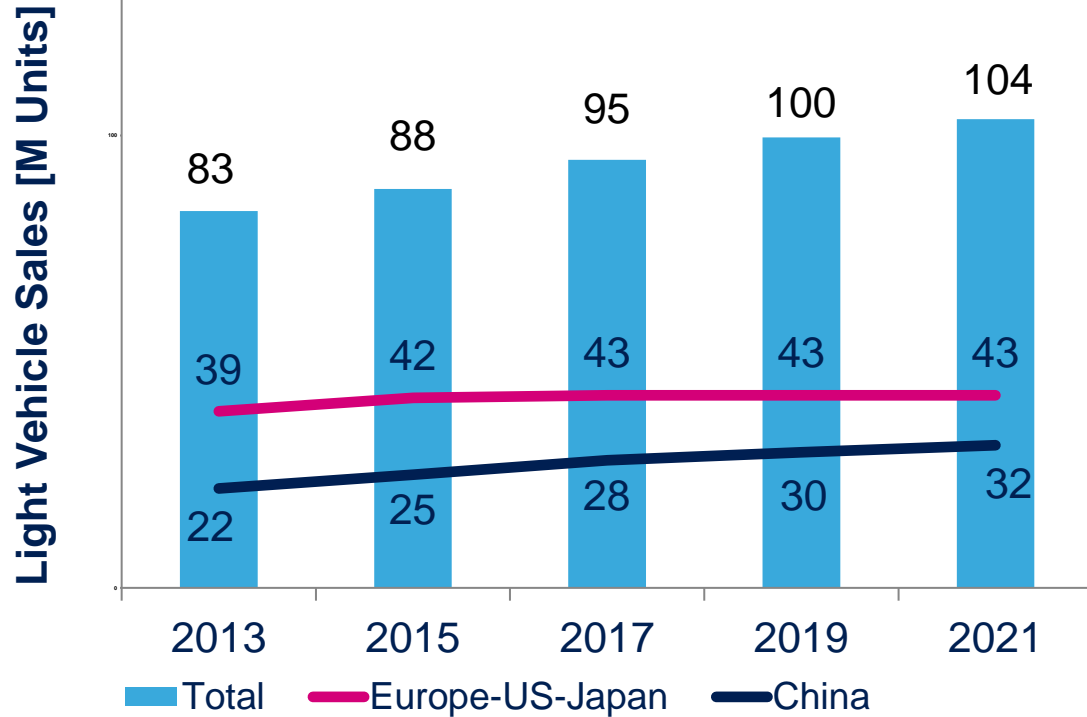
High

High

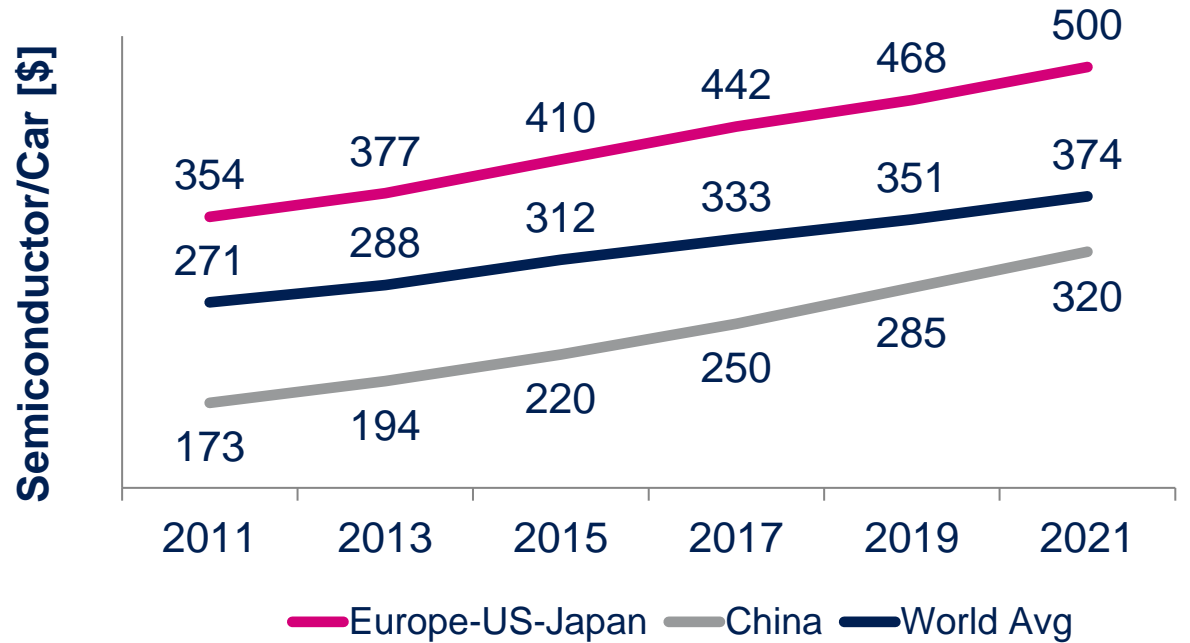
Automotive Market: The Right Place to Be

Addressing a \$26B market

Emerging Markets Opportunity



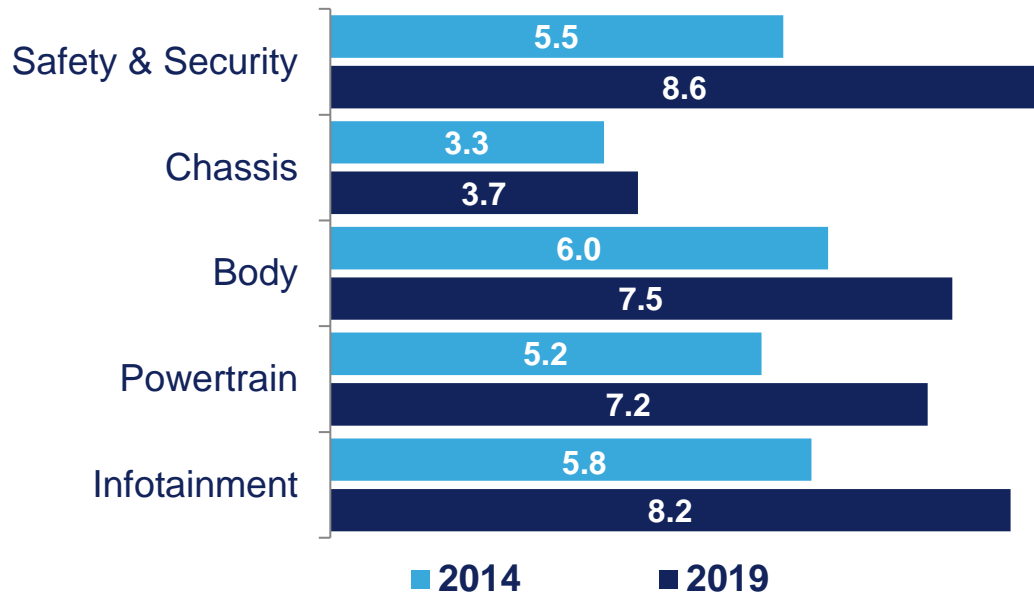
Semiconductor content per Vehicle



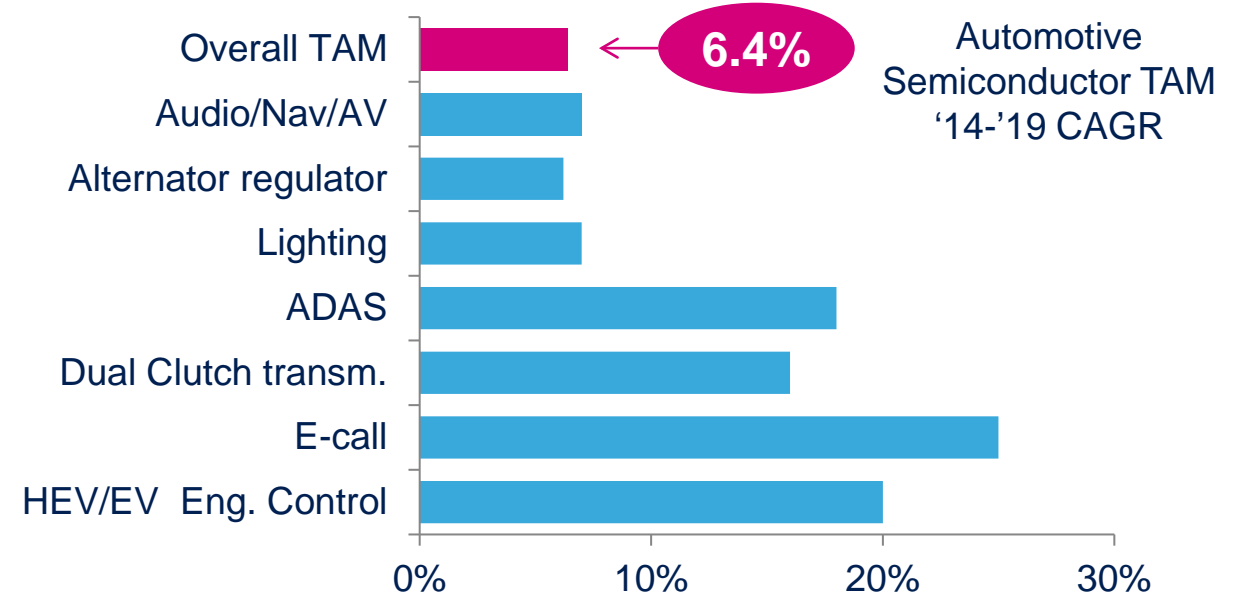
Automotive Market: The Right Place to Be

Addressing a \$26B market

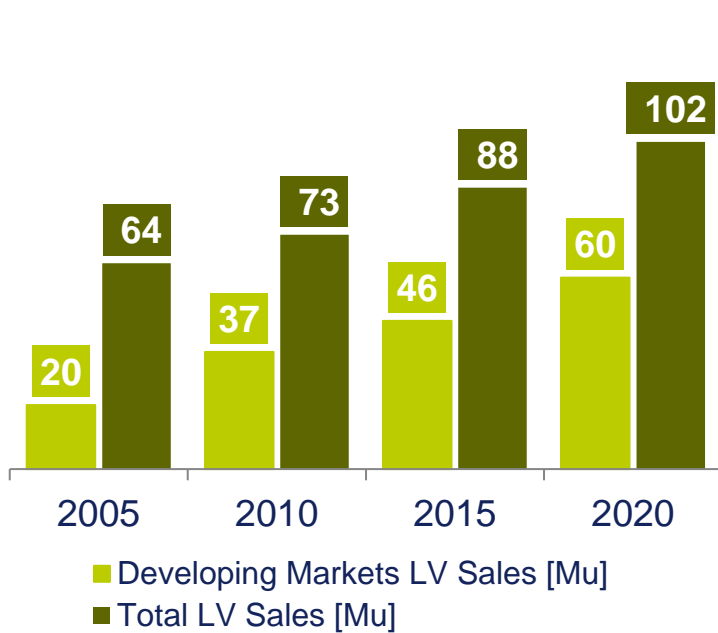
All Segments Growing \$B



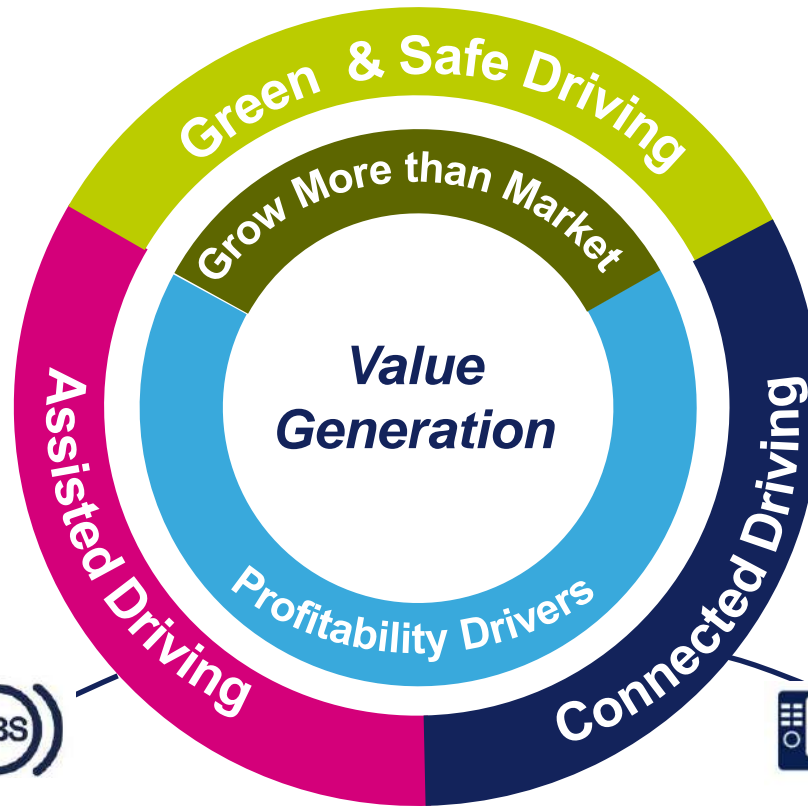
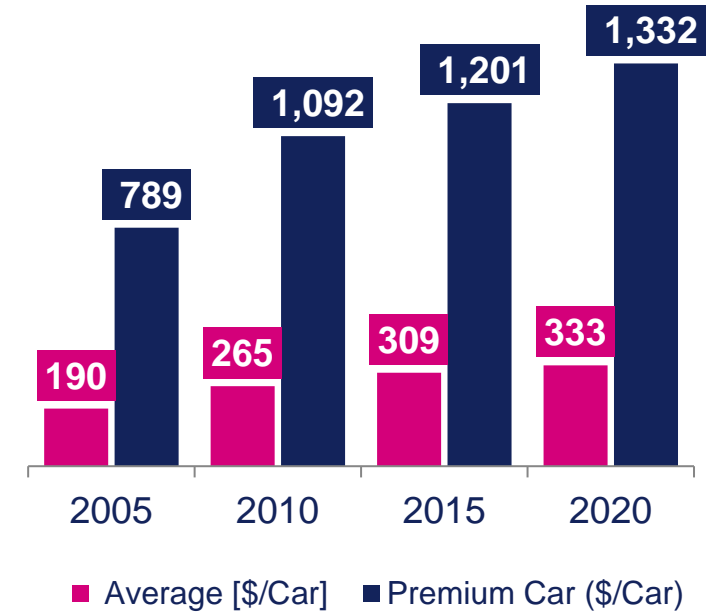
Emerging Applications



Volume Growth

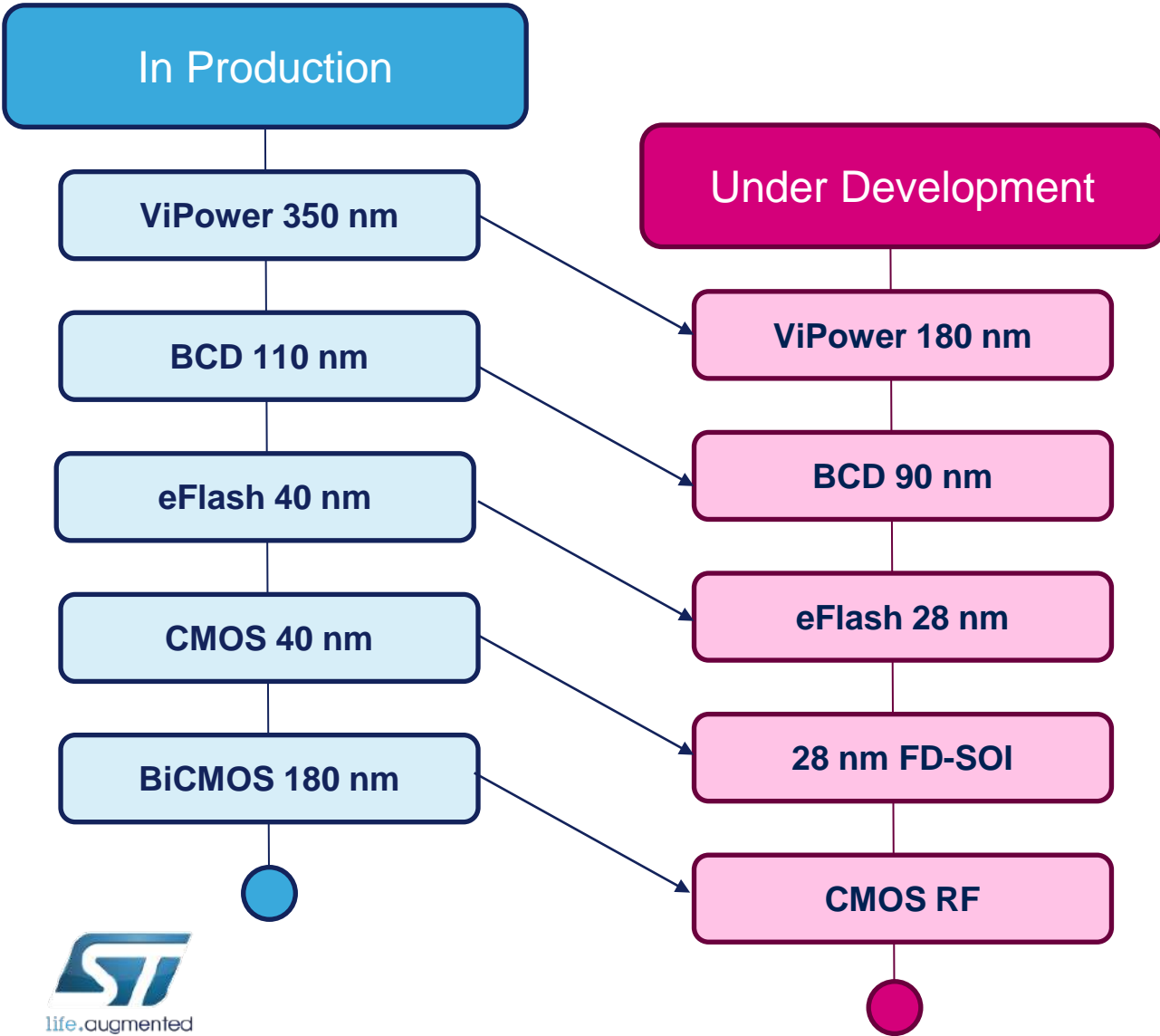


Innovation Pervasivness

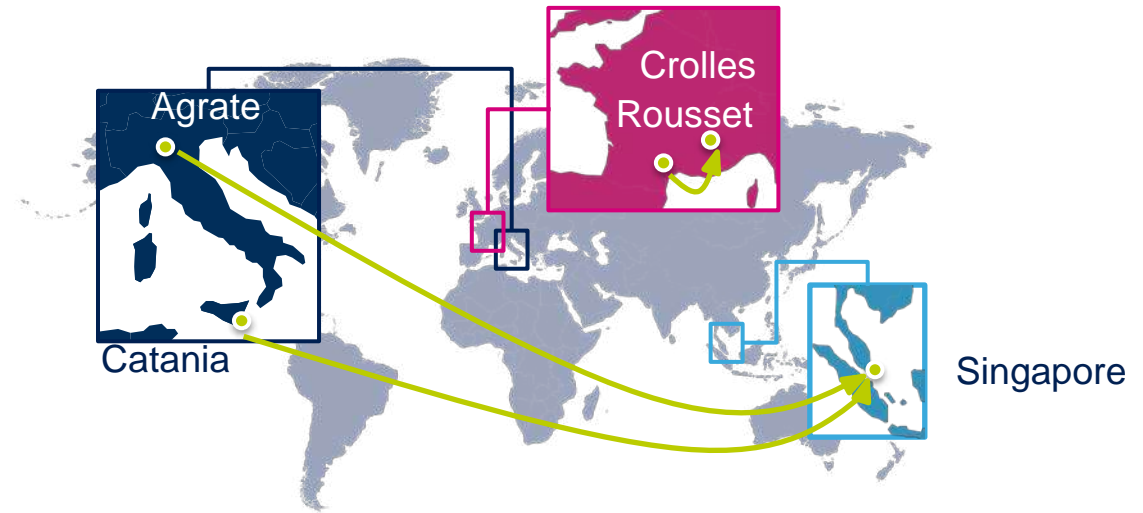


Source: Strategy Analytics, IHS, full market excluding sensors

Leadership in Technology & Manufacturing



Tailored technology roadmap for automotive
With dedicated multi-site in-house manufacturing



Powertrain Smart Power

Direct Injection Engine

- New Award: driver family for Engine Control System for European market leader covering from Low to Hi-end
- New Award: System Chip for Engine Management for leading player in emerging markets



Automatic Gearbox

- In production with Integrated Market Solution for High-Precision Automatic Transmission for Japanese worldwide market leader
- New Award: new BLDC motor driver for Transmission worldwide market leader.



Charging

- New Programmable Solution dedicated to low-end Emerging Markets



Safety Smart Power

Airbag

- In production with new generation IC for worldwide restraint system leader
- New extension devices (up to 40 loops) under design to cover premium segment market
- Complete Product Offer for Low & Hi-End, in production with latest 160 nm Technology



Braking

- New Award: world first integrated solution for ESC and parking braking for Japanese worldwide market leader.
- Extending worldwide leadership (70% mkt share) in parking brake application



Steering

- New Award: new generation BLDC motor driver for European market leader

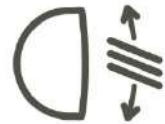


Pervasiveness per Vehicle: Key Opportunities

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Body

- Market leadership in Lighting Reinforced
 - Clear Technology advantage vs. our competition
 - Product Portfolio extension with new high power solutions
 - Several Wins achieved to expand our customer base
 - More than 20 new part numbers entering in production in 2015
 - Complete solutions for LED front and rear lighting

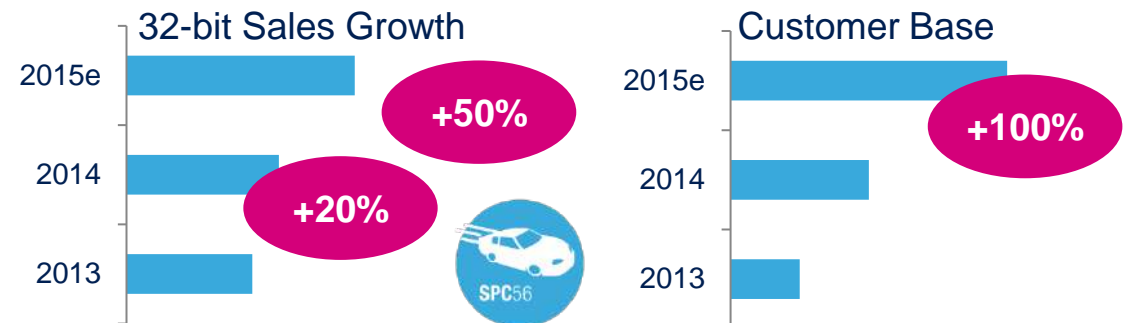


- High efficiency motor drivers
 - New Door Zone ICs in volume ramp-up for several worldwide market leaders to reinforce our leadership



32-bit microcontroller for Automotive

- Announced first 40nm high performance product with multi-core safety architecture and advanced security ready to production
- Product line-up expansion with 50 new part numbers in 2015
- More then doubling our sales in 2015
- Continuing to report outstanding business awards in Power Train, Safety and Body applications with market leaders to sustain our growth



Emerging Markets: Kits & dedicated Products

System Solutions

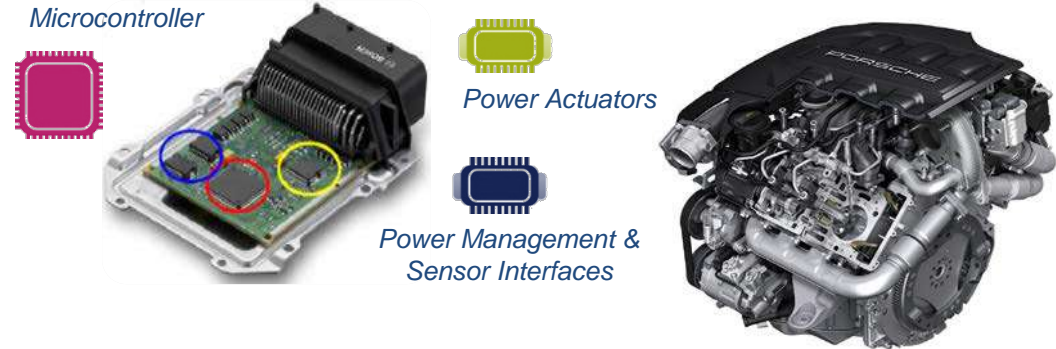
- 4-cycle engine control
- 1/2-cycle motorcycle engine control
- Entry level ABS
- Entry level stability control
- Low to mid-end airbag
- Body control module
- Digital tuners
- Entry level infotainment

Dedicated Roadmap for Mass Market

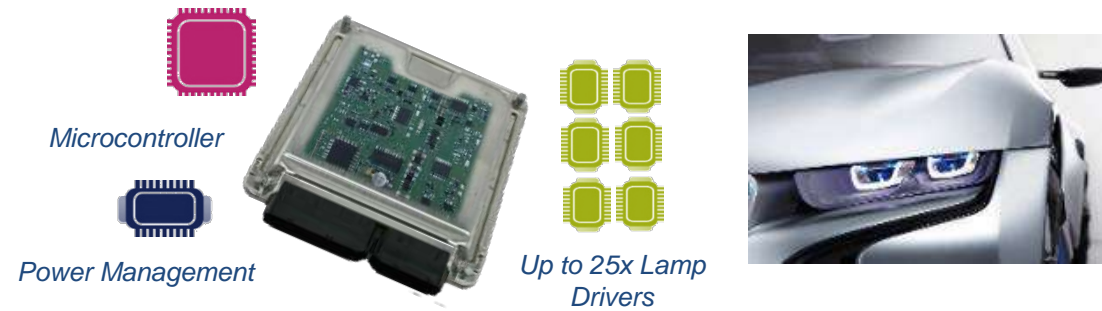
- Low-cost 4-cycle engine control compliant to the China-6 emission regulation
- 4 to 8 channel fully integrated airbag IC
- Alternator regulator for emerging market
- New 32-bit MCU For powertrain (electrical/combustion)



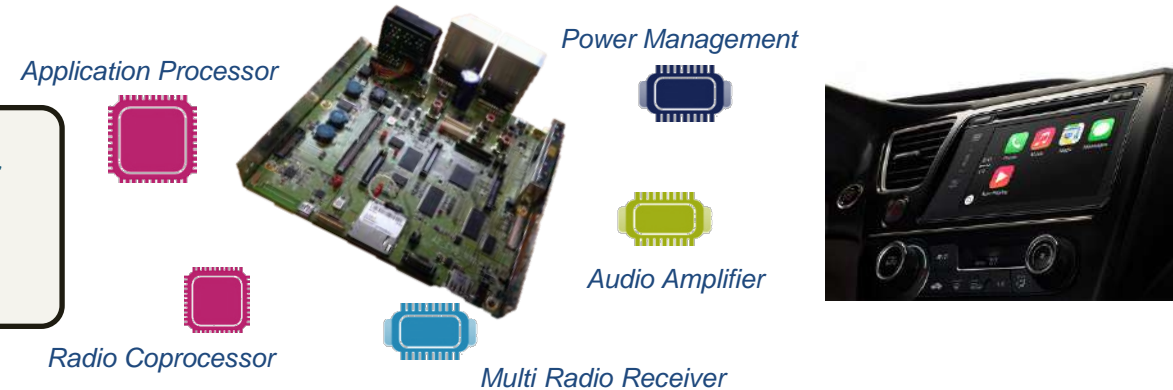
Full Kit Solution for Engine Control
Up to 6 ST ICs



Full Kit Solution for Body Control
Up to 20 ST ICs



Full Kit Solution for Infotainment
Up to 5 ST ICs



From Assisted to Autonomous Driving

- Market leader in **vision based solutions** with presence in more than 27 car brands** . More than 70% market share*
 - 4th generation under development exploiting full autonomous driving in cooperation with Mobileye leveraging on ST 28nm FD-SOI process
- Market Leader in **Short Range and Long Range Radar**
 - First 77GHz single chip RX-TX available
 - Expanded family of 24Ghz receivers with multiple RX/TX channel in a single package
- **V2X Communication**
 - New partnership with Autotalks to complement our IP portfolio (accurate positioning, processing platform and security solution) with Wi-Fi 802.11p Know-How



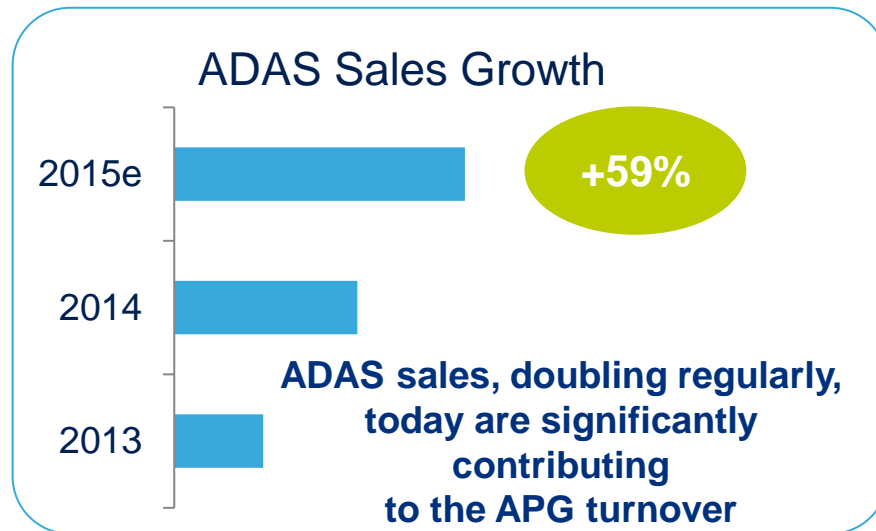
Endorsed by 

Video Processing **#1**

Radar RF **#1**

V2X Communication

New!



Key Profitability Drivers: Infotainment

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Audio

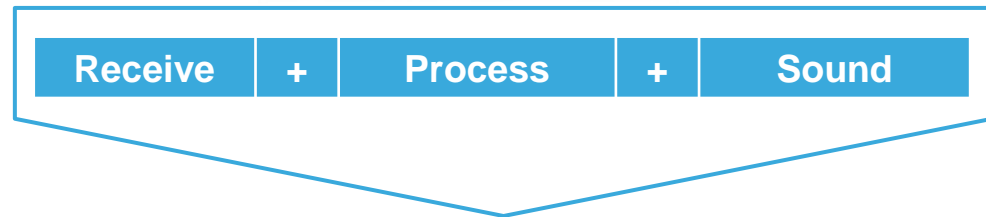
- Long time leader in Audio Power Amplifiers with >45% market share*
- More than 10 new products in production in last two years including 6 new digital audio amplifiers
- Several wins for Class-D fully digital family

Infotainment Processors

- Best in class dual core Cortex-M with optimized audio subsystem to Address the high volume market of connected radio and phone duplication for OEM and Aftermarket
- Several wins with leading Japanese aftermarket Tier-1 and European, Chinese Tier-1

Terrestrial / Satellite Tuners

- More than 20 years presence in tuners for Automotive applications
- Consolidated leadership in Satellite Receivers thanks to long lasting partnership with SiriusXM (now 8th generation)
- Advanced multi-standard software defined radio ready for production



Terrestrial
& Satellite
Tuners

Multicore
Processors

Digital
Audio
Amplifier

Key Profitability Drivers : Telematics

141

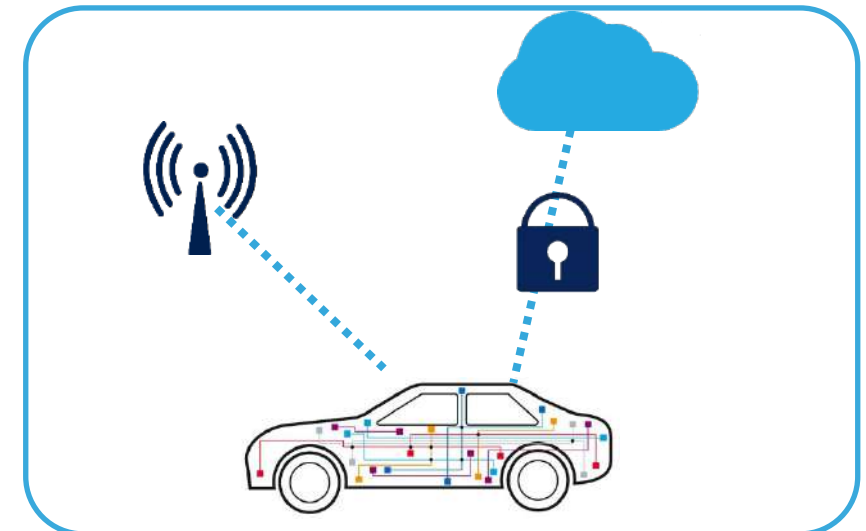
Positioning

- More than 15 years presence in automotive with leading-edge, proprietary solutions for positioning and telematics
- First on the market with a multi-constellation autonomous receiver covering GPS/USA, GALILEO/Europe, GLONASS/Russia, BEIDOU/China single chip solution (Teseo III)
- Multiple wins for navigation systems and entry level telematics box at major Tier-ones in Europe, China and Korea



In-vehicle Telematics

- Optimized 32-bit dual core Cortex-M connectivity processor with independent subsystem to access safely to car communication network
- Multiple win in telematics box with major European and Chinese telematics vendors



APG Main Growth Drivers & Expectations

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- Growth above market
 - Keep our leadership position in power/smart power area
 - Gain market share in steering, transmission and LED domains
 - Double digit growth in 32-bit MCUs
 - Leadership in ARM Cortex processors for mid/low-end infotainment and telematics
 - Increased intimacy with Car makers and engagement on strategic programs
 - Customer base expansion initiatives in both emerging and mature markets
- New drivers for profitability
 - New 90nm BCD with eFlash option and 180nm VIPower technology in advanced development
 - 28nm e-FLASH to support our microcontroller growth
 - Leverage ST know how in security to address multiple aspects of security in ECU protection and data communication
 - Reinforced Leadership in Active Safety with addition of V2X communication solutions

The APG Value Proposition

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**A strong
automotive
commitment**

- Automotive application leadership thanks to our system competence & products IP
- State of the art technology portfolio addressing automotive applications
- Proprietary manufacturing machine committed to Automotive
- Solid market growth and intimacy with key customers at WW level

- Smart Power
- 32-bit Microcontrollers dedicated to Automotive
- Infotainment and Advanced Safety

**Broad product
portfolio
for Automotive**

Industrial & Power Discrete (IPD)

Carmelo Papa

Executive Vice President
General Manager, Industrial and Power Discrete Group

Matteo Lo Presti

IPD Group Vice President
General Manager, Industrial & Power Conversion Division



A Leader in the Industrial Market

#2 in the Industrial Market

#1 Industrial & ASIC

#1 High voltage power MOSFET

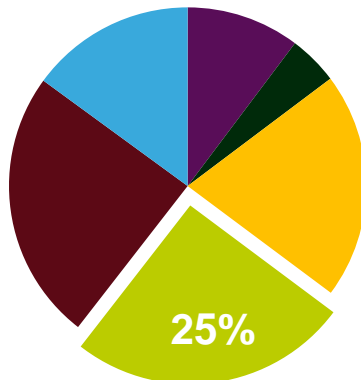
#1 Thyristors & Triacs

25% of ST Revenues in 2014

\$1.87B revenues in 2014

More than 7300 available products

About 6000 served direct customers



Significant breakthroughs in Innovation

- 15% of sales with products < 2 years old
- 70 new patents filed in 2014
- > 240 new silicon lines introduced in 2014

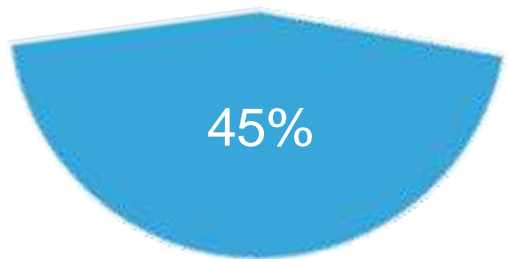
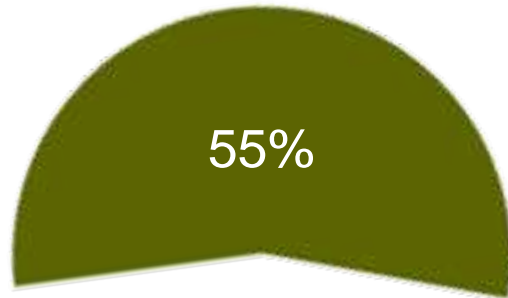
Broad product portfolio

- Applications embedding power discrete, smart power and Analog ICs
- **World-class IP** for discrete and smart power
- High-performance and robust **power packages** for high-power applications with optimized power density
- Technologies: MOSFET IGBT, SiC, GaN, BCD, integrated passives

Established Worldwide Ecosystem for Mass Market

- Strong system **know-how** to support a global **customer base**
- > 400 evaluation boards and associated development tools

% of 2014 Revenues













A Complete Portfolio for Power Applications

Power Discrete and Intelligent Power Module

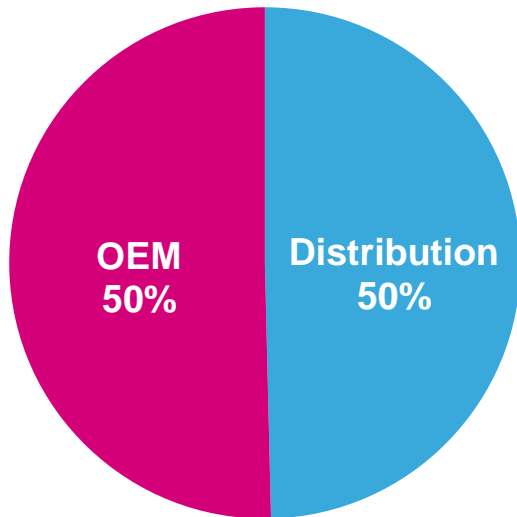
 Power Transistors	 Intelligent Power Module	 Thyristors & AC Switches	 Diodes & Rectifiers	 Protection Devices
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Smart Power ICs

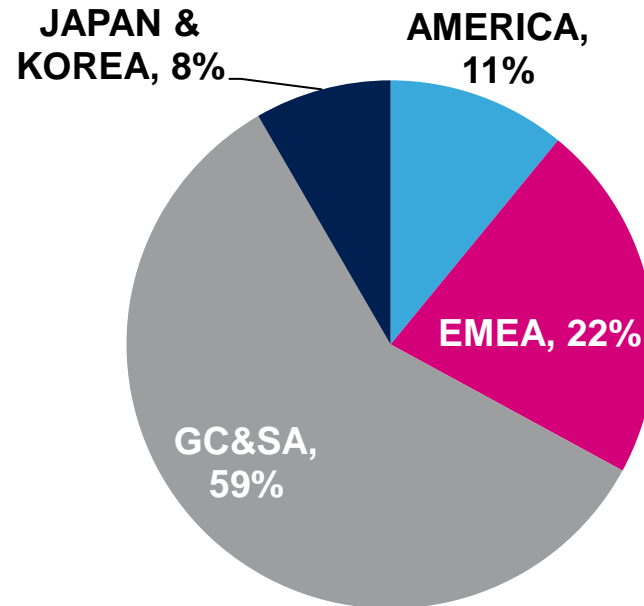
 Energy Management ICs	 Lighting ICs	 Industrial Analog ASSP	 Data Storage PCOMBO & PMIC	 Galvanic Isolation ICs
 Motor Control ICs	 AC/DC & Isolated DC/DC Power Supply	 EMI Filtering, Signal Conditioning	 Digital Power Conversion ICs	 Display PMIC

A large and diversified customer Base

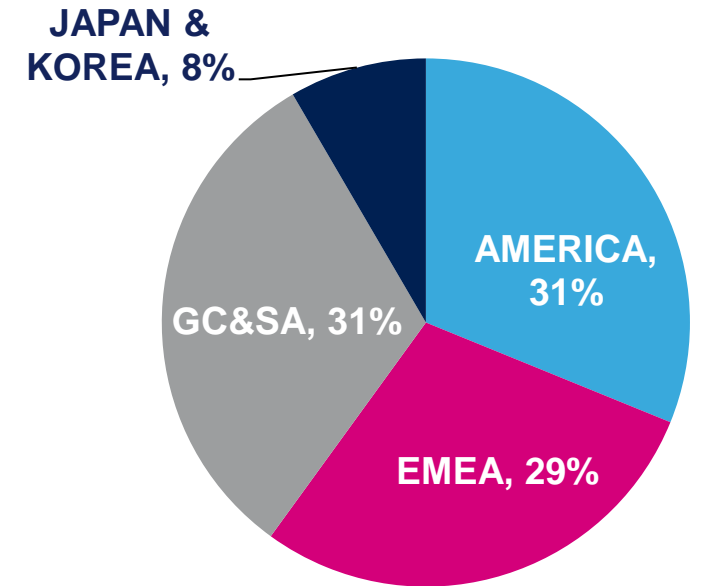
● 2014 Revenue by Customer type



● 2014 Revenue by Region of shipment



● 2014 Revenue by Region of origin

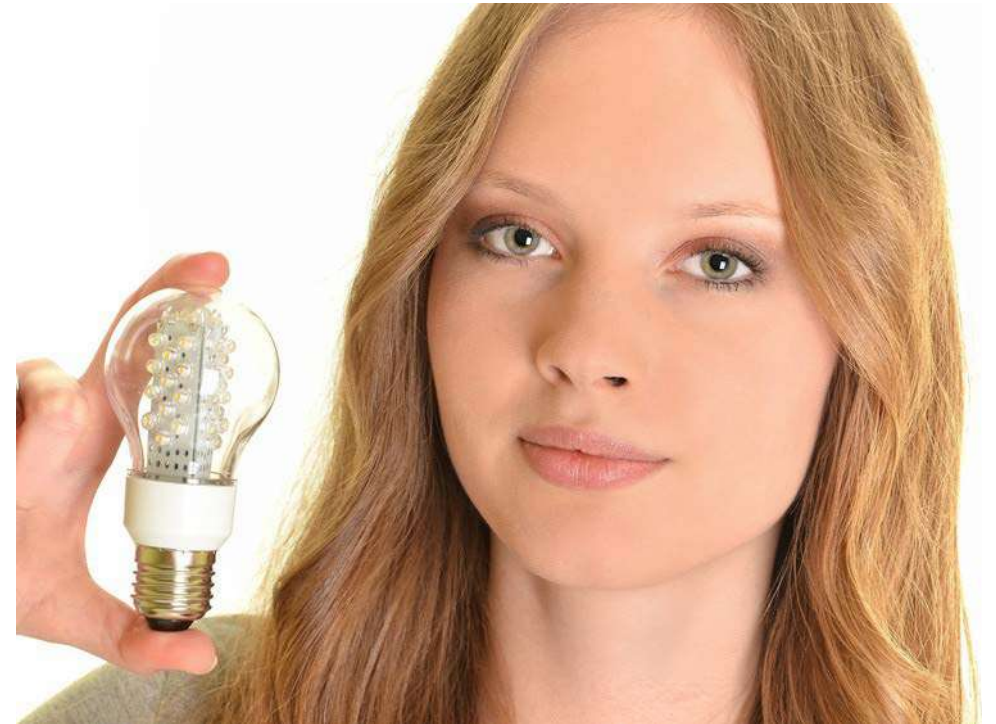


Well balanced across regions and customer types

Strategy and Market Approach

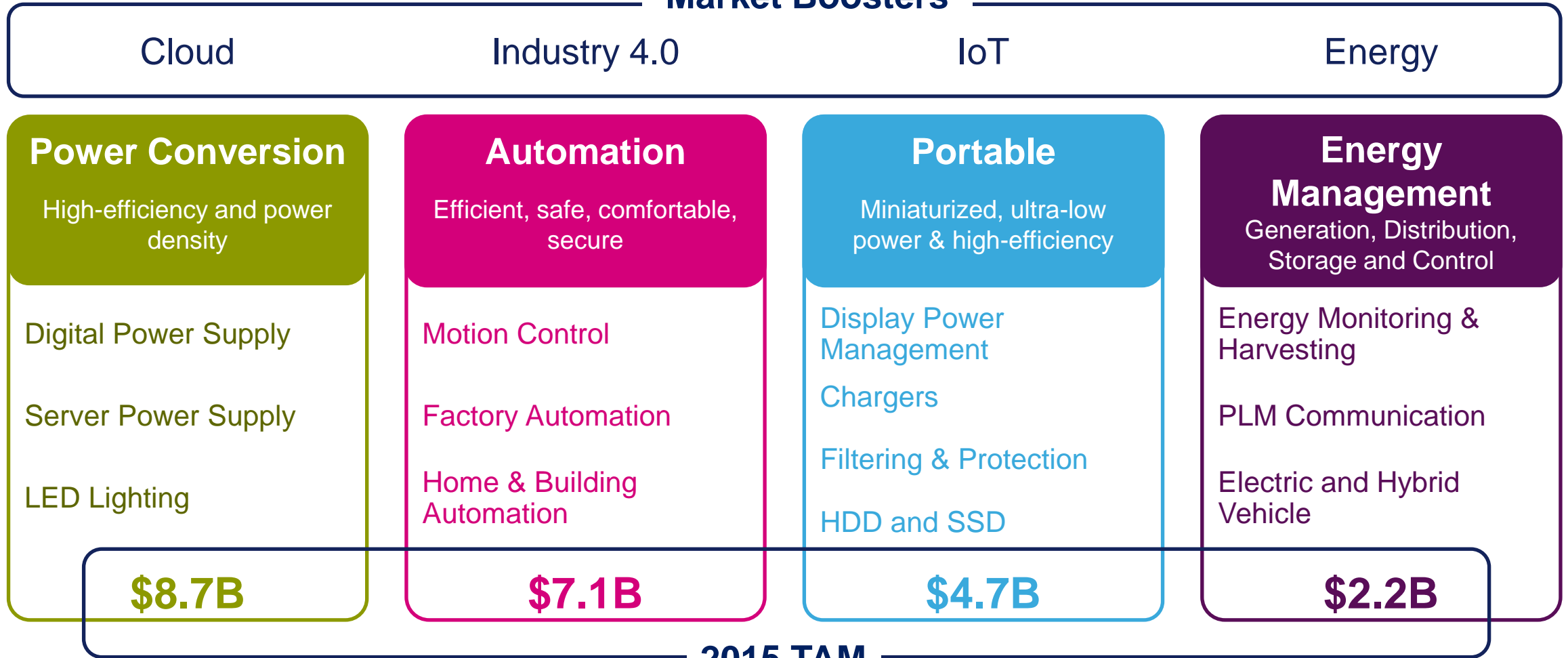
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- Product & Market Leadership in:
 - Power conversion
 - Energy management
 - Automation
 - Portable and computer
- Expansion of the base of **major accounts**
- Strong foothold in the **mass market and distribution**
 - Significant expansion of our customer base, exploiting also new sales channel like on-line marketing with a focusing on :
 - Motion control
 - Digital power
 - LED lighting



Targeting solid and growing Applications

Market Boosters



2015 TAM

Key Power Products and Technologies

Energy Saving & Power Efficiency

150



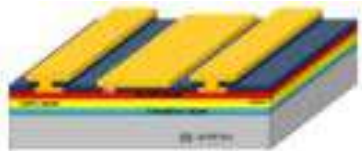
Silicon Carbide (SiC)

- SiC MOSFET (1200V up to 3.3kV)
- SiC Diodes (600V, 650V, 1200V)
- High voltage and high frequency power conversion for automotive and high end industrial



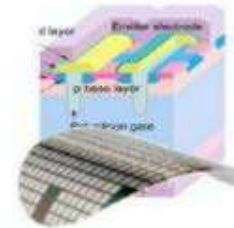
HV MOSFET

- Market leader on high voltage (> 400V)
- New high efficiency technology (up to 1500V) tailored for energy management and servers



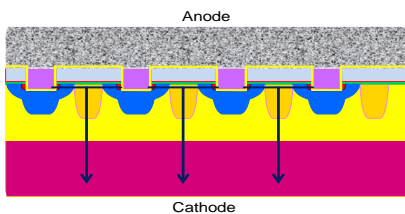
Gallium Nitride (GaN)

- GaN normally off transistor
- High switching frequency (up 20MHz) for high efficiency converters



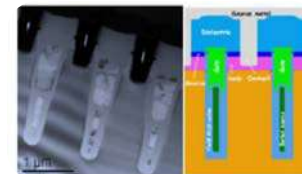
IGBT

- Advanced trench field stop. higher current density tailored for motor control, electric vehicles
- Better reliability and higher operating temperature



FERD: Field Effect Rectifier Diode

- Enhanced performance rectifier
- Higher efficiency



LV MOSFET

- Advanced trench structure (30-150V) for high power motor control, synchronous rectification for industrial and automotive

Key Smart Power Products and Technologies

Flexible & Efficient Power Management

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Digital Power Conversion

- Enables distributed power system architecture
- Remote diagnostic
- Programmability to increase system efficiency



Power Management for Portable & Servers

- Market leader in AMOLED power supply
- High efficiency solutions for energy management
- Innovative PMICs for servers achieving the highest efficiency in the market



Motor Control

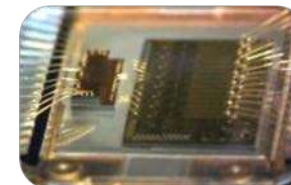
- Safe, easy to use, scalable solutions
- Supporting different motor types
- Industry 4.0 ready



Smart Grid & Metering

- Combining metrology and communication
- Multi-standard support

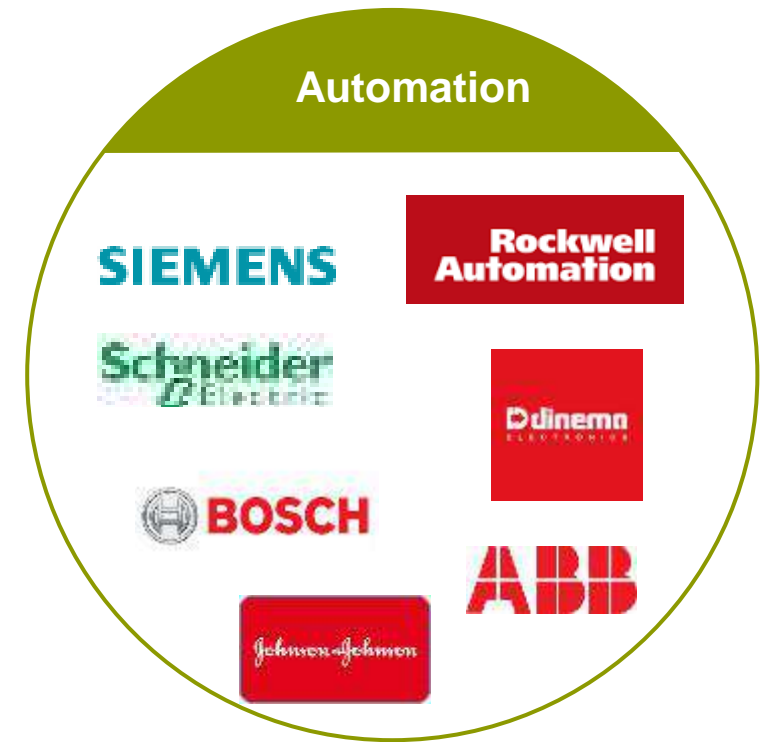
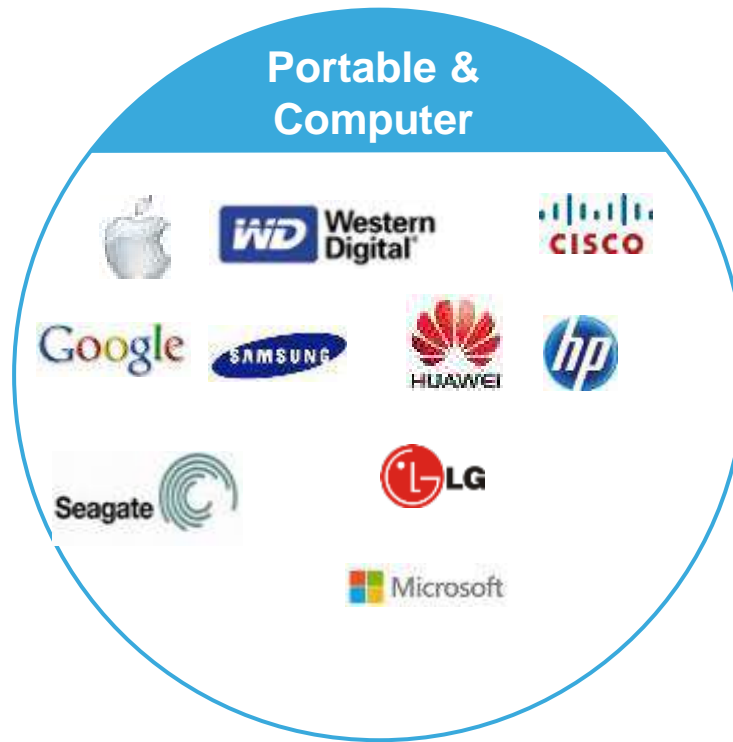
Enabling Technology



BCD with Galvanic Isolation

- System flexibility
- Safety (up to 10kV) and Immunity to magnetic fields

Winning with major Accounts

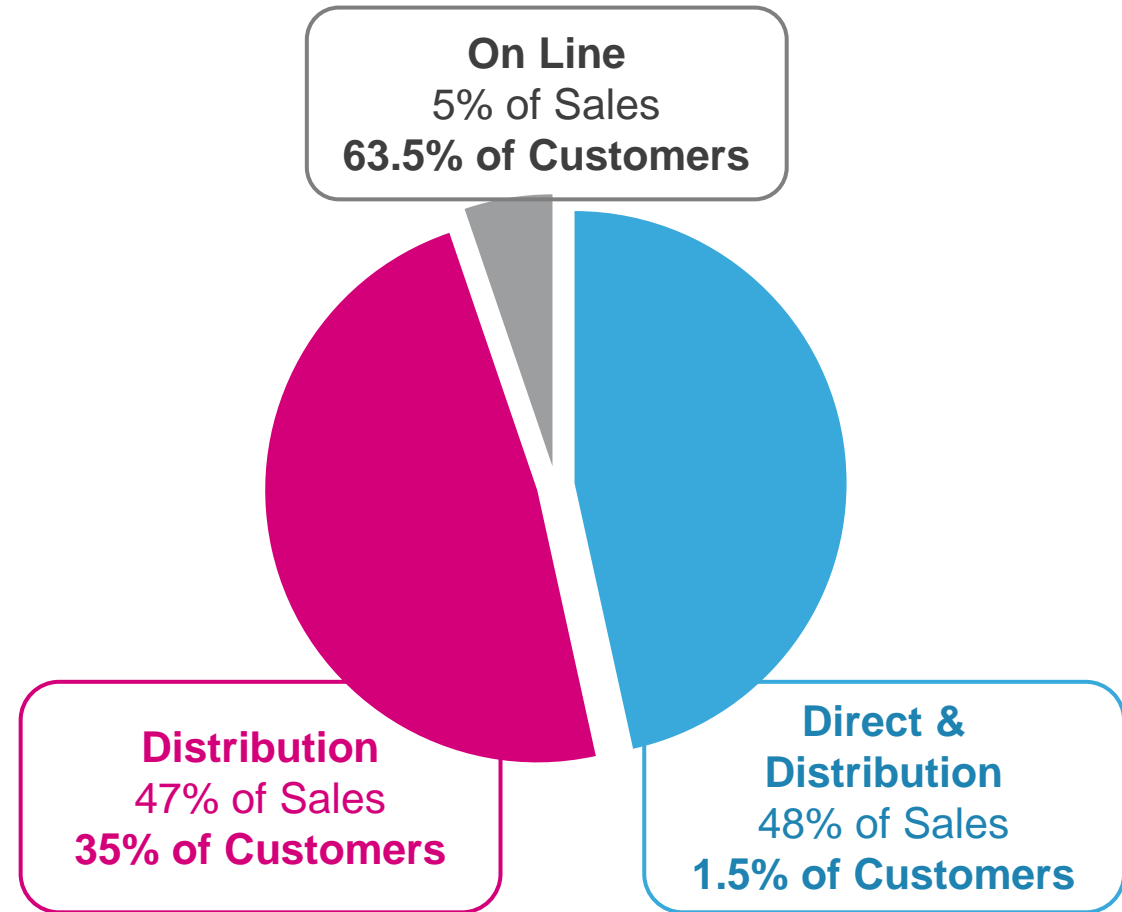


Long-term relationships, deep customer intimacy, strong innovation pipeline with timely new product development execution, solid system and application know-how & support

- The market which encompasses **thousands of customers** of ST outside of our top accounts
 - A broad collection of markets served by ST
 - Different channels used for engagement
 - More than 70% of revenues through distribution
- Diversified customer base brings **higher stability**
 - Multiple market segment cycles
- **Higher margin** potential
 - Distribution margins approximately 5+% better than ST average
- A different method of product development and promotion



“Mass Market” >100,000 customers



IPD Mass Market Programs

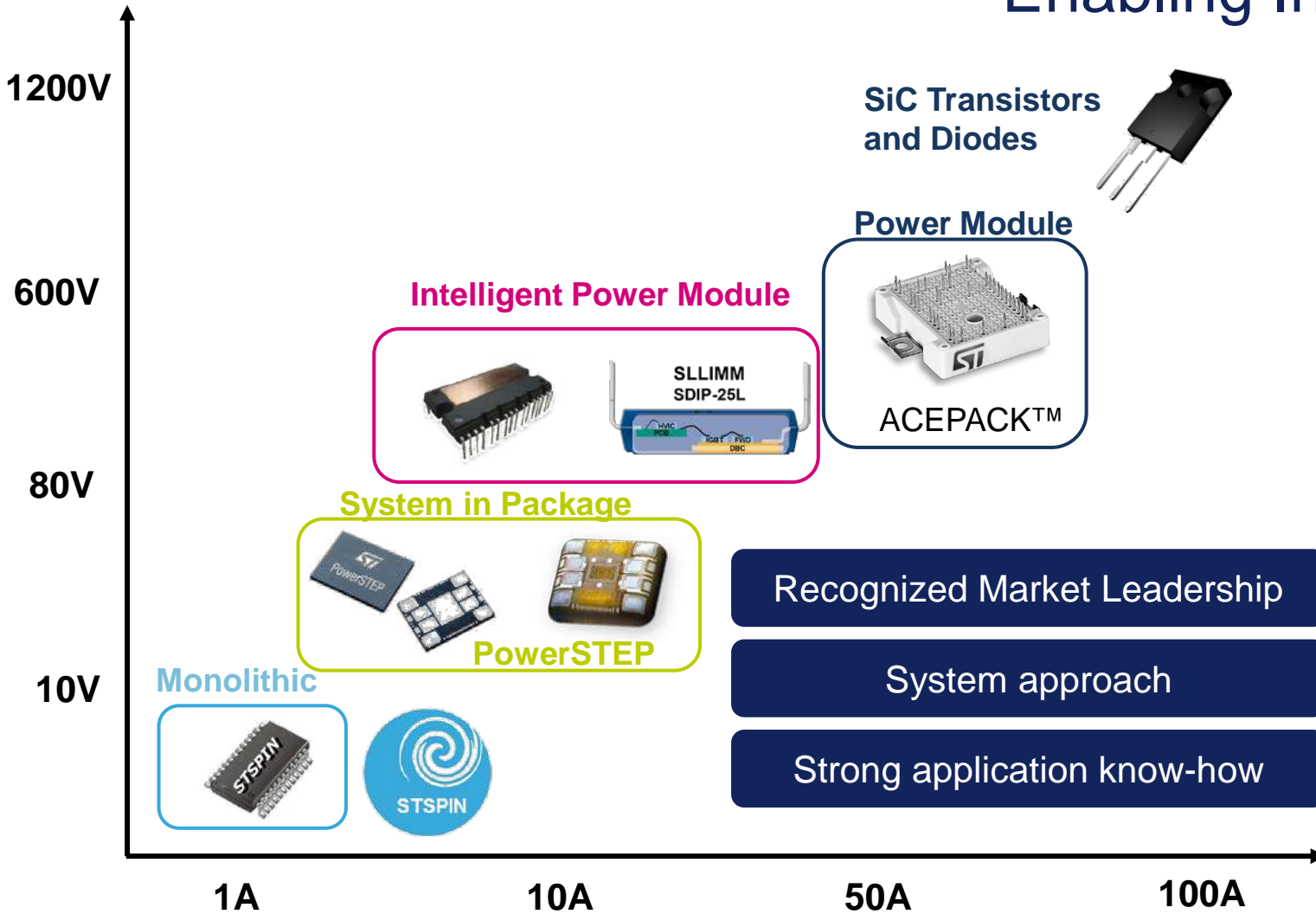
Our objective is to increase the mass market revenues and continuously gain market share

Based on three pillars



Leading the Evolution of Motion Control

Enabling Industry 4.0/Smart Industry



Driving the Evolution of Lighting

Mastering all lighting Technologies since the Beginning

1st Integrated Solution on the market

Most highly Integrated Solution

1st PMIC for LED



L657x
PFC + Half Bridge
in BCD offline
> 500MU sold

L656x/L638x
PFC + Half Bridge
+ fully integrated
PMU
> 1.5BU sold

HVLED
Offline controller for
LED lighting
> 100MU sold

1st Digital Solution
for LED
*> 20MU sold
in < 2 years*

Fluorescent
Lamp

Electric
Discharge
Lamp

LED
Lighting

Smart
Lighting

2000

2005

2010

2015

Key
Products

- Digital Controllers
- Power Discrete
- Connectivity ICs
- LED Driver ICs



LED Lighting
\$2.4B TAM in 2017
CAGR 2014-17:
+25.7%



Mastering the Evolution of Digital Power

From low to high power Applications



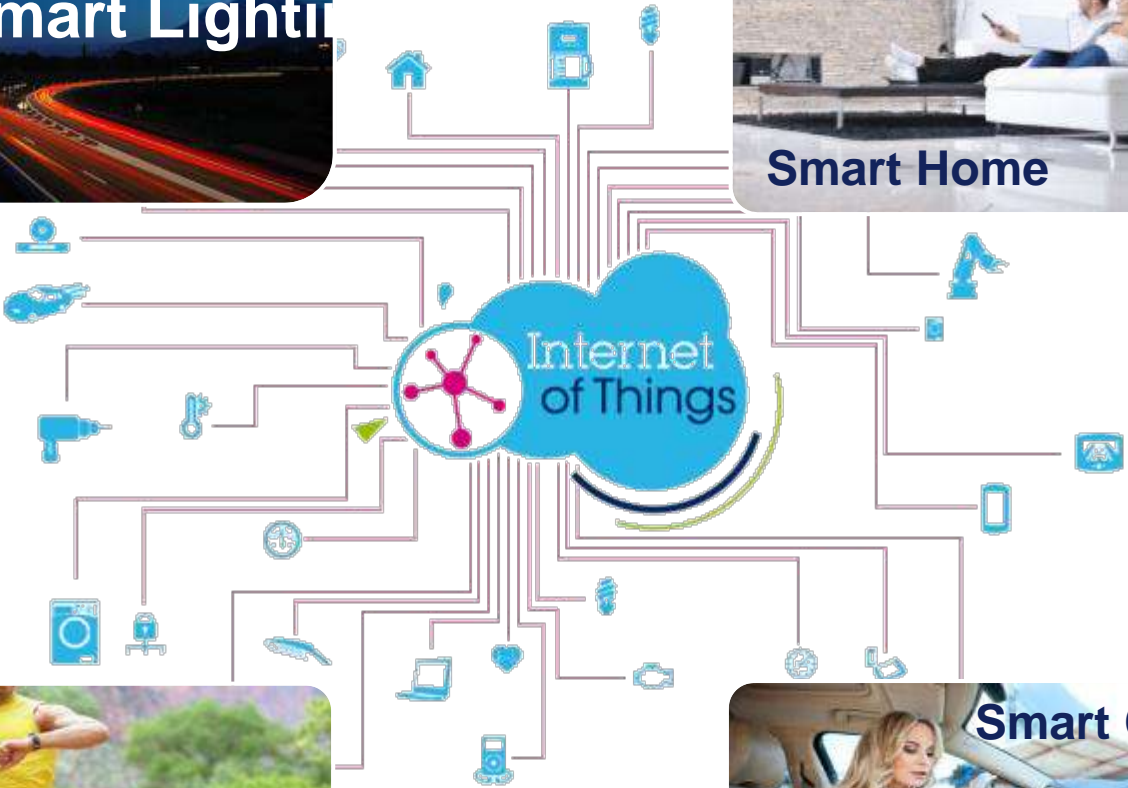
- 3kW STNRG digital power controller
- 1kW HV-DPS high power SMPS driver
- 200W STLUX digital lighting controller
- 200W STNRG011 Digital PFC LLC combo
- 20W Digital controlled Power Factor Corrector
- 20W VIPer Zero Stand By Off Line SMPS
- 5W STWBC Tx/Rx for wireless charging
- 0.1W SPV1050/40 for energy harvesting

- Greater power density
- Faster control loops
- System-level reliability monitoring, and safety
- Higher system efficiency



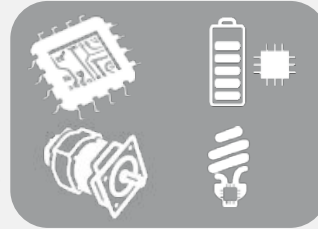
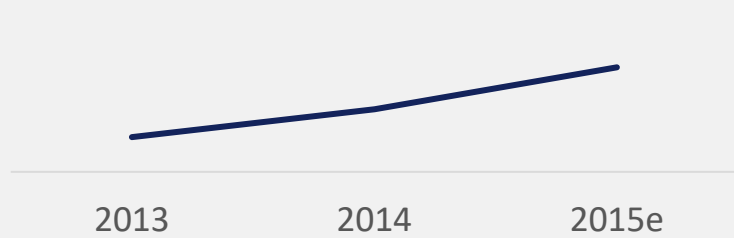
IPD powering the IoT

- Sensors
- Microcontrollers
Memories & Security
- Ultra-low power connectivity
- Analog and mixed signal components
- Power and energy management



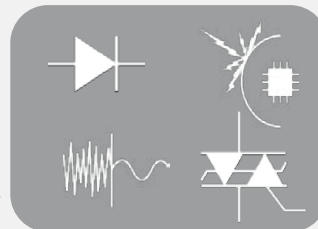
Growing across all Product Lines in 2015

Industrial and Power Conversion ICs



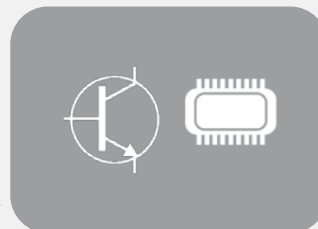
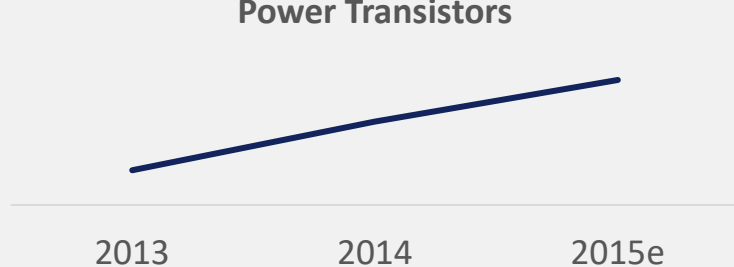
- PMICs for AMOLED in tablets and smartphones
- Digital controllers for lighting and power conversion
- PMICs for Servers
- Motion control and factory automation ICs

Discrete



- RF Modules with RF Couplers and Filters for mobile
- SiC Diodes in servers, telecom and automotive
- SCR and high performance rectifiers for energy management

Power Transistors



- Low Voltage Trench MOSFETs for industrial, servers and automotive
- IGBTs and Intelligent Power Modules
- High Voltage Super Junction and SiC Transistors for energy management and EHV

- Strong portfolio of Front-End Technologies, packages, IP and SW
- Manufacturing strategy aligned with growth opportunities
- Combining efficient and leading power technologies with digital and analog smart power ICs
- Strong system know-how enabling strategic relationship with distributors and mass market customers
- Diversified customer base for a balanced presence in the market
- Focusing on high growth markets with good margin and financial return

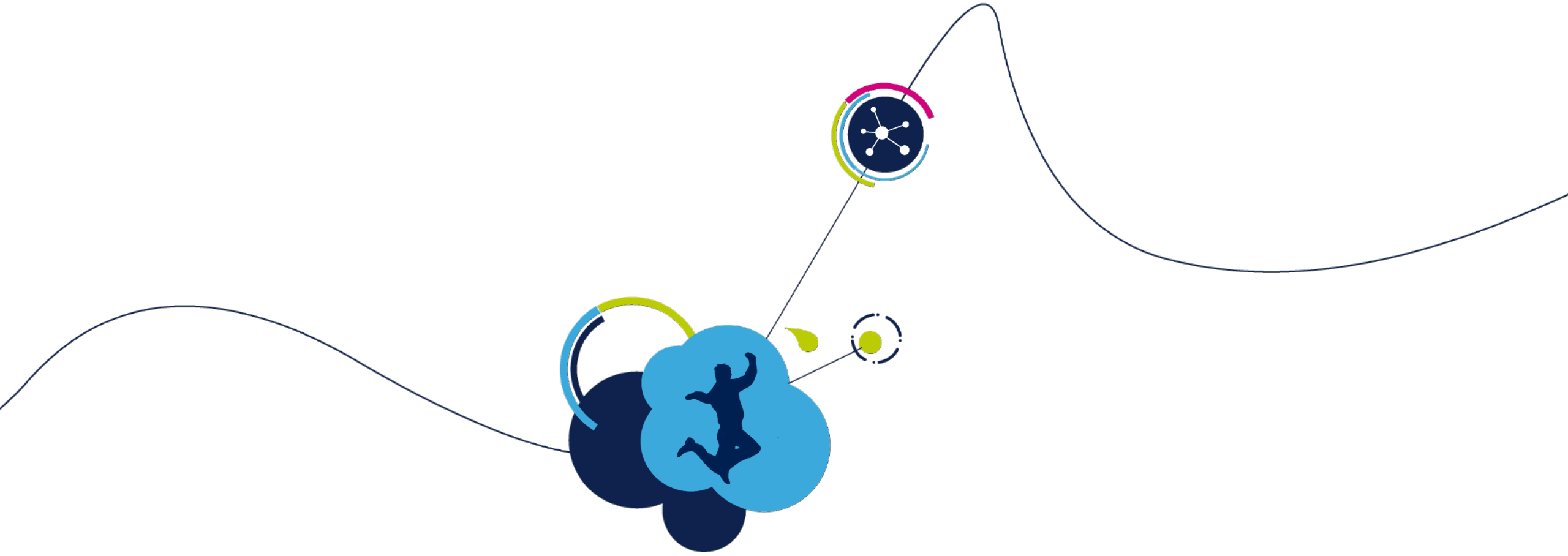


EPS Manufacturing and Technology R&D

Joel Hartmann

Executive Vice President
General Manager, Front-End Manufacturing & Technology R&D
Embedded Processing Solutions (EPS)





Manufacturing

Our Achievements

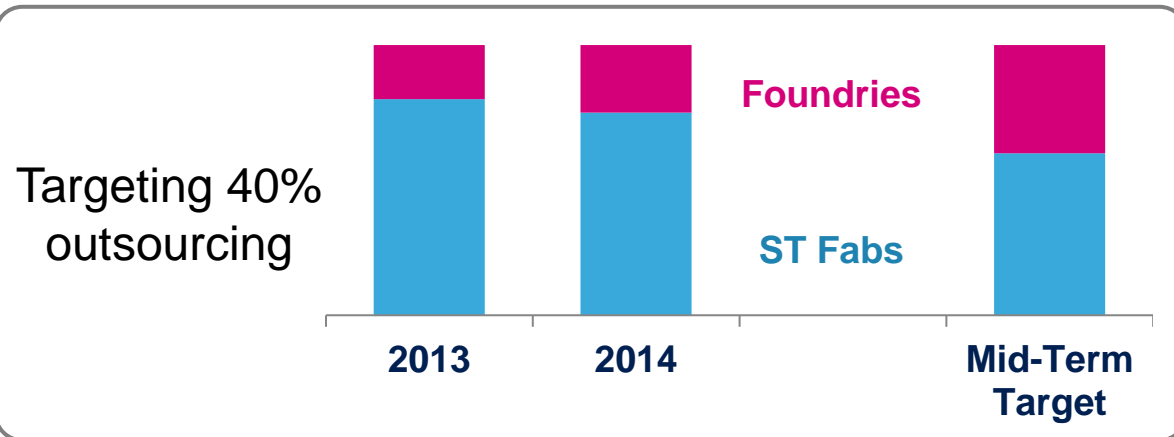
- **Availability of a competitive RFSOI** technology platform, exploiting 200mm manufacturing capability
- **Adoption of 28nm FD-SOI** technology by key customers, with strong prototyping activity
- **Fostered FD-SOI ecosystem** across OEMs, design houses and IP suppliers
- **Risk production qualification of the 28nm FD-SOI** technology in Samsung
- **Volume ramp-up of 90nm eNVM** technology in Crolles-300
- **Volume manufacturing of Photonics sensors**
- Prototyping service with fast cycle time

2015 Priorities

- Full manufacturing qualification of 28nm FD-SOI in Samsung and product introduction
- Proliferation of all product families in 90nm eNVM technology (general purpose, automotive & secure MCUs)
- Volume ramp-up of automotive MCUs in 55nm eNVM technology
- Volume ramp-up of 90nm eNVM secure MCUs
- EEPROM volume manufacturing (130nm...)
- Diversified activity on specialized image sensors

EPS Manufacturing Strategy

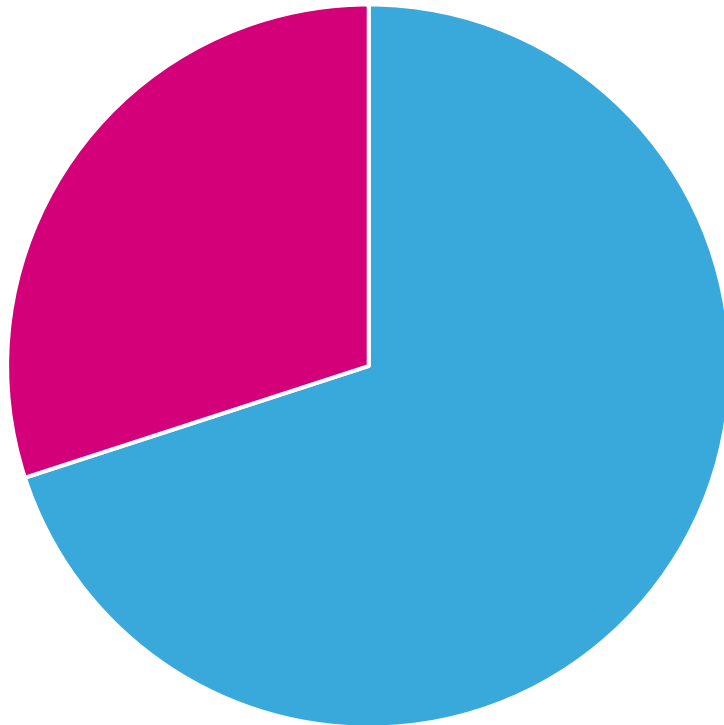
- Multiple sourcing through technology & manufacturing partnerships
- Rousset / Crolles clustering
- Crolles 300mm increase of scale on differentiated technologies according to demand



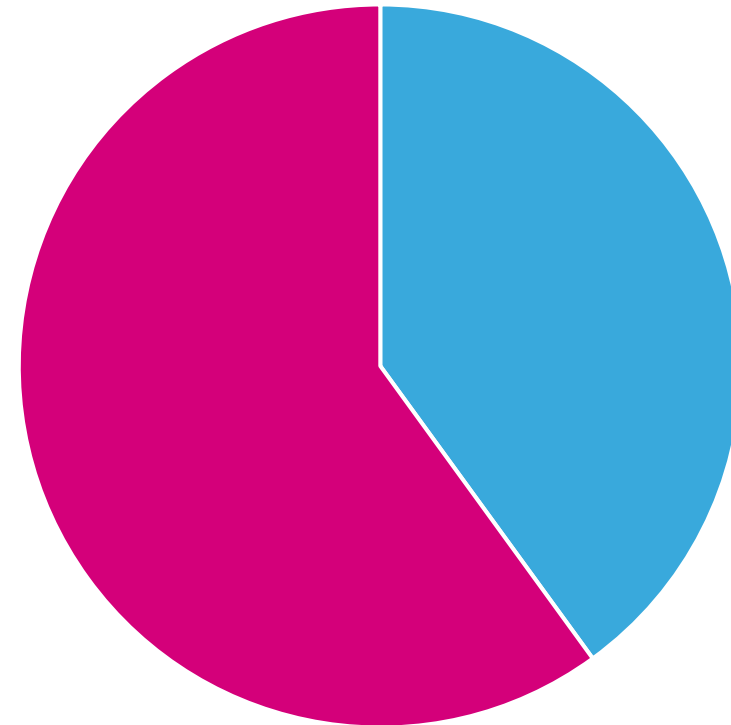
Technology		Driver/First	Second
CMOS Bulk	≥40nm	Crolles 300	Foundry
	<40nm	Foundry	Crolles 300
CMOS FD-SOI	28nm	Crolles 300	Foundry
Differentiated Imaging		Crolles 300	
BiCMOS	≥90nm	Crolles 200	
	<90nm	Crolles 300	
Si Photonics		Crolles 300	
RF SOI		Crolles 200	Crolles 300
HCMOS9A		Crolles 200	Crolles 300
eNVM	≥90nm	Rousset 200	Foundry
	<90nm	Crolles 300	

Crolles 300mm - Mix and Evolution

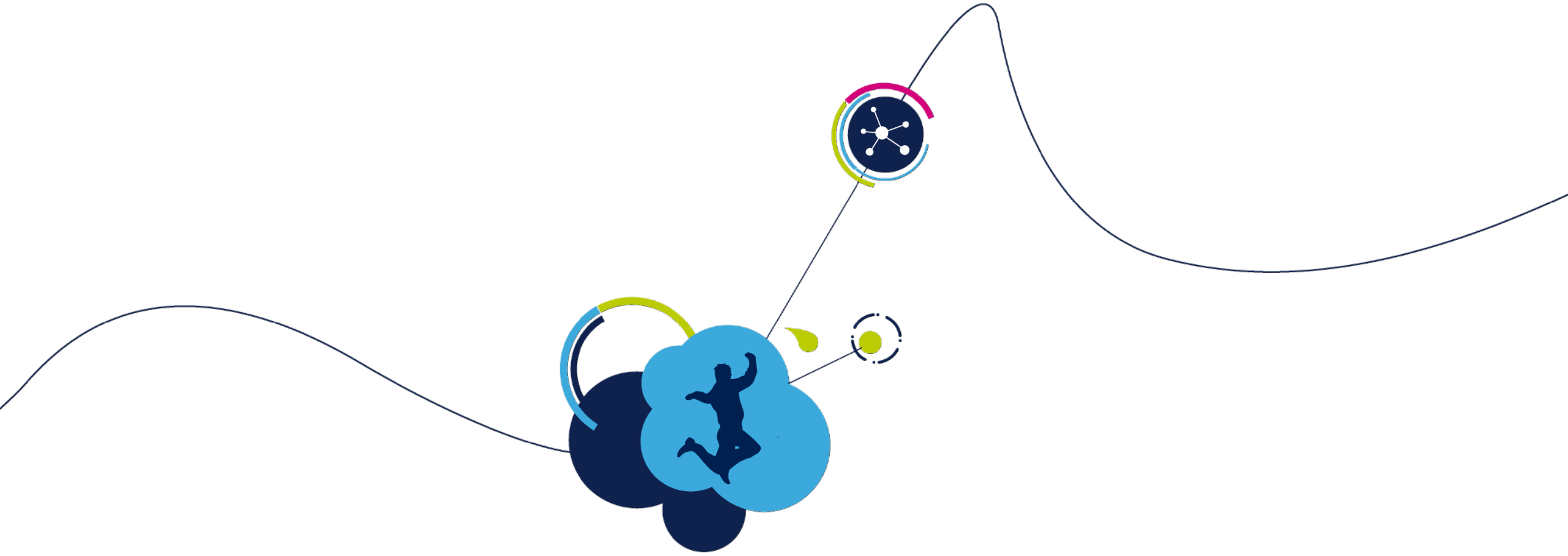
4Q14



4Q17e

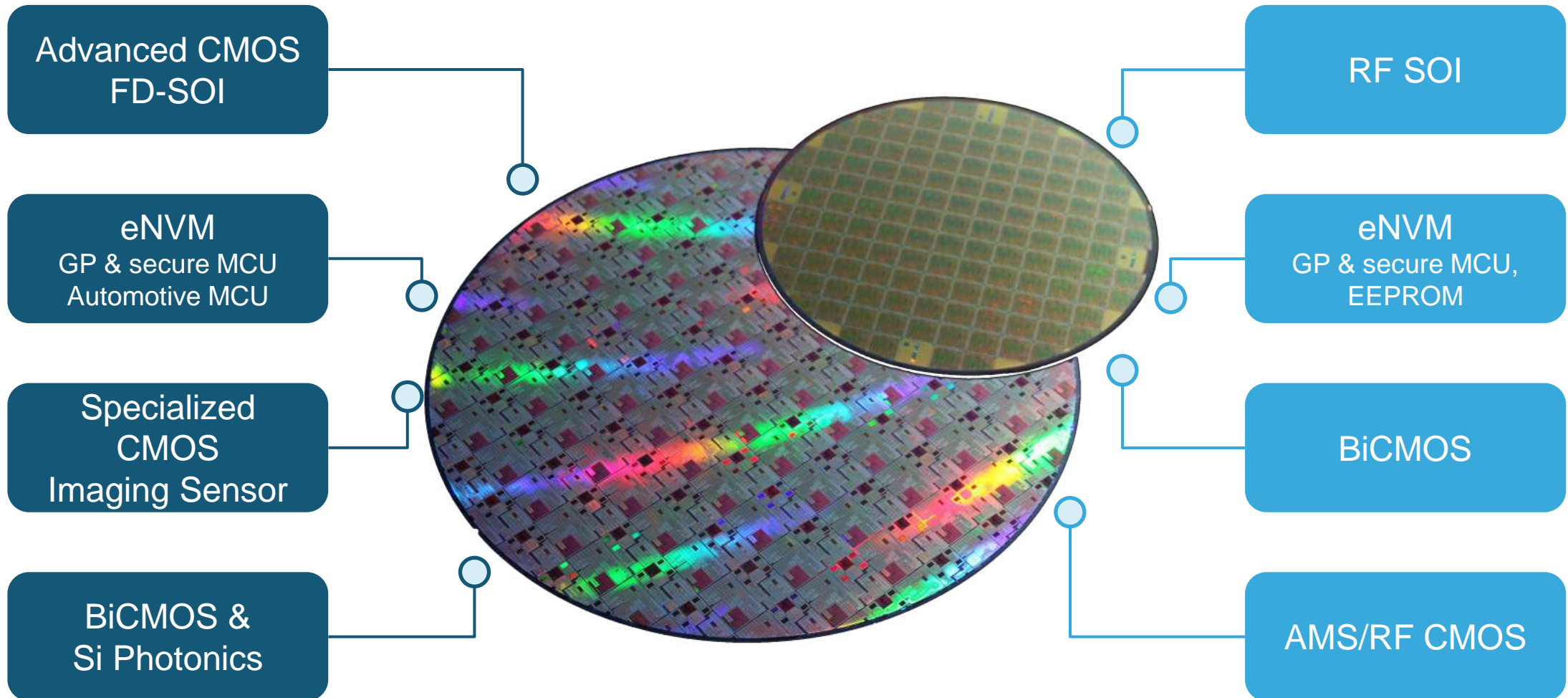


- Embedded Flash
- Advanced Logic and Specialized Imaging



Technology R&D

Balanced 8/12" technology Portfolio



EPS Key R&D Achievements

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Our Achievements

- **Risk Production qualification of 40nm eNVM** technology platform
- **Prototyping activity for 55nm BiCMOS & Silicon Photonics**
- **130nm HCMOSSOI RF** technology reached **110fs $R_{on} * C_{off}$** performance
- **Started the 1st MPW of 14nm FD-SOI** technology

2015 Priorities

- Initiating prototyping of 14nm FD-SOI technology
- Development of 28nm FD-SOI ULP & RF derivatives
- Full manufacturing qualification of 40nm eNVM technology and early prototyping activity (GP, secure & automotive MCUs)
- 55nm BiCMOS and PIC55 Silicon Photonics risk production start
- Specialized Imaging Sensor technology process qualification

Mass
Production

Development

Research

FD-SOI Roadmap

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+35% speed
-50% power

**FD-SOI
14nm**

Derivatives

Feature Path

Performance Path

Body Bias, cost, simplicity, reliability

**FD-SOI
28nm**

RF,
Mixed Signal

Ultra Low
Power

Embedded
Non Volatile

Feature Path

Differentiated options for the long-lasting 28nm process node

FD-SoC Application Benefits per market segment

170



Infrastructure Networking

- Energy efficient **multi-core**
- **Adapt** performance & power **to workload** by FBB
- Excellent performance on **memories**



Consumer

- Optimized SoC integration (Mixed-signal & RF)
- Energy efficient SoC in **all thermal conditions**
- **Optimized leakage** in idle mode



Internet of Things, Wearable

- **Ultra-low voltage** operation
- FBB to solve the **power/performance** paradigm
- Efficient **RF and analog** integration

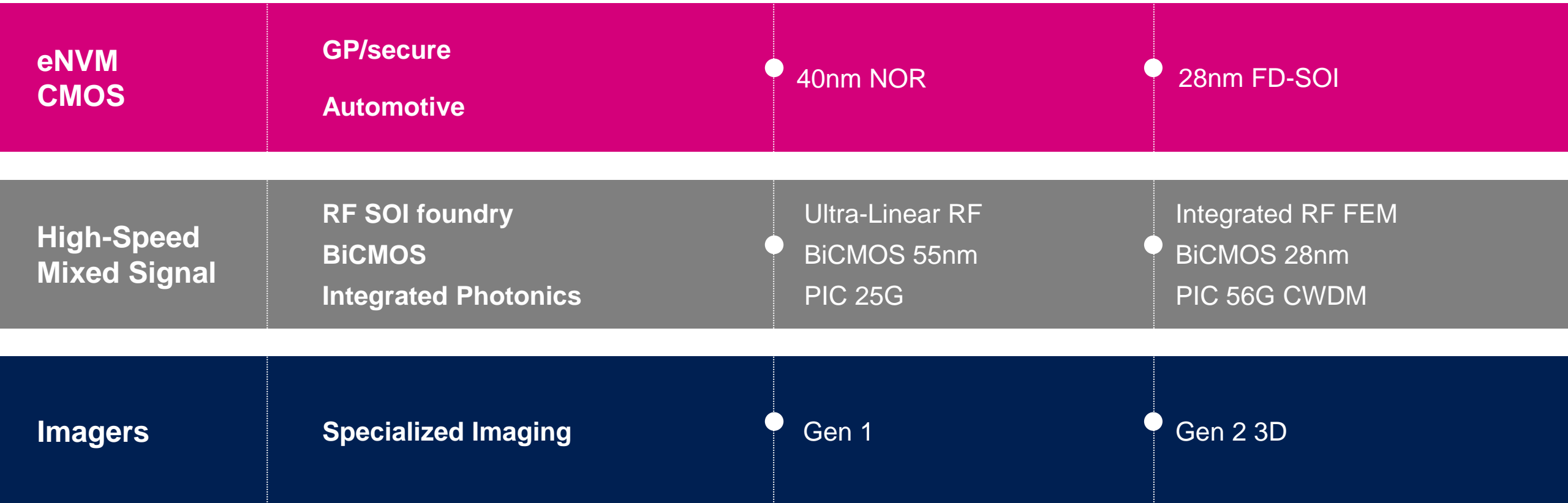


Automotive

- **Well-managed leakage** in high temperature environment
- **High reliability** thanks to highly efficient memories

Differentiated Technology Roadmap

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40nm eFLASH technology for advanced MCUs with NVM addressing a wide range of applications, fully compatible with 40nm logic platform



Consumer & Industrial

- **High performance** logic for **32-bit MCUs**
- **High performance & high density** FLASH
- **High reliability** with extended temperature

Secure

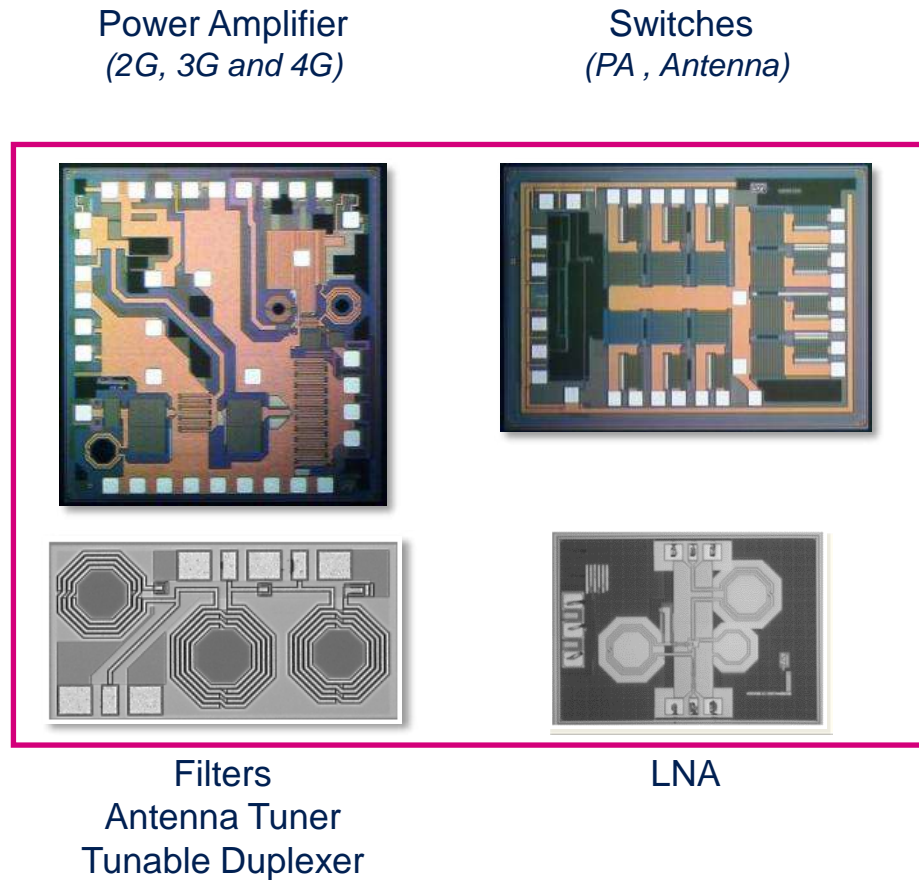
- **High performance page Flash erasable**
- **ROM-less**
- **High reliability & low cost**



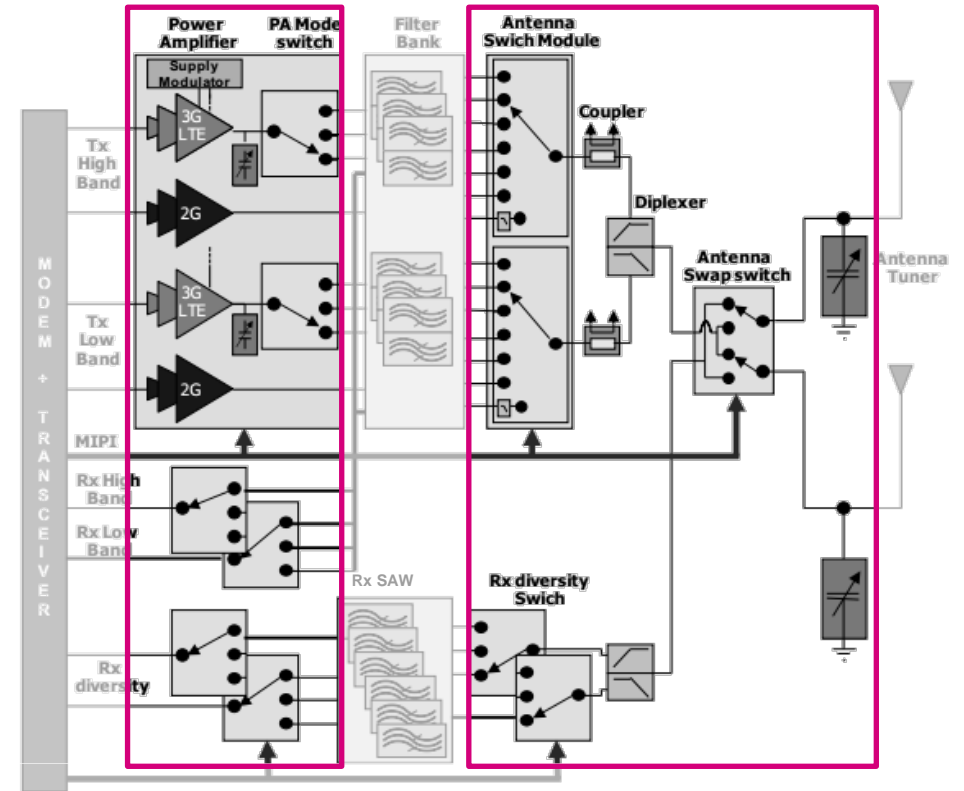
Automotive

- **High performance** logic for **32-bit MCUs**
- **Highly reliable** with state of the art FLASH technology
- **Extended temperature range**

Addressing Mobile FEM integration



H9SOI_FEM



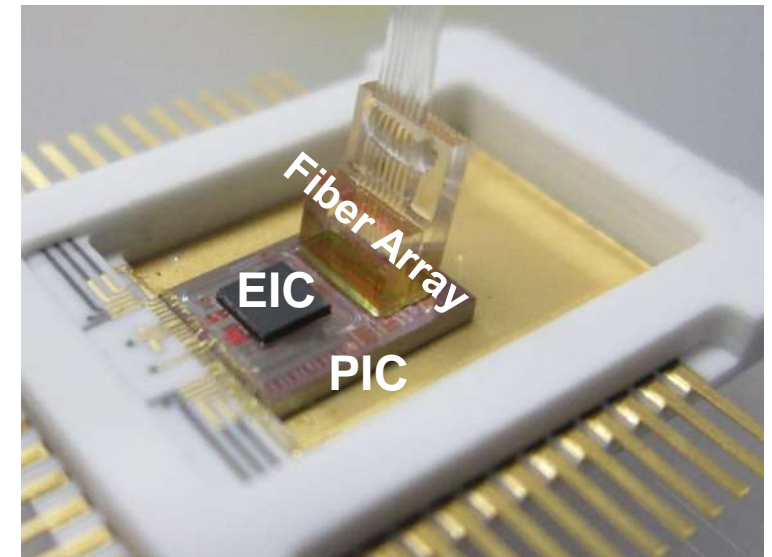
Long-term technology partnership

- BiCMOS55

- Continuous evolution of SiGe HBT architecture & CMOS node towards best performance vs. complexity trade-off
 - $f_T > 300$ GHz
 - $f_{MAX} > 400$ GHz

- Silicon Photonics

- WAN
 - Transport, metro, access
- Enterprise (rack to rack, board to board, chip to chip)
 - LAN, data centers, routers, switches, HPC
- On-chip
 - Parallel processing, multi-core interconnect



Communication & Consumer

Hybrid AF, proximity sensing, gesture...



Home Appliances

Robot cleaners, light control, toys...



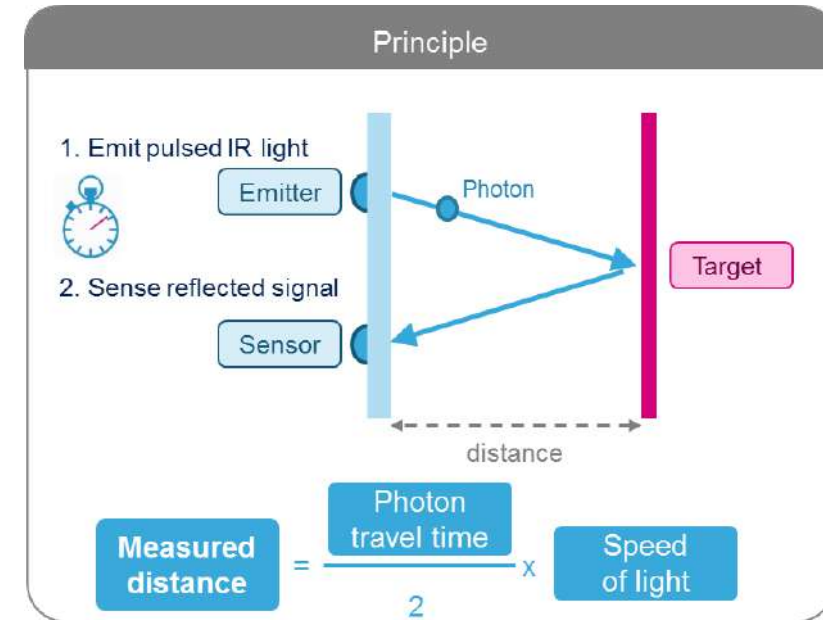
Automotive

Infotainment system control



Industrial

Proximity detection, door control, robotics...



Distances are measured as the time light takes hitting an object and coming back to the sensor

Measuring true distance independently of target size and reflectance

EPS Manufacturing and Technology Summary

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- Differentiated and focused technology roadmap driving internal manufacturing volume
- Time-to-market and time-to-volume, driven by clusters of leadership Crolles / Rousset
- Cost efficiency driven by global lean internal manufacturing initiative and foundry partnership

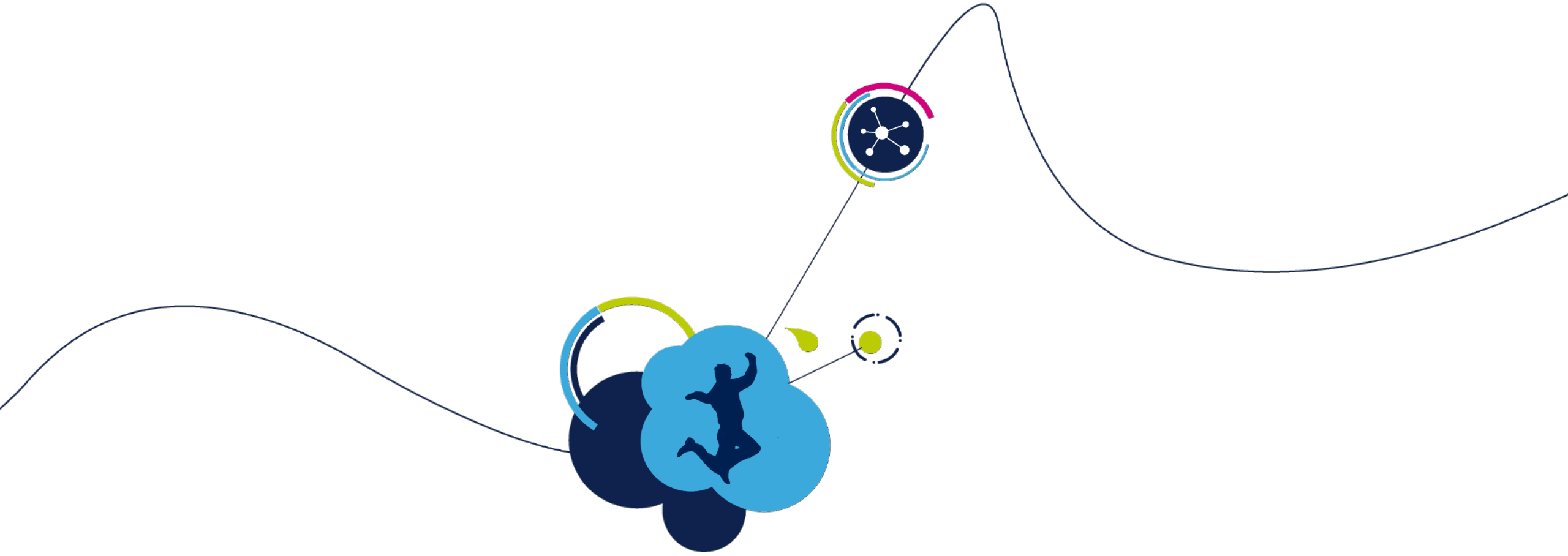


SP&A Manufacturing and Technology R&D

Orio Bellezza

Executive Vice President
General Manager, Front-End Manufacturing & Technology R&D
Sense and Power & Automotive (SP&A)

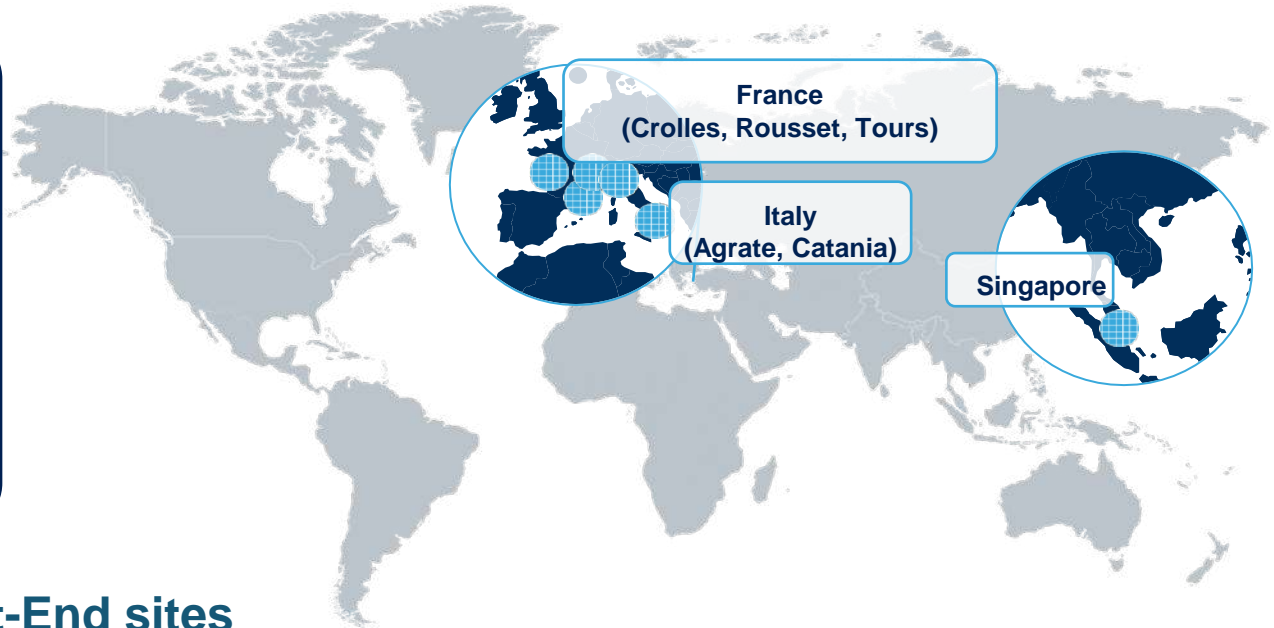




Manufacturing

Front-End Manufacturing: Unique Capability

Large technology portfolio
 Clustering approach
 Internal and external flexibility



6 Front-End sites

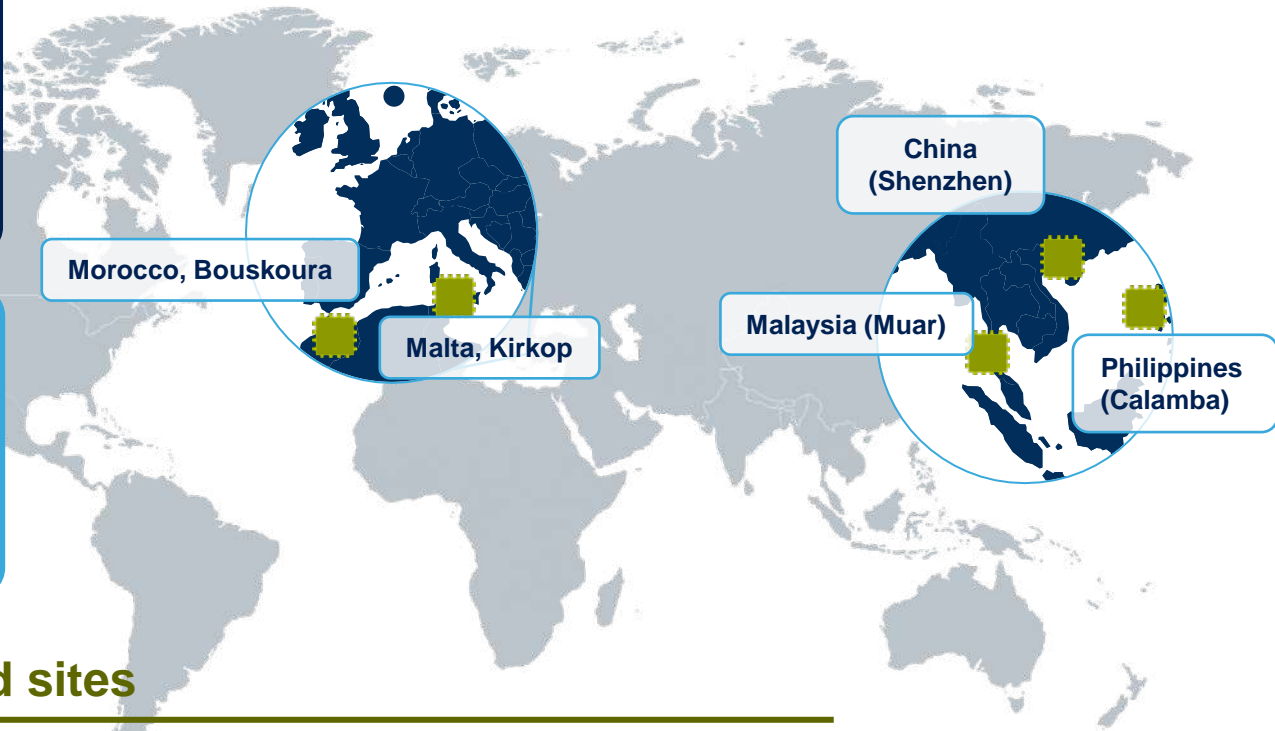
EPS		SP&A	
Crolles	Advanced Logic Image Sensors Embedded-NVM	Tours	Discretes
Rousset	Embedded-NVM Logic	Agrate	Advanced BCD MEMS
		Catania	Advanced BCD Advanced PMOS
		Singapore	Discretes Power BCD

Foundry partners

Packaging & Testing Manufacturing

Consolidation of China operation for cost structure improvement
Longgang closure completed end of 2014

- Fast time to volume and competitive manufacturing
- Multipurpose sites serving both product sectors
- Relentless quality improvement



5 Back-End sites

Bouskoura	Embedded NVM PMOS BCD Bipolar, Discrete	Calamba	Embedded NVM BCD MEMS Discretes	Shenzhen	Embedded NVM Image Sensors, Logic Power, PMOS BiPolar, BCD
Kirkop	Embedded NVM Advanced Logic MEMS	Muar	Embedded NVM Power BCD		

OSAT partners

2015 Capital Spending

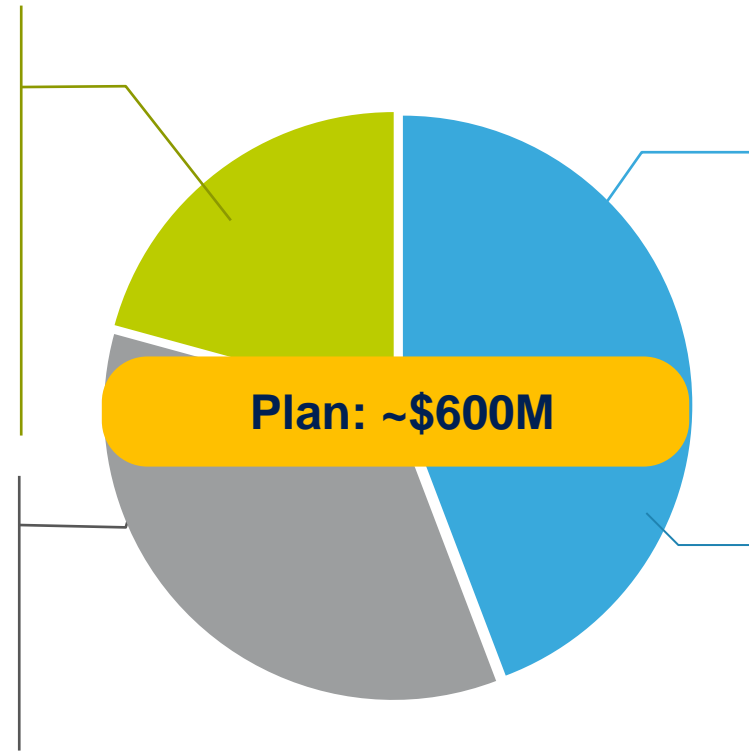
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Back-End Manufacturing

- Capacity increase and mix evolution at Asian plants
- Manufacturing automation and energy savings

Test & Others

- Testing capacity increase to meet demand, IT, quality & safety



Front-End Manufacturing/R&D

- Crolles 300mm technology development and mix change in MCU and automotive
- Ramp-up of 200mm in Singapore for Smart Power and Transistors
- Mix evolution to Advanced BCD and thick copper for automotive and industrial at European fabs

Investments focused on:

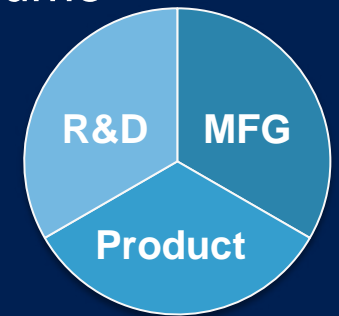
- Strategic business growth and key product ramps
- Proprietary technology and manufacturing

Technology Differentiation

- Smart Power BCD9s for automotive and industrial
- MEMS: motion, microphone, micromirrors
- Trench Power MOSFET
- SiC and GaN

Integrated Manufacturing & R&D

- Time to market – time to volume
- Flexibility
- Clusters of leadership



4 Front-End sites

Tours	Discretes	Catania	Advanced BCD Advanced PMOS
Agrate	Advanced BCD MEMS	Singapore	Discretes Power BCD

**Cost competitive and flexible
high volume manufacturing**

Roadmap, Achievements and Priorities

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Roadmap

- Technology capability for **product differentiation**
- Improve mix toward **higher margin** product lines
- Progressive **conversion from 150mm to 200mm** in the Singapore & Catania fabs

Achievements

- **Volume production** of **BCD8 0.16 μ m** generation for HDD, PMIC and automotive applications in **Agrate** and **Catania** fabs
- **MEMS pressure sensors** ramp in Agrate
- **Volume** ramp of **MDMESH** in Singapore 200mm

2015 Priorities

Smart Power

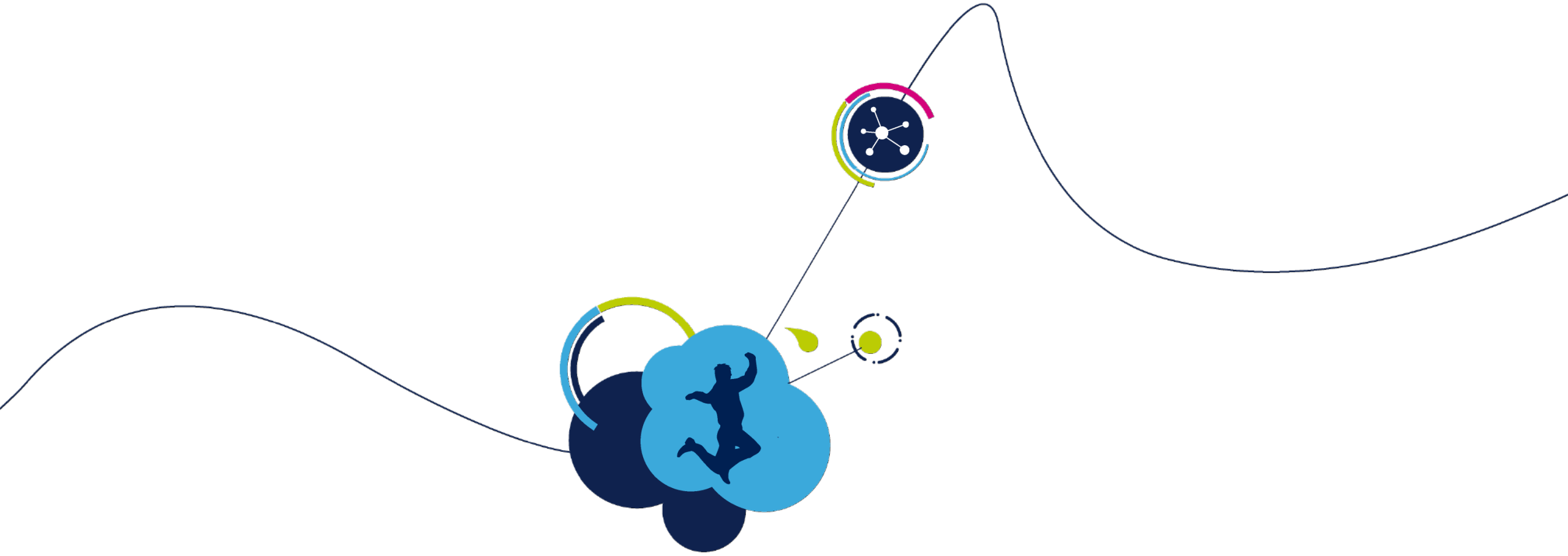
- Volume growth of BCD6 Automotive in Agrate and qualification in Singapore 200mm
- BCD mix evolution to 0.16/0.11 μ m and thick Copper in Catania fab

Discretes

- Oxide Filled Trench qualification in Singapore 200mm
- New RF Integrate Passive Devices ramp in Tours in 200mm

MEMS

- Microphone capacity increase
- Micro-mirror ramp






















Technology R&D

SP&A - Technology Roadmap

	Available	2015/16	2017/18
BIPOLAR CMOS DMOS	<ul style="list-style-type: none"> 160nm / 110nm (7 - 100V) 160nm SOI (200V) 320nm (700V) / Galvanic Is. (4kV) 	<ul style="list-style-type: none"> 90nm / e-PCM (7 - 100V) 160nm SOI (300V) 320nm (1200V) / Galvanic Is. (6kV) 	<ul style="list-style-type: none"> 65nm New Materials Exploration / Integration
MEMS	<ul style="list-style-type: none"> Motion (6 axis, AMR, Hperf) Audio (Hperf Microphone) Actuators (micromirrors, piezo) 	<ul style="list-style-type: none"> Motion (Automotive) Actuators (Piezo autofocus, inkjet) 	<ul style="list-style-type: none"> Electromagnetic Actuators Passive IR Sensors
Power Transistors	<ul style="list-style-type: none"> 0.35µm Oxide Filled Trench 1200V Superjunction 1200V Silicon Carbide (SiC) 	<ul style="list-style-type: none"> 0.2µm Oxide Filled Trench Gen2 New Trench IGBT 1700V Silicon Carbide (SiC) 600V Gallium Nitride (GaN) 	<ul style="list-style-type: none"> New Superjunction structures High T IGBT 3300V Silicon Carbide (SiC) LV Gallium Nitride (GaN)
Other Discretes	<ul style="list-style-type: none"> HV Scr Triacs 1500V SiC Pschottky 650V 	<ul style="list-style-type: none"> HV Scr Triacs 2000V SiC Pschottky 1200V 	<ul style="list-style-type: none"> HV Scr Triacs 2500V GaN Pschottky 600V

BCD Technology Segmentation

SEGMENT	TECHNOLOGY PLATFORM	APPLICATION FIELDS
High Voltage BCD 700V – 6KV	BCD6s Offline (0.32μm)	 Lighting  Motors  Electrical Car
	BCD6s HV Transformer (0.32μm)	
SOI BCD 190V – 300V	SOI-BCD6s (0.32μm)	 Full digital amplifier  Echography  AMOLED  Pico-projector
	SOI-BCD8s (0.16μm)	
	SOI-BCD9s (0.11μm)	
Advanced BCD 7V – 100V	BCD8As (0.16μm)	 HDD  Airbag  Audio amplifier  Printers  ABS  ESP  Power Line modems  Power Supply  Automotive  Power Management for Mobile
	BCD8sP (0.16μm)	
	BCD8sAUTO (0.16μm)	
	BCD9s (0.11μm)	
	BCD9sL (0.11μm)	
	BCD10 (90nm)	
	BCD11 (65nm)	
High Voltage CMOS 16V – 40V	HVCMOS8 (0.18μm)	 Bio Medical  Advanced Analog
	HVG8A (0.18μm)	
	HVCMOS9 (0.11μm)	

e-PCM (Phase Change Memories) in advanced BCD Technologies

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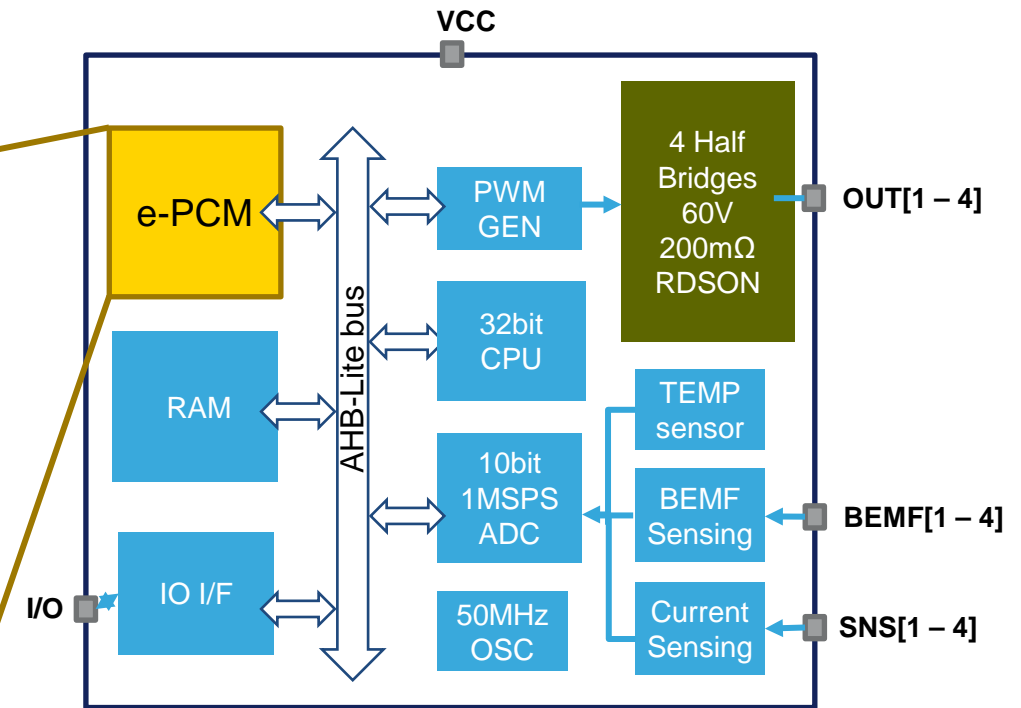
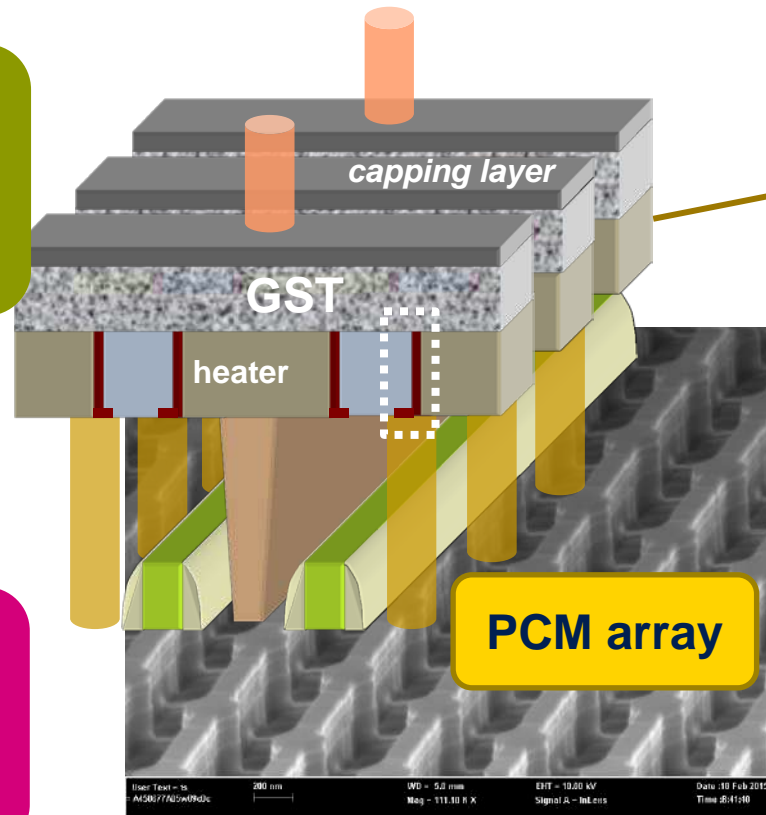
Motor Driver Application

Cost effective

Few additional masks
Smaller cell vs. EEPROM
Smaller over-head vs. FLASH

Easy

Low voltage operation
Flexibility on MV transistor
No impact on CMOS



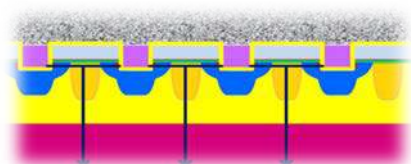
- 32-bit MCU
- Integrated PCM
- 4 Half Bridges 60V, 200mΩ

Power & Discrete Technologies



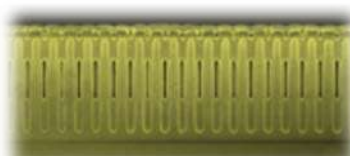
Silicon Carbide (SiC)

- SiC MOSFET ($\geq 1200V$ up to 3.3kV)
- SiC Diode ($\geq 600V$)



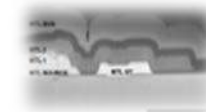
FERD: Field Effect Rectifier Diode

- Enhanced performance rectifier
- Smaller form factor than Schottky



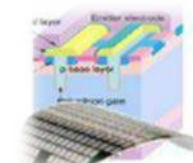
HV MOSFETs

- Market leader on High voltage ($>400V$)
- New high efficiency technology tailored for energy management and servers



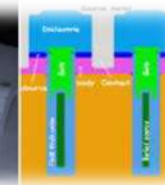
Gallium Nitride (GaN)

- GaN normally off transistor
- Extremely high switching frequency



IGBT

- Advanced Trench Field Stop. Higher current density for Motor Control, Electric Vehicles
- Better reliability and higher operating temperature



LV MOSFETs

- Advanced Trench structure (120-150V) for High Power Motor Control and Synchronous Rectification
- Advanced Trench (40-100V) for low noise high current application also in automotive
- Integrated Schottky up to 60V for Server

Our Achievements

- High volume production and technology customization of **BCD8sP** for **power management** in consumer and industrial applications
- Release of **BCD9s** platform for production in **automotive** applications
- **Qualification** and volume start-up of **SOI-BCD8s** for high voltage Sensors
- **First Generation LV** trench transistors (**OFT**) **40-60-80-100V**
- **SiC MOSFET 1200V** released to production

2015/16 Priorities

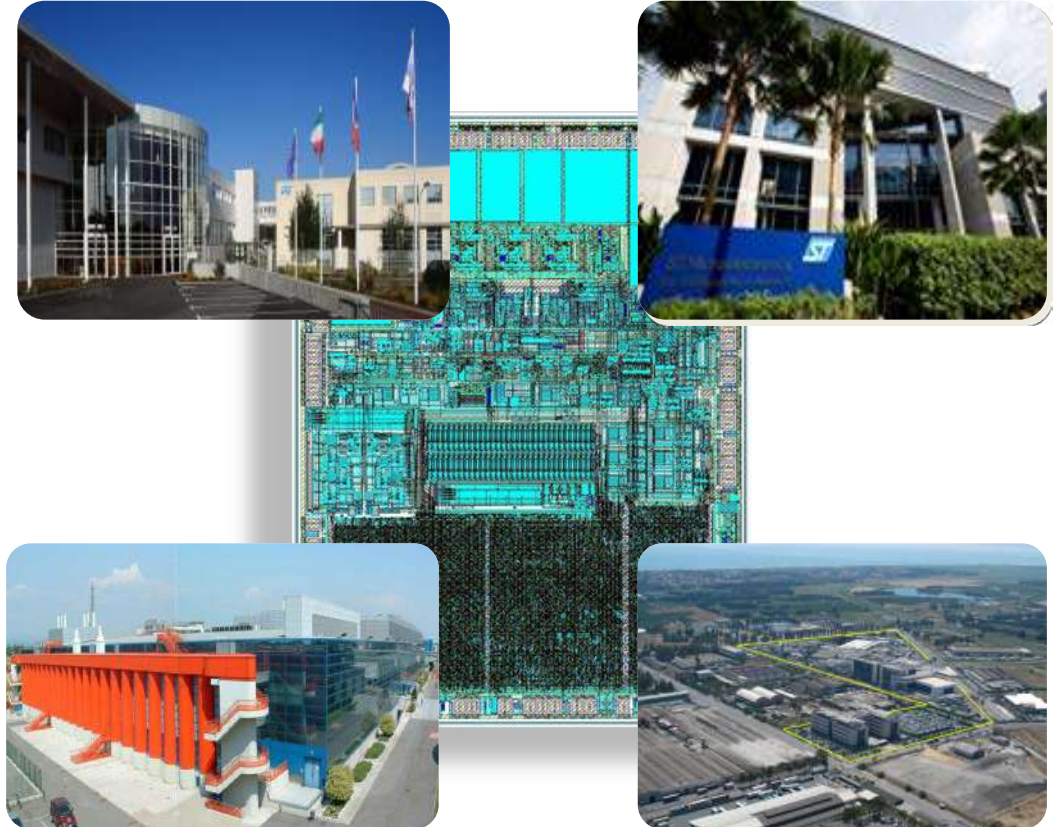
- **e-PCM** integration in **BCD9s** to provide cost effective e-NVM
- **BCD10** platform development
- **Next Gen LV** trench (OFT)
- New Trench Field Stop **IGBT**
- **SiC MOSFET 1700V**

Manufacturing and Technology Summary

Sense & Power and Automotive

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- Competitive technology road-map in the “More-than-Moore” supporting product portfolio differentiation
- Time-to-market and time-to-volume, driven by clusters of leadership
- Improving cost and efficiency by wafer diameter conversion in Singapore and Catania
- Global lean manufacturing culture, driving continuous efficiency improvement



Americas Region

Bob Krysiak

Executive Vice President
President, Americas Region

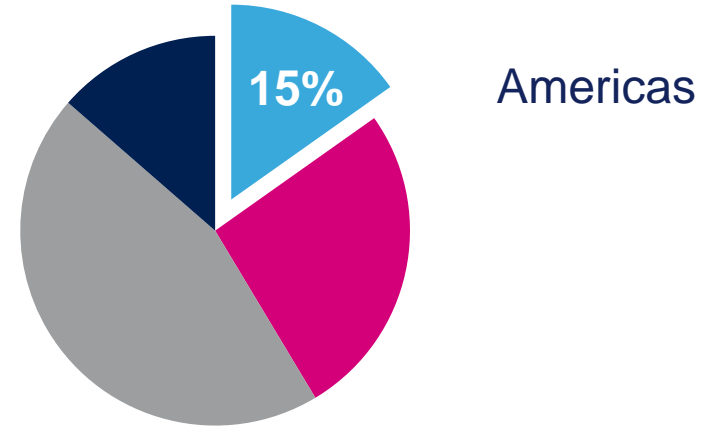


Americas Region at a Glance

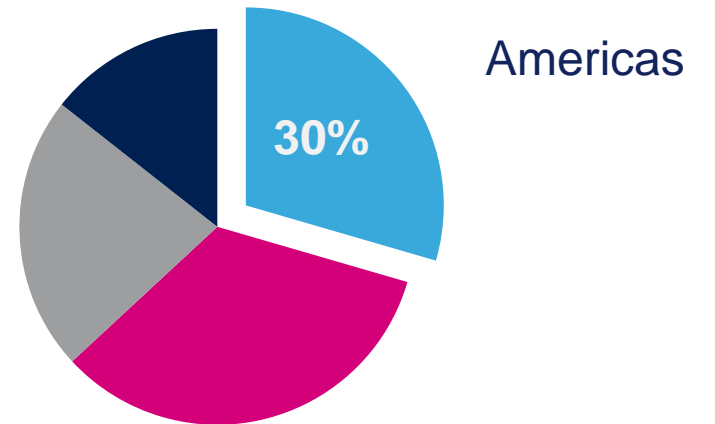


~900 Employees
5 Main Design Centers
10 Sales Organizations
18 Sales Offices

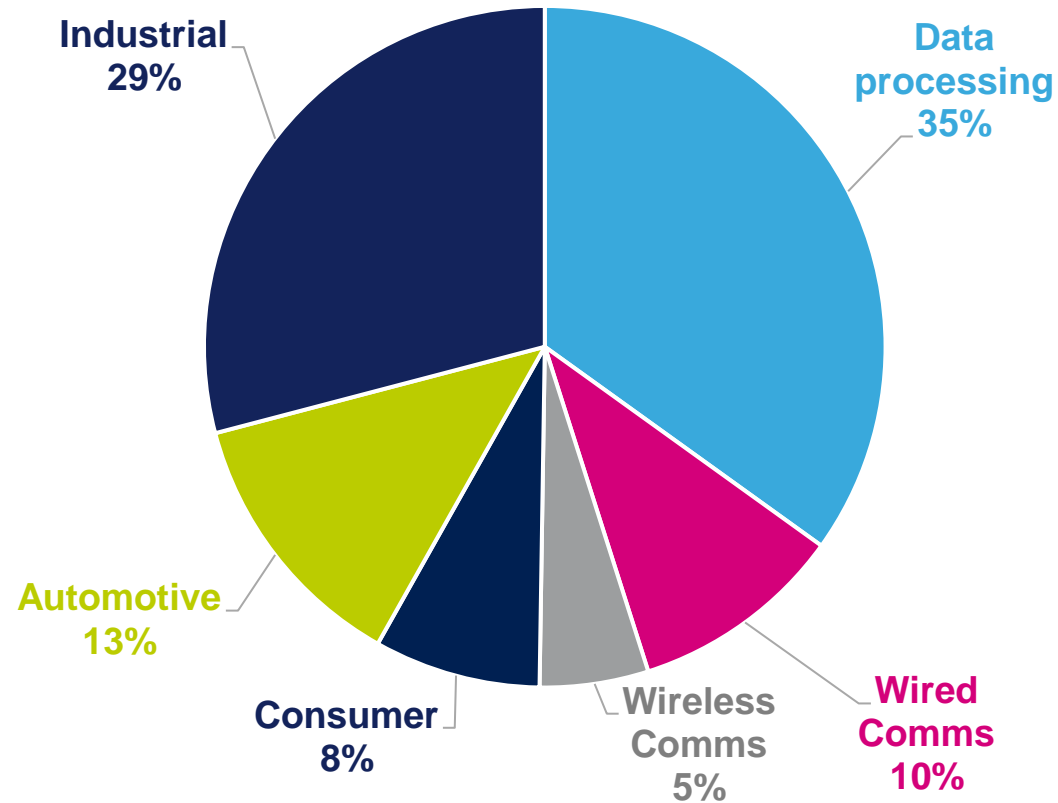
Sales by shipment location FY2014



Sales by customer origin FY2014



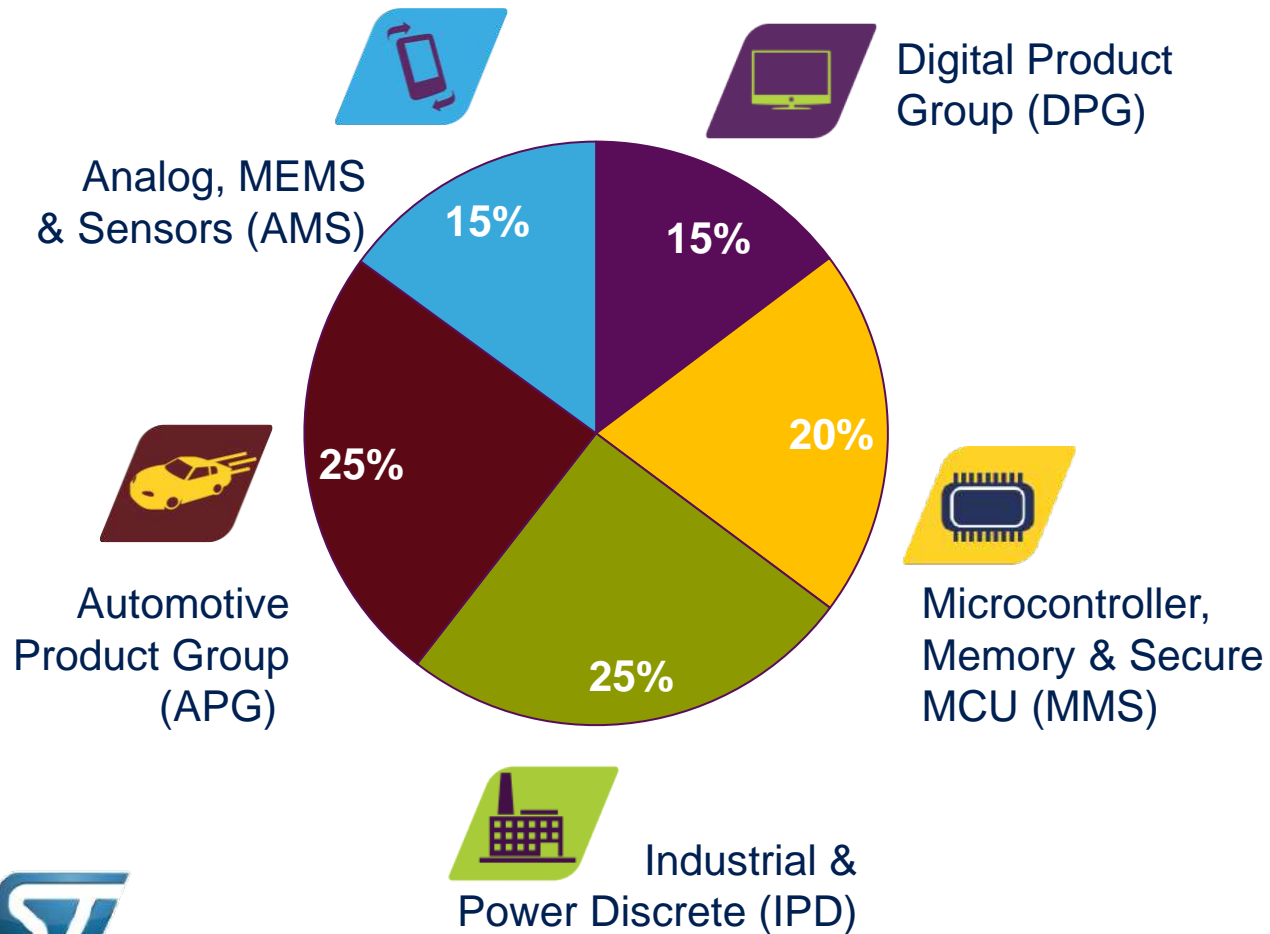
Americas TAM 2014 : \$69B



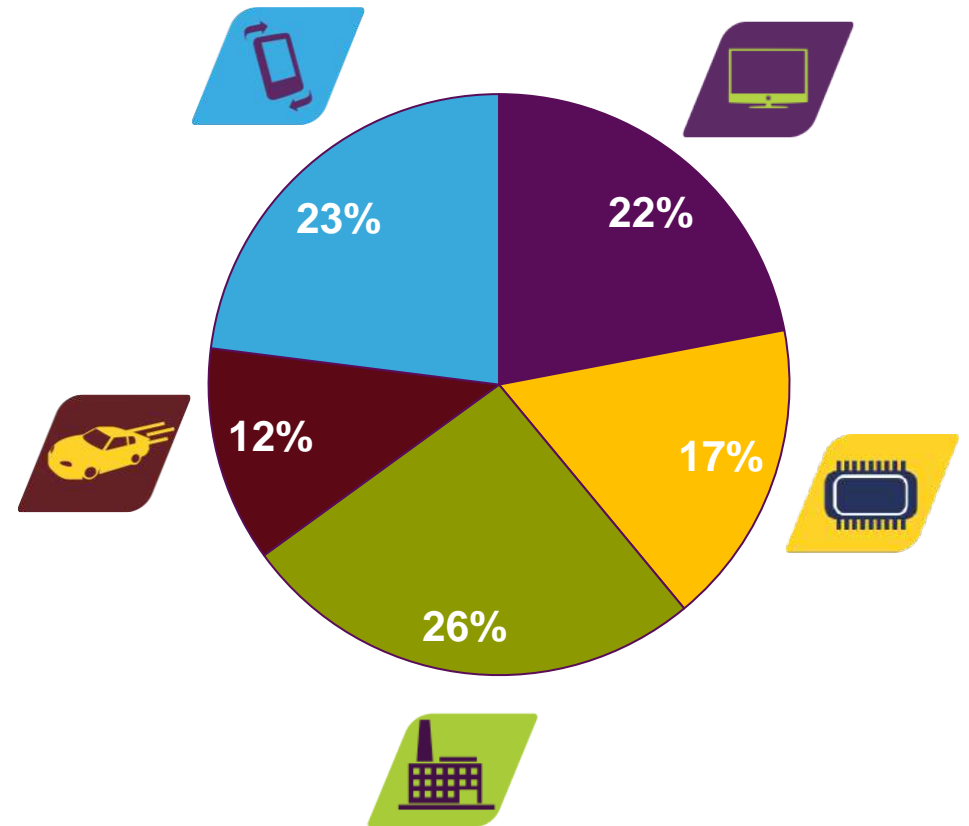
GDP Growth	North America	South America
2014	2.4%	0.7%
2015	3.0%	-0.2%

Sales by Product Group

ST Sales 2014 By Product Group



Americas Sales 2014 By Product Group (customer origin)



Americas Customers

Automotive

DELPHI HARMAN
LEAR CORPORATION BOSE
SIRIUS XM SATELLITE RADIO
GM Ford
FCA FIAT CHRYSLER AUTOMOBILES TESLA

Consumer and PC

Google nest Apple
hp DELL fitbit
Microsoft

Storage and Networking

Western Digital
Seagate
Finisar
CISCO

Set-Top Box and Operators

CISCO
ECHOSTAR
ARRIS
verizon DIRECTV
COMCAST dish

Industrial

GE Rockwell TYCO
Honeywell Whirlpool
SENSING THE DIFFERENCE

Distributors and EMS

FUTURE ELECTRONICS ARROW ELECTRONICS AVNET
JABIL FLEXTRONICS
SANMINA
Celestica

Enablement and Platform

intel Google
QUALCOMM
Microsoft

Automotive



Energy Efficiency

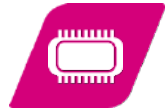


Infotainment



Safety (ADAS)

IoT



Processing



Power



Sense



Connect

Mass Market



Customer Base Expansion



Broad Ecosystem



System Push



Channel Engagement

Set-Top Box



4K Video



Broadband



Connectivity

Mobile & Infrastructure



Cloud Computing



Mobile

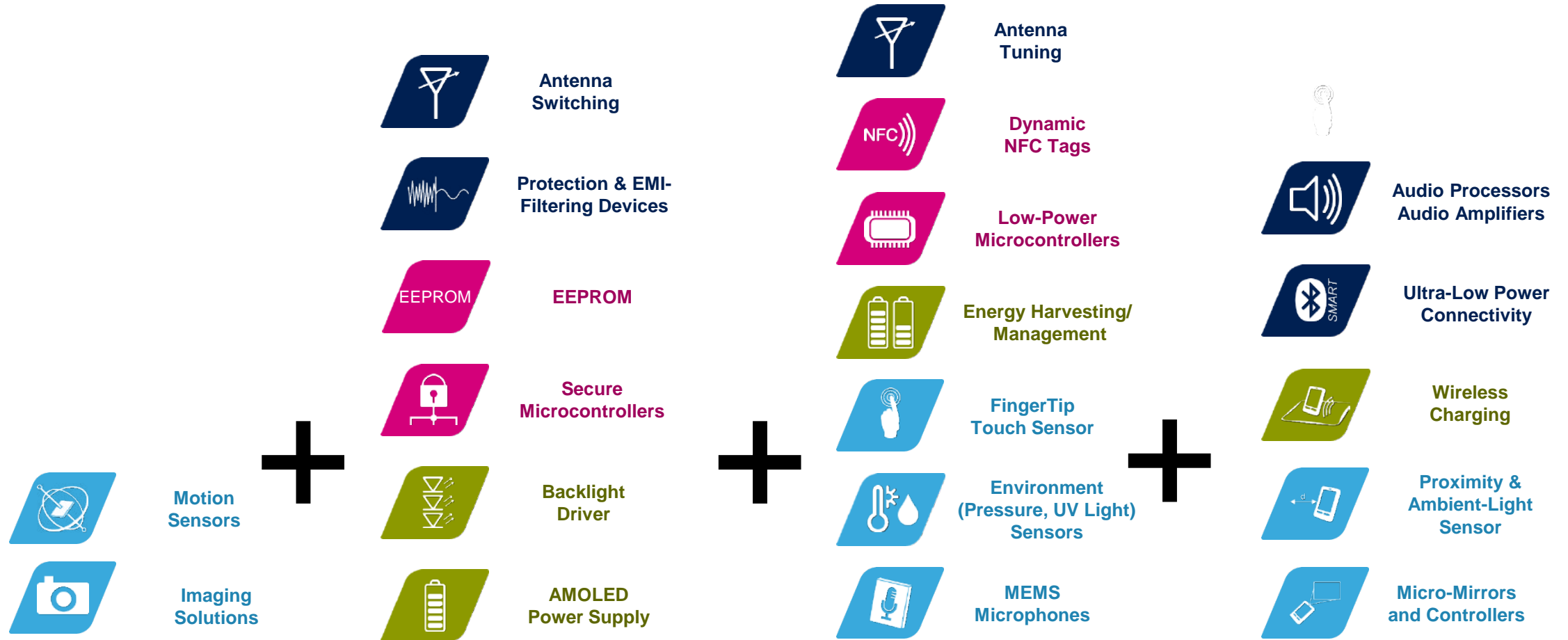


Security

Platforms



Expanding our Mobile Portfolio



Leading with the right products

- The leader in MEMS & sensors for consumer & mobile
- Leading in 32-bit low power microcontrollers
- Complementary power management and connectivity solutions

- Custom ASICs

The right sales model

- Broad market coverage
- Systems approach



Activity Monitor



Heart Monitor



Sports



Smart Watch

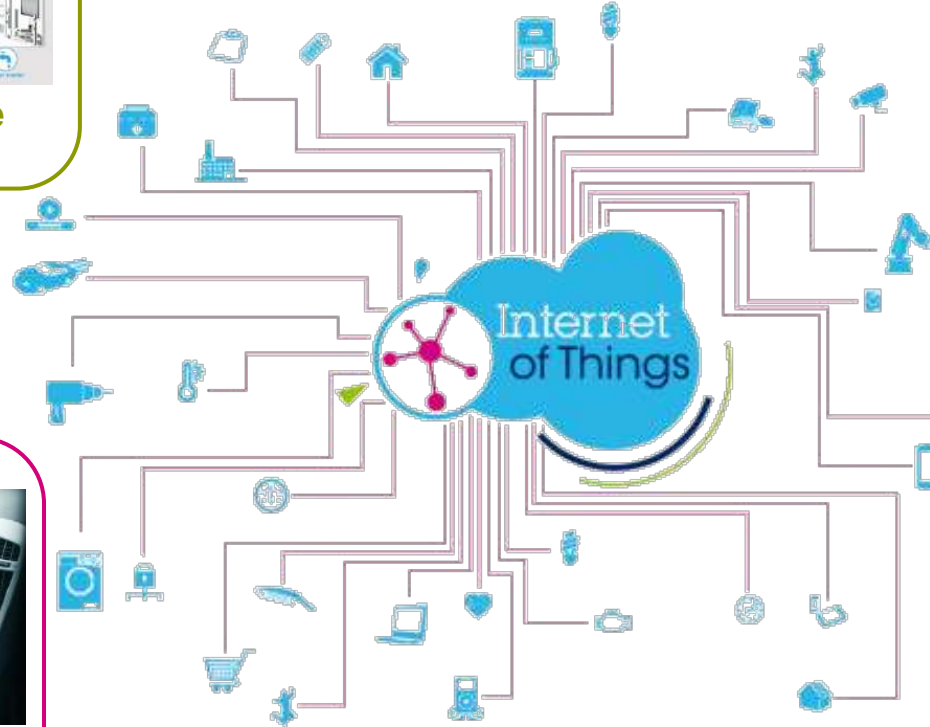
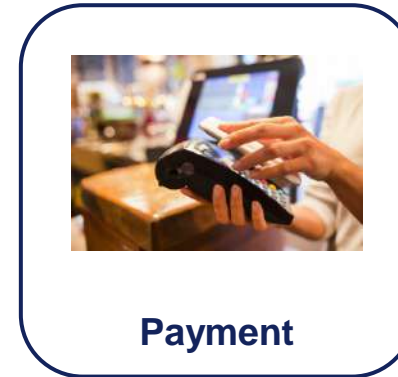


Accessories



Glasses & Goggles

Growth Opportunities beyond 2015



EMEA Region

Europe, Middle East, Africa

Paul Cihak

Executive Vice President, EMEA

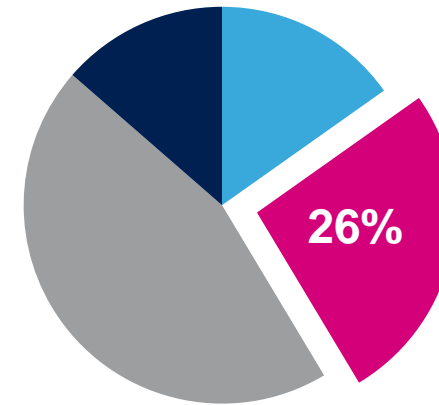


EMEA Region at a Glance

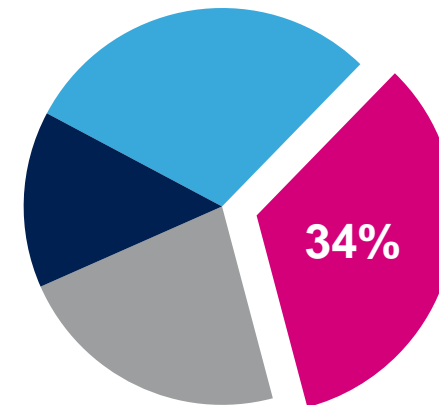


- ~25,400 Employees
- 5 Front-End manufacturing sites
- 2 Back-End plants
- Main design centers in 3 countries
- 7 Sales Organizations
- 18 Sales Offices

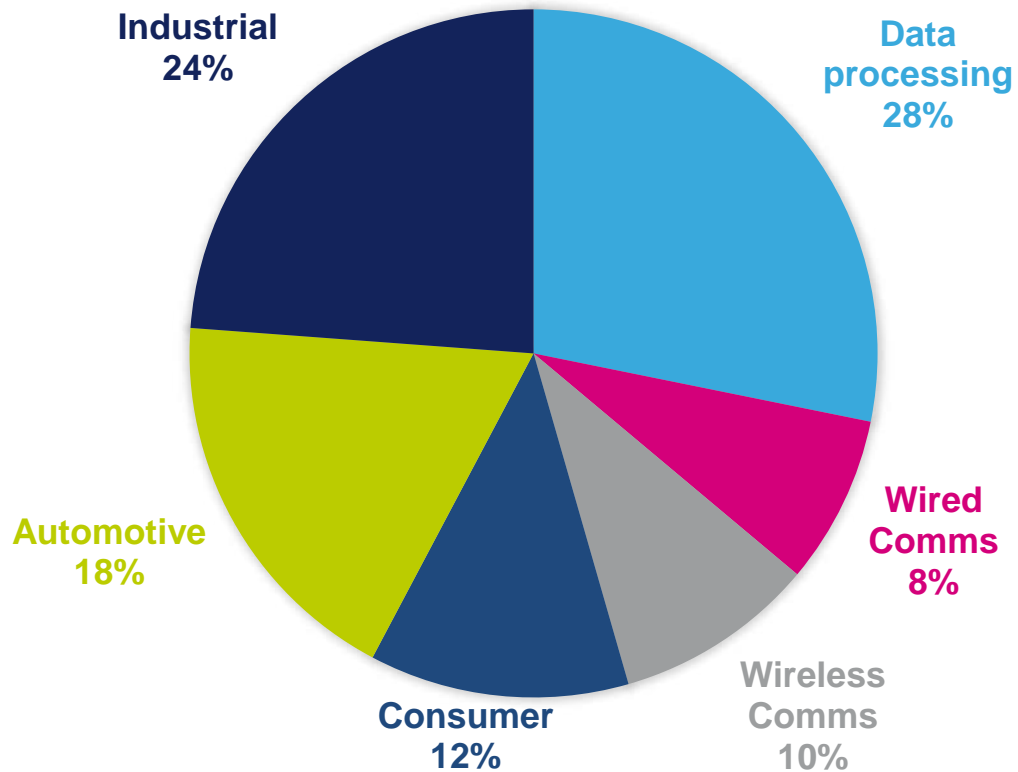
Sales by location of order shipment
FY2014



Sales by customer origin
FY2014



EMEA TAM 2014: \$37B



EUROPE

GDP Growth	2014	2015
	1.5%	1.9%

- Advanced Europe: Recovery in process
- Emerging and developing Europe: slower growth amid weak external demand

CIS

GDP Growth	2014	2015
	1.0%	-2.6%

- Geopolitical risks worsens outlook

MENA

GDP Growth	2014	2015
	2.4%	2.7%

- Growth still tepid across the Middle East & North Africa amid declining oil prices and continued policy uncertainty



Automotive

- Connected driving
- Assisted driving
- Green & safe driving



Secure Transactions

- SWP-SIM & eSE
- Banking & ID
- M2M



Industrial

- Smart home & building
- Industry 4.0
- Infrastructure



Set-Top Box

- UHD Servers & Clients
- Optimized HD HEVC STBs
- DOCSIS 3.x gateways

Automotive



Industrial



Secure Transactions



Set-Top Box & Operators



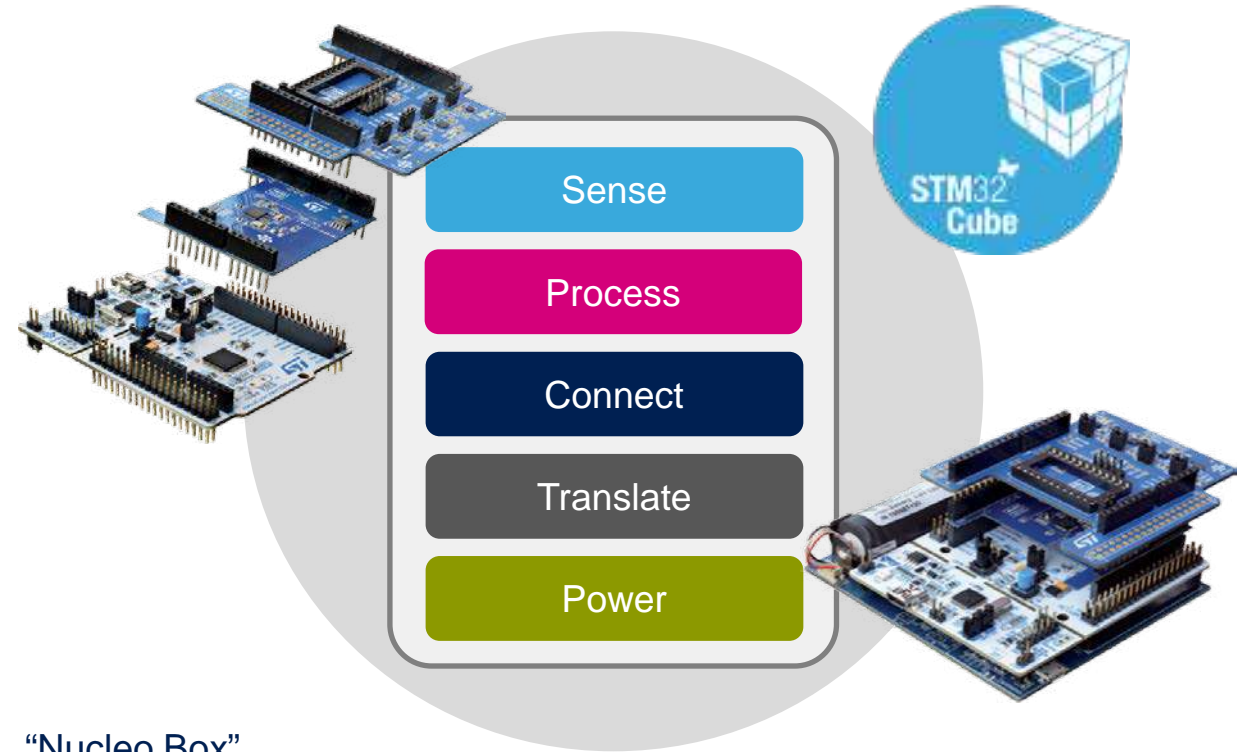
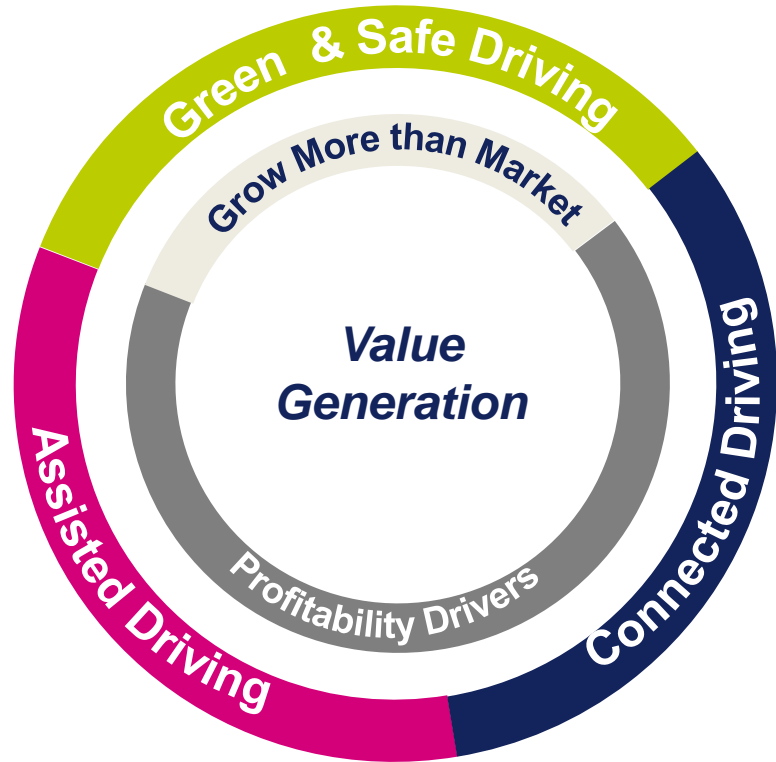
Wireless Infrastructure



Distributors & EMS



Sales & Marketing Initiatives



- Drive with our **lead customers** and **key carmakers** on mega trends and innovation
- New opportunities for **MEMs and SiC/GaN** in Automotive
- Enlarge customer base via the **mass market** to increase profitability
- “Nucleo Box” for mass market in collaboration with **Distribution partners**
- “Go to Market” with key products in **core verticals**
- Partnership with **emerging customers** in IOT and Automotive
- **STM32 Open Development Environment**

Growth Drivers 2015

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AUTOMOTIVE	SET-TOP BOX	HOME	WEARABLE
			
ASIC, ASSP, MCU, MEMS, LV MOS, IGBT	DOCSIS, HD HEVC, UHD	STM32, SPIRIT, BlueNRG, MEMS	STM32, MEMS, BlueNRG, NFC
AUTOMATION	METERING	LIGHTING	APPLIANCES
			
STM32, HV MOS, IGBT, IPS	STM32, STCOMET, STPM3 SPIRIT, BlueNRG, NFC	NFC EEPROM, STLUX, STLED	STM32, IGBT, IPM, VIPER, DRIVER MEMS

Growth Opportunities beyond 2015

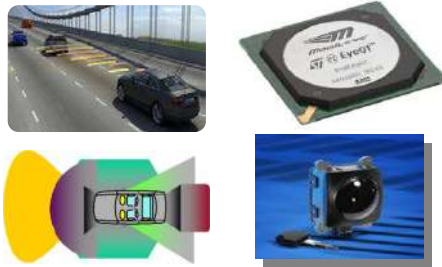
Automotive

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Green & Safe Driving

- Latest product offering for efficient engine management, transmission, charging
- Gaining share in steering, transmission, suspension by complete portfolio
- Full system offering for LED lighting, motor control, power management



Assisted Driving

- Extended offer on 24GHz and new 77/79GHz radar solutions for MMIC & BB
- Launch of next generation vision processing platform EyeQx with partner ME
- Launch of next generation camera sensor, ISP and MEMS for Automotive

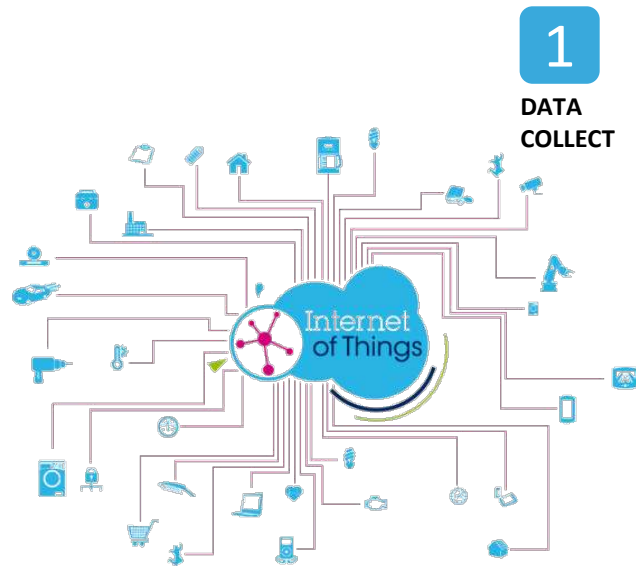


Connected Driving

- Unique offer for positioning with Teseo family and secure element solutions
- Connected car radio & telematics solutions with Accordo2 & Telemaco2 family
- Launch of unmatched V2X system solution co-developed with partner Autotalks







Growth Opportunities beyond 2015

Internet of Things









1
DATA
COLLECT

MEMS & Sensors

 Motion Sensors	 Environmental Sensors	 MEMS microphones
 Ranging & ambient light sensor	 FingerTip Touch Sensor	 MEMS mirrors






2
DATA
TRANSMIT

Connectivity, Audio and Interfaces

 Audio processors Audio amplifiers	 Ultra-low power connectivity	 Long Range connectivity
 Analog ICs	 Protection & EMI- filtering devices	 Positioning Systems







3
DATA
PROCESS

Microcontrollers & NFC

 Low-power microcontrollers	 Secure microcontrollers	 Sensor fusion
 Dynamic NFC tags	 EEPROM	

4
DATA
POWER

Power Management

 AMOLED power supply	 Backlight driver	 Power conversion
 Wireless charging	 Energy harvesting	 Thin film batteries

GC&SA Region Greater China & South Asia

Solomon Ng

Regional Director, Strategic Business Development
Greater China & South Asia Region

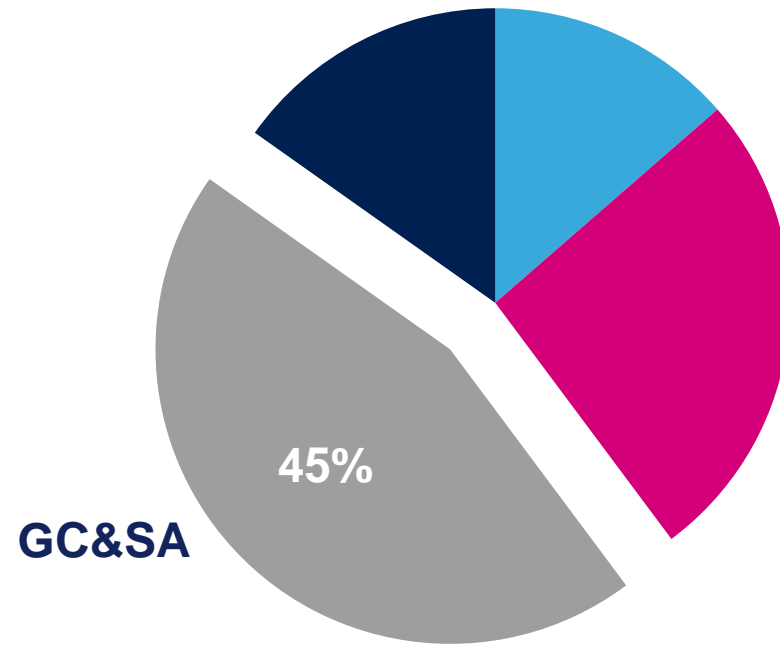


GC&SA Region at a glance

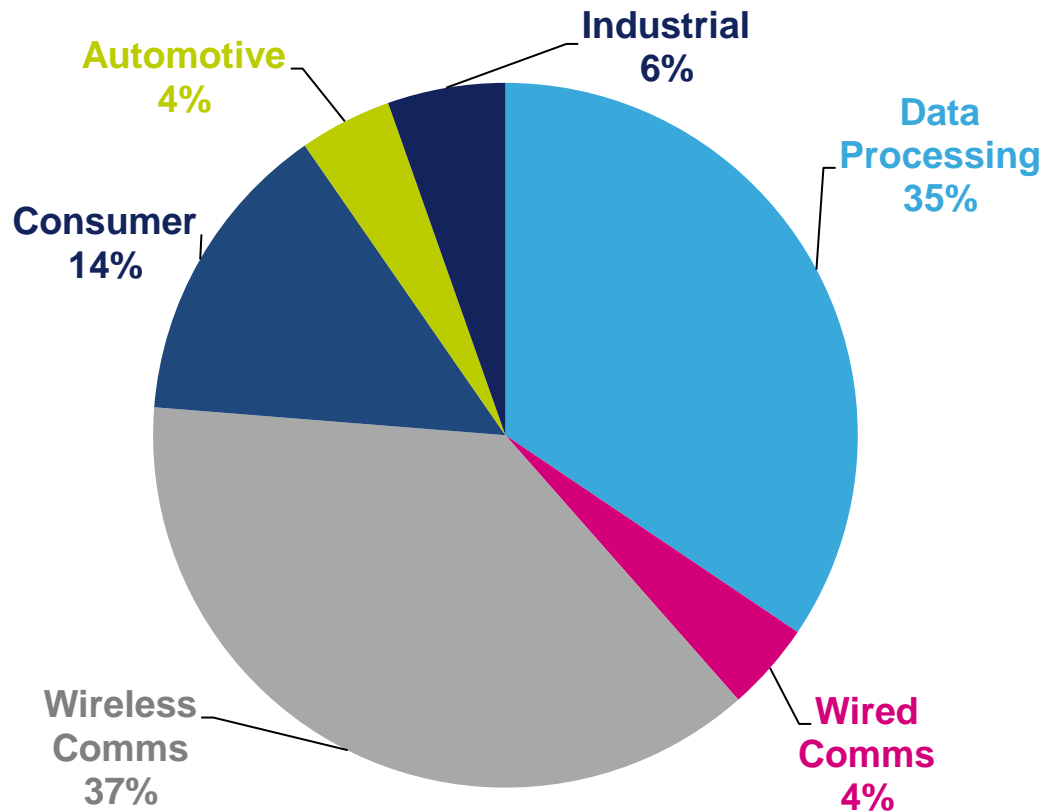


- ~17,000 employees
- 1 Front-End Fab
- 3 Back-End Plants
- 8 Sales Organizations
- 25 Sales Offices
- 4 R&D / IC Design Centers

Sales by location of order shipment FY2014



GC&SA TAM 2014 : \$153B



- 2015 GDP Growth Forecast : +6.1%
 - China +6.8% (2015F), +7.4% (2014)
 - Taiwan +3.8% (2015F), +3.7% (2014)
 - India +7.5% (2015F), +7.2% (2014)
 - ASEAN +4.9% (2015F), +4.6% (2014)
 - ANZ +2.8% (2015F), +2.9% (2014)
- Mostly emerging economies with increasing middle class
- For the electronic industry, some big corporations but mostly SMEs

GC&SA focus Applications

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Industrial

- Power supply
- Home appliances
- Lighting
- E-metering
- Welding



Smartphone

- User experience
- Secure payment
- Power management



Automotive

- Infotainment & telematics
- Body & comfort
- Powertrain & safety



Secure Transaction

- Banking card
- Mobile payment



Telecom Infrastructure

- Power supply
- COT (RFSOI, FD-SOI)



Wearable

- Fitness
- Wellness
- E-payment



Smart Home

- Set-Top Box & gateway
- Network attached storage
- Surveillance
- Home plug

GC&SA Customers

Smartphone



Distributors



EMS & ODM



Automotive



Industrial



Computer



Secure Transactions



Box & Gateway



2014 Success in Smartphones



HUAWEI



Ascend Honor 4
Honor 4X



Ascend G7



Ascend GX1



Ascend Mate7



Ascend P7



Honor X1



Honor 6



Honor 3X



Honor 3C



G730



C199



Xiaomi



Redmi Note
W/C and LTE



Mi3
W/C and T



Mi4



Mi PAD



htc



One W8



One E8 vogue



One M8
M8 Lifestyle



One M8 Eye



Butterfly 2



19 models



ZTE



V5 max



星星2号
Star 2



青漾2
Qingyang 2



Z max



小鲜
Xiaoxian



Blade Vec 4G



Q802C



Nubia X6



清漾
Qingyang



2 models



Xplay3S



Xshot



X5



Vibe Z2



Vibe X2 pro



Vibe X2



B8080-F



S810t



Elife E7



IUNI U2



MX4 Pro



ONEPLUS 1



大神 F1



Find7

Sales & Marketing Initiatives

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- Stronger Sales & Marketing organization
 - Created dedicated sales teams for key mobile customers and power customers
 - Added 7 sales offices in Greater China
 - Created an IoT excellence center in China
- Partnerships with key customers in mobile, power and automotive markets
 - Introduction of latest ST innovative solutions and roadmaps through dedicated technology days
 - Leveraging ST's global engineering resources to provide close support
 - Synergizing efforts from the various key programs to deliver complete customer solutions
- Mass Market through Distribution partners
 - STM32 Open Development Environment workshops with all distributors
 - Demand creation programs for motor control, lighting, power system, and wearable
 - Specific incentive programs for selected ST products

Growth Opportunities 2015



Smartphone

- Motion MEMS
- Photonic sensor
- AMOLED driver
- Touch controller
- MEMS microphone
- Sensor hub
- 4G/LTE RF tuner



Home Appliances

- Motor control
- Power management
- Sensors



Automotive

- Audio
- Positioning
- Telematics
- Airbag



Power Supply

- Server
- Data center
- Gaming
- Telecom



Wearable

- MCU
- Sensors



Drone

- Motor control
- Sensors



Secure Transactions

- Secure solutions



LED Lighting

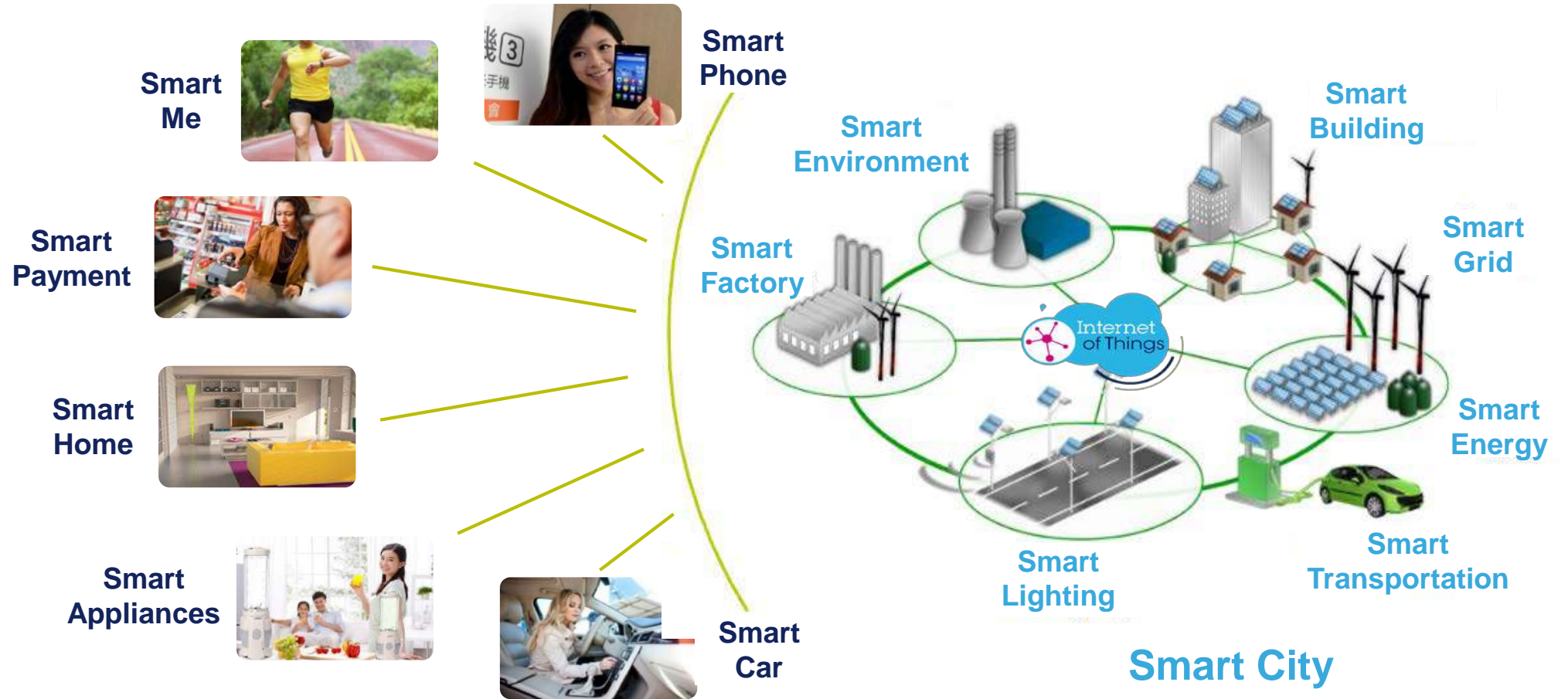
- Power devices
- Protection
- STLUX



Welding

- IGBT
- MCU

Growth Opportunities beyond 2015



Connecting machines, processes and people to make me, my family, my work and my city smarter

Japan & Korea Region

Marco Cassis

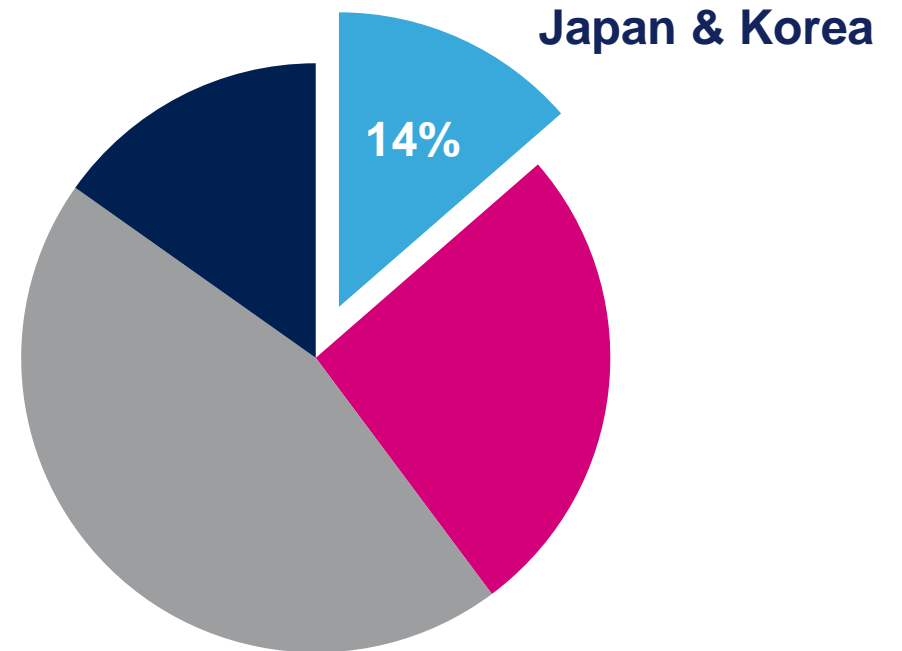
Executive Vice President
President, Japan and Korea Region



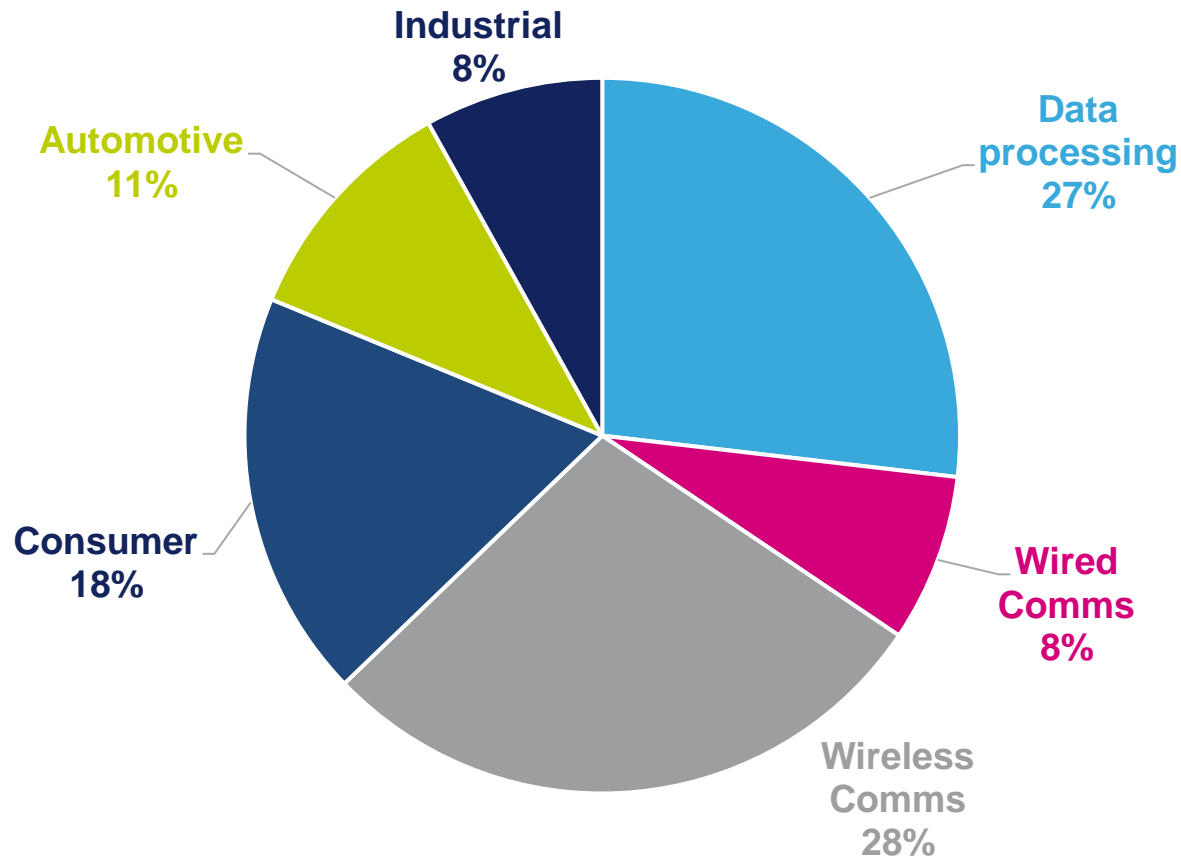
Japan & Korea Region at a glance



Sales by location of order shipment
FY2014



Japan & Korea TAM 2014: \$76B



Japan

GDP growth (%) in 2015 : +1.0%
in 2014 : -0.1%

- Slow growth but on moderate recovery path through improved domestic demand
- Electronics industry reorienting more towards automotive & industrial markets

South Korea

GDP growth (%) in 2015 : +3.3%
in 2014 : +3.3%

- Moderate growth anticipated for the export-driven economy with challenges of foreign currency exchange

Japan & Korea focus Applications



Automotive

- Fuel efficiency
- Active safety
- Car infotainment



Mobile & Wearable

- Smartphone
- Tablet
- Smartwatch
- Glasses
- Secure element



Industrial

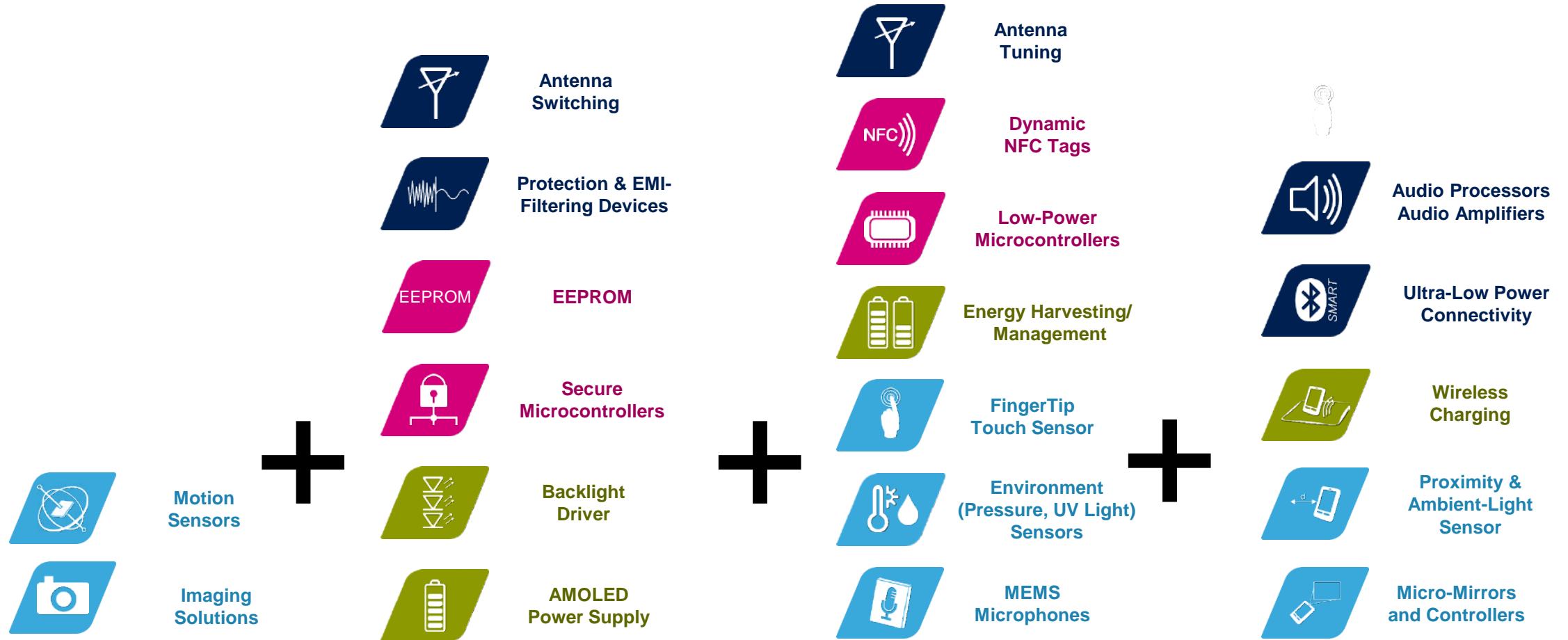
- Home appliance
- SMPS & motors
- Lighting
- Secure solutions



Consumer

- Set-Top Box & TV
- Gaming
- Printer
- Digital still camera

Expanding our Mobile Portfolio



Japan & Korea Customers

Automotive



Mobile & Wearable



Consumer



Industrial



Distributors & EMS

Japan : Sanshin (Axis), Chronix, Hakuto, Macnica, Tomen Electronics, Vitec

Korea : Arrow Electronics, Future Electronics, INSEM, WT(BSI) Microelectronics

Sales & Marketing Initiatives

224

- Strategic relationships with world leading customers in mobile, automotive and consumer markets delivering innovative solutions
 - Orchestrating ST's global engineering resources to provide close support
- Customer base expansion through mass market initiatives and strengthened sales channel
 - Offering ST solutions for wide range applications in "IoT"
 - Expanded distribution network by adding a new major distributor
 - Started on-line sales for mass market through Chip-One-Stop (Arrow subsidiary)
- New business development through collaboration with leading device manufacturers in the region to launch innovative solutions
 - Modules and COT

Growth Opportunities 2015

Mobile & Wearable



- Motion Sensors
- Touch Sensor
- Proximity & ambient light sensor
- Environmental Sensors
- AMOLED power supply
- Low-power 32-bit MCU

Expanding opportunities for sensor, sensor fusion, power management and display

Automotive



Powertrain, Body, Safety, Infotainment

- Power devices
- BCD Products (Drivers, System Power supply)
- Audio Amplifier
Audio Processor
Satellite Receiver
- 32-bit MCU
- Sensors

Enhancing presence of automotive products at leading customers

Mass Market



- 32-bit MCU
- Sensors
- Power devices
- Advanced Analog

Expanding access to customers in mass market through distribution channels

Growth Opportunities beyond 2015

- **Assisted Driving** (ADAS and safety)
- **Connected driving** (infotainment and telematics)
- **Green driving** (engine management, fuel efficiency, electrification)



Smart Driving

- **Mesh network**
- **Smart environments** (solar, energy harvesting, smart lighting, smart grid, smart waste)
- **Smart factory, robot, agriculture**
- **Smart money, finance**

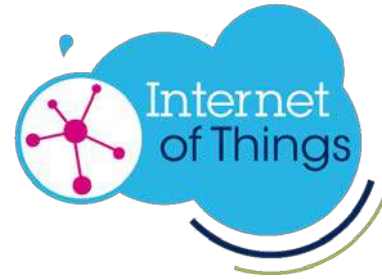


Smart City

- **Energy management** (smart meter, lighting, energy monitoring, solar)
- **Connected house** (home gateway, STB, smart home appliances)
- **Smart healthcare**



Smart Home



Smart Things


- Mobile
- Tablet
- Wearable
- Terminals
- Nodes


Key Components

 Sensors

 Microcontrollers, Memories & Security

 Ultra-low power connectivity

 Analog and mixed signal components

 Power and energy management

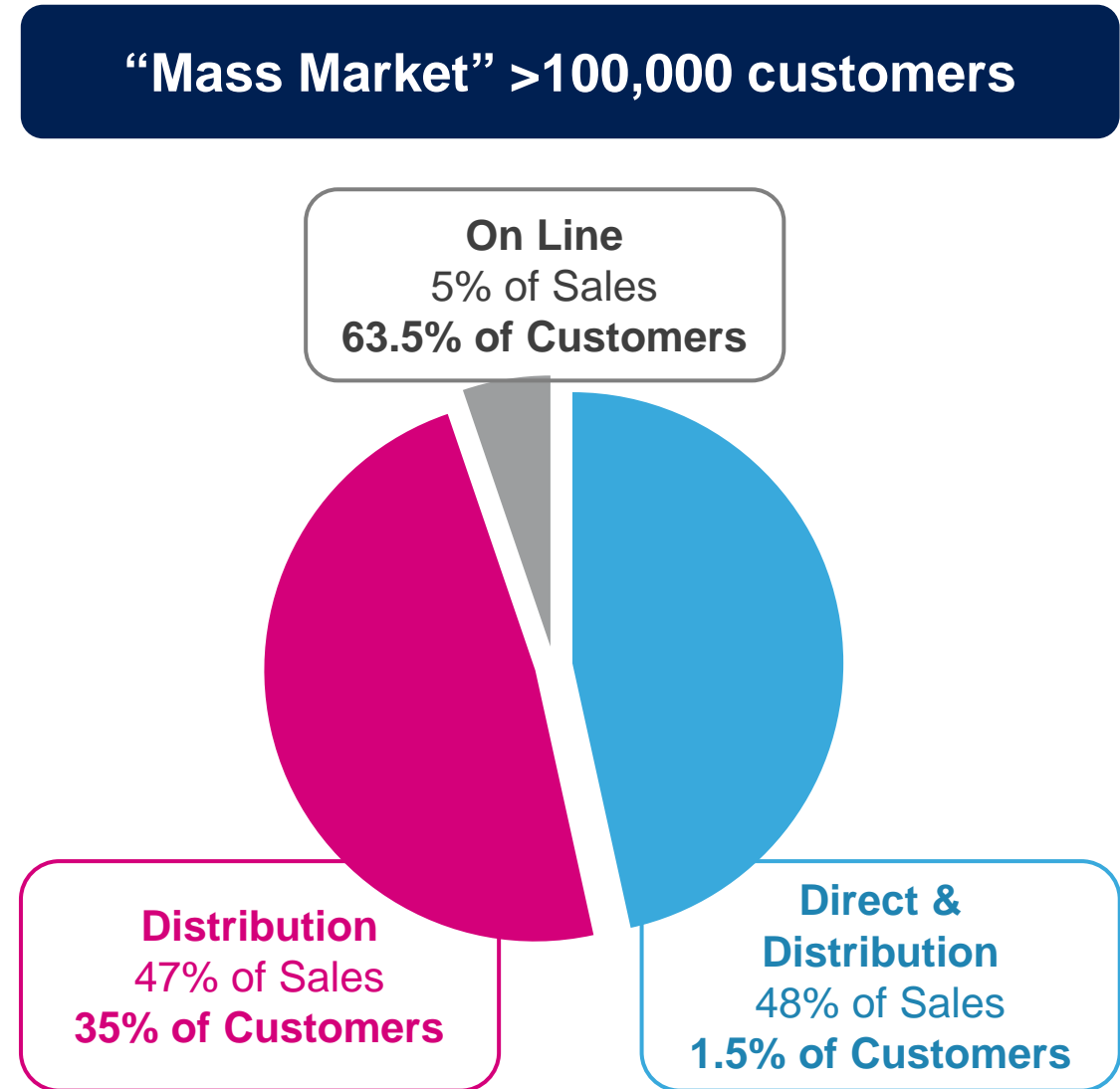
Mass Market

Paul Grimme

Executive Vice President,
Mass Market and Online Marketing Programs



- The market which encompasses **thousands of customers** of ST outside of our top accounts
 - A broad collection of markets served by ST
 - Different channels used for engagement
 - More than 70% of revenues through distribution
- Diversified customer base brings **higher stability**
 - Multiple market segment cycles
- **Higher margin** potential
 - Distribution margins approximately 5+% better than ST average
- A different method of product development and promotion



2014 Mass Market for ST

229

Revenue: \$2.4B

Year over Year growth: +5%

% of ST Revenue: ~33%

Expand our customer base

Core Key Accounts
Channel Accounts
Online Accounts

- >1600 Core Key Accounts (CKA)
 - CKA revenue growth: +9% YoY
- Channel accounts
 - ~1000 new accounts to ST
- ~\$40M in business identified from online leads
- Design win funnel growth >+50%

Promoting leading applications & products

Boost demand creation with full "Go to Market" series of actions

- STM32 Open Development Environment Launched
 - ~105k STM32 Nucleo developer boards shipped
 - ~14k STM32 Nucleo Expansion boards shipped in 4Q
- >800 new products released for Mass Market

Stronger collaboration with channel partners

Intensified cooperation with distributors and certified partners

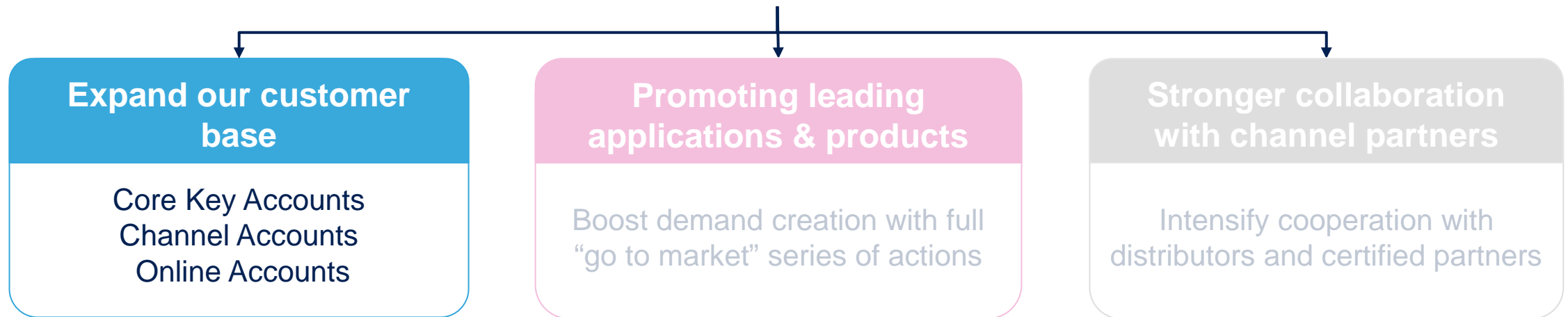
- Distribution: 31% of ST total revenues for 2014 (32% in Q4)
- 2014 POS* increased by +6%



Mass Market Programs

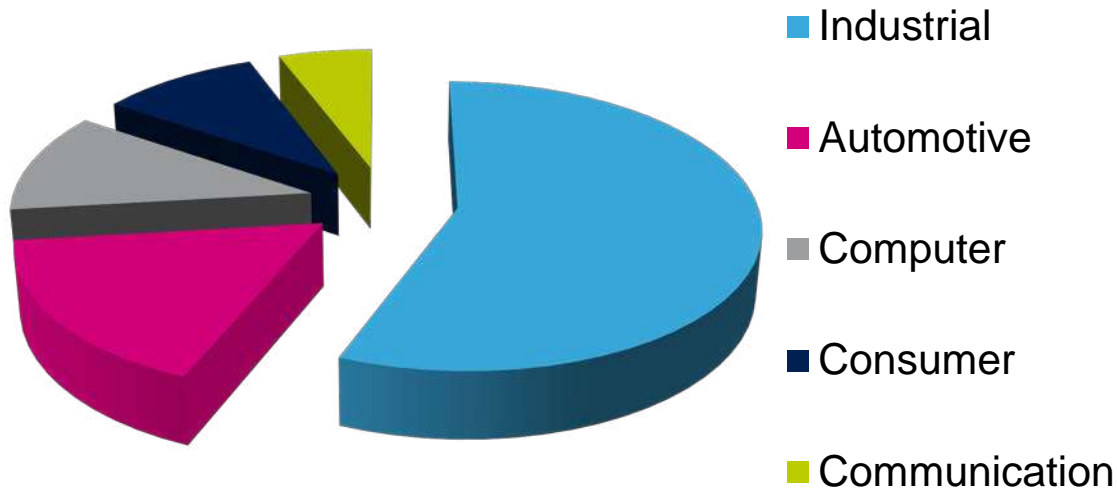
Our objective is to increase the mass market revenues and continuously gain market share

Based on three pillars



Core Key Account Segments

Number of Customers by Application



Total Number of Core Key Accounts: >1600

Americas:	~400
EMEA:	~600
Japan & Korea:	~200
Greater China & South Asia:	~400

- >1600 accounts with dedicated ST resource coverage regardless of channel
- Regular business plan reviews and monitored results
- Judged to be relevant to ST and capable of producing new design wins to grow
- 2014 Core Key Accounts grew +9%

Channel Account Development

Ecosystem

STM32 Open Development Environment



Training



Software



Evaluation Boards



+

Application

Sensors

Bluetooth Low Energy

SubGHz Transceiver

MCU

Op Amp

LED driver

Power Management

+

Products

Motion Sensors

MEMS Microphones

Environmental Sensors

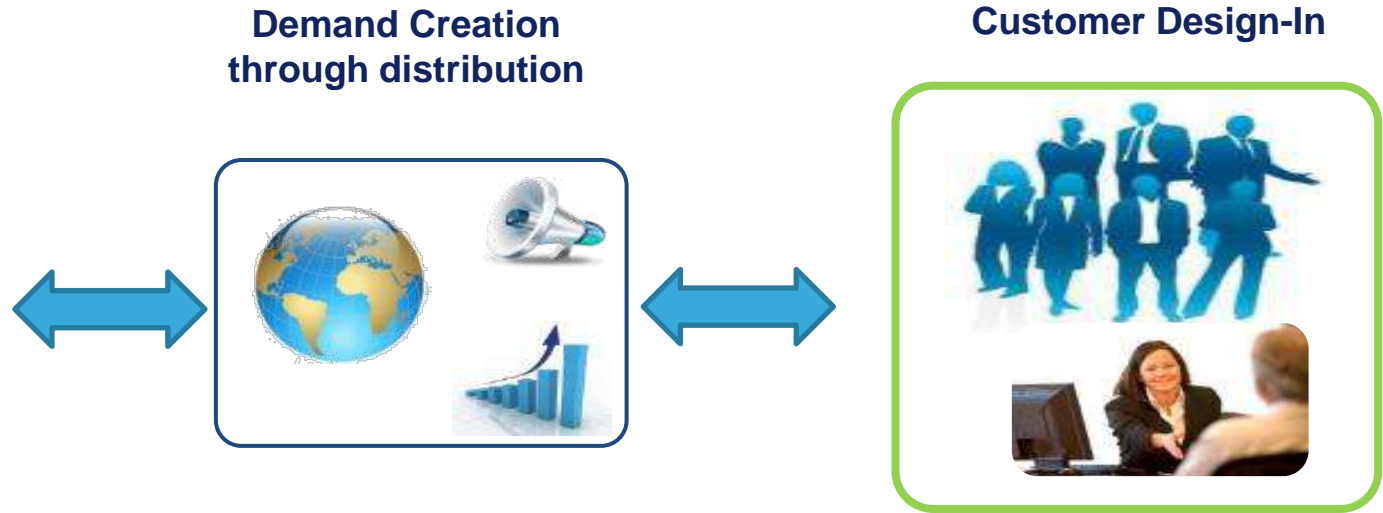
Power Conversion

Bluetooth Smart

SubGHz

NFC

MCU



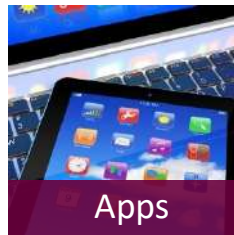
- 35,000 accounts served entirely through distribution
- Programs deployed at distributors
 - Designed to create additional market share in distribution TAM by 2016
 - ~1000 new customers in 2014
 - Global deployment of ST/Distributor engagement to grow the channel accounts

Online Account Development



 **st.com**
life.augmented

- More than 100k registered users of catalog and ST sites
- Marketing information push and customization
- Lead generation capture and new account/new business follow-up engine



- Sales Leads From:**
- Download software (downloaded)
 - Online Free/Paid Samples (shipped)
 - eDesign Studio (project saved)
 - Purchase Tools & Boards (shipped)
 - Other interest expressed and approved

Through 1Q15: Business opportunity valued at ~\$47M

Mass Market Programs

Our objective is to increase the mass market revenues and continuously gain market share

Based on three pillars



Expertise in Key Functions for Applications

Strong expertise in key functions

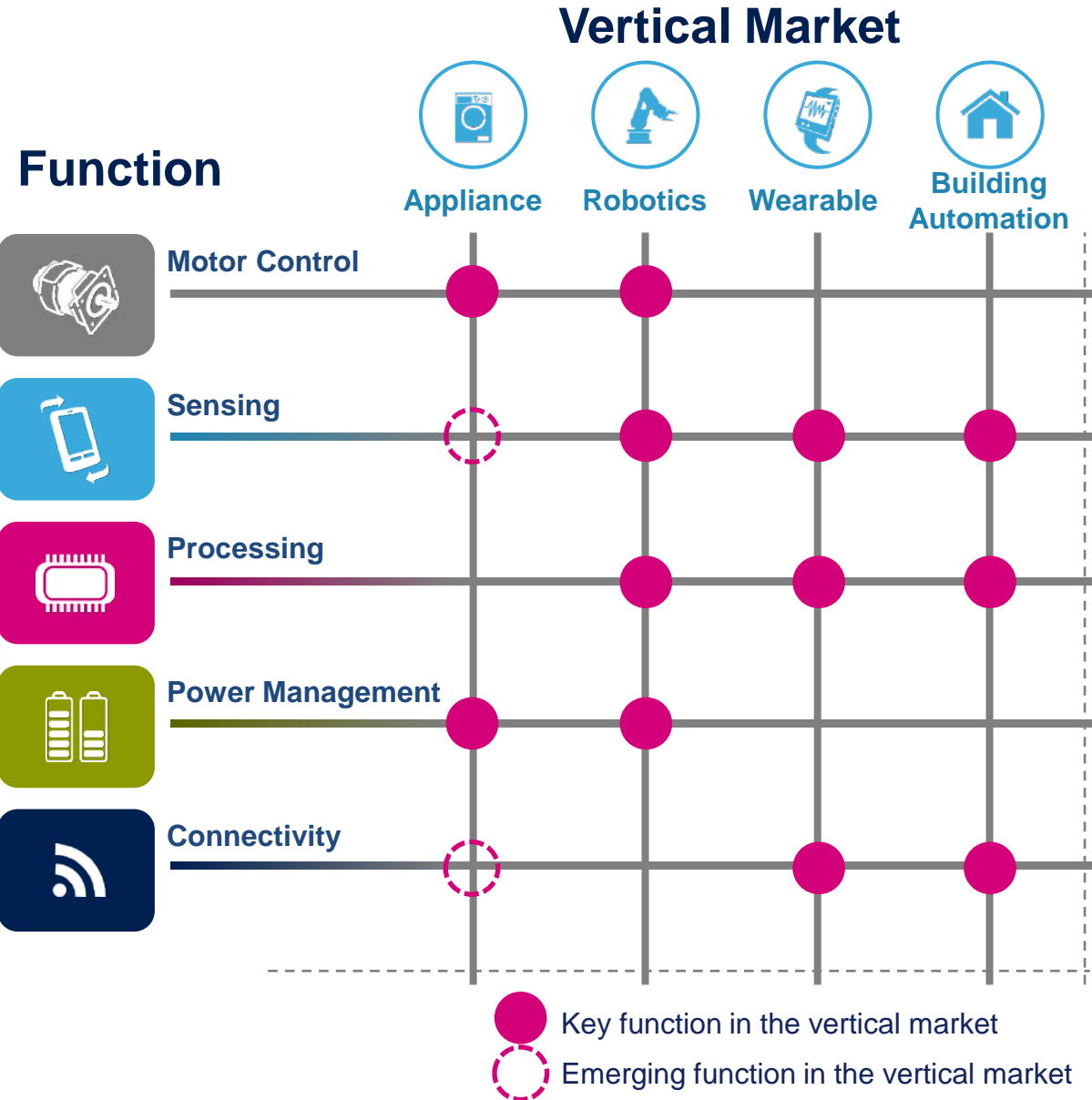
- Motor control, sensing, processing, power management, connectivity, ...

• A network of development resources

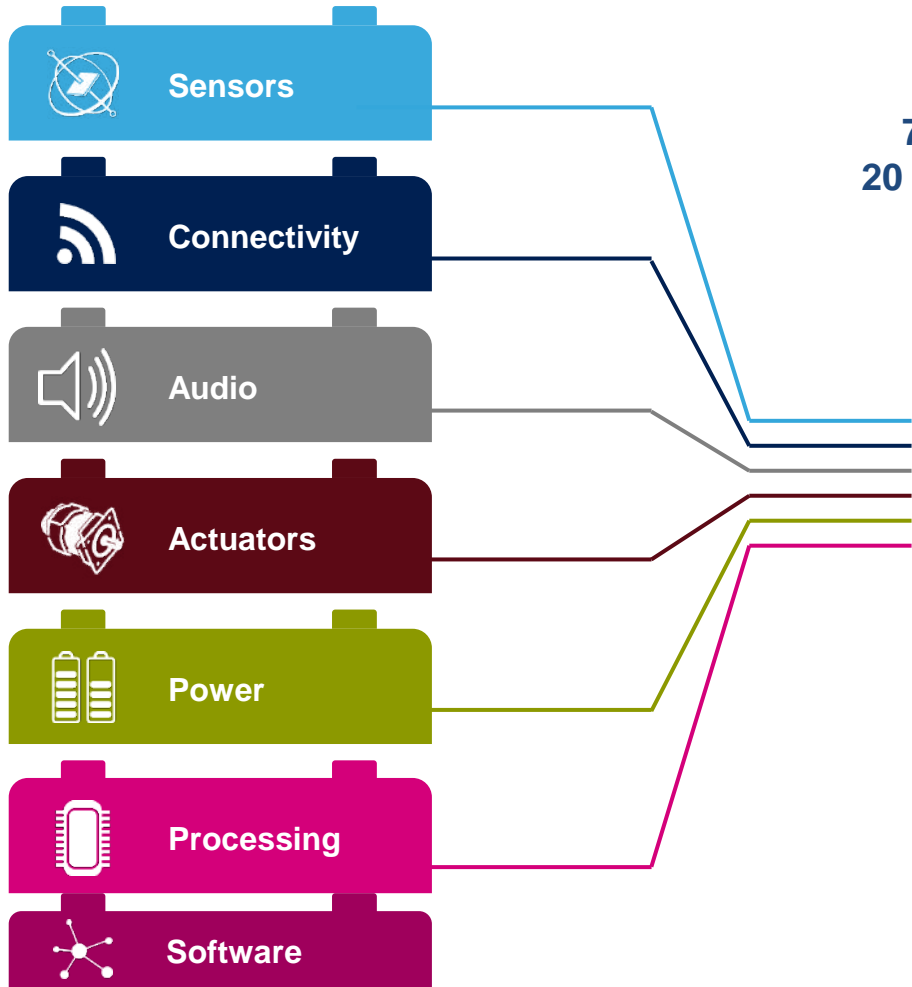
- Central coordination of Central Labs experts
- Regional resources developing further applications expertise for geographic needs
- Partnership with third parties
 - Distributors
 - Design Houses

Access to a fast and easy application development environment

- A wide range of platforms and reference designs
- Accelerate product development with the STM32 Open Development Environment



STM32 Open Development Environment



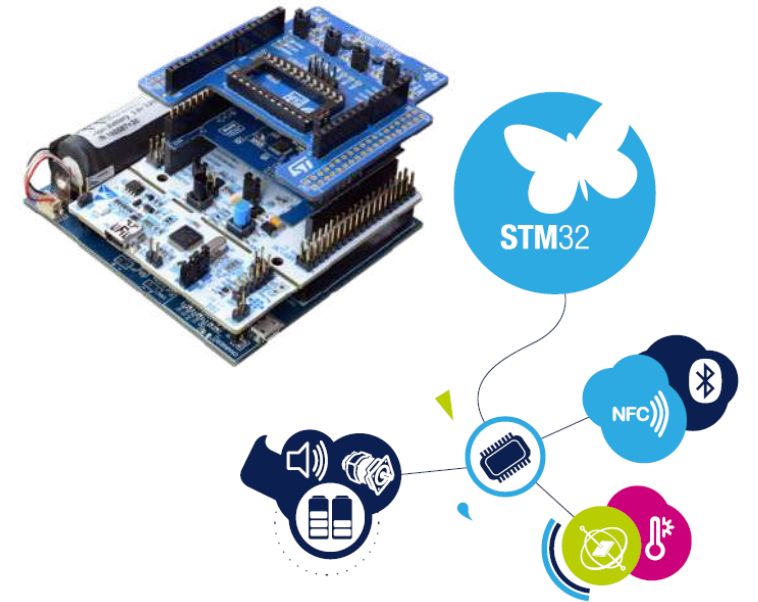
12 Processor Boards
7 Expansion Boards now,
20 Expansion Boards by 4Q15

- Motion & Environ. Sensors
- Bluetooth Low Energy
- Sub-GHZ
- NFC
- Microphone
- Motor control
- Microcontroller

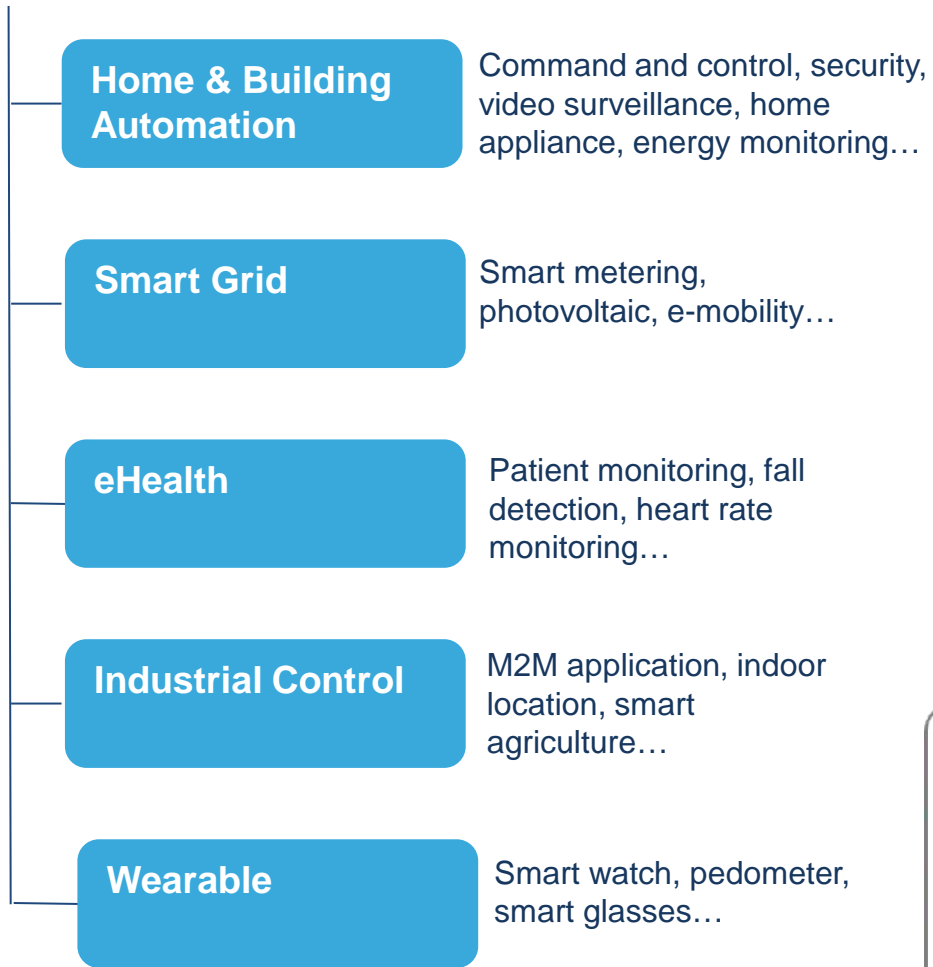
Integrated Development Environment and Middleware



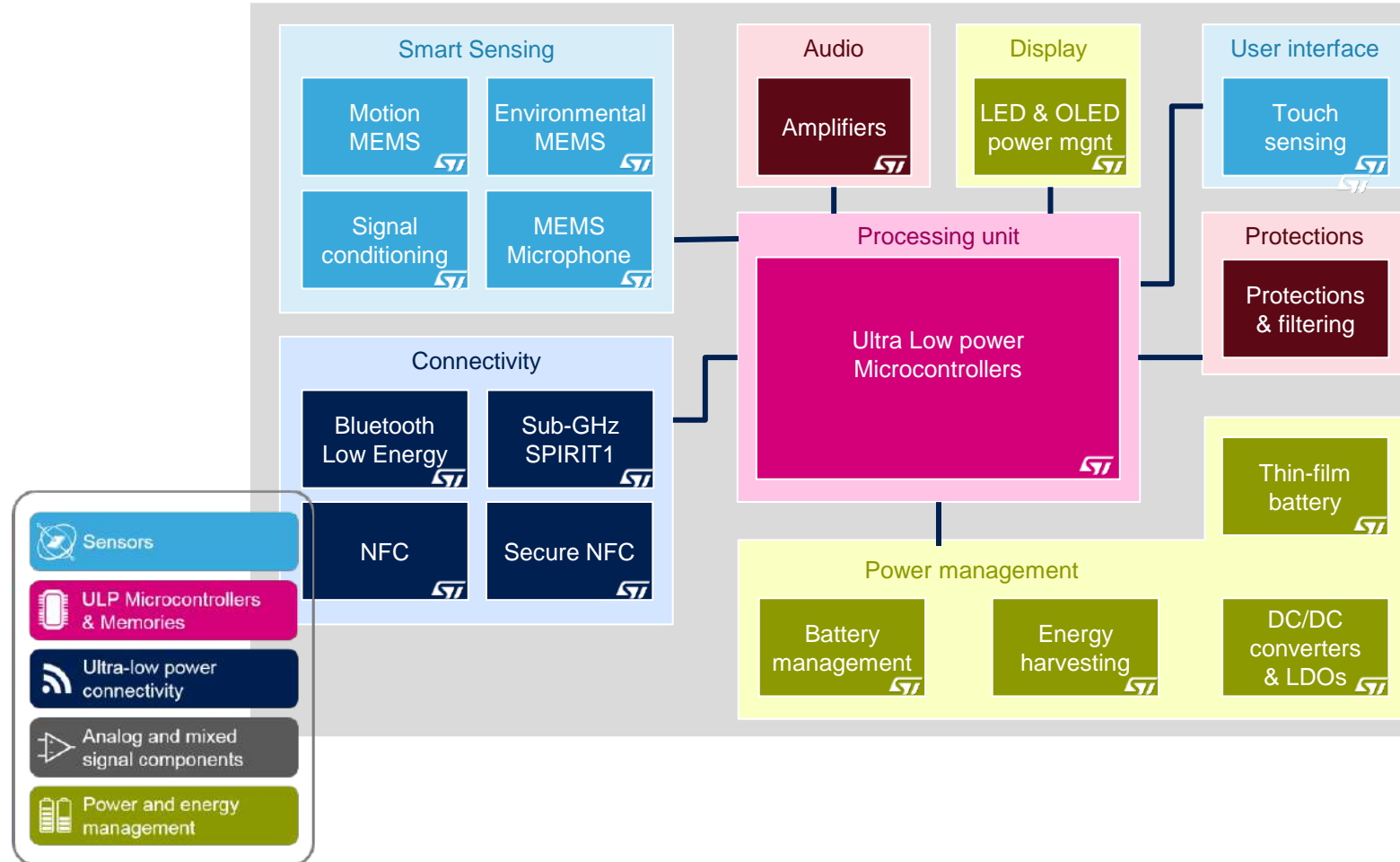
STM32 Open Development Environment



IoT



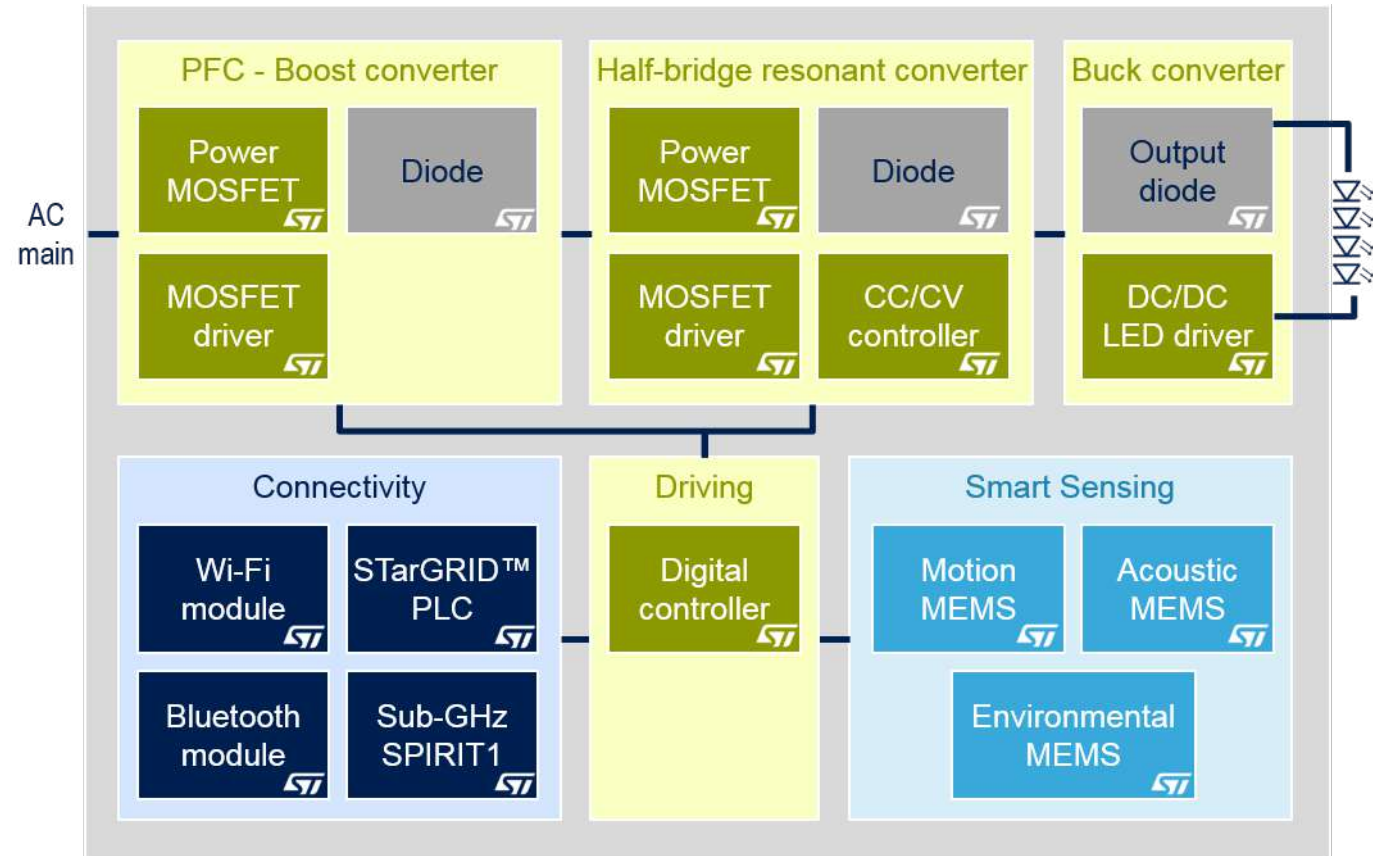
A complete offer of ST devices for wearable applications



Lighting

- Smart street lighting** Networked architectures for smart cities
- LED display and signage** Tight LED current regulation accompanied with dimming and diagnostic
- LED general illumination** Compact and efficient solution
- LED backlighting** Superior brightness control

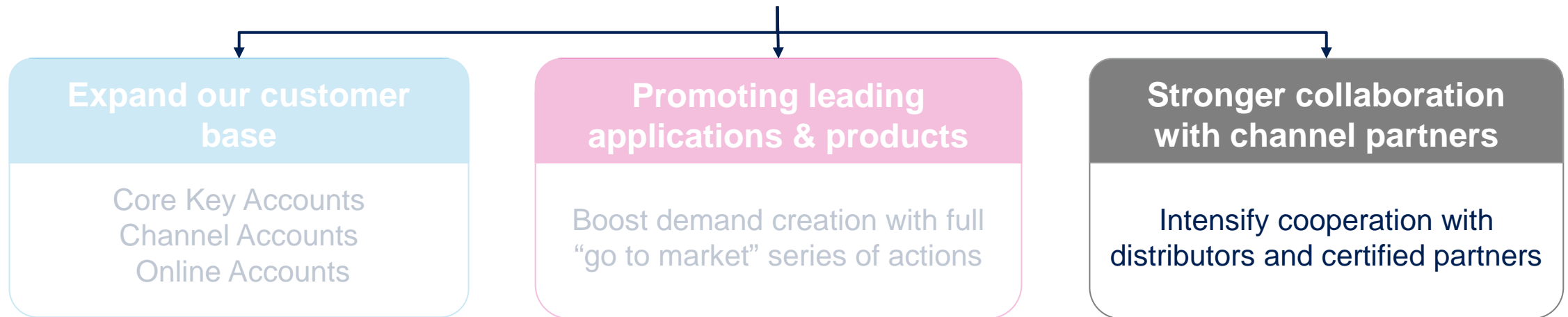
A complete offer of ST devices for Smart LED Lighting



Mass Market Programs

Our objective is to increase the mass market revenues and continuously gain market share

Based on three pillars



Distribution – Vital to Mass Market Success

- Global network of Distributors and Value Added Resellers
 - Extended marketing reach via joint promotion programs
 - Leverage Distribution field resources to engage new customers
 - Stronger technical support from distributor teams thanks to increased knowledge of ST products and application solutions
- Enhanced design support through collaboration with third parties (design houses, training centers, ...)
- Improved collaboration and expanded relationships with online Distributors to acquire interest and design-in activity during sample and low volume phases of customer projects
- Improved technical support by ST to the Mass Market including Distribution field resources



Catalog Distributors

Digi-Key Corporation, Farnell element14, MOUSER ELECTRONICS, RS

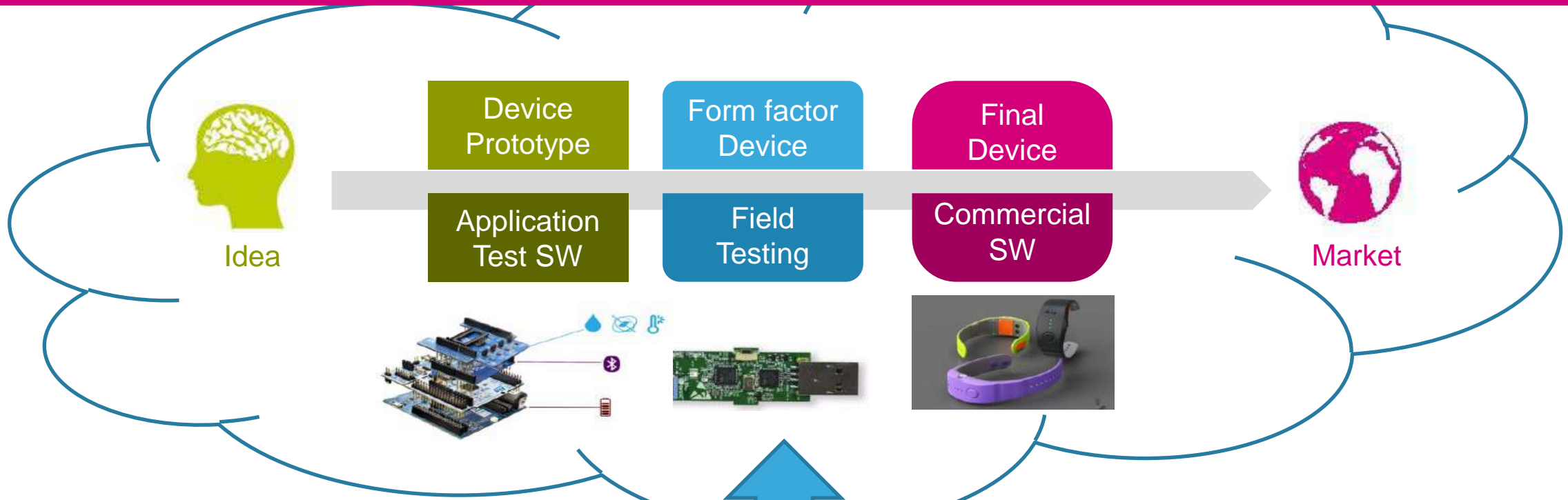
Top 4 Distributors*

AVNET®, WT MICROELECTRONICS, YOSUN GROUP

*Listed alphabetically

3rd Party Driven Ecosystem

>100 3rd Party Relationships



- Mass Market offers a great opportunity to grow
 - **Largest Market** of ST – Over 100,000 customers
 - **Stability of demand** across multiple market segments
 - Ability to generate **better margins**
 - **Targeted to grow** faster than the company average
- Unique position to win in the Mass Market
 - Breadth and depth of **product portfolio**
 - **Expertise** in multiple key functions and application **know-how**
 - **Development environment** allowing faster prototyping and **time to market**
 - **Strong partnership focus** with distribution and 3rd parties
- Focus on Mass Market across all businesses
 - Structure and process with uniform practices
 - Strong global coordination to drive growth